

Search String: ((PBD:[BEG to 2012-12-31] NOT PBC:(US)) OR (APD:[BEG to 2012-12-31] AND PBC:(US))) and D: ((copper and polymer) and (glass wp substrate)) and CPC: H01L21/00\$

Record Number	Publication/Issue Date	Title	Inventors	Applica tion No.	Filing/Applica tion Date
US8859437B2	14-Oct-2014	Solution for etching a thin film transistor and method of manufacturing the same	LI YUANYUAN (US); SUN KAIGE (US); JACKSON THOMAS N (US)	US201 213731 728A	31-Dec-2012
US9871034B1	16-Jan-2018	Semiconductor device and structure	OR BACH ZVI (US); CRONQUIST BRIAN (US)	US201 213731 108A	30-Dec-2012
US9514983B2	6-Dec-2016	Cobalt based interconnects and methods of fabrication thereof	JEZEWSKI CHRISTOPHER J (US); CLARKE JAMES S (US); INDUKURI TEJASWI K (US); GSTREIN FLORIAN (US); ZIERATH DANIEL J (US)	US201 213730 184A	28-Dec-2012
US9520378B2	13-Dec-2016	Thermal matched composite die	ALEKSOV ALEKSANDAR (US); LIFF SHAWNA M (US)	US201 213725 356A	21-Dec-2012
US2015137368A1	21-May-2015	LANDING STRUCTURE FOR THROUGH-SILICON VIA	PELTO CHRISTOPHER M (US); BRAIN RUTH A (US); LEE KEVIN J (US); LEATHERMAN GERALD S (US)	US201 414563 926A	8-Dec-2014
US9093501B2	28-Jul-2015	Interconnection wires of semiconductor devices	SINGH SUNIL KUMAR (IN); YAO HSIN CHIEH (TW); LEE CHUNG JU (TW); LEE HSIANG HUAN (TW)	US201 414322 330A	2-Jul-2014
US9355905B2	31-May-2016	Methods and structure for carrier-less thin wafer handling	UZOH CYPRIAN EMEKA (US); MONADGEMI PEZHMAN (US); NEWMAN MICHAEL (US); WOYCHIK CHARLES G (US); CASKEY TERRENCE (US)	US201 514722 672A	27-May-2015
US10115606B2	30-Oct-2018	Methods of promoting adhesion between underfill and conductive bumps and structures formed thereby	BAI YIQUN (US); WEI YUYING (US); KRISHNAN ARJUN (US); RAMALINGAM SURIYAKALA (US); XIU YONGHAO (US); CANHAM BEVERLY J (US); NAGARAJAN SIVAKUMAR (US); JAYARAMAN SAIKUMAR (US); ANANTHAKRISHNAN NISHA (US)	US201 615139 265A	26-Apr-2016
US2017179099A1	22-Jun-2017	PACKAGE WITH DIELECTRIC OR ANISOTROPIC CONDUCTIVE (ACF) BUILDUP LAYER	HU CHUAN (US); XU DINGYING (US); TOMITA YOSHIHIRO (JP)	US201 715401 717A	9-Jan-2017
US2014170857A1	19-Jun-2014	Customizing Etch Selectivity with Sequential Multi-Stage Etches with Complementary Etchants	LANG CHI I (US); HUANG SHUOGANG (US); LOWE JEFFREY CHIH HOU (US); SCULAC ROBERT ANTHONY (US)	US201 213718 995A	18-Dec-2012
US11094622B2	17-Aug-2021	Packaged semiconductor devices and methods of packaging thereof	CHEN HSIEN WEI (TW)	US201 916390 701A	22-Apr-2019
US9318438B2	19-Apr-2016	Semiconductor structures comprising at least one through-substrate via filled with conductive materials	BOSSLER MARK A (US); GANDHI JASPREET S (US); GAMBEE CHRISTOPHER J (US); PARKER RANDALL S (US)	US201 514679 845A	6-Apr-2015
US11099152B2	24-Aug-2021	Backside CMOS compatible BioFET with no plasma induced damage	LIU YI SHAO (TW); CHENG CHUN REN (TW); CHEN CHING RAY (TW); CHANG YI HSIEN (TW); LAI FEI LUNG (TW); CHENG CHUN WEN (TW)	US201 916679 015A	8-Nov-2019

US8987859B2	24-Mar-2015	Techniques for enhancing dielectric breakdown performance	PLEKHANOV PAVEL S (US); FISCHER KEVIN J (US); FU QIANG (US); HIRAMATSU HIROKI (US)	US201 213693 602A	4-Dec-2012
US9406598B2	2-Aug-2016	Package with a fan-out structure and method of forming the same	MAO YI CHAO (TW); CHANG CHIN CHUAN (TW); HUNG JUI PIN (TW); LIN JING CHENG (TW)	US201 414319 678A	30-Jun-2014
US9157014B2	13-Oct-2015	Adhesives including a filler material and related methods	LUO SHIJIAN (US); LI XIAO (US)	US201 213689 144A	29-Nov-2012
US10283437B2	7-May-2019	Metal density distribution for double pattern lithography	SCHULTZ RICHARD T (US); ROWHANI OMID (CA); TUNG CHARLES P (US)	US201 213686 184A	27-Nov-2012
US10283400B1	7-May-2019	Semiconductor device package and manufacturing method thereof	KELLY MICHAEL G (US); HUOMOELLER RONALD PATRICK (US); DO WON CHUL (KR); HINER DAVID JON (US)	US201 815973 329A	7-May-2018
US8796072B2	5-Aug-2014	Method and system for a semiconductor device package with a die-to-die first bond	KELLY MICHAEL G (US); HUOMOELLER RONALD PATRICK (US); DO WON CHUL (KR)	US201 213678 012A	15-Nov-2012
US8802499B2	12-Aug-2014	Methods for temporary wafer molding for chip-on-wafer assembly	KELLY MICHAEL G (US); HINER DAVID JON (US); HUOMOELLER RONALD PATRICK (US)	US201 213678 026A	15-Nov-2012
US10090234B2	2-Oct-2018	Semiconductor device package and manufacturing method thereof	KELLY MICHAEL G (US); HUOMOELLER RONALD PATRICK (US); DO WON CHUL (KR); HINER DAVID JON (US)	US201 715413 767A	24-Jan-2017
US9000549B2	7-Apr-2015	Spatially distributed CdS in thin film photovoltaic devices and their methods of manufacture	GOSSMAN ROBERT DWAYNE (US); FELDMAN PEABODY SCOTT DANIEL (US); KOREVAAR BASTIAAN ARIE (US)	US201 213676 550A	14-Nov-2012
US8809113B2	19-Aug-2014	Solution-processed metal-selenide semiconductor using selenium nanoparticles	VAIL SEAN ANDREW (US); KOPOSOV ALEXEY (US); LEE JONG JAN (US)	US201 213674 005A	10-Nov-2012
US2014134838A1	15-May-2014	METHODS OF ANNEALING A CONDUCTIVE TRANSPARENT OXIDE FILM LAYER FOR USE IN A THIN FILM PHOTOVOLTAIC DEVICE	GOSSMAN ROBERT DWAYNE (US); OSBORN KALI NICOLE (US); PENG HONGYING (US)	US201 213673 097A	9-Nov-2012
US9159653B2	13-Oct-2015	Copper interconnect structures and methods of making same	YANG CHIH CHAO (US); BERGENDAHL MARC A (US); HORAK DAVID V (US); LI BAOZHEN (US); PONOTH SHOM (US)	US201 414293 116A	2-Jun-2014
US11501978B2	15-Nov-2022	Semiconductor device and manufacturing method thereof	DO WON CHUL (KR); PARK DOO HYUN (KR); PAEK JONG SIK (KR); LEE JI HUN (KR); SEO SEONG MIN (KR)	US202 117234 109A	19-Apr-2021
US9129967B2	8-Sep-2015	Integrated circuit device having a copper interconnect	TSAI CHENG HSIUNG (TW); LEE CHUNG JU (TW); HUANG TSUNG MIN (TW)	US201 213668 837A	5-Nov-2012
US9064934B2	23-Jun-2015	Barrier layer for copper interconnect	LIN YU HUNG (TW); CHOU CHI YU (TW); LEE KUEI PIN (TW); LIEN CHEN KUANG (TW); HSIAO YU CHANG (TW); LIANG YAO HSIANG (TW); CHANG YU MIN (TW)	US201 414495 566A	24-Sep-2014

US9385075B2	5-Jul-2016	Glass carrier with embedded semiconductor device and metal layers on the top surface	BREYMESSER ALEXANDER (AT); BROCKMEIER ANDRE (AT); DIELACHER FRANZ (AT); SANTOS RODRIGUEZ FRANCISCO JAVIER (AT)	US201 26-Oct-2012 213661 923A
US10103097B2	16-Oct-2018	CD control	ZOU ZHENG (SG); SEE ALEX (SG); LIU HUANG (SG); CONG HAI (SG)	US201 11-Sep-2014 414484 220A
US9331007B2	3-May-2016	Semiconductor device and method of forming conductive ink layer as interconnect structure between semiconductor packages	YOON INSANG (KR); CARSON FLYNN (US); SHIM IL KWON (SG); MUN SEONGHUN (KR)	US201 16-Oct-2012 213653 242A
US10297518B2	21-May-2019	Semiconductor device and method of forming supporting layer over semiconductor die in thin fan-out wafer level chip scale package	LIN YAOJIAN (SG); CHEN KANG (SG); GU YU (SG)	US201 27-May-2016 615167 662A
US8796044B2	5-Aug-2014	Ferroelectric random access memory with optimized hardmask	BEECHER JAMES E (US); MURPHY WILLIAM J (US); NAKOS JAMES S (US); PORTH BRUCE W (US)	US201 27-Sep-2012 213628 715A
US9018744B2	28-Apr-2015	Semiconductor device having a clip contact	OTREMBIA RALF (DE); HOEGLAUER JOSEF (DE); HOSSEINI KHALIL (DE)	US201 25-Sep-2012 213626 830A
US10008452B2	26-Jun-2018	Microelectronic structures having laminated or embedded glass routing structures for high density packaging	MA QING (US); SWAN JOHANNA M (US); STARKSTON ROBERT (US); GUZEK JOHN S (US); SANKMAN ROBERT L (US); ALEKSOV ALEKSANDAR (US)	US201 27-Mar-2017 715469 964A
US10115653B2	30-Oct-2018	Thermal dissipation through seal rings in 3DIC structure	LIN JING CHENG (TW)	US201 19-Jan-2015 514599 834A
US9059161B2	16-Jun-2015	Composite wiring board with electrical through connections	ANDRY PAUL S (US); COLGAN EVAN G (US); WISNIEFF ROBERT L (US)	US201 20-Sep-2012 213623 873A
US11101192B2	24-Aug-2021	Wafer level embedded heat spreader	CHANG WEI SEN (TW); CHIANG TSUNG HSIEN (TW); HU YEN CHANG (TW); HSIAO CHING WEN (TW)	US201 24-Dec-2018 816231 783A
US11742217B2	29-Aug-2023	Passive devices in package-on-package structures and methods for forming the same	CHEN CHIH HUA (TW); CHEN CHEN SHIEN (TW)	US202 6-Jan-2021 117142 503A
US8900664B2	2-Dec-2014	Method of fabricating high efficiency CIGS solar cells	LIANG HAIFAN (US); EID JESSICA (US); VAN DUREN JEROEN (US)	US201 27-Dec-2012 213727 845A
US9034197B2	19-May-2015	Method for separately processing regions on a patterned medium	LILLE JEFFREY S (US); RUBIN KURT A (US); RUIZ RICARDO (US); WAN LEI (US)	US201 13-Sep-2012 213615 131A
US9780042B2	3-Oct-2017	Tunable composite interposer	WOYCHIK CHARLES G (US); UZOH CYPRIAN EMEKA (US); SATO HIROAKI (JP)	US201 2-Jun-2016 615171 604A
US8921209B2	30-Dec-2014	Defect free strained silicon on insulator (SSOI) substrates	BEDELL STEPHEN W (US); HEKMATSHOARTABARI BAHMAN (US); SADANA DEVENDRA K (US); SHAHIDI GHAVAM G (US); SHAHRJERDI DAVOOD (US)	US201 12-Sep-2012 213612 675A

US9147660B2	29-Sep-2015	Chip to package interface	SAPONE GIUSEPPINA (AT)	US201 414511 472A	10-Oct-2014
US12334476B2	17-Jun-2025	Semiconductor device with discrete blocks	HSIAO CHING WEN (TW); CHEN CHEN SHIEN (TW); CHANG WEI SEN (TW); HU SHOU CHENG (TW)	US202 318525 273A	30-Nov-2023
US10183401B2	22-Jan-2019	Mass transfer tool	HIGGINSON JOHN A (US); BIBL ANDREAS (US); ALBERTALLI DAVID (US)	US201 615282 225A	30-Sep-2016
US9263388B2	16-Feb-2016	Overlay-tolerant via mask and reactive ion etch (RIE) technique	HOLMES STEVEN J (US); HORAK DAVID V (US); KOBURGER III CHARLES W (US); PONOTH SHOM (US); YANG CHIH CHAO (US)	US201 514688 027A	16-Apr-2015
US8791023B2	29-Jul-2014	Patterned thin film dielectric layer formation	ELLINGER CAROLYN R (US); LEVY DAVID H (US); NELSON SHELBY F (US)	US201 213600 287A	31-Aug-2012
US8927434B2	6-Jan-2015	Patterned thin film dielectric stack formation	ELLINGER CAROLYN R (US); LEVY DAVID H (US); NELSON SHELBY F (US)	US201 213600 274A	31-Aug-2012
US9355977B2	31-May-2016	Bump structures for semiconductor package	LIN JING CHENG (TW); TSAI PO HAO (TW)	US201 514635 889A	2-Mar-2015
US2014061869A1	6-Mar-2014	ELECTRONIC ELEMENT INCLUDING DIELECTRIC STACK	NELSON SHELBY F (US); ELLINGER CAROLYN R (US); LEVY DAVID H (US)	US201 213600 266A	31-Aug-2012
US9953920B2	24-Apr-2018	Interconnect structure and method	CHEN HSIN YU (TW); YANG KU FENG (TW); WU TASI JUNG (TW); HUANG LIN CHIH (TW); LIU YUAN HUNG (TW); WU TSANG JIUH (TW); CHIOU WEN CHIH (TW)	US201 514685 023A	13-Apr-2015
US8835304B2	16-Sep-2014	Method of semiconductor integrated circuit fabrication	LU CHIH WEI (TW); LEE CHUNG JU (TW); LEE HSIANG HUAN (TW); BAO TIEN I (TW)	US201 213599 764A	30-Aug-2012
US9698028B2	4-Jul-2017	Semiconductor package and method of manufacturing the same	LU WEN HSIUNG (TW); CHENG MING DA (TW); WU YI WEN (TW); TSAI YU PENG (TW); TU CHIA WEI (TW); LIU CHUNG SHI (TW)	US201 514799 284A	14-Jul-2015
US8810006B2	19-Aug-2014	Interposer system and method	YU CHEN HUA (TW); JENG SHIN PUU (TW); HOU SHANG YUN (TW); YEH DER CHYANG (TW)	US201 213572 240A	10-Aug-2012
US9595577B2	14-Mar-2017	Semiconductor device with trench structure and methods of manufacturing	SCHULZE HANS JOACHIM (DE); MAUDER ANTON (DE)	US201 414281 329A	19-May-2014
US2014042621A1	13-Feb-2014	Package on Package Devices and Methods of Forming Same	YU CHEN HUA (TW); LII MIRNG JI (TW); LEE CHIEN HSUN (TW); CHEN YUNG CHING (TW); WU JIUN YI (TW)	US201 213570 065A	8-Aug-2012
US8883646B2	11-Nov-2014	Self-assembled monolayer for pattern formation	HUANG TSUNG MIN (TW); LEE CHUNG JU (TW); HUANG CHIEN HUA (TW)	US201 213567 250A	6-Aug-2012

US10020344B2	10-Jul-2018	CIS chips and methods for forming the same	YU CHEN HUA (TW); CHIOU WEN CHIH (TW); LIN JING CHENG (TW)	US201 615137 104A	25-Apr-2016
US9412646B2	9-Aug-2016	Via in substrate with deposited layer	UZOH CYPRIAN EMEKA (US)	US201 514605 654A	26-Jan-2015
US9615447B2	4-Apr-2017	Multilayer electronic support structure with integral constructional elements	HURWITZ DROR (CN); HUANG ALEX (CN)	US201 213555 437A	23-Jul-2012
US8992792B2	31-Mar-2015	Method of fabricating an ultra low-k dielectric self-aligned via	CHANG CHIH YANG (US); KANG SEAN S (US); KAO CHIA LING (US); BEKIARIS NIKOLAOS (US)	US201 213724 698A	21-Dec-2012
US9117715B2	25-Aug-2015	Wafer-level device packaging	TSUI YAT KIT (HK); YANG DAN (HK); LAW PUI CHUNG (HK)	US201 213551 610A	18-Jul-2012
US8816501B2	26-Aug-2014	IC device including package structure and method of forming the same	GAN ZHENGHAO (CN); CHEN FANG (CN)	US201 213684 165A	22-Nov-2012
US9741638B2	22-Aug-2017	Thermal structure for integrated circuit package	HSIEH CHENG CHIEH (TW); JENG SHIN PUU (TW); HOU SHANG YUN (TW); CHENG WAY LEE (TW)	US201 615149 834A	9-May-2016
US9082619B2	14-Jul-2015	Methods and apparatuses for forming semiconductor films	KAPUR VIJAY K (US); HABER JOEL (US); KAPUR VINCENT (US); BANSAL ASHISH (US); GUEVARRA DAN (US)	US201 213544 562A	9-Jul-2012
US9147628B2	29-Sep-2015	Package-in-packages and methods of formation thereof	OTREMBIA RALF (DE); HOEGLAUER JOSEF (DE); SCHREDL JUERGEN (DE); SCHLOEGEL XAVER (DE); SCHIESS KLAUS (DE)	US201 213535 052A	27-Jun-2012
US10867961B2	15-Dec-2020	Single layer low cost wafer level packaging for SFF SiP	HU CHUAN (US); NAIR VIJAY K (US)	US201 816015 052A	21-Jun-2018
US9137905B2	15-Sep-2015	Alignment between layers of multilayer electronic support structures	HURWITZ DROR (CN); CHAN SIMON (CN)	US201 213531 948A	25-Jun-2012
US10217702B2	26-Feb-2019	Semiconductor device and method of forming an embedded SoP fan-out package	LIN YAOJIAN (SG); CHEN KANG (SG)	US201 615167 830A	27-May-2016
US9161461B2	13-Oct-2015	Multilayer electronic structure with stepped holes	HURWITZ DROR (CN); CHAN SIMON (CN); HUANG ALEX (TW)	US201 213523 116A	14-Jun-2012
US8828845B2	9-Sep-2014	Method of fabricating oxide thin film device using laser lift-off and oxide thin film device fabricated by the same	KANG CHONG YUN (KR); YOON SEOK JIN (KR); DO YOUNG HO (KR); CHOI JI WON (KR); BAEK SEUNG HYUB (KR); SONG HYUN CHEOL (KR); KIM JIN SANG (KR)	US201 213713 396A	13-Dec-2012
US9040891B2	26-May-2015	Image device and methods of forming the same	CHEN U TING (TW); YAUNG DUN NIAN (TW); LIU JEN CHENG (TW); SHIH YU HAO (TW); WANG CHIH CHIEN (TW); CHOU SHIH PEI (TW); HUANG WEI TUNG (TW); WU CHENG TA (TW)	US201 213492 348A	8-Jun-2012

US9330944B2	3-May-2016	Bio-implantable hermetic integrated ultra high density device	SMITH BRIAN R (US); SRIRAM TIRUNELVELI S (US); MCLAUGHLIN BRYAN L (US)	US201 4-Dec-2015 514959 647A
US9059240B2	16-Jun-2015	Fixture for shaping a laminate substrate	BLACKSHEAR EDMUND D (US); LOMBARDI THOMAS E (US); MERTE DONALD A (US); OSTRANDER STEVEN P (US); WEISS THOMAS (US); ZHENG JIANTAO (US)	US201 5-Jun-2012 213488 693A
US9129942B2	8-Sep-2015	Method for shaping a laminate substrate	BLACKSHEAR EDMUND D (US)	US201 5-Jun-2012 213488 685A
US9230896B2	5-Jan-2016	Semiconductor device and method of reflow soldering for conductive column structure in flip chip package	LEE CHIEN CHEN (TW); HUNG LI CHIUN (TW)	US201 5-Jun-2012 213489 143A
US9543253B2	10-Jan-2017	Method for shaping a laminate substrate	BLACKSHEAR EDMUND (US); LOMBARDI THOMAS E (US); MERTE DONALD A (US); OSTRANDER STEVEN P (US); WEISS THOMAS (US); ZHENG JIANTAO (US)	US201 16-Jan-2015 514598 258A
US10049932B2	14-Aug-2018	Method of manufacturing of a sidewall opening of an interconnect of a semiconductor device	BARTH HANS JOACHIM (DE)	US201 27-Mar-2017 715469 801A
US10224276B2	5-Mar-2019	Integrated circuit including wire structure, related method and design structure	COONEY III EDWARD C (US); GAMBINO JEFFREY P (US); HE ZHONG XIANG (US); LEIDY ROBERT K (US)	US201 18-Oct-2017 715787 146A
US9440135B2	13-Sep-2016	Multilayer electronic structures with integral vias extending in in- plane direction	HURWITZ DROR (CN)	US201 29-May-2012 213482 045A
US9269593B2	23-Feb-2016	Multilayer electronic structure with integral stepped stacked structures	HURWITZ DROR (CN)	US201 29-May-2012 213482 099A
US8785249B2	22-Jul-2014	Three dimensional microelectronic components and fabrication methods for same	KARPMAN MAURICE (US)	US201 5-Jun-2012 213488 804A
US8778212B2	15-Jul-2014	CMP composition containing zirconia particles and method of use	JIN WIECHANG (US); PARKER JOHN (US); REMSEN ELIZABETH (US)	US201 22-May-2012 213477 535A
US11581250B2	14-Feb-2023	Package with metal-insulator-metal capacitor and method of manufacturing the same	CHEN SHUO MAO (TW); YEH DER CHYANG (TW); YEH CHIUNG HAN (TW)	US202 31-Mar-2021 117218 285A
US9406579B2	2-Aug-2016	Semiconductor device and method of controlling warpage in semiconductor package	CHOI DAESIK (KR); YANG JOUNGIN (KR); PARK SANG MI (KR); KWON WONIL (KR); PARK YISU (KR)	US201 14-May-2012 213471 314A
US9390945B2	12-Jul-2016	Semiconductor device and method of depositing underfill material with uniform flow rate	LEE KYUNGHOON (KR); YANG JOUNGIN (KR); PARK SANG MI (KR); CHOI DAESIK (KR); PARK YISU (KR)	US201 8-May-2012 213466 945A
US8999748B2	7-Apr-2015	Organic thin film transistor and method of manufacturing the same	JUNG JI YOUNG (KR); KIM JOO YOUNG (KR); KIM HYEOK (KR)	US201 6-Nov-2012 213670 001A

US9263674B2	16-Feb-2016	ETCH bias homogenization	PELLIZZER FABIO (IT); CASTRO HERNAN A (US); FLORES EDDIE T (US)	US201 414303 652A	13-Jun-2014
US9040346B2	26-May-2015	Semiconductor package and methods of formation thereof	NIKITIN IVAN (DE); FUERGUT EDWARD (DE)	US201 213463 636A	3-May-2012
US9728533B2	8-Aug-2017	Aqueous cleaning techniques and compositions for use in semiconductor device manufacture	CHOU CHUN LI (TW); KU SHAO YEN (TW); CHEN PEI HUNG (TW); CHUANG JUI PING (TW)	US201 414578 746A	22-Dec-2014
US9127126B2	8-Sep-2015	Development of high-viscosity bonding layer through in-situ polymer chain extension	HONG WENBIN (US); FLAIM TONY D (US); PULIGADDA RAMA (US); BAILEY SUSAN (US)	US201 213460 372A	30-Apr-2012
US9741618B2	22-Aug-2017	Methods of forming semiconductor devices	STRANZL GUDRUN (AT); ZGAGA MARTIN (AT); KAHN MARKUS (AT); DENIFL GUENTER (AT)	US201 514979 200A	22-Dec-2015
US10559546B2	11-Feb-2020	Package on package structure and method for forming the same	YU CHEN HUA (TW); LIU CHUNG SHI (TW); CHENG MING DA (TW); LII MIRNG JI (TW); CHEN MENG TSE (TW); LIN WEI HUNG (TW)	US201 816233 218A	27-Dec-2018
US9853233B2	26-Dec-2017	Functionalization of a substrate	HELANDER MICHAEL (CA); WANG ZHIBIN (CA); QIU JACKY (CA); LU ZHENG HONG (CA)	US201 414471 807A	28-Aug-2014
US9034695B2	19-May-2015	Integrated thermal solutions for packaging integrated circuits	HSIEH CHENG CHIEH (TW); HOU SHANG YUN (TW); JENG SHIN PUU (TW)	US201 213444 662A	11-Apr-2012
US2015287681A1	8-Oct-2015	SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING SAME	SOH SAY HEAN (SG); SIEW YUEN ZIEN (MY); WONG CHUAN WEI (SG); SOH SIEW BOON (SG); CHEN HAOYANG (CN)	US201 214389 763A	6-Apr-2012
US9105628B1	11-Aug-2015	Through substrate via (TSuV) structures and method of making the same	DUBIN VALERY (US)	US201 213434 688A	29-Mar-2012
US9041182B2	26-May-2015	Semiconductor package and method of manufacturing the same	NAGANO TOSHIHIKO (JP); ABE KAZUhide (JP); YAMADA HIROSHI (JP); ITAYA KAZUHIKO (JP); NAKADA TAIHEI (JP)	US201 213688 823A	29-Nov-2012
US9082780B2	14-Jul-2015	Semiconductor device and method of forming a robust fan-out package including vertical interconnects and mechanical support layer	LIN YAOJIAN (SG); CHEN KANG (SG); GU YU (SG)	US201 213428 439A	23-Mar-2012
US9768102B2	19-Sep-2017	Integrated circuit packaging system with support structure and method of manufacture thereof	JEON DONG JU (KR); LEE KOO HONG (KR); KIM SUNG SOO (KR)	US201 213425 768A	21-Mar-2012
US9799621B2	24-Oct-2017	Semiconductor device and method of forming duplex plated bump-on-lead pad over substrate for finer pitch between adjacent traces	LEE SOO WON (KR); LEE KYU WON (KR); JEONG EUN JIN (KR)	US201 414334 229A	17-Jul-2014
US9000557B2	7-Apr-2015	Semiconductor device and structure	OR BACH ZVI (US); SEKAR DEEPAK C (US); CRONQUIST BRIAN (US)	US201 213423 200A	17-Mar-2012

US9245834B2	26-Jan-2016	Semiconductor device and method of forming compliant conductive interconnect structure in flipchip package	HSIEH MING CHE (TW)	US201 213422 981A	16-Mar-2012
US9824977B2	21-Nov-2017	Semiconductor packages and methods of forming the same	STANDING MARTIN (AT); ROBERTS ANDREW (GB)	US201 615063 502A	7-Mar-2016
US9601376B2	21-Mar-2017	Semiconductor device and method of manufacturing a semiconductor device having a glass piece and a single-crystalline semiconductor portion	BREYMESSER ALEXANDER (AT); BROCKMEIER ANDRE (AT); SANTOS RODRIGUEZ FRANCISCO JAVIER (AT); SCHULZE HANS JOACHIM (DE); VON KOBLINSKI CARSTEN (AT); SCHMIDT GERHARD (AT)	US201 514960 505A	7-Dec-2015
US8673771B2	18-Mar-2014	Pattern forming method	KAWAMURA DAISUKE (JP)	US201 213597 014A	28-Aug-2012
US2013224901A1	29-Aug-2013	Production Line to Fabricate CIGS Thin Film Solar Cells via Roll-to-Roll Processes	WANG JIAXIONG (US)	US201 213405 304A	26-Feb-2012
US9394166B1	19-Jul-2016	Increased plasmon resonance frequency stability drawn from a refractive index gradient spanning negative and positive values	SECHRIST ZACHARY A (US); TONUCCI RONALD J (US); CAMBREA LEE R (US)	US201 213622 841A	19-Sep-2012
US2015035175A1	5-Feb-2015	ADHESIVE FOR SEMICONDUCTOR, FLUXING AGENT, MANUFACTURING METHOD FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE	HONDA KAZUTAKA (JP); NAGAI AKIRA (JP); SATOU MAKOTO (JP)	US201 214380 466A	1-Oct-2012
US9803111B2	31-Oct-2017	Adhesive for semiconductor, fluxing agent, manufacturing method for semiconductor device, and semiconductor device	HONDA KAZUTAKA (JP); NAGAI AKIRA (JP); SATOU MAKOTO (JP)	US201 214379 961A	1-Oct-2012
US9238861B2	19-Jan-2016	Closed-space annealing process for production of CIGS thin-films	MUNTEANU MARIANA RODICA (US); MURALI AMITH KUMAR (US); BARTHOLOMEUSZ BRIAN JOSEF (US); CHAWLA VARDAAN (US)	US201 213467 789A	9-May-2012
US9064700B2	23-Jun-2015	Crystallization annealing processes for production of CIGS and CZTS thin-films	WONG KAICHIU (US); SMITH ERIK SEAN (US); FORD CHRIST WILLIE (US)	US201 213467 904A	9-May-2012
US9390917B2	12-Jul-2016	Closed-space sublimation process for production of CZTS thin-films	CHAWLA VARDAAN (US); MUNTEANU MARIANA RODICA (US)	US201 213401 512A	21-Feb-2012
US8922871B2	30-Dec-2014	Electrowetting display device and manufacturing method thereof	CHOI BYUNG SEOK (KR); BAEK SEUNG JIN (KR); LEE JI EUN (KR); HONG WANG SU (KR)	US201 213591 661A	22-Aug-2012
US8900922B2	2-Dec-2014	Fine-pitch package-on-package structures and methods for forming the same	LIN CHENG CHUNG (TW); HUANG KUEI WEI (TW); ANG AI TEE (TW); TSAI TSAI TSUNG (TW); CHENG MING DA (TW); LIU CHUNG SHI (TW)	US201 213398 568A	16-Feb-2012
US8963316B2	24-Feb-2015	Semiconductor device and method for manufacturing the same	HSU CHIH JING (TW); OU YING TE (TW); FU CHIEH CHEN (TW); HUANG CHE HAU (TW)	US201 213397 169A	15-Feb-2012
US8946087B2	3-Feb-2015	Electroless copper deposition	NALLA PRAVEEN REDDY (US)	US201 213364 924A	2-Feb-2012

US2024379638A1	14-Nov-2024	INTERPOSER FRAME AND METHOD OF MANUFACTURING THE SAME	WU JIUN YI (TW)	US202 418782 291A	24-Jul-2024
US9006033B2	14-Apr-2015	Method of making package with interposer frame	WU JIUN YI (TW)	US201 414291 142A	30-May-2014
US10071905B2	11-Sep-2018	Micro-electro mechanical system (MEMS) structures with through substrate vias and methods of forming the same	CHU CHIA HUA (TW); CHANG KUEI SUNG (TW); LEE TE HAO (TW)	US201 615289 794A	10-Oct-2016
US9257508B2	9-Feb-2016	Transistors and methods of manufacturing the same	LEE CHANG SEUNG (KR); LEE JOO HO (KR); KIM YONG SUNG (KR); KIM JUN SEONG (KR); MOON CHANG YOUL (KR)	US201 213595 580A	27-Aug-2012
US9006044B2	14-Apr-2015	Graphene device and method of manufacturing the same	LEE CHANG SEUNG (KR); LEE JOO HO (KR); KIM YONG SUNG (KR); MOON CHANG YOUL (KR)	US201 213546 615A	11-Jul-2012
US10665565B2	26-May-2020	Package assembly	LIN HUNG JEN (TW); WANG TSUNG DING (TW); LEE CHIEN HSIUN (TW); LU WEN HSIUNG (TW); CHENG MING DA (TW); LIU CHUNG SHI (TW)	US201 816221 986A	17-Dec-2018
US10559743B2	11-Feb-2020	Backside integration of RF filters for RF front end modules and design structure	ADKISSON JAMES W (US); CANDRA PANGLIJEN (US); DUNBAR THOMAS J (US); GAMBINO JEFFREY P (US); JAFFE MARK D (US); STAMPER ANTHONY K (US); WOLF RANDY L (US)	US201 715690 828A	30-Aug-2017
US8772930B2	8-Jul-2014	Increased surface area electrical contacts for microelectronic packages	LAW PUI CHUNG SIMON (HK); YANG DAN (HK); SHI XUNQING (HK)	US201 213354 302A	19-Jan-2012
US9258922B2	9-Feb-2016	PoP structures including through-assembly via modules	CHEN CHIH HUA (TW); CHEN CHEN SHIEN (TW); HSIAO CHING WEN (TW)	US201 213352 937A	18-Jan-2012
US9425118B2	23-Aug-2016	Electronic component having a corrosion-protected bonding connection and method for producing the component	BEZ FABIAN (DE); DUERR JOHANNES (DE); BECKER ROLF (DE); LAMERS SVEN (DE); MUELLER LUTZ (DE); SCHLECHT MICHAEL (DE)	US201 214370 858A	29-Nov-2012
US9323010B2	26-Apr-2016	Structures formed using monocrystalline silicon and/or other materials for optical and other applications	KOSENKO VALENTIN (US); MCBAIN EDWARD LEE (US); UZOH CYPRIAN EMEKA (US); MONADGEMI PEZHMAN (US); SAVASTIOUK SERGEY (US)	US201 213454 713A	24-Apr-2012
US9460972B2	4-Oct-2016	Semiconductor device and method of forming reduced surface roughness in molded underfill for improved C-SAM inspection	PARK SEONGWON (KR); JANG KIYOUN (KR); LEE KYUNGHOON (KR); LEE JAEHYUN (KR)	US201 213720 516A	19-Dec-2012
US9263690B2	16-Feb-2016	Organic el device and manufacturing method thereof	KURIBE EIJI (JP); SUZUKI JUMPEI (JP)	US201 214370 754A	20-Dec-2012
US11180365B2	23-Nov-2021	MEMS devices and methods of forming same	LIANG KAI CHIH (ZHUBEI, TW); CHU CHIA HUA (ZHUBEI, TW); LEE TE HAO (HSINCHU, TW); LEE JIOU KANG (ZHUBEI, TW); LIN CHUNG HSIEN (HSINCHU, TW)	US201 916665 468A	28-Oct-2019
US9533838B2	3-Jan-2017	Method for transferring objects onto a substrate by means of a compact film of particles	DELLEA OLIVIER (FR); CORONEL PHILIPPE (FR); FUGIER PASCAL (FR)	US201 214369 752A	28-Dec-2012

US9536737B2	3-Jan-2017	Nanostructure and process of fabricating same	PATOLSKY FERNANDO (IL); PEVZNER ALEXANDER (IL); ENGEL YONI (IL); ELNATHAN ROEY (IL); TSUKERNIK ALEXANDER (CA); BARKAY ZAHAVA (IL)	US201 1-Jan-2012 214370 083A
US9583344B2	28-Feb-2017	Photoresist pattern trimming methods	XU CHENG BAI (US)	US201 11-Nov-2015 514938 348A
US9244351B2	26-Jan-2016	Composition for hardmask, method of forming patterns using the same, and semiconductor integrated circuit device including the patterns	LEE SUNG JAE (KR); MOON JOON YOUNG (KR); CHO YOUN JIN (KR); KIM YOUNG MIN (KR); YOON YONG WOON (KR)	US201 23-Nov-2012 214368 858A
US2017327640A1	16-Nov-2017	MONOMER FOR A HARDMASK COMPOSITION, HARDMASK COMPOSITION COMPRISING THE MONOMER, AND METHOD FOR FORMING A PATTERN USING THE HARDMASK COMPOSITION	KIM YUN JUN (KR); CHEON HWAN SUNG (KR); CHO YOUN JIN (KR); YOON YONG WOON (KR); LEE CHUNG HEON (KR); KWON HYO YOUNG (KR); CHOI YOO JEONG (KR)	US201 3-Aug-2017 715668 159A
US8860184B2	14-Oct-2014	Spacer assisted pitch division lithography	SIVAKUMAR SWAMINATHAN (US); TAN ELLIOT N (US)	US201 29-Dec-2011 113976 077A
US9754892B2	5-Sep-2017	Stacked semiconductor package and manufacturing method thereof	KWON YONG TAE (KR); LEE JUN KYU (KR)	US201 28-Dec-2012 214369 807A
US8716036B2	6-May-2014	Method for collective fabrication of 3D electronic modules comprising only validated PCBs	VAL CHRISTIAN (FR)	US201 28-Dec-2012 213730 047A
US8952372B2	10-Feb-2015	Photoelectric element and method for producing the same	SEKIGUCHI TAKASHI (JP); SUZUKA MICHIO (JP); HAYASHI NAOKI (JP); YAMAKI TAKEYUKI (JP); NISHIDE HIROYUKI (JP); OYAIZU KENICHI (JP); KATO FUMIAKI (JP); SANO NAOKI (JP)	US201 12-Dec-2012 214007 800A
US9029845B2	12-May-2015	Electrode composite and photoelectric element equipped therewith	SUZUKA MICHIO (JP); SEKIGUCHI TAKASHI (JP); NISHIDE HIROYUKI (JP); OYAIZU KENICHI (JP); KATO FUMIAKI (JP)	US201 10-Dec-2012 214008 025A
US8809154B2	19-Aug-2014	Semiconductor device and method for manufacturing the same	KOEZUKA JUNICHI (JP); OKAZAKI KENICHI (JP); HOSAKA YASU HARU (JP); IKEYAMA TERUMASA (JP); YAMAZAKI SHUNPEI (JP)	US201 20-Dec-2012 213721 972A
US9153487B2	6-Oct-2015	Methods of forming wirings in electronic devices	LEE SEUNG HO (KR); HONG YOUNG KI (KR); KANG SUNG GYU (KR); KIM JOONG HYUK (KR); CHUNG JAE WOO (KR)	US201 31-Aug-2012 213601 658A
US9293596B2	22-Mar-2016	Graphene devices and methods of manufacturing the same	XIANYU WENXU (KR); MOON CHANG YOUL (KR); LEE JEONG YUB (KR); LEE CHANG SEUNG (KR)	US201 9-Mar-2015 514642 326A
US9536837B2	3-Jan-2017	TSV via provided with a stress release structure and its fabrication method	LAMY YANN (FR)	US201 21-Dec-2012 213725 020A
US9269652B2	23-Feb-2016	Chemically altered carbosilanes for pore sealing applications	MICHALAK DAVID J (US); BLACKWELL JAMES M (US); BIELEFELD JEFFERY D (US); CLARKE JAMES S (US)	US201 22-Dec-2011 113995 905A
US9596754B2	14-Mar-2017	Dry film, printed wiring board using same, method for producing printed wiring board, and flip chip mounting substrate	IWAYAMA GENTO ; ENDO ARATA (JP); MINEGISHI SHOJI (JP); ARIMA MASAO (JP)	US201 18-Dec-2012 214367 611A

US8987902B2	24-Mar-2015	Semiconductor device, semiconductor package, and method for manufacturing semiconductor device	MIKI SYOTA (JP)	US201 213716 719A	17-Dec-2012
US9157012B2	13-Oct-2015	Process for the manufacture of semiconductor devices comprising the chemical mechanical polishing of borophosphosilicate glass (BPSG) material in the presence of a CMP composition comprising anionic phosphate or phosphonate	VENKATARAMAN SHYAM SUNDAR (DE); SU EASON YU SHEN (TW)	US201 114362 439A	21-Dec-2011
US2013164918A1	27-Jun-2013	Absorbers For High-Efficiency Thin-Film PV	LIANG HAIFAN (US); VAN DUREN JEROEN (US)	US201 213596 387A	28-Aug-2012
US9178097B2	3-Nov-2015	Absorbers for high efficiency thin-film PV	LIANG HAIFAN (US); VAN DUREN JEROEN (US)	US201 414180 120A	13-Feb-2014
US9293739B2	22-Mar-2016	Process and materials for making contained layers and devices made with same	FENNIMORE ADAM (US); MACKARA STEVEN R (US)	US201 214367 426A	20-Dec-2012
US8945961B2	3-Feb-2015	Organic light-emitting display device and method of manufacturing the same	CHO SUNG HWAN (KR)	US201 213585 501A	14-Aug-2012
US9478476B2	25-Oct-2016	Package for a microelectronic die, microelectronic assembly containing same, microelectronic system, and method of reducing die stress in a microelectronic package	MALLIK DEBENDRA (US); NARASIMHAN SRIDHAR (US); MANUSHAROW MATHEW J (US); BOYD THOMAS A (US)	US201 113976 098A	16-Dec-2011
US2013157415A1	20-Jun-2013	METHOD FOR PRODUCING SEMICONDUCTOR DEVICE	MORITA KOSUKE (JP); TAKAMOTO NAOHIDE (JP); SENZAI HIROYUKI (JP)	US201 213715 996A	14-Dec-2012
US10153346B2	11-Dec-2018	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); AKIMOTO KENGO (JP); NONAKA YUSUKE (JP); KANEMURA HIROSHI (JP)	US201 615079 156A	24-Mar-2016
US8940620B2	27-Jan-2015	Composite wafer for fabrication of semiconductor devices	KOUDYMOV ALEXEI (US); RAMDANI JAMAL (US); SWAMINATHAN KIERTHI (US)	US201 113374 206A	15-Dec-2011
US12557337B2	17-Feb-2026	Semiconductor device and display device including the same	YONEDA SEIICHI (ATSUGI, JP)	US202 418675 293A	28-May-2024
US2015245474A1	27-Aug-2015	WIRING BOARD AND METHOD FOR MANUFACTURING THE SAME	TAKAHASHI MICHIMASA (JP); ISHIHARA TERUYUKI (JP)	US201 514707 379A	8-May-2015
US9611406B2	4-Apr-2017	Polishing composition, and polishing method and substrate production method using same	TAMAI KAZUSEI (JP); ASHITAKA KEIJI (JP); TSUBOTA SHOGO (JP)	US201 214363 060A	15-Nov-2012
US9281259B2	8-Mar-2016	Semiconductor device and method of forming thick encapsulant for stiffness with recesses for stress relief in FO-WLCSP	LIN YAOJIAN (SG); CHEN KANG (SG); CAPARAS JOSE ALVIN (SG); OMANDAM GLENN (SG)	US201 314079 273A	13-Nov-2013
US9799582B2	24-Oct-2017	Bump structure design for stress reduction	CHEN HSIEN WEI (TW)	US201 715488 972A	17-Apr-2017

US9385076B2	5-Jul-2016	Semiconductor device with bump structure on an interconnect structure	CHEN HSIEN WEI (TW); WU YI WEN (TW); LU WEN HSIUNG (TW)	US201 113313 677A	7-Dec-2011
US9373575B2	21-Jun-2016	TSV structures and methods for forming the same	LIN YUNG CHI (TW); CHEN HSIN YU (TW); CHIOU WEN CHIH (TW); YANG KU FENG (TW); WU TSANG JIUH (TW); LIN JING CHENG (TW)	US201 514607 865A	28-Jan-2015
US8951845B2	10-Feb-2015	Methods of fabricating a flip chip package for dram with two underfill materials	SAKUMA KAZUO (JP); MOHAMMED ILYAS (US); DAMBERG PHILIP (US)	US201 414163 145A	24-Jan-2014
US9666755B2	30-May-2017	Method of manufacturing sealed body and method of manufacturing light-emitting device	SHIMOMURA AKIHISA (JP)	US201 213687 354A	28-Nov-2012
US9057126B2	16-Jun-2015	Method for manufacturing sputtering target and method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); MARUYAMA TETSUNORI (JP)	US201 213677 656A	15-Nov-2012
US9202723B2	1-Dec-2015	Brush with cantilevered nodules	WITHERS BRADLEY S (US); CROKER MICHAEL G (US); WILLIS ROBERT A (US)	US201 113306 624A	29-Nov-2011
US2013137219A1	30-May-2013	METHOD FOR PRODUCING SEMICONDUCTOR DEVICE	SENZAI HIROYUKI (JP); TAKAMOTO NAOHIDE (JP); MORITA KOSUKE (JP)	US201 213686 852A	27-Nov-2012
US9368421B2	14-Jun-2016	Under-fill material and method for producing semiconductor device	MORITA KOSUKE (JP); TAKAMOTO NAOHIDE (JP); SENZAI HIROYUKI (JP)	US201 514732 517A	5-Jun-2015
US9044793B2	2-Jun-2015	Method for cleaning film formation apparatus and method for manufacturing semiconductor device	TORIUMI SATOSHI (JP); FURUNO MAKOTO (JP)	US201 213680 187A	19-Nov-2012
US9978656B2	22-May-2018	Mechanisms for forming fine-pitch copper bump structures	LIN TSUNG SHU (TW); PU HAN PING (TW); CHENG MING DA (TW); HUANG CHANG CHIA (TW); LIU HAO JUIN (TW)	US201 213406 270A	27-Feb-2012
US9679846B2	13-Jun-2017	Semiconductor device and method of forming conductive layer over substrate with vents to channel bump material and reduce interconnect voids	LEE JAEHYUN (KR); KIM SUNJAE (KR); KIM JOONGGI (KR)	US201 414572 298A	16-Dec-2014
US10256113B2	9-Apr-2019	Transfer substrate for forming metal wiring and method for forming metal wiring with the transfer substrate	OGASHIWA TOSHINORI (JP); KURITA MASAOKI (JP); NISHIMORI TAKASHI (JP); KANEHIRA YUKIO (JP)	US201 214354 134A	8-Nov-2012
US9219245B2	22-Dec-2015	Organic light emitting diode display and manufacturing method thereof	JUNG HAE GOO (KR); LEE JAE HYUK (KR); YANG SEUNG YO (KR)	US201 213612 303A	12-Sep-2012
US2013122687A1	16-May-2013	LASER SCRIBING SYSTEMS, APPARATUS, AND METHODS	HOLDEN JAMES MATTHEW (US)	US201 213677 847A	15-Nov-2012
US9462692B2	4-Oct-2016	Test structure and method of testing electrical characteristics of through vias	HOU SHANG YUN (TW); WU WEI CHENG (TW); HU HSIEN PIN (TW); KO JUNG CHENG (TW); JENG SHIN PUU (TW); YU CHEN HUA (TW); CHEN KIM HONG (US)	US201 514673 400A	30-Mar-2015

US9018770B2	28-Apr-2015	Chip package	LIU TSANG YU (TW); CHENG CHIA MING (TW)	US201 414337 011A	21-Jul-2014
US8810012B2	19-Aug-2014	Chip package, method for forming the same, and package wafer	CHAN YUAN RU (TW)	US201 213678 503A	15-Nov-2012
US9159925B2	13-Oct-2015	Process for imprint patterning materials in thin-film devices	DEFRANCO JOHN (US)	US201 214357 835A	14-Nov-2012
US9082700B2	14-Jul-2015	Ultraviolet treatment of metal oxide electrodes	VAIL SEAN ANDREW (US); EVANS DAVID R (US); PAN WEI (US); LEE JONG JAN (US)	US201 113296 191A	14-Nov-2011
US8980696B2	17-Mar-2015	Method of packaging semiconductor die	MENG DOMINIC KOEY POH (MY); GONG ZHIWEI (US); MUNIANDY KESVAKUMAR V C (MY); YAP WENG FOONG (MY)	US201 113292 103A	9-Nov-2011
US2014263167A1	18-Sep-2014	POLISHING COMPOSITION AND POLISHING METHOD USING SAME, AND SUBSTRATE MANUFACTURING METHOD	KACHI YOSHIHIRO (JP); TANAKA TOMOE (JP); UMEDA TAKAHIRO (JP)	US201 214355 620A	8-Nov-2012
US2015133356A1	14-May-2015	PHOTORESIST AND POST ETCH RESIDUE CLEANING SOLUTION	POLLARD KIMBERLY DONA (US); PFETTSCHER DONALD JAMES (US); HATFIELD MEAGAN (US); HOCHSTETLER SPENCER ERICH (US); GILBERT NICHELLE MARIA (US); PHENIS MICHAEL TOD (US)	US201 514601 550A	21-Jan-2015
US9318459B2	19-Apr-2016	Through via package	HWANG HOW YUAN (MY); GAN KAH WEE (SG)	US201 414548 090A	19-Nov-2014
US9881898B2	30-Jan-2018	System in package process flow	WANG TSUNG DING (TW); LEE CHIEN HSUN (TW)	US201 213602 650A	4-Sep-2012
US9190441B2	17-Nov-2015	Image sensor trench isolation with conformal doping	LAI CHIH YU (TW); TU YEUR LUEN (TW); HUANG CHIH HUI (TW); WU CHENG TA (TW); TSAI CHIA SHIUNG (TW); TRAN LUAN C (TW)	US201 414507 895A	7-Oct-2014
US10163877B2	25-Dec-2018	System in package process flow	WANG TSUNG DING (TW); LEE CHIEN HSIUN (TW)	US201 113290 208A	7-Nov-2011
US2022270978A1	25-Aug-2022	METHODS AND APPARATUSES TO FORM SELF-ALIGNED CAPS	BOYANOV BOYAN (US); SINGH KANWAL JIT (US)	US202 217742 792A	12-May-2022
US9076919B2	7-Jul-2015	Process of forming an aluminum p-doped surface region of a semiconductor substrate	HANG KENNETH WARREN (US); PRINCE ALISTAIR GRAEME (GB); ROSE MICHAEL (GB); YOUNG RICHARD JOHN SHEFFIELD (GB)	US201 213667 047A	2-Nov-2012
US10032857B2	24-Jul-2018	Etchstop layers and capacitors	BRAIN RUTH A (US)	US201 715428 087A	8-Feb-2017
US9431605B2	30-Aug-2016	Methods of forming semiconductor device structures	SILLS SCOTT E (US); MILLWARD DAN B (US)	US201 414546 897A	18-Nov-2014

US9054100B2	9-Jun-2015	Semiconductor die and method of forming sloped surface in photoresist layer to enhance flow of underfill material between semiconductor die and substrate	LEE JAEHYUN (KR); JANG KIYOUN (KR)	US201 113287 006A	1-Nov-2011
US9111917B2	18-Aug-2015	Low cost and high performance bonding of wafer to interposer and method of forming vias and circuits	MOBLEY TIM (US)	US201 213666 089A	1-Nov-2012
US2013247935A1	26-Sep-2013	GETTER RETICLE	PARK SEH JIN (US)	US201 113991 621A	31-Oct-2011
US9816173B2	14-Nov-2017	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP); TAKAHASHI MASAHIRO (JP); NAKASHIMA MOTOKI (JP); SHIMAZU TAKASHI (JP)	US201 213657 196A	22-Oct-2012
US9365681B2	14-Jun-2016	Wafer processing laminate, wafer processing member, temporary bonding arrangement, and thin wafer manufacturing method	KATO HIDETO (JP); SUGO MICHIIRO (JP); TAGAMI SHOHEI (JP)	US201 213659 168A	24-Oct-2012
US2019027414A1	24-Jan-2019	ENCAPSULATION BARRIER STACK	RAMADAS SENTHIL KUMAR (SG); SHANMUGAVEL SARAVANAN (SG)	US201 816140 065A	24-Sep-2018
US9579769B2	28-Feb-2017	Composition for polishing purposes, polishing method using same, and method for producing substrate	TSUCHIYA KOHSUKE (JP); MORI YOSHIO (JP); TAKAMI SHINICHIRO (JP); TAKAHASHI SHUHEI (JP)	US201 214352 393A	9-Oct-2012
US9741866B2	22-Aug-2017	Semiconductor device	CHO TAKAYUKI (JP); KOSHIOKA SHUNSUKE (JP); YOKOYAMA MASATOSHI (JP); YAMAZAKI SHUNPEI (JP)	US201 414585 918A	30-Dec-2014
US9147773B2	29-Sep-2015	Semiconductor device and method for manufacturing the same	TOCHIBAYASHI KATSUAKI (JP); HIGANO SATOSHI (JP); YAMAZAKI SHUNPEI (JP)	US201 414336 127A	21-Jul-2014
US8728918B2	20-May-2014	Method and apparatus for fabricating silicon heterojunction solar cells	SHENG SHURAN (US); ZHANG LIN (US); YUAN ZHENG (US); WANG RONGPING (US); TSO ALAN (US)	US201 213656 420A	19-Oct-2012
US9214338B2	15-Dec-2015	Method of making graphene layers, and articles made thereby	MALIAKAL ASHOK J (US)	US201 514693 670A	22-Apr-2015
US9722110B2	1-Aug-2017	Plasmonic graphene and method of making the same	WU JUDY (US); XU GUOWEI (US); LIU JIANWEI (US)	US201 213657 161A	22-Oct-2012
US9099456B2	4-Aug-2015	Package of electronic device including connecting bump, system including the same and method for fabricating the same	HAN KWON WHAN (KR)	US201 213589 259A	20-Aug-2012
US2025331228A1	23-Oct-2025	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	YAMAZAKI SHUNPEI (JP); HAYAKAWA MASAHIKO (JP); HONDA TATSUYA (JP)	US202 519256 393A	1-Jul-2025
US9082825B2	14-Jul-2015	Manufacturing method for semiconductor package, semiconductor package, and semiconductor device	TAKASHITA HIROMITSU (JP); TAKEDA TSUYOSHI (JP); KASHIHARA KEIKO (JP); FUJIWARA HIROAKI (JP); YOSHIOKA SHINGO (JP)	US201 214235 766A	18-Oct-2012

US10644175B2	5-May-2020	Methods of increasing the thickness of colloidal nanosheets and materials consisting of said nanosheets	MAHLER BENOIT (FR)	US201 715582 996A	1-May-2017
US10253415B2	9-Apr-2019	Process for the thickness growth of colloidal nanosheets and materials composed of said nanosheets	MAHLER BENOIT (FR)	US201 214352 887A	19-Oct-2012
US9029173B2	12-May-2015	Method for fabrication of a semiconductor device and structure	OR BACH ZVI (US); SEKAR DEEPAK C (US); CRONQUIST BRIAN (US); WURMAN ZE EV (US)	US201 113276 312A	18-Oct-2011
US9824923B2	21-Nov-2017	Semiconductor device and method of forming conductive pillar having an expanded base	SHARIFF DZAFIR (SG); YAM KWONG LOON (SG); CHIA LAI YEE (SG); HSIAO YUNG KUAN (SG)	US201 213468 981A	10-May-2012
US2013092929A1	18-Apr-2013	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	OKAZAKI KENICHI (JP); MIYAMOTO TOSHIYUKI (JP); HAMOCHI TAKASHI (JP); NOMURA MASAFUMI (JP)	US201 213649 645A	11-Oct-2012
US9453146B2	27-Sep-2016	Cover tape	SUGIMOTO KAZUYA (JP); TOKUNAGA HISATSUGU (JP); HIROOKA TADAAKI (JP)	US201 214351 329A	12-Oct-2012
US9236360B2	12-Jan-2016	IC chip package and chip-on-glass structure using the same	LIN TAI HUNG (TW)	US201 213650 873A	12-Oct-2012
US9287137B2	15-Mar-2016	Methods for depositing a silicon containing layer with argon gas dilution	WANG QUNHUA (US); WANG WEIJIE (US); CHOI YOUNG JIN (US); CHO SEON MEE (US); CUI YI (US); PARK BEOM SOO (US); CHOI SOO YOUNG (US)	US201 213630 901A	28-Sep-2012
US8796822B2	5-Aug-2014	Stacked semiconductor devices	PELLEY PERRY H (US); HESS KEVIN J (US); MCSHANE MICHAEL B (US)	US201 113268 681A	7-Oct-2011
US9076664B2	7-Jul-2015	Stacked semiconductor die with continuous conductive vias	PELLEY PERRY H (US); HESS KEVIN J (US); MCSHANE MICHAEL B (US)	US201 113268 580A	7-Oct-2011
US8815619B2	26-Aug-2014	Method of manufacturing display unit	ARAI TOSHIAKI (JP); FUJIMORI TAKASHIGE (JP)	US201 213613 337A	13-Sep-2012
US2013256923A1	3-Oct-2013	Semiconductor Device and Method of Forming Reconstituted Wafer With Larger Carrier to Achieve More EWL B Packages Per Wafer with Encapsulant Deposited Under Temperature and Pressure	PHUA YOKE HOR (SG); HSIAO YUNG KUAN (SG)	US201 313906 060A	30-May-2013
US8975722B2	10-Mar-2015	MEMS device and method of manufacture	HALL JAMES N (US); BARRON LANCE W (US); GONG CUILING (US)	US201 414282 892A	20-May-2014
US10133180B2	20-Nov-2018	Microelectronic substrate cleaning compositions having copper/azole polymer inhibition	HSU CHIEN PIN SHERMAN (US)	US201 214348 955A	5-Oct-2012
US10056670B2	21-Aug-2018	Method for making electrical structure with air dielectric and related electrical structures	WEATHERSPOON MICHAEL RAYMOND (US); RENDEK JR LOUIS JOSEPH (US); SHACKLETTE LAWRENCE WAYNE (US); MALONEY ROBERT PATRICK (US); SMITH DAVID M (US)	US201 514857 943A	18-Sep-2015

US8866265B2	21-Oct-2014	Carbon-based semiconductors	BAO ZHENAN (US); RAMUZ MARC (FR); VOSGUERITCHIAN MICHAEL (US)	US201 3-Oct-2012 213573 726A
US9093488B2	28-Jul-2015	AC-driven electrostatic chuck	ANADA KAZUKI (JP); ISHIKAWA KADUKO (JP); YOSHII YUICHI (JP); YONEZAWA JUNJI (JP)	US201 27-Sep-2012 214344 736A
US2014227527A1	14-Aug-2014	INORGANIC MATERIALS, METHODS AND APPARATUS FOR MAKING SAME, AND USES THEREOF	BRORS DANIEL (US); DE MARAY RICHARD ERNEST (US); SLUTZ DAVID (US)	US201 27-Sep-2012 214348 406A
US10332657B2	25-Jun-2019	Methods for forming gold nanowires on a substrate and gold nanowires formed thereof	CHEN HONGYU (SG); HE JIATING (SG); WANG YAWEN (SG)	US201 24-Sep-2012 214346 243A
US10607946B2	31-Mar-2020	Semiconductor device and method of forming interconnect substrate for FO-WLCSP	LIN YAOJIAN (CN); FANG JIANMIN (CN); FENG XIA (SG); CHEN KANG (SG)	US201 2-May-2017 715584 697A
US10170385B2	1-Jan-2019	Semiconductor device and method of forming stacked vias within interconnect structure for FO-WLCSP	LIN YAOJIAN (SG); HUANG RUI (SG); CHEN KANG (SG); GU YU (SG)	US201 31-May-2016 615169 261A
US9431545B2	30-Aug-2016	Semiconductor device and method for manufacturing the same	SAITO TOSHIHIKO (JP); ISOBE ATSUO (JP); HANAOKA KAZUYA (JP); KOEZUKA JUNICHI (JP); SASAGAWA SHINYA (JP); KURATA MOTOMU (JP); ISHIZUKA AKIHIRO (JP)	US201 6-Sep-2012 213604 962A
US9953845B2	24-Apr-2018	Methods and systems for forming electronic modules	MALSTROM CHARLES RANDALL (US); SARRAF DAVID (US); MORALES MIGUEL ANGEL (US); RADZILOWSKI LEONARD HENRY (US); LAUB MICHAEL FREDRICK (US)	US201 23-Sep-2011 113242 240A
US9362126B2	7-Jun-2016	Process for making a patterned metal oxide structure	GANESAN RAMAKRISHNAN (SG); DUMOND JARRETT (SG); SAIFULLAH M S M (SG); LIM SU HUI (SG); HUSSAIN HAZRAT (SG); LOW HONG YEE (SG)	US201 24-Sep-2012 213625 400A
US9082832B2	14-Jul-2015	Semiconductor device and method of forming protection and support structure for conductive interconnect structure	LIN YAOJIAN (SG); CHEN KANG (SG); FANG JIANMIN (CN)	US201 22-May-2012 213478 008A
US9484259B2	1-Nov-2016	Semiconductor device and method of forming protection and support structure for conductive interconnect structure	LIN YAOJIAN (SG); CHEN KANG (SG); FANG JIANMIN (CN)	US201 21-Sep-2011 113239 080A
US9275877B2	1-Mar-2016	Semiconductor device and method of forming semiconductor package using panel form carrier	LIN YAOJIAN (SG); HUANG RUI (SG); KUAN HEAP HOE (SG); CHOW SENG GUAN (SG)	US201 20-Sep-2011 113236 952A
US8835212B2	16-Sep-2014	Combinatorial methods for developing superstrate thin film solar cells	AVACHAT UPENDRA (US)	US201 19-Sep-2011 113236 430A
US9460999B2	4-Oct-2016	Solution process for improved nanowire electrodes and devices that use the electrodes	YANG YANG (US); ZHU RUI (US)	US201 13-Sep-2012 214344 038A
US2013244922A1	19-Sep-2013	AZEOTROPIC COMPOSITIONS COMPRISING METHYL PERFLUOROPENTENE ETHERS FOR CLEANING APPLICATIONS	BARTELT JOAN ELLEN (US); MINOR BARBARA HAVILAND (US)	US201 11-Sep-2012 213609 857A

US8906454B2	9-Dec-2014	Methods for depositing metal-polymer composite materials atop a substrate	CHATTERJEE SUKTI (US); CHATTERJEE AMIT (US)	US201 213608 172A	10-Sep-2012
US9459534B2	4-Oct-2016	Photolithographic methods	BAE YOUNG CHEOL (US); BELL ROSEMARY (US); PARK JONG KEUN (US); LEE SEUNG HYUN (KR)	US201 514826 344A	14-Aug-2015
US10008419B2	26-Jun-2018	Separation method, computer storage medium, and separation system	OKADA SHINJI (JP); SHIRAISHI MASATOSHI (JP); DEGUCHI MASATOSHI (JP); BRUN XAVIER FRANCOIS (US); SINGLETON JR CHARLES WAYNE (US); MIRPURI KABIRKUMAR (US)	US201 214343 598A	22-Aug-2012
US9362451B2	7-Jun-2016	Light emitting diode and light emitting device package including the same	JUNG MYUNG HOON (KR); LIM HYUN CHUL (KR); KIM SUL HEE (KR); CHOI RAK JUN (KR)	US201 514594 487A	12-Jan-2015
US10158049B2	18-Dec-2018	Method of bonding a substrate to a semiconductor light emitting device	BASIN GRIGORIY (US); EPLER JOHN EDWARD (US); MARTIN PAUL SCOTT (US)	US201 214131 686A	30-Jul-2012
US8569086B2	29-Oct-2013	Semiconductor device and method of dicing semiconductor devices	LIN JING CHENG (TW); WU CHIH WEI (TW); LU SZU WEI (TW); JENG SHIN PUU (TW); YU CHEN HUA (TW)	US201 113216 825A	24-Aug-2011
US9633871B2	25-Apr-2017	Light-emitting device	HATANO KAORU (JP); NISHIDO YUSUKE (JP); YAMAZAKI SHUNPEI (JP)	US201 213588 605A	17-Aug-2012
US9099406B2	4-Aug-2015	Organic electroluminescence display device, and electronic system	MATSUMI TATSUYA (JP); IMAI TOSHIAKI (JP)	US201 213571 109A	9-Aug-2012
US9291915B2	22-Mar-2016	Lithographic method with the capability of spectrum engineering to create complex microstructures	CSETE MARIA (HU); SIPOS ARON (HU); SZALAI ANIKO (HU)	US201 214240 170A	23-Aug-2012
US8969174B2	3-Mar-2015	Fixed curvature force loading of mechanically spalled films	BEDELL STEPHEN W (US); FOGEL KEITH E (US); LAURO PAUL A (US); LIU XIAO H (US); SADANA DEVENDRA K (US)	US201 414168 471A	30-Jan-2014
US8828489B2	9-Sep-2014	Homogeneous modification of porous films	DUBOIS GERAUD JEAN MICHEL (US); FROT THEO J (US); VOLKSEN WILLI (US)	US201 113213 740A	19-Aug-2011
US2014357081A1	4-Dec-2014	METHOD OF FORMING A CONDUCTIVE IMAGE ON A NON-CONDUCTIVE SURFACE	WISMANN WILLIAM (US)	US201 414304 609A	13-Jun-2014
US10734347B2	4-Aug-2020	Dummy flip chip bumps for reducing stress	WU SHENG YU (TW); KUO TIN HAO (TW); CHUANG CHITA (TW); CHEN CHEN SHIEN (TW)	US201 916400 504A	1-May-2019
US10087545B2	2-Oct-2018	Automated cleaning of wafer plating assembly	MAYER STEVEN T (US); PONNUSWAMY THOMAS A (US); CHUA LEE PENG (US); RASH ROBERT (US)	US201 514949 681A	23-Nov-2015
US10283674B2	7-May-2019	Graphene-based solid state devices capable of emitting electromagnetic radiation and improvements thereof	MORREALE JAY P (US)	US201 715696 796A	6-Sep-2017

US9653335B2	16-May-2017	Wafer processing laminate, wafer processing member, temporary bonding arrangement, and thin wafer manufacturing method	KATO HIDETO (JP); SUGO MICHIIHIRO (JP); TAGAMI SHOHEI (JP)	US201 24-Jul-2012 213556 655A
US9455152B2	27-Sep-2016	Hydrogenation method and hydrogenation apparatus	KITANO KATSUHISA (JP)	US201 19-Jul-2012 214235 055A
US9388498B2	12-Jul-2016	Electrochemical liquid-liquid-solid deposition processes for production of group IV semiconductor materials	MALDONADO STEPHEN (US); CARIM AZHAR (US)	US201 20-Jul-2012 214234 084A
US9034139B2	19-May-2015	Temporary adhesion of chemically similar substrates	KOELLNBERGER ANDREAS (DE); ACHENBACH FRANK (DE)	US201 11-Jul-2012 214233 071A
US8796768B2	5-Aug-2014	Organic light emitting display device including nano silver particles and method of manufacturing the same	YOU CHUN GI (KR)	US201 1-Dec-2011 113309 235A
US8766411B2	1-Jul-2014	Filler for filling a gap, method of preparing the same and method of manufacturing semiconductor capacitor using the same	PARK EUN SU (KR); KIM BONG HWAN (KR); LIM SANG HAK (KR); KWAK TAEK SOO (KR); BAE JIN HEE (KR); YUN HUI CHAN (KR); KIM SANG KYUN (KR); LEE JIN WOOK (KR)	US201 13-Jul-2012 213548 519A
US8871632B2	28-Oct-2014	Reduction of pore fill material dewetting	DUBOIS GERAUD JEAN MICHEL (US); FROT THEO J (US); MAGBITANG TEDDIE P (US); VOLKSEN WILLI (US)	US201 19-Oct-2012 213655 599A
US8927430B2	6-Jan-2015	Overburden removal for pore fill integration approach	BRUCE ROBERT L (US); DUBOIS GERAUD JEAN MICHEL (US); FROT THEO J (US); VOLKSEN WILLI (US)	US201 12-Jul-2011 113180 710A
US8951819B2	10-Feb-2015	Wafer dicing using hybrid split-beam laser scribing process with plasma etch	LEI WEI SHENG (US); EATON BRAD (US); YALAMANCHILI MADHAVA RAO (US); SINGH SARAVJEET (US); KUMAR AJAY (US); IYER APARNA (US)	US201 11-Jul-2011 113180 021A
US8435824B2	7-May-2013	Backside illumination sensor having a bonding pad structure and method of making the same	TSAI SHUANG JI (TW); YAUNG DUN NIAN (TW); LIN JENG SHYAN (TW); LIU JEN CHENG (TW); WANG WEN DE (TW); LIN YUEH CHIOU (TW)	US201 7-Jul-2011 113177 686A
US8685843B2	1-Apr-2014	Direct growth of graphene on substrates	LI LAIN JONG (TW); SU CHING YUAN (TW); LU ANG YU (TW); WU CHIH YU (TW); LIU KENG KU (TW)	US201 9-Jan-2012 213346 152A
US9373731B2	21-Jun-2016	Dielectric structures in solar cells	LENNON ALISON JOAN (AU); LI ZHONGTIAN (AU); WENHAM STUART ROSS (AU); LU PEI HSUAN (AU)	US201 28-Jun-2012 214128 465A
US8940621B2	27-Jan-2015	Methods of forming semiconductor modules including flexible panels	HAN SANG UK (KR); HA JEONG KYU (KR); KWON YOUNGSHIN (KR); KIM SEUNG HWAN (KR); LEE KWANJAI (KR)	US201 25-Jun-2012 213531 983A
US8993994B2	31-Mar-2015	Light-emitting device and organic light emitting display apparatus including the same	SONG JUNG BAE (KR); LEE SANG PIL (KR); SONG YOUNG ROK (KR)	US201 28-Jun-2012 213537 001A
US2015061085A1	5-Mar-2015	PACKAGE INTERCONNECTS	YU HONG (SG); LIU HUANG (SG)	US201 7-Nov-2014 414535 337A

US10672765B2	2-Jun-2020	Methods of manufacturing transistors including forming a depression in a surface of a covering of resist material	PRICE RICHARD (GB); WHITE SCOTT (GB)	US201 12-Aug-2016 615236 057A
US9006031B2	14-Apr-2015	Semiconductor device and method of forming EWL package with standoff conductive layer over encapsulant bumps	CAMACHO ZIGMUND R (SG); BATHAN HENRY D (SG); ESPIRITU EMMANUEL A (SG)	US201 23-Jun-2011 113167 133A
US11164891B2	2-Nov-2021	Integrated circuits with components on both sides of a selected substrate and methods of fabrication	CABLE JAMES S (US); MISCIONE ANTHONY MARK (US); REEDY RONALD EUGENE (US)	US201 9-Apr-2018 815948 939A
US9190340B2	17-Nov-2015	Semiconductor device and method of forming RF FEM and RF transceiver in semiconductor package	LEE YONGTAEK (KR); KIM HYUNTAI (KR); KIM GWANG (KR); AHN BYUNGHOON (KR); LIU KAI (US)	US201 17-Jun-2011 113163 026A
US9768307B2	19-Sep-2017	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); HONDA TATSUYA (JP)	US201 27-Dec-2016 615391 027A
US9040975B2	26-May-2015	Organic electroluminescence element, illumination device, and display device	TANI KUNIO (JP); KATAKURA RIE (JP); INOUE SATORU (JP)	US201 11-Jun-2012 214119 533A
US9126285B2	8-Sep-2015	Laser and plasma etch wafer dicing using physically-removable mask	LEI WEI SHENG (US); SINGH SARAVJEET (US); YALAMANCHILI MADHAVA RAO (US); EATON BRAD (US); KUMAR AJAY (US)	US201 15-Jun-2011 113161 036A
US9129904B2	8-Sep-2015	Wafer dicing using pulse train laser with multiple-pulse bursts and plasma etch	LEI WEI SHENG (US); SINGH SARAVJEET (US); YALAMANCHILI MADHAVA RAO (US); EATON BRAD (US); KUMAR AJAY (US)	US201 15-Jun-2011 113161 026A
US2012322235A1	20-Dec-2012	WAFER DICING USING HYBRID GALVANIC LASER SCRIBING PROCESS WITH PLASMA ETCH	LEI WEI SHENG (US); SINGH SARAVJEET (US); YALAMANCHILI MADHAVA RAO (US); EATON BRAD (US); KUMAR AJAY (US)	US201 15-Jun-2011 113161 006A
US8865395B2	21-Oct-2014	Method of forming resist pattern	NAKAMURA TSUYOSHI (JP); ISHIKAWA KIYOSHI (JP)	US201 6-Jun-2012 213489 862A
US9112036B2	18-Aug-2015	Manufacturing method of semiconductor device	KOEZUKA JUNICHI (JP); OHNO SHINJI (JP); SATO YUICHI (JP); YAMAZAKI SHUNPEI (JP)	US201 29-May-2012 213482 398A
US10833202B2	10-Nov-2020	Manufacturing method of semiconductor device	KOEZUKA JUNICHI (JP); OHNO SHINJI (JP); SATO YUICHI (JP); YAMAZAKI SHUNPEI (JP)	US201 30-Nov-2017 715827 426A
US10192990B2	29-Jan-2019	Semiconductor device and method of manufacturing the same	YOKOI TOMOKAZU (JP); YAMANE YASUMASA (JP)	US201 11-Dec-2014 414567 214A
US9470380B2	18-Oct-2016	Lighting device with electrostatically adhered scattering particles and method of manufacture	CORNELISSEN HUGO JOHAN (NL); VAN DELDEN MARTINUS HERMANUS WILHELMUS MARIA (NL); GOMMANS HENDRIKUS HUBERTUS PETRUS (NL); STOFMEEL LEON WILHELMUS GODEFRIDUS (NL); CENNINI GIOVANNI (NL); YU JIANGHONG (NL)	US201 5-Jun-2012 214122 288A
US9997497B2	12-Jun-2018	Through silicon via structure	YU CHEN HUA (TW); JENG SHIN PUU (TW); CHIOU WEN CHIH (TW); TSAI FANG WEN (TW); TSAI CHEN YU (TW)	US201 11-Apr-2017 715485 104A

US2016254247A1	1-Sep-2016	Fan-out WLP with package	SATO HIROAKI (JP); HASHIMOTO KIYOAKI (JP); NAKADAIRA YOSHIKUNI (JP); MASUDA NORIHITO (JP); HABA BELGACEM (US); MOHAMMED ILYAS (US); DAMBERG PHILIP (US)	US201 9-May-2016 615150 295A
US10262966B2	16-Apr-2019	Methods for surface attachment of flipped active components	BOWER CHRISTOPHER (US)	US201 25-May-2018 815990 449A
US9117918B2	25-Aug-2015	Metal oxide TFT with improved source/drain contacts	SHIEH CHAN LONG (US); YU GANG (US); FOONG FATT (US)	US201 7-Feb-2014 414175 521A
US8435891B2	7-May-2013	Converting metal mask to metal-oxide etch stop layer and related semiconductor structure	ENGEL BRETT H (US); LI YING (US); SARDESAI VIRAJ Y (US); WISE RICHARD S (US)	US201 2-Jun-2011 113151 646A
US9054267B2	9-Jun-2015	Method of manufacturing light absorbing layer for solar cell using selenization process under element selenium vapor ambience and thermal treatment apparatus for manufacturing light absorbing layer	SONG SEONG HOON (KR)	US201 15-Oct-2014 414514 691A
US2012309187A1	6-Dec-2012	Conformal Coining of Solder Joints in Electronic Packages	SRI JAYANTHA SRI M (US); KHANNA VIJAYESHWAR D (US)	US201 29-Jul-2011 113194 902A
US9570384B2	14-Feb-2017	Semiconductor device	WHITE LAWRENCE H (US); VINA ROBERT (US); MCMAHON TERRY (US); PRZYBYLA JAMES R (US)	US201 5-Aug-2015 514818 922A
US10157831B2	18-Dec-2018	Semiconductor device having a conductive via structure	CHANG KUO CHIN (TW); SHIEH YUH CHERN (TW)	US201 15-Nov-2016 615351 697A
US8367545B2	5-Feb-2013	System and method for monitoring copper barrier layer preclean process	SUNG KUO LIANG (TW); WENG CHENG HUI (TW)	US201 25-May-2011 113115 563A
US10723112B2	28-Jul-2020	Method of transferring thin film	CHUA LAY LAY (SG); HO PETER (SG); PNG RUI QI (SG); KAM FONG YU (SG); SONG JIE (SG); WONG LOKE YUEN (SG); ZHUO JING MEI (SG); LOH KIAN PING (SG); LIM GEOK KIENG (SG)	US201 23-May-2012 214119 830A
US9472787B2	18-Oct-2016	Fabrication apparatus for fabricating a patterned layer	RICKERS CHRISTOPH (DE); KRUIJT PIETER GIJSBERTUS MARIA (NL)	US201 9-May-2012 214117 436A
US2014087090A1	27-Mar-2014	METHOD FOR MANUFACTURING PATTERN STRUCTURE	MIYAGAWA TAKASHI (JP); MURAKAMI TETSUYA (JP); OKAMOTO KIMIYASU (JP)	US201 16-May-2012 214118 247A
US2014083458A1	27-Mar-2014	PHOTORESIST STRIPPING SOLUTION, STRIPPING SOLUTION RECYCLING SYSTEM AND OPERATING METHOD, AND METHOD FOR RECYCLING STRIPPING SOLUTION	FUCHIGAMI SHINICHIROU (JP); YAMAGUCHI NORIO (JP); AIKOU MASAHIKO (JP); SHIMIZU KOJI (JP); TAKEZAWA HIROYOSHI (JP)	US201 6-Oct-2011 114115 658A
US8779557B2	15-Jul-2014	Chip package and package wafer with a recognition mark, and method for forming the same	LIU TSANG YU (TW); LIN CHIA SHENG (TW); CHENG CHIA MING (TW); LIN PO SHEN (TW)	US201 21-May-2012 213476 748A

US8664736B2	4-Mar-2014	Bonding pad structure for a backside illuminated image sensor device and method of manufacturing the same	TSAI SHUANG JI (TW); YAUNG DUN NIAN (TW); LIU JEN CHENG (TW); LIN JENG SHYAN (TW); WANG WEN DE (TW); LIN YUEH CHIOU (TW)	US201 20-May-2011 113112 755A
US9082551B2	14-Jul-2015	High dielectric nanosheet laminate, high dielectric element and method for producing the same	OSADA MINORU (JP); EBINA YASUO (JP); SASAKI TAKAYOSHI (JP)	US201 18-May-2012 214118 354A
US9153489B2	6-Oct-2015	Microelectronic devices having conductive through via electrodes insulated by gap regions	LEE HO JIN (KR); PARK BYUNG LYUL (KR); JEONG SEYOUNG (KR); CHUNG HYUNSOO (KR); CHOI GILHEYUN (KR)	US201 18-May-2012 213474 992A
US9336850B2	10-May-2016	Semiconductor device	SHIONOIRI YUTAKA (JP); KOBAYASHI HIDETOMO (JP)	US201 2-Sep-2014 414474 454A
US9117920B2	25-Aug-2015	Method for manufacturing semiconductor device using oxide semiconductor	KOEZUKA JUNICHI (JP); SATO YUHEI (JP); YAMAZAKI SHUNPEI (JP)	US201 9-May-2012 213467 493A
US9214374B2	15-Dec-2015	Semiconductor devices including stress relief structures	LEE DOSUN (KR); YUN KIYOUNG (KR); PARK YEONGLYEOL (KR); CHOI GILHEYUN (KR); BAE KISOON (KR); MOON KWANGJIN (KR)	US201 13-Mar-2012 213418 915A
US9076768B2	7-Jul-2015	Systems and methods for producing low work function electrodes	KIPPELEN BERNARD (US); FUENTES HERNANDEZ CANEK (US); ZHOU YINHUA (US); KAHN ANTOINE (US); MEYER JENS (US); SHIM JAE WON (US); MARDER SETH R (US)	US201 16-May-2012 214117 965A
US9765934B2	19-Sep-2017	Thermally managed LED arrays assembled by printing	ROGERS JOHN A (US); KIM HOON SIK (US); HUANG YONGGANG (US)	US201 15-May-2012 213472 165A
US9159841B2	13-Oct-2015	Method for manufacturing semiconductor device	TANAKA TETSUHIRO (JP); SASAGAWA SHINYA (JP)	US201 8-May-2012 213466 480A
US9934998B2	3-Apr-2018	Semiconductor device and method of singulating thin semiconductor wafer on carrier along modified region within non-active region formed by irradiating energy	HAN BYUNG JOON (SG); SHIM IL KWON (SG); CHOI WON KYOUNG (SG)	US201 14-Dec-2016 615379 178A
US9653327B2	16-May-2017	Methods of removing a material layer from a substrate using water vapor treatment	LEE KWANGDUK DOUGLAS (US); RATHI SUDHA (US); CHAN CHIU (US); SEAMONS MARTIN J (US); KIM BOK HEON (US)	US201 8-Nov-2011 113291 286A
US2012285627A1	15-Nov-2012	Elastomer Bonded Item and Method for Debonding	SCATENA RYAN A (US); SIMPSON WAYNE R (US)	US201 8-May-2012 213466 890A
US9054196B2	9-Jun-2015	Sputtering target comprising an oxide sintered body comprising In, Ga, and Zn	ITOSE MASAYUKI (JP); NISHIMURA MAMI (JP); KAWASHIMA HIROKAZU (JP); SUNAGAWA MISA (JP); KASAMI MASASHI (JP); YANO KOKI (JP)	US201 1-May-2012 214116 328A
US2014080249A1	20-Mar-2014	HEAT TREATMENT BY INJECTION OF A HEAT-TRANSFER GAS	SAVIDAND GREGORY (FR); LINCOT DANIEL (FR)	US201 3-May-2012 214115 664A
US9306116B2	5-Apr-2016	Semiconductor wafer bonding incorporating electrical and optical interconnects	EL GHOROURY HUSSEIN S (US); CHUANG CHIH LI (US); YADAVALLI KAMESHWAR (US); FAN QIAN (US)	US201 10-Nov-2014 414537 627A

US9035456B2	19-May-2015	Chip package and method for forming the same	LIU CHIEN HUNG (TW)	US201 213467 887A	9-May-2012
US9305790B2	5-Apr-2016	Device and method for knife coating an ink based on copper and indium	KARST NICOLAS (FR); PERRAUD SIMON (FR)	US201 214113 664A	3-May-2012
US8748203B2	10-Jun-2014	Method for making light emitting diode	WEI YANG (CN); FAN SHOU SHAN (CN)	US201 314030 108A	18-Sep-2013
US8367447B2	5-Feb-2013	Method for making light emitting diode	WEI YANG (CN); FAN SHOU SHAN (CN)	US201 113288 234A	3-Nov-2011
US8435819B2	7-May-2013	Method for making light emitting diode	WEI YANG (CN); FAN SHOU SHAN (CN)	US201 113288 246A	3-Nov-2011
US9070794B2	30-Jun-2015	Method for making light emitting diode	WEI YANG (CN); FAN SHOU SHAN (CN)	US201 414529 092A	30-Oct-2014
US2014069488A1	13-Mar-2014	CONDUCTIVE MEMBER, METHOD OF PRODUCING THE SAME, TOUCH PANEL, AND SOLAR CELL	TANAKA SATOSHI (JP); NAKAHIRA SHINICHI (JP); MATSUNAMI YUKI (JP); ASAI TOMOHITO (JP)	US201 314062 504A	24-Oct-2013
US9871088B2	16-Jan-2018	Light-emitting device and manufacturing method thereof	HATANO KAORU (JP)	US201 615162 806A	24-May-2016
US9018110B2	28-Apr-2015	Apparatus and methods for microwave processing of semiconductor substrates	STOWELL MICHAEL W (US); FOAD MAJEED A (US); HOFMANN RALF (US); ADERHOLD WOLFGANG R (US); MOFFATT STEPHEN (US)	US201 214112 012A	29-Mar-2012
US2014120270A1	1-May-2014	DIRECT GROWTH OF GRAPHENE FILMS ON NON-CATALYST SURFACES	TOUR JAMES M (US); YAN ZHENG (US); PENG ZHIWEI (US); SUN ZHENGZONG (CN)	US201 114113 856A	9-Sep-2011
US9023221B2	5-May-2015	Method of forming multi-layer graphene	WOO YUN SUNG (KR); CHOI JAE YOUNG (KR); CHOI WON MOOK (KR); SHIN HYEON JIN (KR); YOON SEON MI (KR)	US201 213451 775A	20-Apr-2012
US9455181B2	27-Sep-2016	Vias in porous substrates	MOHAMMED ILYAS (US); HABA BELGACEM (US); UZOH CYPRIAN EMEKA (US); SAVALIA PIYUSH (US)	US201 514610 300A	30-Jan-2015
US9406532B2	2-Aug-2016	Interposer having molded low CTE dielectric	HABA BELGACEM (US); MOHAMMED ILYAS (US)	US201 414221 486A	21-Mar-2014
US8871573B2	28-Oct-2014	Method for forming a semiconductor device	HIRLER FRANZ (DE); MEISER ANDREAS (DE)	US201 213547 339A	12-Jul-2012
US9604391B2	28-Mar-2017	Laminate, production method for same, and method of creating device structure using laminate	TAMADA MASAHIRO (JP); TSUCHIYA TOSHIYUKI (JP); OKUYAMA TETSUO (JP); OUYA KAZUYUKI (JP); MAEDA SATOSHI (JP)	US201 214111 374A	13-Apr-2012

US9429537B2	30-Aug-2016	Method of detecting volatile organic compounds	KANG MYUNGCHAN (US); PALAZZOTTO MICHAEL C (US); GRYSKA STEFAN H (US)	US201 2-Apr-2012 214007 230A
US10328683B2	25-Jun-2019	Adhesive agent, adhesive material using the same, and method of use thereof	MASUDA KATSUYUKI (JP); YAMAGUCHI MASATOSHI (JP); SHINADA EIICHI (JP); FUKUYAMA TAKEHIRO (JP); SAKAIRI YOSHIHIRO (JP)	US201 12-Apr-2012 213445 398A
US9196760B2	24-Nov-2015	Methods for producing complex films, and films produced thereby	DUTY CHAD E (US); BENNETT CHARLEE J C (US); MOON JI WON (US); PHELPS TOMMY J (US); BLUE CRAIG A (US); DAI QUANQIN (US); HU MICHAEL Z (US); IVANOV ILIA N (US); JELLISON JR GERALD E (US); LOVE LONNIE J (US); OTT RONALD D (US); PARISH CHAD M (US); WALKER STEVEN (US)	US201 22-Mar-2012 214110 222A
US9327982B2	3-May-2016	Method of forming graphene on a surface	KUB FRANCIS J (US); ANDERSON TRAVIS (US); FEYGELSON BORIS N (US)	US201 5-Mar-2013 313785 081A
US2018182894A1	28-Jun-2018	MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE	SATO YUHEI (JP); SATO KEIJI (JP); SASAKI TOSHINARI (JP); MARUYAMA TETSUNORI (JP); ISOBE ATSUO (JP); MURAKAWA TSUTOMU (JP); TEZUKA SACHIAKI (JP)	US201 26-Feb-2018 815904 830A
US9246008B2	26-Jan-2016	Thin-film device, method of manufacturing the same, and method of manufacturing image display apparatus	FUKUDA TOSHIO (JP); ISHII YUI (JP)	US201 21-Aug-2014 414465 640A
US8951911B2	10-Feb-2015	Process for damascene structure with reduced low-k damage	NAIK MEHUL B (US); CUI ZHENJIANG (US)	US201 30-Jun-2011 113174 621A
US8796136B2	5-Aug-2014	Semiconductor device and manufacturing method thereof	SUGIYAMA SATORU (JP); NISHIOKA YUUTA (JP)	US201 30-Mar-2012 213435 403A
US2014017845A1	16-Jan-2014	Method Of Forming A Photovoltaic Cell Module With A Cell Press	JUEN DONNIE (US); KETOLA BARRY (US); SIBBICK RICHARD (GB)	US201 28-Mar-2012 214008 046A
US9281186B2	8-Mar-2016	Colored photovoltaic modules and methods of construction	WOOTTON GERALD R (CA)	US201 2-Apr-2012 213437 378A
US10008588B2	26-Jun-2018	Method for manufacturing oxide semiconductor device	IMOTO YUKI (JP); SATO YUHEI (JP)	US201 26-Dec-2014 414583 416A
US9054042B2	9-Jun-2015	Surface planarisation	FLEISSNER ARNE (DE); MALIK SURAMA (GB); BAKER COLIN (GB); SCULLION LAURENCE (GB); BURROUGHES JEREMY (GB)	US201 21-Mar-2012 214009 069A
US9040832B2	26-May-2015	Wiring substrate and method of manufacturing the same	SHIMIZU YUICHIRO (JP); FUKASAWA RYO (JP)	US201 29-Mar-2012 213433 680A
US8847229B2	30-Sep-2014	Flexible semiconductor device, method for manufacturing the same, image display device using the same and method for manufacturing the image display device	SUZUKI TAKESHI (JP); HIRANO KOICHI (JP); MASUDA SHINOBU (JP)	US201 21-Feb-2012 213820 859A

US8993387B2	31-Mar-2015	Flexible semiconductor device, method for manufacturing the same, image display device using the same and method for manufacturing the image display device	SUZUKI TAKESHI (JP); HIRANO KOICHI (JP); MASUDA SHINOBU (JP)	US201 21-Feb-2012 213821 352A
US8859330B2	14-Oct-2014	Method for manufacturing semiconductor device	KOEZUKA JUNICHI (JP); OHNO SHINJI (JP); SATO YUICHI (JP)	US201 14-Mar-2012 213419 468A
US8911558B2	16-Dec-2014	Post-tungsten CMP cleaning solution and method of using the same	LI HONGQI (US); JINDAL ANURAG (US); LU JIN (US)	US201 23-Mar-2011 113069 408A
US2012241069A1	27-Sep-2012	Direct Synthesis of Patterned Graphene by Deposition	HOFMANN MARIO (US); KONG JING (US)	US201 21-Mar-2012 213425 659A
US8647897B2	11-Feb-2014	Air-stable ink for scalable, high-throughput layer deposition	WEIL BENJAMIN D (US); CONNOR STEPHEN T (US); CUI YI (US)	US201 21-Mar-2012 213426 307A
US2012235315A1	20-Sep-2012	METHOD FOR FABRICATING A FLEXIBLE DEVICE	WU CHUNG JEN (TW); LEE CHUAN ZONG (TW); AN CHIH MIN (TW); SHIH YI CHUNG (TW); HO CHANG HONG (TW)	US201 9-Mar-2012 213415 928A
US2014004320A1	2-Jan-2014	Photopatterning	BENTLEY PHILIP GARETH (GB); THOMAS DAVID STEPHEN (GB)	US201 27-Feb-2012 214004 716A
US2014000690A1	2-Jan-2014	Intrinsically Semitransparent Solar Cell and Method of Making Same	PLOTNIKOV VICTOR V (US); CARTER CHAD W (US); STAYANCHO JOHN M (US); COMPAAN ALVIN D (US)	US201 15-Mar-2012 214004 272A
US2012231583A1	13-Sep-2012	DIE-BONDING FILM AND USE THEREOF	ONISHI KENJI (JP); MORITA MIKI (JP)	US201 8-Mar-2012 213415 689A
US8753928B2	17-Jun-2014	Method of manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); SATO YUHEI (JP); SATO KEIJI (JP); MARUYAMA TETSUNORI (JP)	US201 7-Mar-2012 213413 686A
US11387116B2	12-Jul-2022	Method of manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); SATO YUHEI (JP); SATO KEIJI (JP); MARUYAMA TETSUNORI (JP); KOEZUKA JUNICHI (JP)	US202 2-Mar-2020 016806 211A
US9337097B2	10-May-2016	Chip package and method for forming the same	HUANG YU TING (TW)	US201 25-Mar-2014 414225 336A
US9087954B2	21-Jul-2015	Method for producing the pentanary compound semiconductor CZTSSe, and thin-film solar cell	JOST STEFAN (DE); PALM JORG (DE)	US201 22-Feb-2012 214002 686A
US2014154450A1	5-Jun-2014	ADHESIVE TAPE OR SHEET	YUTOU TAKUMI (JP); ASAI FUMITERU (JP); SHINTANI TOSHIO (JP); SUZUKI TOSHITAKA (JP); HANAOKA MINORU (JP); THYS EDWIN (BE); FORIER BART (BE)	US201 2-Mar-2012 214003 974A
US2015266098A1	24-Sep-2015	PROCESS FOR MAKING SILVER POWDER PARTICLES WITH VERY SMALL SIZE CRYSTALLITES	IRIZARRY RIVERA ROBERTO (US); YANG HAIXIN (US)	US201 22-May-2015 514719 443A

US9515205B2	6-Dec-2016	Method for metallizing textured surfaces	PERNEL CAROLE (FR); CHAIX NICOLAS (FR); LANDIS STEFAN (FR)	US201 214002 854A	5-Mar-2012
US2013330546A1	12-Dec-2013	HEAT-PEELABLE ADHESIVE SHEET	TAKAMI YOSHIHITO (JP); SHIMOKAWA DAISUKE (JP); MURATA AKIHISA (JP)	US201 213810 342A	1-Mar-2012
US8435896B2	7-May-2013	Stable, concentratable chemical mechanical polishing composition and methods relating thereto	LAKROUT HAMED (US); SHI JINJIE (US); LETIZIA JOSEPH (US); LI XU (US); KALANTAR THOMAS H (US); KELLEY FRANCIS (US); HARRIS J KEITH (US); TUCKER CHRISTOPHER J (US)	US201 113039 723A	3-Mar-2011
US8440097B2	14-May-2013	Stable, concentratable, water soluble cellulose free chemical mechanical polishing composition	LAKROUT HAMED (US); SHI JINJIE (US); LETIZIA JOSEPH (US); LI XU (US); KALANTAR THOMAS H (US); KELLEY FRANCIS (US); HARRIS J KEITH (US); TUCKER CHRISTOPHER J (US)	US201 113039 705A	3-Mar-2011
US9385147B2	5-Jul-2016	Electronic systems, thin film transistors, methods of manufacturing thin film transistors and thin film transistor arrays	HONG YOUNG KI (KR); CHUNG JAE WOO (KR); LEE SEUNG HO (KR); KIM JOONG HYUK (KR)	US201 213410 393A	2-Mar-2012
US2025098523A1	20-Mar-2025	Light-Emitting Device	YAMAZAKI SHUNPEI (JP); SEO SATOSHI (JP); OHSAWA NOBUHARU (JP); SHITAGAKI SATOKO (JP); INOUE HIDEKO (JP); KADOMA HIROSHI (JP); OSAKA HARUE (JP); SUZUKI KUNIHIKO (JP); TAKEMURA YASUHIKO (JP)	US202 418899 501A	27-Sep-2024
US8980536B2	17-Mar-2015	Developer compositions and methods of forming photolithographic patterns	BAE YOUNG CHEOL (US); LEE SEUNG HYUN (US)	US201 213407 467A	28-Feb-2012
US9773701B2	26-Sep-2017	Methods of making integrated circuits including conductive structures through substrates	LIU YUAN HUNG (TW); YANG KU FENG (TW); KUO PEI CHING (TW); CHUNG MING TSU (TW); CHEN HSIN YU (TW); WU TSANG JIUH (TW); CHIOU WEN CHIH (TW)	US201 514692 799A	22-Apr-2015
US8710735B2	29-Apr-2014	Organic electroluminescence element	SHIRAI TAKEO (JP); NAKAMURA YOSHIHARU (JP); TAKANO HITOMICHI (JP)	US201 214000 531A	10-Feb-2012
US9793165B2	17-Oct-2017	Methods of fabricating semiconductor devices	JEONG SEYOUNG (KR); CHO TAEJE (KR); SONG HOGEON (KR); LEE KYU HA (KR)	US201 213345 441A	6-Jan-2012
US9502294B2	22-Nov-2016	Method and system for wafer level singulation	SCHUEGRAF KLAUS (US); RAMASWAMI SESHADRI (US); RICE MICHAEL R (US); SALEK MOHSEN S (US); BJORKMAN CLAES H (US)	US201 314075 603A	8-Nov-2013
US2014220728A1	7-Aug-2014	METHODS OF FORMING SEMICONDUCTOR FILMS INCLUDING I2-II-IV-VI4 AND I2-(II,IV)-IV-VI4 SEMICONDUCTOR FILMS AND ELECTRONIC DEVICES INCLUDING THE SEMICONDUCTOR FILMS	HILLHOUSE HUGH (US); KI WOOSEOK (US)	US201 214000 183A	17-Feb-2012
US9080068B2	14-Jul-2015	Gallium formulated ink and methods of making and using same	MOSLEY DAVID (US); THORSEN DAVID (US)	US201 213679 519A	16-Nov-2012
US8673401B2	18-Mar-2014	Gallium ink and methods of making and using same	MOSLEY DAVID (US); THORSEN DAVID (US)	US201 313735 497A	7-Jan-2013

US8906253B2	9-Dec-2014	Gap embedding composition, method of embedding gap and method of producing semiconductor device by using the composition	YAMAMOTO KEIJI (JP)	US201 313906 027A	30-May-2013
US8956969B2	17-Feb-2015	Hole formation method, multilayer wiring, semiconductor device, display element, image display device, and system containing via hole formed by the hole formation method	SONE YUJI (JP); UEDA NAOYUKI (JP); NAKAMURA YUKI (JP); ABE YUKIKO (JP); MURATA KAZUHIRO (JP); MASUDA KAZUYUKI (JP)	US201 213372 874A	14-Feb-2012
US9060415B2	16-Jun-2015	Method for producing substrate having surface nanostructure	FUJIKAWA SHIGENORI (JP); HAYAKAWA HARUMI (JP); SENZAKI TAKAHIRO (JP); MIYAGI KEN (JP)	US201 213984 405A	15-Feb-2012
US8593059B2	26-Nov-2013	Lighting device	TANAKA KOICHIRO (JP); NISHIDO YUSUKE (JP)	US201 213371 779A	13-Feb-2012
US8828859B2	9-Sep-2014	Method for forming semiconductor film and method for manufacturing semiconductor device	TANAKA TETSUHIRO (JP); TOKUMARU RYO (JP); OHTSUKI TAKASHI (JP); TAJIMA RYOTA (JP); KATO ERIKA (JP)	US201 213368 379A	8-Feb-2012
US9034685B2	19-May-2015	Methodology for forming pnictide compositions suitable for use in microelectronic devices	KIMBALL GREGORY M (US); BOSCO JEFFREY P (US); ATWATER HARRY A (US); LEWIS NATHAN S (US); DEGROOT MARTY W (US); STEVENS JAMES C (US)	US201 213984 765A	10-Feb-2012
US9437767B2	6-Sep-2016	Multiple solar cell and method for manufacturing the same	STROBL GERHARD (DE)	US201 514689 652A	17-Apr-2015
US8928141B2	6-Jan-2015	Method for fabricating two substrates connected by at least one mechanical and electrically conductive connection and structure obtained	SOURIAU JEAN CHARLES (FR)	US201 213983 201A	31-Jan-2012
US10522695B2	31-Dec-2019	Inorganic multilayer stack and methods and compositions relating thereto	PRASAD RAVI (US); HOLLARS DENNIS R (US)	US201 213981 317A	27-Jan-2012
US10541140B2	21-Jan-2020	Process for filling vias in the microelectronics	RICHARDSON THOMAS B (US); ABYS JOSEPH A (US); SHAO WENBO (US); WANG CHEN (US); PANECCASIO JR VINCENT (US); WANG CAI (US); LIN XUAN (US); ANTONELLIS THEODORE (US)	US201 213981 974A	26-Jan-2012
US2013306597A1	21-Nov-2013	PROCESSING APPARATUS AND METHOD FOR PROCESSING METAL FILM	GUNJI ISAO (JP); MIYOSHI HIDENORI (JP); HARA KENICHI (JP)	US201 313950 658A	25-Jul-2013
US9048327B2	2-Jun-2015	Microcrystalline semiconductor film, method for manufacturing the same, and method for manufacturing semiconductor device	TANAKA TETSUHIRO (JP); IENAGA TAKASHI (JP); KOMATSU RYU (JP); KATO ERIKA (JP); TAJIMA RYOTA (JP); JINBO YASUHIRO (JP)	US201 213355 340A	20-Jan-2012
US2012190180A1	26-Jul-2012	Thin film crystallization device and method for making a polycrystalline composition	LOBUE JOSEPH D (US); LU DINGYUAN (US); ELDADA LOUAY (US)	US931 06711A	24-Jan-2011
US9666689B2	30-May-2017	Semiconductor device and method for manufacturing the same	KUWABARA HIDEAKI (JP)	US201 514696 681A	27-Apr-2015
US8759161B2	24-Jun-2014	Surface coating method, semiconductor device, and circuit board package	KON JUNICHI (JP)	US201 213347 951A	11-Jan-2012

US9691698B2	27-Jun-2017	Method of transferring and electrically joining a high density multilevel thin film to a circuitized and flexible organic substrate and associated devices	WEATHERSPOON MICHAEL RAYMOND (US); NICOL DAVID B (US); RENDEK JR LOUIS JOSEPH (US)	US201 8-Jul-2016 615205 416A
US9399693B2	26-Jul-2016	Resin composition for photoimprinting, pattern forming process and etching mask	HAYASHIDA YOSHIHISA (JP); SATSUKA TAKURO (JP); IKEDA TERUYO (JP); FUTAESAKU NORIO (JP); TAKEMORI TOSHIFUMI (JP)	US201 2-Dec-2011 113979 527A
US10593786B2	17-Mar-2020	Manufacturing method of the semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 1-May-2017 715583 132A
US9166026B2	20-Oct-2015	Manufacturing method of semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 12-Sep-2013 314025 040A
US9570484B2	14-Feb-2017	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP)	US201 20-Oct-2014 414518 125A
US2012175244A1	12-Jul-2012	Film Formation Apparatus and Manufacturing Apparatus	YAMAZAKI SHUNPEI (JP)	US201 10-Jan-2012 213347 075A
US10622516B2	14-Apr-2020	Epitaxial structure and method for making the same	WEI YANG (CN); FAN SHOU SHAN (CN)	US201 1-Nov-2018 816177 449A
US8735284B2	27-May-2014	Conductive metal and diffusion barrier seed compositions, and methods of use in semiconductor and interlevel dielectric substrates	MALONE KELLY (US); HICHRI HABIB (US)	US201 12-Nov-2013 314077 805A
US8853819B2	7-Oct-2014	Semiconductor structure with passive element network and manufacturing method thereof	CHEN CHIEN HUA (TW); LEE TECK CHONG (TW); SHIH HSU CHIANG (TW); HSIEH MENG WEI (TW)	US201 27-Dec-2011 113338 087A
US8847232B2	30-Sep-2014	Transistor including reduced channel length	TUTT LEE W (US); NELSON SHELBY F (US)	US986 7-Jan-2011 19711A
US8852991B2	7-Oct-2014	Methods of manufacturing solar cell	CHUNG YONG DUCK (KR)	US201 30-Dec-2011 113340 723A
US2019354015A1	21-Nov-2019	COATING COMPOSITIONS FOR USE WITH AN OVERCOATED PHOTORESIST	ONGAYI OWENDI (US); JAIN VIPUL (US); COLEY SUZANNE (US); ZAMPINI ANTHONY (US)	US201 29-Jul-2019 916525 526A
US8415751B2	9-Apr-2013	Method to reduce contact resistance of N-channel transistors by using a III-V semiconductor interlayer in source and drain	MUKHERJEE NILOY (US); DEWEY GILBERT (US); RADOSAVLJEVIC MARKO (US); CHAU ROBERT S (US); METZ MATTHEW V (US)	US982 30-Dec-2010 08310A
US8741540B2	3-Jun-2014	Hard mask composition, method of forming a pattern, and semiconductor integrated circuit device including the pattern	KIM MIN SOO (KR); CHEON HWAN SUNG (KR); SONG JEE YUN (KR); KIM YOUNG MIN (KR); LEE CHEOL HO (KR); LEE CHUNG HEON (KR)	US201 23-Sep-2011 113241 389A
US9508553B2	29-Nov-2016	Photoresists and methods for use thereof	POHLERS GERD (US); CAPORALE STEFAN J (US)	US201 30-Dec-2011 113341 359A

US8426299B2	23-Apr-2013	Method of manufacturing semiconductor device	KIM JOON SUNG (KR); SHIN HYE SOO (KR); KIM MI YOUN (KR); KIM YOUNG SOO (KR)	US201 113337 748A	27-Dec-2011
US8329575B2	11-Dec-2012	Fabrication of through-silicon vias on silicon wafers	RAJAGOPALAN NAGARAJAN (US); PARK JI AE (US); YAMASE RYAN (US); PATEL SHAMIK (US); NOWAK THOMAS (US); XIA LI QUN (US); KIM BOK HOEN (US); DING RAN (US); BALDINO JIM (US); NAIK MEHUL (US); RAMASWAMI SESH (US)	US977 06010A	22-Dec-2010
US2017309593A1	26-Oct-2017	Semiconductor chip assembly and method for making same	KANG TECK GYU (US); WANG WEI SHUN (US); SATO HIROAKI (JP); HASHIMOTO KIYOAKI (JP); NAKADAIRA YOSHIKUNI (JP); MASUDA NORIHITO (JP); HABA BELGACEM (US); MOHAMMED ILYAS (US); DAMBERG PHILIP (US)	US201 715644 552A	7-Jul-2017
US11090903B2	17-Aug-2021	Superhydrophobic and superoleophobic nanosurfaces	JIN SUNGHO (US); CHOI CHULMIN (US)	US201 916689 946A	20-Nov-2019
US9228118B2	5-Jan-2016	Production method for polyamide acid particles, production method for polyimide particles, polyimide particles and bonding material for electronic component	HAYASHI SATOSHI (JP)	US201 113993 808A	14-Dec-2011
US8415805B2	9-Apr-2013	Etched wafers and methods of forming the same	SHEN HONG (US)	US971 46510A	17-Dec-2010
US8741539B2	3-Jun-2014	Hardmask composition, method of forming a pattern using the same, and semiconductor integrated circuit device including the pattern	OH SEUNG BAE (KR); CHEON HWAN SUNG (KR); CHO SUNG WOOK (KR); KIM MIN SOO (KR); SONG JEE YUN (KR); CHOI YOO JEONG (KR)	US201 113241 332A	23-Sep-2011
US8981360B2	17-Mar-2015	Method for manufacturing an OLED device	BILAINE MATTHIEU (FR); LIENHART FABIEN (FR); YEH LI YA (DE); ALSCHINGER MATTHIAS (DE)	US201 113990 560A	19-Dec-2011
US9018776B2	28-Apr-2015	Hardmask composition including aromatic ring-containing compound, method of forming patterns, and semiconductor integrated circuit device including the patterns	SONG JEE YUN (KR); KIM MIN SOO (KR); CHEON HWAN SUNG (KR); OH SEUNG BAE (KR); CHOI YOO JEONG (KR)	US201 113241 479A	23-Sep-2011
US9318577B2	19-Apr-2016	Semiconductor device and method for manufacturing semiconductor device	KOEZUKA JUNICHI (JP); SHINOHARA SATOSHI (JP); SUZUKI MIKI (JP); OHNUMA HIDETO (JP)	US201 414284 857A	22-May-2014
US8552536B2	8-Oct-2013	Flexible integrated circuit device layers and processes	SASAGAWA TERUO (US); ARBUCKLE BRIAN (US)	US970 14010A	16-Dec-2010
US9613847B2	4-Apr-2017	Integration of shallow trench isolation and through-substrate vias into integrated circuit designs	BACHMAN MARK A (US); MERCHANT SAILESH M (US); OSENBACH JOHN (US)	US201 414251 258A	11-Apr-2014
US9230829B2	5-Jan-2016	Adhesive compound and method for encapsulating an electronic arrangement	TELGENBUSCHER KLAUS (DE); GRUNAUER JUDITH (DE); ELLINGER JAN (DE)	US201 113992 269A	3-Nov-2011
US9524874B2	20-Dec-2016	Aqueous polishing composition and process for chemically mechanically polishing substrates containing silicon oxide dielectric and polysilicon films	VENKATARAMAN SHYAM SUNDAR (TW); SU EASON YU SHEN (TW); KINGMA AREND JOUKE (DE); NOLLER BASTIAN MARTEN (DE)	US201 113991 924A	7-Dec-2011

US9437557B2	6-Sep-2016	High density three-dimensional integrated capacitors	MOHAMMED ILYAS (US); HABA BELGACEM (US); UZOH CYPRIAN EMEKA (US); SAVALIA PIYUSH (US); OGANESIAN VAGE (US)	US201 6-Nov-2015 514934 544A
US9120199B2	1-Sep-2015	Polishing liquid composition	YOSHINO TAIKI (JP)	US201 8-Dec-2011 113314 397A
US2021265460A1	26-Aug-2021	High Density Three-dimensional Integrated Capacitors	OGANESIAN VAGE (US); HABA BELGACEM (US); MOHAMMED ILYAS (US); SAVALIA PIYUSH (US)	US202 10-May-2021 117316 102A
US8847231B2	30-Sep-2014	Organic light emitting display device and manufacturing method for the same	LEE JUNE WOO (KR); YOU CHUN GI (KR); CHOI JOON HOO (KR)	US201 29-Nov-2013 314093 333A
US10388559B2	20-Aug-2019	Apparatus for depositing a layer on a substrate in a processing gas	RIESCHL SVEN UWE (CH); ELGHAZZALI MOHAMED (AT); WEICHART JURGEN (LI)	US201 23-Sep-2016 615273 811A
US9390921B2	12-Jul-2016	Adhesion layer for solution-processed transition metal oxides on inert metal contacts	KUGLER THOMAS (GB)	US201 1-Dec-2011 113992 237A
US8541309B2	24-Sep-2013	Processing assembly for semiconductor workpiece and methods of processing same	RYE JASON (US); HANSON KYLE M (US)	US960 3-Dec-2010 37210A
US9478600B2	25-Oct-2016	Method of forming substrate contact for semiconductor on insulator (SOI) substrate	WANG GENG (US); BOOTH JR ROGER A (US); CHENG KANGGUO (US); ERVIN JOSEPH (US); PEI CHENGWEN (US); TODI RAVI M (US)	US201 7-Feb-2014 414175 587A
US9799537B2	24-Oct-2017	Processing assembly for semiconductor workpiece and methods of processing same	RYE JASON (US); HANSON KYLE M (US)	US960 3-Dec-2010 37810A
US2013264526A1	10-Oct-2013	MOLECULAR PRECURSORS AND PROCESSES FOR PREPARING COPPER INDIUM GALLIUM SULFIDE/SELENIDE COATINGS AND FILMS	CAO YANYAN (US); CATRON JR JOHN W (US); JOHNSON LYNDIA KAYE (US); LU MEIJUN (US); MALAJOVICH IRINA (US); RADU DANIELA RODICA (US)	US201 1-Dec-2011 113885 105A
US8624241B2	7-Jan-2014	Semiconductor chip, stack-type semiconductor package	OH TAC KEUN (KR)	US201 30-Nov-2011 113307 197A
US2019211467A1	11-Jul-2019	High Rate Electric Field Driven Nanoelement Assembly on an Insulated Surface	SIRMAN ASLI (US); BUSNAINA AHMED (US); YILMAZ CIHAN (US); HUANG JUN (US); SOMU SIVASUBRAMANIAN (US)	US201 19-Mar-2019 916358 324A
US8314020B2	20-Nov-2012	Method for patterning a metal layer and method for manufacturing semiconductor devices by using the same	HUANG SUNG HUI (TW); LAN WEI CHOU (TW); YEH CHIA CHUN (TW); SHINN TED HONG (TW)	US201 10-Feb-2011 113024 335A
US8575760B2	5-Nov-2013	Semiconductor devices having electrodes	PHEE JAE HYUN (KR); LEE UIHYOUNG (KR); CHOI JU IL (KR); KIM JUNG HWAN (KR)	US201 23-Nov-2011 113303 255A
US8912088B2	16-Dec-2014	Transfer substrate for forming metal wiring and method for forming metal wiring using said transfer substrate	OGASHIWA TOSHINORI (JP); KURITA MASAOKI (JP); NISHIMORI TAKASHI (JP); KANEHIRA YUKIO (JP)	US201 18-Nov-2011 113879 803A

US2013245167A1	19-Sep-2013	RESIN COMPOSITION, INSULATING FILM, FILM FORMING METHOD, AND ELECTRONIC PART	OKANIWA MOTOKI (JP); UNO TAKAAKI (JP); OKADA TAKASHI (JP)	US201 113989 073A	22-Nov-2011
US9508840B2	29-Nov-2016	Diode, use thereof, and a method for producing the same	BERGGREN MAGNUS (SE); WANG XIN (SE); ROBERTSSON MATS (SE); NORBERG PETRONELLA (SE); COOPER PHILIP GEORGE (GB); ERSMAN PETER ANDERSSON (SE)	US201 113988 976A	22-Nov-2011
US9134614B2	15-Sep-2015	Photoimaging	KENNETT JONATHAN (GB); CUNNINGHAM JOHN (GB); GIBSON ROBERT (GB)	US201 113824 019A	11-Nov-2011
US8865525B2	21-Oct-2014	Method of making cavity substrate with built-in stiffener and cavity substrate manufactured thereby	LIN CHARLES W C (SG); WANG CHIA CHUNG (TW)	US201 213532 941A	26-Jun-2012
US2013221489A1	29-Aug-2013	INKS AND PROCESSES TO MAKE A CHALCOGEN-CONTAINING SEMICONDUCTOR	CAO YANYAN (US); DENNY JR MICHAEL S (US); JOHNSON LYNDA KAYE (US); LU MEIJUN (US); MALAJOVICH IRINA (US)	US201 113883 293A	20-Nov-2011
US9054162B2	9-Jun-2015	Method and an apparatus for forming electrically conductive vias in a substrate, an automated robot-based manufacturing system, a component comprising a substrate with via holes, and an interposer device	FISCHER ANDREAS (SE); STEMME GORAN (SE); NIKLAUS FRANK (SE)	US201 113988 796A	21-Nov-2011
US2012126379A1	24-May-2012	DIE BOND FILM, DICING DIE BOND FILM, METHOD OF MANUFACTURING DIE BOND FILM, AND SEMICONDUCTOR DEVICE HAVING DIE BOND FILM	UENDA DAISUKE (JP); MATSUMURA TAKESHI (JP); INOUE KOICHI (JP); MORITA MIKI (JP)	US201 113298 613A	17-Nov-2011
US2015194545A1	9-Jul-2015	Dendritic Metal Structures, Methods for Making Dendritic Metal Structures, and Devices Including Them	KOZICKI MICHAEL N (US); REN MINGHAN (US)	US201 514661 994A	18-Mar-2015
US8202334B2	19-Jun-2012	Method of forming silicate polishing pad	ALDEN DONNA M (US); WANK ANDREW R (US); GARGIONE ROBERT (US); GAZZE MARK E (US); SO JOSEPH K (US); DROP DAVID (US); RILEY SHAWN (US); BANH MAI TIEU (CA)	US945 50410A	12-Nov-2010
US8257152B2	4-Sep-2012	Silicate composite polishing pad	WANK ANDREW R (US); ALDEN DONNA M (US); SO JOSEPH K (US); GARGIONE ROBERT (US); GAZZE MARK E (US); DROP DAVID (US); CAMERON JR COLIN F (US); BANH MAI TIEU (CA); RILEY SHAWN (US)	US945 55710A	12-Nov-2010
US2016233169A1	11-Aug-2016	WAFER LEVEL SEMICONDUCTOR PACKAGE AND MANUFACTURING METHODS THEREOF	HUNT JOHN RICHARD (US)	US201 615133 994A	20-Apr-2016
US11631756B2	18-Apr-2023	Semiconductor device and method for manufacturing the same	ENDO YUTA (JP); SASAKI TOSHINARI (JP); NODA KOSEI (JP)	US202 017073 520A	19-Oct-2020
US8786058B2	22-Jul-2014	Semiconductor devices and methods of manufacturing the same	HAN KYU HEE (KR); PARK BYUNG LYUL (KR); KIM BYUNGHEE (KR); AHN SANGHOON (KR); NAM SANGDON (KR); KIM KYOUNG HEE (KR)	US201 113289 576A	4-Nov-2011
US2012111616A1	10-May-2012	ELECTRONIC-COMPONENT-MOUNTED WIRING SUBSTRATE AND METHOD OF MANUFACTURING THE SAME	INOUE MASAHIRO (JP); SAIKI HAJIME (JP); SUGIMOTO ATSUHIKO (JP)	US201 113290 737A	7-Nov-2011

US8957468B2	17-Feb-2015	Variable capacitor and liquid crystal display device	UOCHI HIDEKI (JP)	US201 113285 367A	31-Oct-2011
US11511316B2	29-Nov-2022	Plasma annealing method and device for the same	FURUSHO HITOSHI (JP)	US201 113883 042A	31-Oct-2011
US8450158B2	28-May-2013	Method for forming microcrystalline semiconductor film and method for manufacturing semiconductor device	KOMATSU RYU (JP); JINBO YASUHIRO (JP); MIYAIRI HIDEKAZU (JP)	US201 113282 650A	27-Oct-2011
US9874585B2	23-Jan-2018	Resilient electrical interposers, systems that include the interposers, and methods for using and forming the same	SMITH KENNETH R (US); JOLLEY MIKE (US); STRID ERIC (US); HANAWAY PETER (US); GLEASON K REED (US); DUCKWORTH KOBY L (US)	US201 514788 288A	30-Jun-2015
US2026018559A1	15-Jan-2026	SINTERING MATERIALS AND ATTACHMENT METHODS USING SAME	KHASELEV OSCAR (US); SINGH BAWA (US); MO BIN (US); MARCZI MICHAEL T (US); BOUREGHDA MONNIR (US)	US202 519334 628A	19-Sep-2025
US9167694B2	20-Oct-2015	Ultra-thin interposer assemblies with through vias	SUNDARAM VENKATESH V (US); TUMMALA RAO R (US)	US201 113285 912A	31-Oct-2011
US8765600B2	1-Jul-2014	Contact structure for reducing gate resistance and method of making the same	CHANG CHUNG LONG (TW); CHAO CHIH PING (TW); CHEN CHUN HUNG (TW); TSENG HUA CHAO (TW); CHENG JYE YEN (TW); CHUANG HARRY HAK LAY (TW)	US913 98210A	28-Oct-2010
US9233840B2	12-Jan-2016	Method for improving self-assembled polymer features	CHENG JOY (US); NAMAI HAYATO (US); SANDERS DANIEL P (US)	US913 83510A	28-Oct-2010
US8476162B2	2-Jul-2013	Methods of forming layers on substrates	HA TAE HONG (US); LAM WINSOR (US); GUNG TZA JING (US); LEE JOUNG JOO (US)	US201 113269 243A	7-Oct-2011
US2012061235A1	15-Mar-2012	MIXED SPUTTERING TARGET OF CADMIUM SULFIDE AND CADMIUM TELLURIDE AND METHODS OF THEIR USE	FELDMAN PEABODY SCOTT DANIEL (US)	US913 45410A	27-Oct-2010
US8748216B2	10-Jun-2014	Non-vacuum method for fabrication of a photovoltaic absorber layer	GUO WEI (US); JIN YU (US); LIU BING (US); CHE YONG (US); HAGEDORN KEVIN V (US)	US201 113198 744A	5-Aug-2011
US9603257B2	21-Mar-2017	Pattern substrate, method of producing the same, information input apparatus, and display apparatus	TAZAWA HIROSHI (JP); HAYASHIBE KAZUYA (JP)	US201 113879 778A	14-Oct-2011
US8877425B2	4-Nov-2014	Silicon-containing resist underlayer film forming composition having fluorine-based additive	KANNO YUTA (JP); NAKAJIMA MAKOTO (JP); MISAKI TOMOKO (JP); MATSUYAMA MOTONOBU (JP); HARAGUCHI MASAYUKI (JP)	US201 113880 787A	20-Oct-2011
US9502334B2	22-Nov-2016	Method of making a semiconductor device package with dummy gate	YANG HSUEH AN (TW)	US201 614996 979A	15-Jan-2016
US2012090671A1	19-Apr-2012	MODIFIED BAND GAP WINDOW LAYER FOR A CIGS ABSORBER CONTAINING PHOTOVOLTAIC CELL AND METHOD OF MAKING THEREOF	SHUFFLEBOTHAM PAUL (US); MACKIE NEIL (US); TAS ROBERT (US)	US907 55110A	19-Oct-2010

US8338214B2	25-Dec-2012	Sodium salt containing CIG targets, methods of making and methods of use thereof	JULIANO DANIEL R (US); TAS ROBERT (US); MACKIE NEIL (US); ZIANI ABDELOUAHAB (US)	US201 113073 159A	28-Mar-2011
US8258003B2	4-Sep-2012	Manufacturing method of compound semiconductor solar cell	PARK RAE MAN (KR)	US201 113023 030A	8-Feb-2011
US9107306B2	11-Aug-2015	Hybrid substrate, method for manufacturing the same, and semiconductor integrated circuit package	NAKATANI SEIICHI (JP); KAWAKITA KOJI (JP)	US201 113879 139A	5-Oct-2011
US9543500B2	10-Jan-2017	Ferroelectric thin film having superlattice structure, manufacturing method thereof, ferroelectric element, and manufacturing method thereof	OSADA MINORU (JP); SASAKI TAKAYOSHI (JP)	US201 113878 571A	4-Oct-2011
US8642897B2	4-Feb-2014	Wiring board and method for manufacturing the same	SAKAI SHUNSUKE (JP)	US201 113218 968A	26-Aug-2011
US9070632B2	30-Jun-2015	Aqueous polishing composition and process for chemically mechanically polishing substrates having patterned or unpatterned low-k dielectric layers	RAMAN VIJAY IMMANUEL (DE); RITTIG FRANK (DE); LI YUZHUO (DE); CHIU WEI LAN WILLIAM (TW)	US201 113878 361A	4-Oct-2011
US8536068B2	17-Sep-2013	Atomic layer deposition of photoresist materials and hard mask precursors	WEIDMAN TIMOTHY W (US); MICHAELSON TIMOTHY (US); DEATON PAUL (US)	US201 113267 213A	6-Oct-2011
US8872176B2	28-Oct-2014	Elastic encapsulated carbon nanotube based electrical contacts	FANG TRELIANT (US); GRITTERS JOHN K (US); YAGLIOGLU ONNIK (US)	US201 113253 665A	5-Oct-2011
US9773579B2	26-Sep-2017	Single component, low temperature curable polymeric composition and related method	JIANG HONG (US); SHAIKH AZIZ S (US)	US201 113877 713A	28-Sep-2011
US2013280854A1	24-Oct-2013	SINTERED DEVICE	JASIENIAK JACEK (AU); MACDONALD BRANDON (US); MULVANEY PAUL (AU)	US201 113877 881A	5-Oct-2011
US9905484B2	27-Feb-2018	Methods for shielding a plasma etcher electrode	BERKOH DANIEL KWADWO AMPONSAH (US); WOODARD ELENA BECERRA (US); SCOTT DEAN G (US)	US201 615200 516A	1-Jul-2016
US9622382B2	11-Apr-2017	Heat-sink device intended for at least one electronic component and corresponding method	GASSE ADRIEN (FR); REVIRAND PASCAL (FR)	US201 113877 752A	27-Sep-2011
US2012080091A1	5-Apr-2012	FABRICATION OF CIS OR CIGS THIN FILM FOR SOLAR CELLS USING PASTE OR INK	MIN BYOUNG KOUN (KR); PARK SE JIN (KR)	US986 74911A	7-Jan-2011
US2014322914A1	30-Oct-2014	GAP EMBEDDING COMPOSITION, METHOD OF EMBEDDING GAP AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE BY USING THE COMPOSITION	YAMAMOTO KEIJI (JP); SEKI HIROYUKI (JP)	US201 414328 623A	10-Jul-2014
US9142457B2	22-Sep-2015	Dicing die bond film and method of manufacturing semiconductor device	TANAKA SHUMPEI (JP); MATSUMURA TAKESHI (JP)	US201 113876 199A	21-Sep-2011

US9780223B2	3-Oct-2017	Gallium arsenide based materials used in thin film transistor applications	SINGH KAUSHAL K (US); VISSER ROBERT JAN (US); KUMAR BHASKAR (US)	US201 14-Jul-2016 615210 637A
US8282995B2	9-Oct-2012	Selenium/group 1b/group 3a ink and methods of making and using same	CALZIA KEVIN (US); MOSLEY DAVID (US); THORSEN DAVID L (US)	US895 30-Sep-2010 29710A
US2013298985A1	14-Nov-2013	MICROELECTRONIC STRUCTURES INCLUDING CUPROUS OXIDE SEMICONDUCTORS AND HAVING IMPROVED P-N HETEROJUNCTIONS	DARVISH DAVIS S (US); ATWATER HARRY A (US)	US201 29-Sep-2011 113876 652A
US9263374B2	16-Feb-2016	Semiconductor device and manufacturing method therefor	MASUDA MASACHIKA (JP); TOMITA KOJI (JP); OKAMOTO TADASHI (JP); TANAKA YASUNORI (JP); OHSAWA HIROSHI (JP); MIYANO KAZUYUKI (JP); KURAHASHI ATSUSHI (JP); SUZUKI HIROMICHI (JP)	US201 12-Sep-2011 113230 128A
US8731852B2	20-May-2014	Method for analysing photovoltaic layer systems using thermography	DALIBOR THOMAS (DE)	US201 28-Sep-2011 113819 845A
US8994132B2	31-Mar-2015	Photoelectric conversion element, solid-state imaging element, imaging apparatus, and method for manufacturing photoelectric conversion element	MITSUI TETSURO (JP); KURAMOTO YUKI (JP)	US201 26-Sep-2011 113245 603A
US9130094B2	8-Sep-2015	Method and apparatus for dividing thin film device into separate cells	BRUNTON ADAM NORTH (GB)	US201 16-Sep-2011 113825 629A
US8970516B2	3-Mar-2015	Integrated passives and power amplifier	BLACK JUSTIN PHELPS (US); SHENOY RAVINDRA V (US); GOUSEV EVGENI PETROVICH (US); HADJICHRISTOS ARISTOTELE (US); MYERS THOMAS ANDREW (US); KIM JONGHAE (US); VELEZ MARIO FRANCISCO (US); LAN JE HSIUNG JEFFREY (US); LO CHI SHUN (US)	US201 16-Sep-2011 113235 158A
US9636777B2	2-May-2017	Laser micro/nano processing system and method	DUAN XUANMING (CN); CHEN SHU (CN); CAO HONGZHONG (CN); DONG XIANZI (CN); ZHAO ZHENSHENG (CN)	US201 3-Nov-2015 514930 856A
US8847400B2	30-Sep-2014	Semiconductor device, method for manufacturing the same, and data processing device	FUJITA OSAMU (JP); TOGASHI YUKI (JP)	US201 29-Feb-2012 213408 318A
US9029270B2	12-May-2015	Phenolic resin composition, and methods for manufacturing cured relief pattern and semiconductor	SASAKI TAKAHIRO (JP); LI JUN (JP)	US201 12-Sep-2011 113820 772A
US8883550B2	11-Nov-2014	Deposition processes for photovoltaic devices	FUJIDALA KYLE L (US); ZHU ZHONGLIANG (US); PADOWITZ DAVID (US); MARKOFF JOHNSON PAUL R (US); CHOMITZ WAYNE A (US); KUCHTA MATTHEW C (US)	US201 15-Sep-2011 113233 990A
US2015207018A1	23-Jul-2015	Apparatus and Method for Manufacturing of Thin Film Type Solar Cell	YANG CHEOL HOON (KR)	US201 31-Mar-2015 514674 698A
US9525150B2	20-Dec-2016	Optoelectronic devices made using layers detached from inherently lamellar semiconductor donors	JAIN AJAYKUMAR R (US)	US201 14-Jan-2016 614995 439A

US2013161285A1	27-Jun-2013	AQUEOUS POLISHING COMPOSITION AND PROCESS FOR CHEMICALLY MECHANICALLY POLISHING SUBSTRATE MATERIALS FOR ELECTRICAL, MECHANICAL AND OPTICAL DEVICES	LI YUZHUAO (DE); CHU JEA JU (TW); VENKATARAMAN SHYAM SUNDAR (TW); USMAN IBRAHIM SHEIK ANSAR (US); PINDER HARVEY WAYNE (US)	US201 6-Sep-2011 113821 757A
US2013171824A1	4-Jul-2013	PROCESS FOR CHEMICALLY MECHANICALLY POLISHING SUBSTRATES CONTAINING SILICON OXIDE DIELECTRIC FILMS AND POLYSILICON AND/OR SILICON NITRIDE FILMS	LI YUZHUAO (DE); VENKATARAMAN SHYAM SUNDAR (TW); PINDER HARVEY WAYNE (US)	US201 6-Sep-2011 113821 769A
US2013168348A1	4-Jul-2013	AQUEOUS POLISHING COMPOSITION AND PROCESS FOR CHEMICALLY MECHANICALLY POLISHING SUBSTRATES CONTAINING SILICON OXIDE DIELECTRIC AND POLYSILICON FILMS	LI YUZHUAO (DE); CHU JEA JU (TW); VENKATARAMAN SHYAM SUNDAR (TW); CHIU WEI LAN WILLIAM (TW); PINDER HARVEY WAYNE (US)	US201 5-Sep-2011 113821 746A
US2012058625A1	8-Mar-2012	FILM FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE	AMANO YASUHIRO (JP); MORITA MIKI (JP)	US201 2-Sep-2011 113224 554A
US9425334B2	23-Aug-2016	Methods and apparatus for patterning photovoltaic devices and materials for use with such devices	BAIRD BRIAN W (US); GERKE TIMOTHY D (US)	US201 6-Sep-2011 113820 997A
US10886126B2	5-Jan-2021	Uniform multilayer graphene by chemical vapor deposition	ZHONG ZHAOHUI (US); LEE SEUNGHYUN (US); LEE KYUNGHOO (US)	US201 2-Sep-2011 113225 135A
US9406730B2	2-Aug-2016	Thin film transistor and organic light emitting device including polycrystalline silicon layer	PARK BYOUNG KEON (KR); PARK JONG RYUK (KR); CHUNG YUN MO (KR); LEE TAK YOUNG (KR); SEO JIN WOOK (KR); LEE KI YONG (KR); JEONG MIN JAE (KR); SON YONG DUCK (KR); SO BYUNG SOO (KR); PARK SEUNG KYU (KR); LEE DONG HYUN (KR); LEE KIL WON (KR); JUNG JAE WAN (KR)	US201 19-Sep-2014 414490 725A
US2012056181A1	8-Mar-2012	METHOD OF MANUFACTURING ELECTRONIC ELEMENT AND ELECTRONIC ELEMENT	KAMATA MASANAO (JP); YAMANA HIROAKI (JP); YAGI IWAO (JP); KAWASHIMA NORIYUKI (JP)	US201 26-Aug-2011 113218 907A
US9401443B2	26-Jul-2016	Electrodeposition methods of gallium and gallium alloy films and related photovoltaic structures	AHMED SHAFAT (US); DELIGIANI HARIKLIA (US); HUANG QIANG (US); REUTER KATHLEEN B (US); ROMANKIW LUBOMYR T (US); VAIDYANATHAN RAMAN (US)	US201 5-Sep-2012 213604 054A
US9365802B2	14-Jun-2016	Cleaning liquid for semiconductor device substrates and method of cleaning substrate for semiconductor devices	HARADA KEN (JP); ITO ATSUSHI (JP); SUZUKI TOSHIYUKI (JP)	US201 28-Feb-2013 313780 544A
US2015137333A1	21-May-2015	METHODS OF SELECTIVELY FORMING A MATERIAL USING A PARYLENE COATING AND RELATED SEMICONDUCTOR STRUCTURES	MARSH EUGENE P (US)	US201 8-Dec-2014 414562 921A
US2012049199A1	1-Mar-2012	Method of forming polycrystalline silicon layer, method of manufacturing thin film transistor including the method, thin-film transistor manufactured by using the method of manufacturing thin-film transistor, and organic light-emitting display device including the thin-film transistor	CHUNG YUN MO (KR); LEE KI YONG (KR); SEO JIN WOOK (KR); JEONG MIN JAE (KR); PARK SEUNG KYU (KR); SON YONG DUCK (KR); SO BYUNG SOO (KR); PARK BYOUNG KEON (KR); LEE KIL WON (KR); LEE DONG HYUN (KR); LEE TAK YOUNG (KR); PARK JONG RYUK (KR)	US201 15-Aug-2011 113137 428A

US8709841B2	29-Apr-2014	Woven mesh substrate with semiconductor elements, and method and device for manufacturing the same	NAKATA JOSUKE (JP)	US201 8-Feb-2011 113816 858A
US2014147959A1	29-May-2014	LIQUID METAL EMULSION	RACCURT OLIVIER (FR); DUFOURCQ JOEL (FR); JOUHANNAUD JULIEN (FR); PONCELET OLIVIER (FR); SONIER FLORE (FR); ROUMANIE MARYLINE (FR)	US201 24-Aug-2011 113819 300A
US8859404B2	14-Oct-2014	Method for forming microcrystalline semiconductor film and method for manufacturing semiconductor device	KOMATSU RYU (JP); JINBO YASUHIRO (JP); MIYAIRI HIDEKAZU (JP)	US201 17-Aug-2011 113211 565A
US9123707B2	1-Sep-2015	Methods for forming a hydrogen free silicon containing dielectric film	CHOI SOO YOUNG (US)	US201 20-Aug-2011 113214 161A
US8581401B2	12-Nov-2013	Mechanisms for forming copper pillar bumps using patterned anodes	LU WEN HSIUNG (TW); CHENG MING DA (TW); LIN CHIH WEI (TW); LIU CHUNG SHI (TW)	US201 6-Jul-2012 213543 438A
US8836114B2	16-Sep-2014	Semiconductor device and method of forming Fo-WLCSP having conductive layers and conductive vias separated by polymer layers	OH JIHOON (KR); LEE SINJAE (KR); KIM JINGWAN (KR)	US201 16-Nov-2012 213679 792A
US9418941B2	16-Aug-2016	Semiconductor device and method of forming B-stage conductive polymer over contact pads of semiconductor die in Fo-WLCSP	DO BYUNG TAI (SG); PAGAILA REZA A (SG)	US201 3-Apr-2012 213438 713A
US9842808B2	12-Dec-2017	Semiconductor device and method of forming vertical interconnect in FO-WLCSP using leadframe disposed between semiconductor die	SHIN HANGIL (KR); CHO NAMJU (KR); CHI HEEJO (KR)	US201 4-Oct-2012 213645 385A
US9472436B2	18-Oct-2016	Multiple bonding layers for thin-wafer handling	PULIGADDA RAMA (US); ZHONG XING FU (US); FLAIM TONY D (US); MCCUTCHEON JEREMY (US)	US201 8-May-2014 414273 369A
US2015357274A1	10-Dec-2015	Semiconductor Die and Method of Forming FO-WLCSP Vertical Interconnect Using TSV and TMV	CHOI DAESIK (KR); WOO YOUNG JIN (KR); LEE TAEWOO (KR)	US201 21-Aug-2015 514832 644A
US9010343B2	21-Apr-2015	Cleaning device, cleaning method, and composition	MIYANARI ATSUSHI (JP)	US201 2-Aug-2011 113196 306A
US2012031492A1	9-Feb-2012	Gallium-Containing Transition Metal Thin Film for CIGS Nucleation	SEVVANA SWATI (US); DEMIRKAN KORTHAN (US); ZUBECK ROBERT B (US)	US850 4-Aug-2010 19010A
US8586477B2	19-Nov-2013	Semiconductor apparatus, method of manufacturing the same, and method of manufacturing semiconductor package	JEONG SE YOUNG (KR); LEE HO JIN (KR); SONG HO GEON (KR); PHEE JAE HYUN (KR)	US201 1-Aug-2011 113195 128A
US8426947B2	23-Apr-2013	Laminated semiconductor wafer, laminated chip package and method of manufacturing the same	SASAKI YOSHITAKA (US); ITO HIROYUKI (US); IIJIMA ATSUSHI (CN)	US848 2-Aug-2010 56910A
US8860932B2	14-Oct-2014	Detection of layer clearing using spectral monitoring	ZHANG JIMIN (US); WANG ZHIHONG (US); LEE HARRY Q (US); TU WEN CHIANG (US)	US201 22-Jul-2011 113189 277A

US9293387B2	22-Mar-2016	Film for flip chip type semiconductor back surface, dicing tape-integrated film for semiconductor back surface, process for producing semiconductor device, and flip chip type semiconductor device	KOMOTO YUSUKE (JP); TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP); ASAI FUMITERU (JP)	US201 113191 791A	27-Jul-2011
US8242012B2	14-Aug-2012	Integrated circuit structure incorporating a conductor layer with both top surface and sidewall passivation and a method of forming the integrated circuit structure	DAUBENSPECK TIMOTHY H (US); GAMBINO JEFFREY P (US); MUZZY CHRISTOPHER D (US); SAUTER WOLFGANG (US); SULLIVAN TIMOTHY D (US)	US845 06510A	28-Jul-2010
US9761475B2	12-Sep-2017	Film for semiconductor device production, method for producing film for semiconductor device production, and method for semiconductor device production	TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP); ASAI FUMITERU (JP)	US201 514624 702A	18-Feb-2015
US10522689B2	31-Dec-2019	Semiconductor device and method of manufacturing the same	SASAKI TOSHINARI (JP); SATO HITOMI (JP); NODA KOSEI (JP); ENDO YUTA (JP); IKARASHI MIZUHO (JP); IMAI KEITARO (JP); ISOBE ATSUO (JP); OKAZAKI YUTAKA (JP)	US201 715605 211A	25-May-2017
US9978628B2	22-May-2018	Bonding method including adjusting surface contours of a bonding system	LIN YU LIANG (TW); WU WENG JIN (TW); LIN JING CHENG (TW)	US201 615075 729A	21-Mar-2016
US9275965B2	1-Mar-2016	Copper pillar bump with cobalt-containing sidewall protection layer	HWANG CHIEN LING (TW); LIM ZHENG YI (TW); LIU CHUNG SHI (TW)	US201 414341 021A	25-Jul-2014
US11894429B2	6-Feb-2024	Amorphous metal oxide semiconductor layer and semiconductor device	HIROI YOSHIOMI (JP); MAEDA SHINICHI (JP)	US202 217851 868A	28-Jun-2022
US8975115B2	10-Mar-2015	Semiconductor device and method for manufacturing the same	ENDO YUTA (JP); NODA KOSEI (JP); SASAKI TOSHINARI (JP)	US201 414148 906A	7-Jan-2014
US8814631B2	26-Aug-2014	Tracking spectrum features in two dimensions for endpoint detection	DAVID JEFFREY DRUE (US); HU XIAOYUAN (US); ZHU ZHIZE (US); LEE HARRY Q (US)	US201 113187 220A	20-Jul-2011
US9305470B2	5-Apr-2016	Cu alloy film for display device and display device	MIKI AYA (JP); KUGIMIYA TOSHIHIRO (JP); TERAOKA YASUAKI (JP)	US201 113810 949A	21-Jul-2011
US8927978B2	6-Jan-2015	Organic EL element	MIMA SHOJI (JP); ONO YOSHINOBU (JP)	US201 113811 107A	20-Jul-2011
US9074113B2	7-Jul-2015	Film for flip chip type semiconductor back surface, dicing tape-integrated film for semiconductor back surface, process for producing semiconductor device, and flip chip type semiconductor device	TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP); ASAI FUMITERU (JP)	US201 113184 994A	18-Jul-2011
US9553076B2	24-Jan-2017	Stackable molded microelectronic packages with area array unit connectors	HABA BELGACEM (US)	US201 514878 548A	8-Oct-2015
US2012015299A1	19-Jan-2012	RESIST COMPOSITION, METHOD OF FORMING RESIST PATTERN, NOVEL COMPOUND, AND ACID GENERATOR	KOMURO YOSHITAKA (JP); UTSUMI YOSHIYUKI (JP)	US201 113179 864A	11-Jul-2011

US2012015112A1	19-Jan-2012	METHOD OF FABRICATING PATTERN	YANG MINYANG (KR); KANG BONGCHUL (KR)	US201 12-Jul-2011 113180 921A
US8759989B2	24-Jun-2014	Photosensitive adhesive composition, photosensitive adhesive film, and semiconductor device using each	MATSUMURA KAZUYUKI (JP); SUGIMOTO KANAKO (JP); NIWA HIROYUKI (JP); INAGAKI CHIKARA (JP)	US201 10-Jun-2011 113808 782A
US9328318B2	3-May-2016	Method for wafer dicing and composition useful thereof	TAMBOLI DNYANESH CHANDRAKANT (US); RAMAMURTHI RAJKUMAR (US); RENNIE DAVID BARRY (US); RAO MADHUKAR BHASKARA (US); BANERJEE GAUTAM (US); PARRIS GENE EVERAD (US)	US201 3-Mar-2014 414195 285A
US10164207B2	25-Dec-2018	Organic light-emitting device and method for manufacturing same	LEE JUNG HYOUNG (KR); KIM JUNG BUM (KR)	US201 2-Jul-2015 514790 883A
US8871631B2	28-Oct-2014	Method to form solder deposits on substrates	LAMPRECHT SVEN (DE); MATEJAT KAI JENS (DE); EWERT INGO (DE); KENNY STEPHEN (DE)	US201 23-Jun-2011 113701 501A
US9450139B2	20-Sep-2016	Manufacturing method of semiconductor film, manufacturing method of semiconductor device, and manufacturing method of photoelectric conversion device	TANAKA TETSUHIRO (JP); KATO ERIKA (JP)	US201 22-Dec-2015 514978 463A
US9837544B2	5-Dec-2017	Semiconductor device having an oxide semiconductor layer	YAMAZAKI SHUNPEI (JP)	US201 5-Jan-2016 614988 628A
US8241938B2	14-Aug-2012	Methods of forming a conductive transparent oxide film layer for use in a cadmium telluride based thin film photovoltaic device	FELDMAN PEABODY SCOTT DANIEL (US); GOSSMAN ROBERT DWAYNE (US)	US829 2-Jul-2010 56310A
US2013120485A1	16-May-2013	LIQUID APPLICATION DEVICE, LIQUID APPLICATION METHOD, AND NANOIMPRINT SYSTEM	KODAMA KENICHI (JP); OMATSU TADASHI (JP); WAKAMATSU SATOSHI (JP); KODAMA KUNIHIKO (JP)	US201 28-Dec-2012 213730 476A
US2013104931A1	2-May-2013	Liquid Chemical for Forming Protective Film, and Cleaning Method for Wafer Surface	ARATA SHINOBU (JP); SAITO MASANORI (JP); SAIO TAKASHI (JP); KUMON SOICHI (JP); NANAI HIDEHISA (JP)	US201 15-Jun-2011 113807 708A
US8846530B2	30-Sep-2014	Method for forming semiconductor region and method for manufacturing power storage device	FURUNO MAKOTO (JP); SHIMAZU TAKASHI (JP)	US201 13-Jun-2011 113158 629A
US9478480B2	25-Oct-2016	Alignment mark and method of formation	TSAI CHEN YU (TW); WANG SHIH HUI (TW); CHIU CHIEN MING (TW); CHEN CHIA HO (TW); TSAI FANG WEN (TW); WU WENG JIN (TW); LIN JING CHENG (TW); CHIOU WEN CHIH (TW); JENG SHIN PUU (TW); YU CHEN HUA (TW)	US201 14-Nov-2014 414542 317A
US8946053B2	3-Feb-2015	Method for reducing irregularities at the surface of a layer transferred from a source substrate to a glass-based support substrate	DELPRAT DANIEL (FR); DURET CARINE (FR); BEN MOHAMED NADIA (FR); LALLEMENT FABRICE (FR)	US201 20-Jun-2011 113702 062A
US9944827B2	17-Apr-2018	CMP polishing solution and polishing method	MISHIMA KOUJI (JP); SAKURADA TAKAFUMI (JP); SHIMADA TOMOKAZU (JP)	US201 29-Jun-2011 113172 397A
US8778745B2	15-Jul-2014	Method for manufacturing semiconductor device	KOMATSU RYU (JP); JINBO YASUHIRO (JP); MIYAIRI HIDEKAZU (JP)	US201 14-Jun-2011 113159 830A

US9117964B2	25-Aug-2015	Preparation of semiconductor films	DESHMUKH RANJAN DEEPAK (US); KUEGLER RALF (DE); SCHNEIDER JOERG J (DE); HOFFMANN RUDOLF (DE)	US201 113807 382A	31-May-2011
US8405222B2	26-Mar-2013	Integrated circuit system with via and method of manufacture thereof	YU HONG (SG); LIU HUANG (SG); ZHAO FENG (SG); ZHOU MEISHENG (SG); HSIA LIANG CHOO (SG)	US825 26610A	28-Jun-2010
US9799682B2	24-Oct-2017	Method for manufacturing semiconductor device	CHIDA AKIHIRO (JP)	US201 514597 548A	15-Jan-2015
US8598020B2	3-Dec-2013	Plasma-enhanced chemical vapor deposition of crystalline germanium	NGUYEN VICTOR (US); BALSEANU MIHAELA (US); XIA LI QUN (US); WITTY DEREK R (US)	US824 09510A	25-Jun-2010
US9437538B2	6-Sep-2016	Semiconductor device including RDL along sloped side surface of semiconductor die for Z-direction interconnect	PAGAILA REZA A (ID); LIN YAOJIAN (SG); KOO JUN MO (SG)	US201 414292 925A	1-Jun-2014
US9620455B2	11-Apr-2017	Semiconductor device and method of forming anisotropic conductive film between semiconductor die and build-up interconnect structure	PAGAILA REZA A (SG); LIN YAOJIAN (SG); KOO JUN MO (SG)	US822 45810A	24-Jun-2010
US8822561B2	2-Sep-2014	Curable composition and process for producing cured film	ITO MASAHIRO (JP); ABE TAKEFUMI (JP); TSURUOKA KAORI (JP); ERIGUCHI TAKESHI (JP)	US201 213724 571A	21-Dec-2012
US8795955B2	5-Aug-2014	Naphthalene derivative, resist bottom layer material, resist bottom layer forming method, and patterning process	KINSHO TAKESHI (JP); TAKEMURA KATSUYA (JP); KORI DAISUKE (JP); WATANABE TAKERU (JP); OGIHARA TSUTOMU (JP)	US201 113165 536A	21-Jun-2011
US8852391B2	7-Oct-2014	Method and apparatus for removing a reversibly mounted device wafer from a carrier substrate	MCCUTCHEON JEREMY W (US); BROWN ROBERT D (US)	US819 68010A	21-Jun-2010
US9252103B2	2-Feb-2016	Method for manufacturing semiconductor device	ISHIZUKA AKIHIRO (JP); YONEMITSU YUTAKA (JP); SASAGAWA SHINYA (JP)	US201 414558 989A	3-Dec-2014
US9281385B2	8-Mar-2016	Semiconducting graphene composition, and electrical device including the same	SHIN HYEON JIN (KR); CHOI JAE YOUNG (KR); AHN JOUNG REAL (KR); JEON CHEOL HO (KR)	US201 113164 532A	20-Jun-2011
US8586281B2	19-Nov-2013	Positive resist composition and method of forming resist pattern	IWASHITA JUN (JP); YAHAGI MASAHIRO (JP); KONNO KENRI (JP); TAKAGI ISAMU (JP)	US201 113156 159A	8-Jun-2011
US2013087959A1	11-Apr-2013	OPITCALLY TUNED METALIZED LIGHT TO HEAT CONVERSION LAYER FOR WAFER SUPPORT SYSTEM	TRAN HUNG T (US); SAITO KAZUTA (JP)	US201 113704 146A	27-May-2011
US9023581B2	5-May-2015	Resist composition, method of forming resist pattern, polymeric compound, and compound	KAWAUE AKIYA (JP); DOHTANI KAZUSHIGE (JP); UTSUMI YOSHIYUKI (JP); IWASHITA JUN (JP); KONNO KENRI (JP); SHIONO DAIJU (JP); TAKAKI DAICHI (JP)	US201 113703 865A	14-Jun-2011
US2011311913A1	22-Dec-2011	POSITIVE RESIST COMPOSITION AND METHOD OF FORMING RESIST PATTERN	SUZUKI KENTA (JP); SHIONO DAIJU (JP)	US201 113156 180A	8-Jun-2011

US8859310B2	14-Oct-2014	Methods of fabricating optoelectronic devices using semiconductor-particle monolayers and devices made thereby	JAIN AJAYKUMAR R (US)	US201 113704 088A	10-Jun-2011
US9040369B2	26-May-2015	Structure and method for replacement gate MOSFET with self-aligned contact using sacrificial mandrel dielectric	SIDDIQUI SHAHAB (US); CHUDZIK MICHAEL P (US); RADENS CARL J (US)	US201 313752 567A	29-Jan-2013
US8999760B2	7-Apr-2015	Semiconductor device and method of forming thermally conductive layer between semiconductor die and build-up interconnect structure	PAGAILA REZA A (SG); LIN YAOJIAN (SG); KOO JUN MO (SG)	US201 213492 687A	8-Jun-2012
US9685372B2	20-Jun-2017	Method of forming Cu pillar bump with non-metal sidewall spacer and metal top cap	HWANG CHIEN LING (TW); TSAI HUI JUNG (TW); WU YI WEN (TW); LIU CHUNG SHI (TW)	US201 514694 524A	23-Apr-2015
US10643952B2	5-May-2020	Semiconductor device and method of forming EMI shielding layer with conductive material around semiconductor die	PAGAILA REZA A (ID); CARSON FLYNN (US); YOON SEUNG UK (SG)	US201 615280 632A	29-Sep-2016
US8586481B2	19-Nov-2013	Chemical planarization of copper wafer polishing	WANG YOU (US); TU WEN CHIANG (US); LIU FENG Q (US); WANG YUCHUN (US); KARUPPIAH LAKSHMANAN (US); MCCLINTOCK WILLIAM H (US); CHIN BARRY L (US)	US201 113105 658A	11-May-2011
US2011291068A1	1-Dec-2011	FIELD EFFECT TRANSISTOR MANUFACTURING METHOD, FIELD EFFECT TRANSISTOR, AND SEMICONDUCTOR GRAPHENE OXIDE MANUFACTURING METHOD	KOBAYASHI TOSHIYUKI (JP)	US201 113116 125A	26-May-2011
US9482948B2	1-Nov-2016	Photoresist compositions and methods of forming photolithographic patterns	BAE YOUNG CHEOL (US); WANG DEYAN (US); CARDOLACCIA THOMAS (US); KANG SEOKHO (US); BELL ROSEMARY (US)	US201 514919 822A	22-Oct-2015
US2011294237A1	1-Dec-2011	PACKAGING METHOD OF SEMICONDUCTOR DEVICE	CHANG WEN HSIUNG (TW)	US788 36010A	27-May-2010
US8419895B2	16-Apr-2013	Laser ablation for integrated circuit fabrication	DANG BING (US); KNICKERBOCKER JOHN (US); PRABHAKAR APARNA (US); SORCE PETER (US); TRZCINSKI ROBERT E (US); TSANG CORNELIA K (US)	US788 84310A	27-May-2010
US2012132246A1	31-May-2012	PHOTOVOLTAIC MODULES WITH IMPROVED ELECTRICAL CHARACTERISTICS AND METHODS THEREOF	HUNT THOMAS (US); SWAHN ANDERS (US); OELS WOLFGANG HARALD (US)	US201 113116 996A	26-May-2011
US10573600B2	25-Feb-2020	Semiconductor device and method of forming ultra thin multi-die face-to-face WLCSP	CHI HEEJO (KR); CHO NAMJU (KR); MYUNG JUNWOO (KR)	US201 715649 491A	13-Jul-2017
US9275875B2	1-Mar-2016	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); WATANABE RYOSUKE (JP); HIRAISHI SUZUNOSUKE (JP); SAKATA JUNICHIRO (JP)	US201 414529 525A	31-Oct-2014
US9396939B2	19-Jul-2016	Semiconductor device	ENDO YUTA (JP); SASAKI TOSHINARI (JP); NODA KOSEI (JP); SATO MIZUHO (JP)	US201 514678 119A	3-Apr-2015
US9263589B2	16-Feb-2016	Semiconductor device	ENDO YUTA (JP); SASAKI TOSHINARI (JP); NODA KOSEI (JP); SATO MIZUHO (JP)	US201 113110 236A	18-May-2011

US10186603B2	22-Jan-2019	Manufacturing method of semiconductor device including oxygen doping treatment	YAMAZAKI SHUNPEI (JP); SASAKI TOSHINARI (JP); NODA KOSEI (JP)	US201 615232 092A	9-Aug-2016
US9685394B2	20-Jun-2017	Electronic device and manufacturing method therefor	SEKINE SHIGENOBU (JP); SEKINE YURINA (JP); KUWANA YOSHIHARU (JP)	US201 113106 933A	13-May-2011
US9773755B2	26-Sep-2017	Substrate interconnections having different sizes	SHEN WEN WEI (TW); SHIH YING CHING (TW); CHEN CHEN SHIEN (TW); CHEN MING FA (TW)	US201 514860 362A	21-Sep-2015
US9275964B2	1-Mar-2016	Substrate contact opening	YU CHEN HUA (TW); WU JIUN YI (TW)	US201 414184 849A	20-Feb-2014
US10468531B2	5-Nov-2019	Semiconductor device and manufacturing method of the same	KIMURA KUNIO (JP); ICHIJO MITSUHIRO (JP); ENDO TOSHIYA (JP)	US201 615293 434A	14-Oct-2016
US8932910B2	13-Jan-2015	Method for producing chip stacks, and a carrier for carrying out the method	WIMPLINGER MARKUS (AT)	US201 013698 088A	20-May-2010
US9425067B2	23-Aug-2016	Method for forming package systems having interposers	LIN YUNG CHI (TW); LIN JING CHENG (TW); YU CHEN HUA (TW)	US201 514879 880A	9-Oct-2015
US9153476B2	6-Oct-2015	Semiconductor device and method of forming prefabricated multi-die leadframe for electrical interconnect of stacked semiconductor die	CHI HEEJO (KR); PARK YEONGIM (KR); LEE HYUNGMIN (KR)	US201 213691 464A	30-Nov-2012
US8440510B2	14-May-2013	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 113104 574A	10-May-2011
US9153544B2	6-Oct-2015	Semiconductor device and method of forming discontinuous ESD protection layers between semiconductor die	PAGAILA REZA A (ID); CAPARAS JOSE A (SG); MARIMUTHU PANDI C (SG)	US201 414194 691A	1-Mar-2014
US8410486B2	2-Apr-2013	Method for manufacturing microcrystalline semiconductor film and method for manufacturing semiconductor device	TEZUKA SACHIAKI (JP); JINBO YASUHIRO (JP); SASAKI TOSHINARI (JP); MIYAIRI HIDEKAZU (JP)	US201 113102 386A	6-May-2011
US8497142B2	30-Jul-2013	Methods of forming conductive layer patterns using gas phase cleaning process and methods of manufacturing semiconductor devices	YANG JUN KYU (KR); PARK YOUNG GEUN (KR); HWANG KI HYUN (KR); CHOI HAN MEI (KR); YOO DONG CHUL (KR)	US201 113102 218A	6-May-2011
US8917539B2	23-Dec-2014	Solid, multi-state molecular random access memory	VAN DER BOOM MILKO E (IL); DE RUITER GRAHAM (IL)	US201 113696 854A	11-May-2011
US2013068287A1	21-Mar-2013	Rapid Thermal Activation of Flexible Photovoltaic Cells and Modules	COMPAAN ALVIN D (US)	US201 113697 169A	10-May-2011
US9202895B2	1-Dec-2015	Process for production of functional device, process for production of ferroelectric material layer, process for production of field effect transistor, thin film transistor, field effect transistor, and piezoelectric inkjet head	SHIMODA TATSUYA (JP); TOKUMITSU EISUKE (JP); MIYASAKO TAKAAKI (JP); KANEDA TOSHIHIKO (JP)	US201 113696 551A	6-May-2011

US9035330B2	19-May-2015	Organic light-emitting display device and method of manufacturing the organic light emitting display device	KANG JIN GOO (KR); KIM MU HYUN (KR); KIM JAE BOK (KR); LEE DONG KYU (KR); KIM JI YOUNG (KR)	US201 113088 261A	15-Apr-2011
US9431316B2	30-Aug-2016	Semiconductor device and method of forming channels in back surface of FO-WLCSP for heat dissipation	PAGAILA REZA ARGENTY (SG)	US773 66910A	4-May-2010
US8623450B2	7-Jan-2014	Method for producing a flexible circuit configuration	FEURER ERNST (DE); HOLL BRUNO (DE); KAISER ALEXANDER (DE); RUESS KARIN (DE)	US896 35010A	1-Oct-2010
US2011269309A1	3-Nov-2011	PHOTORESIST COMPOSITION, METHOD OF FORMING PATTERN BY USING THE PHOTORESIST COMPOSITION, AND METHOD OF MANUFACTURING THIN-FILM TRANSISTOR SUBSTRATE	HONG PIL SOON (KR); PARK GWUI HYUN (KR); JU JIN HO (KR); SONG JEAN HO (KR); KIM SANG TAE (KR); KIM SEONG HYEON (KR); CHANG WON YOUNG (KR); YOON JONG HEUM (KR); LEE EUN SANG (KR); IM MIN JU (KR)	US981 30410A	29-Dec-2010
US2016155886A1	2-Jun-2016	METHOD OF MANUFACTURE OF CHALCOGENIDE-BASED PHOTOVOLTAIC CELLS	BRYDEN TODD R (DE); FENTON JR JEFFREY L (US); MITCHELL GARY E (US); THOMPSON KIRK R (US); MILLS MICHAEL E (US); PARRILLO DAVID J (US)	US201 615015 211A	4-Feb-2016
US2017005182A1	5-Jan-2017	METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP)	US201 615267 450A	16-Sep-2016
US9156735B2	13-Oct-2015	Hermetic sealing of glass plates	MALONEY JOHN J (US); BLONSKI ROBERT P (US); KHADILKAR CHANDRASHEKHAR S (US); SRIDHARAN SRINIVASAN (US)	US201 113642 553A	27-Apr-2011
US8343857B2	1-Jan-2013	Manufacturing method of microcrystalline semiconductor film and manufacturing method of semiconductor device	TORIUMI SATOSHI (JP)	US201 113093 174A	25-Apr-2011
US9520529B2	13-Dec-2016	Composition for forming P-type diffusion layer, method of forming P-type diffusion layer, and method of producing photovoltaic cell	MACHII YOICHI (JP); YOSHIDA MASATO (JP); NOJIRI TAKESHI (JP); OKANIWA KAORU (JP); IWAMURO MITSUNORI (JP); ADACHI SHUICHIRO (JP); SATO TETSUYA (JP); KIZAWA KEIKO (JP)	US201 314076 212A	9-Nov-2013
US9608143B2	28-Mar-2017	Composition for forming N-type diffusion layer, method of forming N-type diffusion layer, and method of producing photovoltaic cell	MACHII YOUICHI (JP); YOSHIDA MASATO (JP); NOJIRI TAKESHI (JP); OKANIWA KAORU (JP); IWAMURO MITSUNORI (JP); ADACHI SHUICHIRO (JP); SATO TETSUYA (JP); KIZAWA KEIKO (JP)	US201 314076 225A	10-Nov-2013
US8912537B2	16-Dec-2014	Semiconductor device, RFID tag using the same and display device	WAKANA HIRONORI (JP); KAWAMURA TETSUFUMI (JP); UCHIYAMA HIROYUKI (JP); FUJII KUNIHARU (JP)	US201 113642 612A	22-Apr-2011
US9812533B2	7-Nov-2017	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 313740 313A	14-Jan-2013
US9245983B2	26-Jan-2016	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 514741 547A	17-Jun-2015
US8546225B2	1-Oct-2013	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 113091 192A	21-Apr-2011

US9373707B2	21-Jun-2016	Manufacturing method of semiconductor device with steps of heat treatment in nitrogen containing atmosphere, oxygen doping treatment and heat treatment in oxygen containing atmosphere	YAMAZAKI SHUNPEI (JP)	US201 514710 675A	13-May-2015
US9689533B2	27-Jun-2017	Coating method for gas delivery system	KENWORTHY IAN (US); OUTKA DUANE (US); HAO FANGLI (US); SHARPLESS LEONARD (US); DU YIJUN (US)	US201 414472 713A	29-Aug-2014
US2012285375A1	15-Nov-2012	APPARATUS FOR TREATING THIN FILM LAYERS DURING PHOTOVOLTAIC MODULE MANUFACTURE	SCHAEFFER CORY ALLEN (US); MURPHY BRIAN ROBERT (US)	US201 213561 575A	30-Jul-2012
US8881907B2	11-Nov-2014	Substrate storage container with gravity center adjustment member	YAMAGISHI HIROKI (JP); KAMADA TOSHIYUKI (JP)	US201 113641 707A	8-Apr-2011
US9011729B2	21-Apr-2015	Organic thin-film transistor	NAKAMURA HIROAKI (JP); SAITO MASATOSHI (JP); KONDO HIROFUMI (JP); BANDO TORU (JP)	US201 113642 722A	21-Apr-2011
US9196533B2	24-Nov-2015	Film for back surface of flip-chip semiconductor, dicing-tape-integrated film for back surface of semiconductor, process for producing semiconductor device, and flip-chip semiconductor device	TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP)	US201 113642 229A	18-Apr-2011
US9911683B2	6-Mar-2018	Film for back surface of flip-chip semiconductor	TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP)	US201 113642 325A	18-Apr-2011
US9478454B2	25-Oct-2016	Dicing tape-integrated film for semiconductor back surface	TAKAMOTO NAOHIDE (JP); SHIGA GOJI (JP); ASAI FUMITERU (JP); SUGIMURA TOSHIMASA (JP)	US201 414221 314A	21-Mar-2014
US8940610B2	27-Jan-2015	Electrode for energy storage device and method for manufacturing the same	KURIKI KAZUTAKA (JP); MORIWAKA TAMAE (JP); MURAKAMI SATOSHI (JP); YAMAZAKI SHUNPEI (JP)	US201 113085 234A	12-Apr-2011
US2011256666A1	20-Oct-2011	THERMOSETTING DIE BOND FILM, DICING DIE BOND FILM AND SEMICONDUCTOR DEVICE	SUGO YUKI (JP); TANAKA SHUMPEI (JP); INOUE KOUICHI (JP)	US201 113087 617A	15-Apr-2011
US2015236169A1	20-Aug-2015	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME	PARK SANG HEE (KR); HWANG CHI SUN (KR); BYUN CHUN WON (KR); FORTUNATO ELVIRA M C (PT); MARTINS RODRIGO F P (PT); BARROS ANA R X (PT); CORREIA NUNO F O (PT); BARQUINHA PEDRO M C (PT); FIGUEIREDO VITOR M L (PT)	US201 514704 300A	5-May-2015
US2013104957A1	2-May-2013	METHOD FOR PRODUCING A PHOTOVOLTAIC MODULE HAVING BACKSIDE-CONTACTED SEMICONDUCTOR CELLS, AND PHOTOVOLTAIC MODULE	KOYUNCU METIN (DE); SCHAAF ULRICH (DE); KUGLER ANDREAS (DE); ZERRER PATRICK (DE); ZIPPEL MARTIN (DE); STIHLER PATRICK (DE)	US201 013640 878A	26-Oct-2010
US2013126860A1	23-May-2013	THIN FILM TRANSISTOR SUBSTRATE	FUKUDA SHUNJI (JP); SAKAYORI KATSUYA (JP); ARIHARA KEITA (JP)	US201 213645 226A	4-Oct-2012
US2011247851A1	13-Oct-2011	APPARATUS FOR CURING THIN FILMS ON A MOVING SUBSTRATE	JACKSON DOUGLAS K (US); SCHRODER KURT A (US); MCCOOL STEVEN C (US)	US201 113081 561A	7-Apr-2011

US2016312055A1	27-Oct-2016	LIQUID SILANE-BASED COMPOSITIONS AND METHODS FOR PRODUCING SILICON-BASED MATERIALS	SCHULZ DOUGLAS L (US); HOEY JUSTIN (US); WU XIANGFA (US); AKHATOV ISKANDER (US); BOUDJOUK PHILIP (US); DAI XULIANG (US); PEDERSON LARRY (US); SMITH JEREMIAH (US); ELANGOVAN ARUMUGASAMY (US); HAN SIJIN (US)	US201 25-Apr-2016 615138 126A
US8900915B2	2-Dec-2014	Epitaxial structures and methods of forming the same	ROCKENBERGER JOERG (US); ZURCHER FABIO (US); TAKASHIMA MAO (US)	US201 6-Apr-2011 113081 257A
US9196689B2	24-Nov-2015	P-type oxide alloys based on copper oxides, tin oxides, tin—copper alloy oxides and metal alloy thereof, and nickel oxide, with embedded metals thereof, fabrication process and use thereof	CORREIA FORTUNATO ELVIRA MARIA (PT); DE PAIVA MARTINS RODRIGO FERRAO (PT); XAROUCO DE BARROS ANA RAQUEL (PT); DE OLIVEIRA CORREIA NUNO FILIPE (PT); LOUREIRO FIGUEIREDO VITOR MANUEL (PT); CANDIDO BARQUINHA PEDRO MIGUEL (PT); KO PARK SANG HEE (KR); HWANG CHI SUN (KR)	US201 6-Apr-2011 113640 214A
US10497619B2	3-Dec-2019	Method of manufacturing a semiconductor device including through silicon plugs	YU CHEN HUA (TW); YU CHIA LIN (TW); CHANG HUNG PIN (TW); HWANG CHIEN LING (TW); HUNG JUI PIN (TW); LIN YUNG CHI (TW)	US201 10-Aug-2018 816100 603A
US8475869B2	2-Jul-2013	Selective nanoparticle assembly systems and methods	BADRE CHANTAL (US); CHAPEL JEAN PAUL (FR); YANG SHU (US); CASTAING JEAN CHRISTOPHE (US)	US201 1-Apr-2011 113078 583A
US12557665B2	17-Feb-2026	Embedded semiconductive chips in reconstituted wafers, and systems containing same	SANKMAN ROBERT L (PHOENIX, US); GUZEK JOHN S (CHANDLER, US)	US202 27-Jun-2022 217850 790A
US2011244636A1	6-Oct-2011	MANUFACTURING METHOD OF SEMICONDUCTOR CHIP-EMBEDDED WIRING SUBSTRATE	KONDO KENJI (JP)	US201 20-Jan-2011 113009 898A
US9899240B2	20-Feb-2018	Substrate treatment apparatus	HASHIZUME AKIO (JP); AKANISHI YUYA (JP); KAWAGUCHI KENJI (JP); YAMAMOTO MANABU (JP)	US201 26-Jun-2013 313928 127A
US2011240354A1	6-Oct-2011	WIRING BOARD AND METHOD FOR MANUFACTURING WIRING BOARD	FURUHATA NAOKI (JP); SAKAI SHUNSUKE (JP); MIKADO YUKINOBU (JP)	US201 30-Mar-2011 113075 480A
US9966517B2	8-May-2018	LED leadframe or LED substrate, semiconductor device, and method for manufacturing LED leadframe or LED substrate	ODA KAZUNORI (JP); SAKAMOTO AKIRA (JP); MURATA YOSHINORI (JP); KAWAI KENZABURO (JP); SUZUKI KOICHI (JP); OISHI MEGUMI (JP)	US201 10-Dec-2015 514965 083A
US8841773B2	23-Sep-2014	Multi-layer interconnect structure for stacked dies	CHANG HUNG PIN (TW); CHIU CHIEN MING (TW); WU TSANG JIUH (TW); SHUE SHAU LIN (TW); YU CHEN HUA (TW)	US201 10-Sep-2012 213608 456A
US8257561B2	4-Sep-2012	Methods of forming a conductive transparent oxide film layer for use in a cadmium telluride based thin film photovoltaic device	FELDMAN PEABODY SCOTT DANIEL (US); DRAYTON JENNIFER ANN (US); GOSSMAN ROBERT DWAYNE (US); SADEGHI MEHRAN (GB)	US750 30-Mar-2010 05610A
US9263553B2	16-Feb-2016	Transistor and its method of manufacture	PRICE RICHARD DAVID (GB)	US201 29-Mar-2011 113638 061A
US2015327388A1	12-Nov-2015	Electrically Bonded Arrays of Transfer Printed Active Components	MENARD ETIENNE (FR); BOWER CHRISTOPHER (US); MEITL MATTHEW (US); GARROU PHILIP (US)	US201 18-May-2015 514715 191A

US8742568B2	3-Jun-2014	Circuit board, semiconductor device, process for manufacturing circuit board and process for manufacturing semiconductor device	KONDO MASAYOSHI (JP); MAKINO NATSUKI (JP); FUJIWARA DAISUKE (JP); ITO YUKA (JP)	US201 24-Feb-2011 113637 296A
US9954084B2	24-Apr-2018	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 1-Aug-2016 615224 968A
US8704219B2	22-Apr-2014	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); GODO HIROMICHI (JP)	US201 25-Mar-2011 113071 845A
US10141222B2	27-Nov-2018	Semiconductor device and method of forming conductive vias through interconnect structures and encapsulant of WLCSP	LIN YAOJIAN (SG); MARIMUTHU PANDI C (SG)	US201 11-Dec-2014 414566 870A
US9218954B2	22-Dec-2015	Defect capping method for reduced defect density epitaxial articles	SINGH RAJIV K (US); ARJUNAN ARUL CHAKKARAVARTHI (US)	US201 29-Apr-2013 313872 821A
US8455337B2	4-Jun-2013	Crystallization apparatus, crystallization method, method of manufacturing thin film transistor and method of manufacturing organic light emitting display apparatus	JIN SEONG HYUN (KR); CHANG YOUNG JIN (KR); OH JAE HWAN (KR); LEE WON KYU (KR)	US201 13-Sep-2012 213613 923A
US9003654B2	14-Apr-2015	Method for metalizing blind vias	JACQUET FABRICE (FR); BOLIS SEBASTIEN (FR); SAINT PATRICE DAMIEN (FR)	US201 3-Mar-2011 113039 902A
US9437552B2	6-Sep-2016	Semiconductor device and method of forming insulating layer around semiconductor die	LIN YAOJIAN (SG); CHEN KANG (SG); FANG JIANMIN (CN); FENG XIA (CN); BAO XUSHENG (SG)	US201 1-Aug-2014 414449 869A
US10388538B2	20-Aug-2019	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP); KISHIDA HIDEYUKI (JP)	US201 24-Oct-2016 615332 198A
US2011215325A1	8-Sep-2011	METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP); SUZUKI KUNIIHIKO (JP)	US201 25-Feb-2011 113034 727A
US8697180B2	15-Apr-2014	Large-area transparent conductive coatings including alloyed carbon nanotubes and nanowire composites, and methods of making the same	VEERASAMY VIJAYEN S (US)	US201 13-May-2013 313892 386A
US10672718B2	2-Jun-2020	Through-package-via (TPV) structures on inorganic interposer and methods for fabricating same	SUNDARAM VENKATESH (US); LIU FUHAN (US); TUMMALA RAO R (US); SUKUMARAN VIJAY (US); SRIDHARAN VIVEK (US); CHEN QIAO (US)	US201 25-Jan-2016 615005 275A
US9202954B2	1-Dec-2015	Nanostructure and photovoltaic cell implementing same	EVELSIZER VINCENT (US); BAWDEN LARRY (US); FISHER JOHN (US)	US201 2-Mar-2011 113039 208A
US8334216B2	18-Dec-2012	Method for producing silicon nanostructures	LIN CHING FUH (TW); SYU SHU JIA (TW)	US790 28-May-2010 33110A
US9401240B2	26-Jul-2016	Integrated passive iron shims in silicon	SCHERER AXEL (US); HENRY MICHAEL DAVID (US)	US201 1-Mar-2011 113037 365A

US10038213B2	31-Jul-2018	Group IV metal or semiconductor nanowire fabric	KORGEL BRIAN A (US); SMITH DAMON A (US); HOLMBERG VINCENT C (US); PATEL REKEN (US); THURK PAUL (US)	US201 24-Feb-2011 113034 667A
US8939818B2	27-Jan-2015	Polishing pad	SHIMIZU SHINJI (JP); KAZUNO ATSUSHI (JP)	US201 24-Feb-2011 113579 527A
US9343396B2	17-May-2016	Semiconductor device and method of forming IPD in fan-out wafer level chip scale package	LIN YAOJIAN (SG); FRYE ROBERT C (US); MARIMUTHU PANDI CHELVAM (SG); LIU KAI (US)	US201 6-Jul-2012 213543 088A
US8999208B2	7-Apr-2015	In-Ga-Sn oxide sinter, target, oxide semiconductor film, and semiconductor element	ITOSE MASAYUKI (JP); NISHIMURA MAMI (JP); KASAMI MASASHI (JP); YANO KOKI (JP)	US201 22-Feb-2011 113580 355A
US9309448B2	12-Apr-2016	Abrasive articles, method for their preparation and method of their use	KUJAT CHRISTOF (DE); LI YUZHUO (DE); RUSHING KENNETH (DE)	US201 19-Jan-2011 113580 807A
US8323871B2	4-Dec-2012	Antireflective hardmask composition and a method of preparing a patterned material using same	BURNS SEAN D (US); MEDEIROS DAVID R (US); PFEIFFER DIRK (US)	US711 24-Feb-2010 74810A
US9224693B2	29-Dec-2015	Semiconductor device and method of forming TMV and TSV in WLCSP using same carrier	PAGAILA REZA A (ID); LIN YAOJIAN (SG); YOON SEUNG WOOK (SG)	US201 8-Jul-2014 414326 237A
US10714537B2	14-Jul-2020	Logic elements comprising carbon nanotube field effect transistor (CNTFET) devices and methods of making same	BERTIN CLAUDE L (US)	US201 11-Jun-2018 816005 011A
US2016035582A1	4-Feb-2016	CHEMICAL-MECHANICAL PLANARIZATION OF SUBSTRATES CONTAINING COPPER, RUTHENIUM, AND TANTALUM LAYERS	LI YUZHUO (DE); WANG KE (CN)	US201 16-Oct-2015 514884 984A
US8956906B2	17-Feb-2015	Method and device for producing a semiconductor layer	ZACHMANN HENDRIK (DE); OTTE KARSTEN (DE); NEUMANN HORST (DE); SCHOLZE FRANK (DE); PISTOL LUTZ (DE)	US201 22-Feb-2010 013580 243A
US9537056B2	3-Jan-2017	Light emitting device	BAE JUNG HYEOK (KR); JEONG YOUNG KYU (KR); PARK KYUNG WOOK (KR); PARK DUK HYUN (KR)	US201 10-Apr-2014 414250 039A
US9013018B2	21-Apr-2015	Multilayer moisture barrier	PANKOW JOEL W (US); JORGENSEN GARY J (US); TERWILLIGER KENT M (US); GLICK STEPHEN H (US); ISOMAKI NORA (FI); HARKONEN KARI (FI); TURKULAINEN TOMMY (FI)	US201 17-Feb-2011 113579 459A
US8895651B2	25-Nov-2014	Composition for printing a seed layer and process for producing conductor tracks	HERMES STEPHAN (DE); IVANOVICI SORIN (DE)	US201 15-Feb-2011 113027 706A
US2014225271A1	14-Aug-2014	PANELIZED PACKAGING WITH TRANSFERRED DIELECTRIC	SCANLAN CHRISTOPHER M (US)	US201 24-Apr-2014 414261 265A
US9799532B2	24-Oct-2017	CMP polishing solution and polishing method	MINAMI HISATAKA (JP); AMANOKURA JIN (JP); ANZAI SOU (JP)	US201 4-Jan-2011 113510 273A

US8252682B2	28-Aug-2012	Method for thinning a wafer	YANG KU FENG (TW); WU WENG JIN (TW); LU HSIN HSIEN (TW); YU CHIA LIN (TW); SHIH CHU SUNG (TW); HSU FU CHI (TW); SHUE SHAU LIN (TW)	US704 69510A	12-Feb-2010
US8647964B2	11-Feb-2014	Temporary wafer bonding method for semiconductor processing	HARKNESS BRIAN (US)	US201 013583 007A	15-Dec-2010
US2012301825A1	29-Nov-2012	LAYERED STRUCTURE AND PHOTSENSITIVE DRY FILM TO BE USED THEREFOR	YOSHIDA TAKAHIRO (JP); MINEGISHI SHOUJI (JP); ARIMA MASAO (JP)	US201 213569 715A	8-Aug-2012
US2025098316A1	20-Mar-2025	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME	YAMAZAKI SHUNPEI (JP)	US202 418905 330A	3-Oct-2024
US2012297856A1	29-Nov-2012	METHOD AND PROCESS FOR METALLIC STAMP REPLICATION FOR LARGE AREA NANOPATTERNS	KEIL MATTHIAS (SE); LUO GANG (SE); ZHOU YE (SE)	US201 013576 411A	5-Feb-2010
US9502234B2	22-Nov-2016	Methods to prepare silicon-containing films	XIAO MANCHAO (US); LEI XINJIAN (US); HAN BING (CN); O NEILL MARK LEONARD (US)	US201 414193 417A	28-Feb-2014
US8530274B2	10-Sep-2013	Semiconductor device and method of forming air gap adjacent to stress sensitive region of the die	PAGAILA REZA A (ID)	US201 213706 818A	6-Dec-2012
US9558965B2	31-Jan-2017	Semiconductor device with thin profile WLCSP with vertical interconnect over package footprint	CHI HEEJO (KR); CHO NAMJU (KR); SHIN HANGIL (KR)	US201 213403 889A	23-Feb-2012
US9476019B2	25-Oct-2016	Cleaning agent for semiconductor provided with metal wiring	NAKANISHI MUTSUMI (JP); YOSHIMUCHI HIROSHI (JP); KOJI YUKICHI (JP)	US201 514725 836A	29-May-2015
US8623741B2	7-Jan-2014	Homogeneous porous low dielectric constant materials	PURUSHOTHAMAN SAMPATH (US); DUBOIS GERAUD JEAN MICHEL (US); MAGBITANG TEDDIE P (US); VOLKSEN WILLI (US); FROT THEO J (US)	US201 213553 264A	19-Jul-2012
US2014060385A1	6-Mar-2014	COMPOSITION FOR FORMING N-TYPE DIFFUSION LAYER, METHOD FOR FORMING N-TYPE DIFFUSION LAYER, AND METHOD FOR PRODUCING PHOTOVOLTAIC CELL	MACHII YOUICHI (JP); YOSHIDA MASATO (JP); NOJIRI TAKESHI (JP); OKANIWA KAORU (JP); IWAMURO MITSUNORI (JP); ADACHI SHUUICHIROU (JP); AOYAGI TAKUYA (JP)	US201 314071 720A	5-Nov-2013
US9059319B2	16-Jun-2015	Embedded dynamic random access memory device and method	ANDERSON BRENT A (US); BARTH JR JOHN E (US); HO HERBERT L (US); NOWAK EDWARD J (US); TRICKLE WAYNE (US)	US692 76010A	25-Jan-2010
US9475763B2	25-Oct-2016	Photoresist comprising nitrogen-containing compound	LIU CONG (US); WU CHUNYI (US); POHLERS GERHARD (US); PROKOPOWICZ GREGORY P (US); XU CHENG BAI (US)	US201 514589 759A	5-Jan-2015
US8580384B2	12-Nov-2013	Dielectric materials and methods of preparation and use thereof	ZHENG YAN (US); QUINN JORDAN (US); YAN HE (US); HU YAN (US); LU SHAOFENG (US); FACCHETTI ANTONIO (US)	US201 113007 148A	14-Jan-2011
US2012247388A1	4-Oct-2012	ROLL-TO-ROLL EVAPORATION SYSTEM AND METHOD TO MANUFACTURE GROUP IBIIIAVIA PHOTOVOLTAICS	VASQUEZ JORGE (US); FREITAG JAMES (US); PINARBASI MUSTAFA (US)	US201 213342 648A	3-Jan-2012

US9305842B2	5-Apr-2016	Fabrication methods of chip device packages	LIN CHIA SHENG (TW); LEE PO HAN (TW)	US201 8-Jan-2015 514592 818A
US8329512B2	11-Dec-2012	Patterning method for high density pillar structures	NGUYEN NATALIE (US); POON PAUL WAI KIE (US); RADIGAN STEVEN J (US); KONEVECKI MICHAEL (US); CHEN YUNG TIN (US); MAKALA RAGHUVeer (US); DUNTON VANCE (US)	US201 3-May-2012 213463 260A
US8778600B2	15-Jul-2014	Method of manufacturing high resolution organic thin film pattern	SUH MIN CHUL (KR); LEE SIN DOO (KR); CHOI WON SUK (KR); KIM MIN HOI (KR)	US979 27-Dec-2010 26010A
US8980524B2	17-Mar-2015	Positive resist composition and method of forming resist pattern	HIRANO TOMOYUKI (JP); SHIONO DAIJU (JP); ARAI MASATOSHI (JP)	US979 27-Dec-2010 06710A
US8633558B2	21-Jan-2014	Package structure for a chip and method for fabricating the same	LIN TA HSUAN (TW); SHIU CHUAN JIN (TW); CHENG CHIA MING (TW); LIU TSANG YU (TW)	US981 30-Dec-2010 64010A
US2013068723A1	21-Mar-2013	Method of Using a Mask to Provide a Patterned Substrate	STAY MATTHEW S (US); PEKUROVSKY MIKHAIL L (US)	US201 20-Dec-2010 013518 915A
US2011294254A1	1-Dec-2011	LOW COST SOLAR CELLS FORMED USING A CHALCOGENIZATION RATE MODIFIER	JACKREL DAVID B (US); DICKEY KATHERINE (US); WOODRUFF JACOB (US)	US980 28-Dec-2010 27610A
US10141425B2	27-Nov-2018	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); HIROHASHI TAKUYA (JP); TAKAHASHI MASAHIRO (JP); SHIMAZU TAKASHI (JP)	US201 28-Dec-2017 715856 763A
US9653306B2	16-May-2017	Method for forming crystalline cobalt silicide film	SHIMODA TATSUYA (JP); MATSUKI YASUO (JP); KAWAJIRI RYO (JP)	US201 22-Dec-2010 013518 986A
US2012164819A1	28-Jun-2012	APPARATUS AND METHOD FOR MANUFACTURING POLY-SI THIN FILM	RO JAE SANG (KR); HONG WON EUI (KR)	US979 27-Dec-2010 00010A
US9994684B2	12-Jun-2018	Method for forming bond between different elements	FURUSHO HITOSHI (JP); NOHARA YUKI (JP); WATANABE HISAYUKI (JP); GOTO YUICHI (JP)	US201 20-Apr-2015 514691 214A
US9362156B2	7-Jun-2016	Dicing tape-integrated film for semiconductor back surface	TAKAMOTO NAOHIDE (JP); MATSUMURA TAKESHI (JP); SHIGA GOJI (JP)	US201 25-Feb-2014 414188 991A
US9035192B2	19-May-2015	Anisotropic conductive adhesive composite and film, and circuit connecting structure including the same	LEE GYU HO (KR); PARK YOUNG WOO (KR); CHO IL RAE (KR); KIM YOUNG HUN (KR); PARK KYOUNG SOO (KR); PARK JIN SEONG (KR); UH DONG SEON (KR); LEE KYUNG JIN (KR); JUNG KWANG JIN (KR)	US974 21-Dec-2010 47610A
US8541631B2	24-Sep-2013	Surface treatment method for solid material	KIYOMORI AYUMU (JP); ITOH YUSUKE (JP); KUBOTA TOHRU (JP)	US975 22-Dec-2010 93110A
US8486609B2	16-Jul-2013	Antireflective coating composition and process thereof	RAHMAN M DALIL (US); MCKENZIE DOUGLAS (US); YAO HUIRONG (US); CHO JOONYEON (US); YL YI (US); LIN GUANYANG (US)	US646 23-Dec-2009 19109A

US8551887B2	8-Oct-2013	Method for chemical mechanical planarization of a copper-containing substrate	SHI XIAOBO (US)	US964 10-Dec-2010 94310A
US8950324B2	10-Feb-2015	Apparatus and method for microcontact printing using a pressurized roller	BERNIARD TRACIE J (US); FREY MATTHEW H (US); BEHYMER LANCE E (US); PEKUROVSKY MIKHAIL L (US); GREGER RICHARD W (US); MEEHAN DANIEL P (US); O HARE JONATHAN J (US)	US201 17-Dec-2010 013514 170A
US2012322348A1	20-Dec-2012	PAD FOR CHEMICAL MECHANICAL POLISHING AND METHOD OF CHEMICAL MECHANICAL POLISHING USING SAME	YOKOI KATSUTAKA (JP); MAEKAWA AYAKO (JP); SHIDA HIROTAKA (JP); KAMO SATOSHI (JP); TONSHO SHINJI (JP); SATOU KEIICHI (JP); NISHIGUCHI NAOKI (JP); TANO HIROYUKI (JP)	US201 14-Dec-2010 013518 230A
US9034104B2	19-May-2015	Method for manufacturing a semiconductor device comprising single- and multi-component oxide semiconductor layers	YAMAZAKI SHUNPEI (JP); HIROHASHI TAKUYA (JP); TAKAHASHI MASAHIRO (JP); SHIMAZU TAKASHI (JP)	US968 15-Dec-2010 36710A
US10453964B2	22-Oct-2019	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); KOEZUKA JUNICHI (JP)	US201 27-Jul-2017 715661 307A
US10070524B2	4-Sep-2018	Method of making glass core substrate for integrated circuit devices	MA QING (US); TRAN QUAN A (US); SANKMAN ROBERT L (US); SWAN JOHANNA M (US); RAO VALLURI R (US)	US201 9-Apr-2012 213442 092A
US2020315488A1	8-Oct-2020	FLEXIBLE AND STRETCHABLE ELECTRONIC SYSTEMS FOR EPIDERMAL ELECTRONICS	ROGERS JOHN A (US); KIM DAE HYEONG (US)	US201 27-Aug-2019 916552 215A
US10918298B2	16-Feb-2021	High-speed, high-resolution electrophysiology in-vivo using conformal electronics	ROGERS JOHN A (US); KIM DAE HYEONG (US); MOSS JOSHUA D (US); CALLANS DAVID J (US); LITT BRIAN (US); VIVENTI JONATHAN (US)	US968 15-Dec-2010 63710A
US9665001B2	30-May-2017	Photoresists and methods for use thereof	POHLERS GERHARD (US)	US969 15-Dec-2010 31910A
US10295910B2	21-May-2019	Photoresists and methods of use thereof	POHLERS GERHARD (US)	US969 15-Dec-2010 23610A
US9502254B2	22-Nov-2016	Photoresists and methods for use thereof	POHLERS GERHARD (US)	US201 25-Aug-2014 414467 630A
US8916473B2	23-Dec-2014	Method for forming through-base wafer vias for fabrication of stacked devices	HENRY JAMES MATTHEW (US); CASTILLO II DANIEL HERNANDEZ (US)	US959 3-Dec-2010 45210A
US9696627B2	4-Jul-2017	Compositions comprising base-reactive component and processes for photolithography	WANG DEYAN (US); LIU JINRONG (US); LIU CONG (US); KANG DORIS (US); ZAMPINI ANTHONY (US); XU CHENG BAI (US)	US966 13-Dec-2010 92810A
US2011143489A1	16-Jun-2011	PROCESS FOR MAKING THIN FILM SOLAR CELL	KOREVAAR BASTIAAN ARIE (US)	US635 11-Dec-2009 76709A
US9768355B2	19-Sep-2017	Production of graphene and nanoparticle catalysts supported on graphene using laser radiation	EL SHALL M SAMY (US); ABDELSAYED VICTOR (US); AL RESAYES SAUD I (SA); ALOTHMAN ZEID ABDULLAH M (SA)	US201 10-Dec-2010 013514 671A

US9337161B2	10-May-2016	Integrated circuit package system with removable backing element having plated terminal leads and method of manufacture thereof	CAMACHO ZIGMUND R (SG); MERILO DIOSCORO A (SG); BATHAN HENRY DESCALZO (SG); TAY LIONEL CHIEN HUI (SG)	US201 24-Jul-2014 414340 436A
US8298872B2	30-Oct-2012	Manufacturing method for semiconductor device	ODA TAKASHI (JP); TOYODA EIJI (JP); FUSUMADA MITSUAKI (JP)	US964 9-Dec-2010 20410A
US2016124304A1	5-May-2016	PHOTOACID GENERATORS AND PHOTORESISTS COMPRISING SAME	LI MINGQI (US); AQAD EMAD (US); LIU CONG (US); MATTIA JOSEPH (US); XU CHENG BAI (US); BARCLAY GEORGE G (US)	US201 11-Jan-2016 614992 692A
US8592300B2	26-Nov-2013	Interface structure for copper-copper peeling integrity	LIN CHENG CHUNG (TW); LIU CHUNG SUI (TW); YU CHEN HUA (TW)	US201 27-Dec-2012 213728 833A
US10332996B2	25-Jun-2019	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP)	US201 3-Dec-2015 514958 066A
US2024258119A1	1-Aug-2024	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	YAMAZAKI SHUNPEI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP)	US202 8-Feb-2024 418436 395A
US8058711B2	15-Nov-2011	Filler for filling a gap and method for manufacturing semiconductor capacitor using the same	LIM SANG HAK (KR); YUN HUI CHAN (KR); HAN DONG IL (KR); KWAK TAEK SOO (KR); BAE JIN HEE (KR); OH JUNG KANG (KR); KIM SANG KYUN (KR); KIM JONG SEOB (KR)	US956 30-Nov-2010 54910A
US9064950B2	23-Jun-2015	Fabrication method for a chip package	TSAI CHIA LUN (TW); CHENG CHIA MING (TW); YEOU LONG SHENG (TW)	US201 19-Dec-2013 314135 506A
US9028708B2	12-May-2015	Process for removing a bulk material layer from a substrate and a chemical mechanical polishing agent suitable for this process	RAMAN VIJAY IMMANUEL (DE); LI YUZHUAO (DE); BRANDS MARIO (DE); LAN YONGQING (US); RUSHING KENNETH (DE); RAMJI KARPAGAVALLI (US)	US201 25-Nov-2010 013510 514A
US10392531B2	27-Aug-2019	Process for removing a bulk material layer from a substrate and a chemical mechanical polishing agent suitable for this process	RAMAN VIJAY IMMANUEL (DE); EBERT SOPHIA (DE); BRANDS MARIO (DE); LAN YONGQING (US); ZACHARIAS PHILIPP (DE); GUBAYDULLIN ILSHAT (DE); LI YUZHUAO (DE)	US201 25-Nov-2010 013510 830A
US10347771B2	9-Jul-2019	Stacked oxide material, semiconductor device, and method for manufacturing the semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 10-Jul-2018 816031 336A
US8765522B2	1-Jul-2014	Stacked oxide material, semiconductor device, and method for manufacturing the semiconductor device	YAMAZAKI SHUNPEI (JP)	US951 22-Nov-2010 22510A
US2011120614A1	26-May-2011	THERMOSETTING ADHESIVE FILM, ADHESIVE FILM WITH DICING FILM, AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE USING THE THERMOSETTING ADHESIVE FILM OR THE ADHESIVE FILM WITH DICING FILM	SUGO YUKI (JP); INOUE KOUICHI (JP); OONISHI KENJI (JP)	US948 18-Nov-2010 99210A
US9105796B2	11-Aug-2015	CZTS/Se precursor inks and methods for preparing CZTS/Se thin films and CZTS/Se-based photovoltaic cells	CAO YANYAN (US); CASPAR JONATHAN V (US); DENNY JR MICHAEL S (US); JOHNSON LYNDIA KAYE (US); LU MEIJUN (US); RADU DANIELA RODICA (US)	US201 14-May-2012 213470 430A

US9508621B2	29-Nov-2016	Semiconductor device and method of forming compliant stress relief buffer around large array WLCSP	LIN YAOJIAN (SG); SHIM IL KWON (SG); CHOW SENG GUAN (SG)	US201 414564 427A	9-Dec-2014
US9196491B2	24-Nov-2015	End-cut first approach for critical dimension control	LIN LI TE S (TW); WANG MENG JUN (TW); CHANG YA HUI (TW); OUYANG HUI (TW)	US201 314059 898A	22-Oct-2013
US8470636B2	25-Jun-2013	Aqueous process for producing crystalline copper chalcogenide nanoparticles, the nanoparticles so-produced, and inks and coated substrates incorporating the nanoparticles	RADU DANIELA RODICA (US); JOHNSON LYNDA KAYE (US); LAI CHENG YU (US); LU MEIJUN (US); MALAJOVICH IRINA (US)	US201 013511 699A	22-Nov-2010
US2011120557A1	26-May-2011	MANUFACTURING METHOD FOR THIN FILM TYPE LIGHT ABSORBING LAYER, MANUFACTURING METHOD FOR THIN FILM SOLAR CELL USING THEREOF AND THIN FILM SOLAR CELL	SUH JEONGDAE (KR); SONG KIBONG (KR); HAM CHANGWOO (KR); CHUNG MYUNGAE (KR); SOHN SUNGWON (KR)	US817 06210A	16-Jun-2010
US8318249B2	27-Nov-2012	Method for selective deposition and devices	LEVY DAVID H (US)	US622 51909A	20-Nov-2009
US10186619B2	22-Jan-2019	Method for manufacturing semiconductor device	HOSOBAY MIYUKI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP); YAMAZAKI SHUNPEI (JP)	US201 615265 936A	15-Sep-2016
US8653512B2	18-Feb-2014	Thin film transistor compositions, and methods relating thereto	AUMAN BRIAN C (US); DUNBAR MEREDITH L (US); HE TAO (US); KOURTAKIS KOSTANTINOS (US)	US201 013510 628A	19-Nov-2010
US8598578B2	3-Dec-2013	Sputtering target and thin film transistor equipped with same	YANO KOKI (JP); ITOSE MASAYUKI (JP)	US201 013510 934A	18-Nov-2010
US2011117680A1	19-May-2011	INLINE DETECTION OF SUBSTRATE POSITIONING DURING PROCESSING	SVIDENKO VICKY (US); ABRAHAM MATHEW (US); KINCAL SERKAN (US)	US948 08910A	17-Nov-2010
US10071913B2	11-Sep-2018	Graphene laminate and method of preparing the same	SHIN HYEON JIN (KR); CHOI JAE YOUNG (KR); HAN GANG HEE (KR); LEE YOUNG HEE (KR)	US201 314068 676A	31-Oct-2013
US9372283B2	21-Jun-2016	Nanoengineered devices based on electro-optical modulation of the electrical and optical properties of plasmonic nanoparticles	NIKOOLBAKHT BABAK (US)	US943 32510A	10-Nov-2010
US8450044B2	28-May-2013	Positive resist composition and method of forming resist pattern	HIRANO TOMOYUKI (JP); SHIONO DAIJU (JP); TAKAKI DAICHI (JP)	US945 52610A	12-Nov-2010
US10056523B2	21-Aug-2018	Device including quantum dots	KAZLAS PETER T (US); MORRIS JOHN SPENCER (US); NICK ROBERT J (US); POPOVIC ZORAN (CA); STEVENSON MATTHEW (US); STECKEL JONATHAN S (US)	US201 615350 068A	13-Nov-2016
US9536752B2	3-Jan-2017	Slurry for chemical mechanical polishing and polishing method for substrate using same	TAKEGOSHI MINORI (JP); KATO MITSURU (JP); OKAMOTO CHIIHIRO (JP); KATO SHINYA (JP)	US201 013508 924A	8-Nov-2010

US8709864B2	29-Apr-2014	Method for manufacturing semiconductor element and semiconductor device, and deposition apparatus	YAMAZAKI SHUNPEI (JP); SAKATA JUNICHIRO (JP); TAKAYAMA TORU (JP)	US938 3-Nov-2010 53810A
US8530892B2	10-Sep-2013	Semiconductor device	YAMAZAKI SHUNPEI (JP); HIRAISHI SUZUNOSUKE (JP); AKIMOTO KENGO (JP); SAKATA JUNICHIRO (JP)	US917 2-Nov-2010 56910A
US10002949B2	19-Jun-2018	Semiconductor device	YAMAZAKI SHUNPEI (JP); HIRAISHI SUZUNOSUKE (JP); AKIMOTO KENGO (JP); SAKATA JUNICHIRO (JP)	US201 18-Sep-2014 414489 522A
US2026006919A1	1-Jan-2026	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	YAMAZAKI SHUNPEI (JP); KOYAMA JUN (JP); MIYAKE HIROYUKI (JP)	US202 8-Jul-2025 519262 335A
US8569887B2	29-Oct-2013	Post passivation interconnect with oxidation prevention layer	HWANG CHIEN LING (TW); WU YI WEN (TW); LIU CHUNG SHI (TW)	US907 19-Oct-2010 24910A
US9735301B2	15-Aug-2017	Manufacture of N-type chalcogenide compositions and their uses in photovoltaic devices	BRYDEN TODD R (US); LEMON BUFORD I (US); GEORGE JOSEPH (US); LIGMAN FEIST REBEKAH KRISTINE (US)	US201 15-Nov-2013 314081 641A
US9305897B2	5-Apr-2016	Semiconductor package and method of mounting semiconductor die to opposite sides of TSV substrate	CHOI DAESIK (KR); KIM JONGHO (KR); LEE HYUNGMIN (KR)	US201 23-Dec-2013 314138 646A
US9309446B2	12-Apr-2016	Photosensitive adhesive composition, film-like adhesive, adhesive sheet, adhesive pattern, semiconductor wafer with adhesive layer, semiconductor device	MITSUMURA KAZUYUKI (JP); KAWAMORI TAKASHI (JP); MASUKO TAKASHI (JP); KATOI SHIGEKI (JP)	US201 2-Mar-2012 213410 702A
US10566459B2	18-Feb-2020	Semiconductor device having a first region comprising silicon, oxygen and at least one metal element formed between an oxide semiconductor layer and an insulating layer	YAMAZAKI SHUNPEI (JP); MIYANAGA AKIHARU (JP); TAKAHASHI MASAHIRO (JP); KISHIDA HIDEYUKI (JP); SAKATA JUNICHIRO (JP)	US201 27-Oct-2017 715795 736A
US2011041899A1	24-Feb-2011	Three Dimensionally Structured Thin Film Photovoltaic Devices with Self-Aligned Back Contacts	JOSELL DANIEL (US); BEAUCHAMP CARLOS R (US); MOFFAT THOMAS P (US)	US609 30-Oct-2009 69909A
US8771533B2	8-Jul-2014	Edge protection seal for bonded substrates	FAROOQ MUKTA G (US); KINSER EMILY (US); WISE RICHARD S (US); AKINMADE YUSUFF HAKEEM B S (US)	US201 28-Feb-2013 313780 854A
US8440498B2	14-May-2013	Thin-film devices formed from solid particles	ROBINSON MATTHEW R (US); EBERSPACHER CHRIS (US); VAN DUREN JEROEN K J (US)	US201 5-Dec-2011 113311 483A
US9118013B2	25-Aug-2015	Method for producing organic EL element	KAIHO AKIO (JP)	US201 22-Oct-2010 013504 169A
US8735045B2	27-May-2014	Positive resist composition, method of forming resist pattern, and polymeric compound	HIRANO TOMOYUKI (JP); SHIONO DAIJU (JP); TAKAKI DAICHI (JP)	US911 25-Oct-2010 41110A
US10147604B2	4-Dec-2018	Aqueous-based method of forming semiconductor film and photovoltaic device including the film	MITZI DAVID B (US); TODOROV TEODOR K (US)	US718 5-Mar-2010 03910A

US9390919B2	12-Jul-2016	Method of forming semiconductor film and photovoltaic device including the film	MITZI DAVID B (US); TODOROV TEODOR K (US)	US201 18-Jul-2012 213552 080A
US8441772B2	14-May-2013	Substrate for electrostatic chuck and electrostatic chuck	YOSHIKAWA TADAYOSHI (JP); TAMAGAWA KOKI (JP); WATANABE NAOTO (JP)	US910 22-Oct-2010 49310A
US8486777B2	16-Jul-2013	Method for manufacturing microcrystalline semiconductor and thin film transistor	ICHIJO MITSUHIRO (JP); KURIKI KAZUTAKA (JP); YOKOI TOMOKAZU (JP); ENDO TOSHIYA (JP)	US201 5-Jan-2012 213343 734A
US8847365B2	30-Sep-2014	Inductors and methods for integrated circuits	ELLUL JOSEPH P (US); TRAN KHANH (US); GODSHALK EDWARD MARTIN (US); BERGEMONT ALBERT (US)	US201 14-Nov-2012 213677 061A
US8890111B2	18-Nov-2014	Method for manufacturing a very-high-resolution screen using a nanowire-based emitting anisotropic conductive film	TEMPLIER FRANCOIS (FR); CLAVELIER LAURENT (FR); RABAROT MARC (FR)	US201 19-Oct-2010 013503 480A
US8728341B2	20-May-2014	Polishing agent, concentrated one-pack type polishing agent, two-pack type polishing agent and method for polishing substrate	RYUZAKI DAISUKE (JP); NARITA TAKENORI (JP); HOSHI YOUSUKE (JP); IWANO TOMOHIRO (JP)	US201 14-Sep-2010 013388 169A
US8202800B2	19-Jun-2012	Method of forming through silicon via with dummy structure	CHEN CHIH HUA (TW); CHEN CHEN SHIEN (TW); KUO CHEN CHENG (TW); SHEN WEN WEI (TW)	US201 20-May-2011 113112 347A
US8894800B2	25-Nov-2014	Polymeric edge seal for bonded substrates	FAROOQ MUTKA G (US); HOUGHTON THOMAS F (US); PARBHOO NITIN (US); VOLANT RICHARD P (US)	US201 26-Feb-2013 313777 376A
US9224591B2	29-Dec-2015	Method of depositing a thin film	CHOI YONG SUP (KR); LEE KANG IL (KR); JO CHANG MOG (KR)	US201 15-Oct-2013 314054 536A
US10565946B2	18-Feb-2020	Liquid crystal display device and electronic device including the liquid crystal display device	YAMAZAKI SHUNPEI (JP); ARASAWA RYO (JP); KOYAMA JUN (JP); TSUBUKU MASASHI (JP); NODA KOSEI (JP)	US201 28-Nov-2017 715824 343A
US9911856B2	6-Mar-2018	Semiconductor device	YAMAZAKI SHUNPEI (JP); MIYANAGA AKIHARU (JP); TAKAHASHI MASAHIRO (JP); KISHIDA HIDEYUKI (JP); SAKATA JUNICHIRO (JP)	US900 7-Oct-2010 14510A
US10141450B2	27-Nov-2018	Semiconductor device	MIYANAGA AKIHARU (JP); SAKATA JUNICHIRO (JP); SAKAKURA MASAYUKI (JP); TAKAHASHI MASAHIRO (JP); KISHIDA HIDEYUKI (JP); YAMAZAKI SHUNPEI (JP)	US201 22-Aug-2016 615242 802A
US9754784B2	5-Sep-2017	Method for manufacturing oxide semiconductor device	YAMAZAKI SHUNPEI (JP); MIYANAGA AKIHARU (JP); TAKAHASHI MASAHIRO (JP); KISHIDA HIDEYUKI (JP); SAKATA JUNICHIRO (JP)	US201 23-Feb-2017 715440 427A
US8623695B2	7-Jan-2014	Method for producing semiconductor device	NOMOTO AKIHIRO (JP); ONO HIDEKI (JP)	US888 23-Sep-2010 48810A
US2012184066A1	19-Jul-2012	SINTERED In-Ga-Zn-O-TYPE OXIDE	YANO KOKI (JP); KAWASHIMA HIROKAZU (JP); ITOSE MASAYUKI (JP); INOUE KAUZYOSHI (JP)	US201 30-Sep-2010 013261 239A

US8952490B2	10-Feb-2015	Redox capacitor and manufacturing method thereof	KURIKI KAZUTAKA (JP); OGINO KIYOFUMI (JP); SAITO YUMIKO (JP); SAKATA JUNICHIRO (JP)	US891 27-Sep-2010 46110A
US9090119B2	28-Jul-2015	Pattern forming method	MINEGISHI SHIN YA (JP); NAKAFUJI SHIN YA (JP); NAKANO TAKANORI (JP)	US201 14-Mar-2014 414210 803A
US8408977B2	2-Apr-2013	Dual-pore structure polishing pad	JAMES DAVID B (US); SANFORD CRANE HENRY (US)	US201 16-Mar-2012 213422 180A
US8563088B2	22-Oct-2013	Selenium/group 1B ink and methods of making and using same	CALZIA KEVIN (US); MOSLEY DAVID (US); THORSEN DAVID L (US); SZMANDA CHARLES R (US)	US201 12-Oct-2012 213650 672A
US8841066B2	23-Sep-2014	Photoresist stripping technique	WANG CHIEN WEI (TW); CHANG CHING YU (TW)	US201 15-Jul-2013 313942 357A
US9418878B2	16-Aug-2016	Semiconductor device and method of forming adhesive material to secure semiconductor die to carrier in WLCSP	PAGAILA REZA A (ID); LIN YAOJIAN (SG)	US201 24-Jul-2014 414340 187A
US9520288B2	13-Dec-2016	Semiconductor device including IGZO layer and manufacturing method thereof	MIYANAGA AKIHARU (JP); SAKATA JUNICHIRO (JP); SAKAKURA MASAYUKI (JP); YAMAZAKI SHUNPEI (JP)	US201 28-May-2015 514723 981A
US12113124B2	8-Oct-2024	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); TSUJI TAKAHIRO (JP); SUZUKI KUNIIHIKO (JP)	US202 13-Jul-2022 217863 437A
US10418491B2	17-Sep-2019	Oxide semiconductor film and semiconductor device	YAMAZAKI SHUNPEI (JP); SAKAKURA MASAYUKI (JP); WATANABE RYOSUKE (JP); SAKATA JUNICHIRO (JP); AKIMOTO KENGO (JP); MIYANAGA AKIHARU (JP); HIROHASHI TAKUYA (JP); KISHIDA HIDEYUKI (JP)	US201 19-Dec-2017 715846 518A
US11688612B2	27-Jun-2023	Semiconductor device and method of forming interposer with opening to contain semiconductor die	PAGAILA REZA A (ID); LIN YAOJIAN (CN); KOO JUN MO (SG); CHI HEEJO (KR)	US201 18-Dec-2017 715846 014A
US9263332B2	16-Feb-2016	Semiconductor device and method of forming open cavity in TSV interposer to contain semiconductor die in WLCSP	CHI HEEJO (KR); CHO NAMJU (KR); SHIN HANGIL (KR)	US201 16-Jul-2013 313943 737A
US2015221698A1	6-Aug-2015	THICK BOND PAD FOR CHIP WITH CAVITY PACKAGE	GAMBINO JEFFREY P (US); LEIDY ROBERT K (US); RASSEL RICHARD J (US)	US201 16-Apr-2015 514688 215A
US8859040B2	14-Oct-2014	Method of applying atomic layer deposition coatings onto porous non-ceramic substrates	DODGE BILL H (US)	US201 15-Sep-2010 013392 213A
US2015191616A1	9-Jul-2015	SILICON/GERMANIUM NANOPARTICLES AND INKS HAVING LOW METAL CONTAMINATION	CHIRUVOLU SHIVKUMAR (US); ALTMAN IGOR (US); FREY BERNARD M (US); LI WEIDONG (US); LIU GUOJUN (CN); LYNCH ROBERT B (US); PENGRA LEUNG GINA ELIZABETH (US); SRINIVASAN UMA (US)	US201 20-Mar-2015 514663 965A
US10446726B2	15-Oct-2019	Wafer level packaging of electronic devices	MARGALIT MORDEHAI (IL); PETRONIUS ISRAEL (IL)	US201 21-Jun-2016 615188 225A

US8492841B2	23-Jul-2013	Trench-generated transistor structures, device structures, and design structures	ANDERSON BRENT A (US); NOWAK EDWARD J (US)	US201 213351 012A	16-Jan-2012
US8030189B2	4-Oct-2011	Method for maintaining a smooth surface of crystallizable material	LIN CHING FUH (TW); CHAO CHA HSIN (TW); LIN WEN HAN (TW)	US607 96309A	28-Oct-2009
US8828879B2	9-Sep-2014	Silicon-containing composition having sulfonamide group for forming resist underlayer film	KANNO YUTA (JP); NAKAJIMA MAKOTO (JP); SHIBAYAMA WATARU (JP)	US201 013496 768A	7-Sep-2010
US9484334B2	1-Nov-2016	Semiconductor device and method of forming directional RF coupler with IPD for additional RF signal processing	FRYE ROBERT C (US); LIU KAI (US)	US201 213716 799A	17-Dec-2012
US8748078B2	10-Jun-2014	Cyclic compound, process for preparation thereof, radiation-sensitive composition, and method for formation of resist pattern	HAYASHI HIROMI (JP); ECHIGO MASATOSHI (JP); OGURO DAI (JP)	US201 013393 988A	30-Aug-2010
US8997341B2	7-Apr-2015	Substrate for mounting semiconductor chip and method for producing same	EJIRI YOSHINORI (JP); HASEGAWA KIYOSHI (JP); SAKURAI TAKEHISA (JP); TSUBOMATSU YOSHIAKI (JP)	US201 013394 688A	6-Sep-2010
US8961836B2	24-Feb-2015	Composition for printing conductor tracks and a process for producing solar cells	KLEINE JAEGER FRANK (DE); HERMES STEPHAN (DE)	US201 013394 008A	25-Aug-2010
US8252509B2	28-Aug-2012	Resist composition and method of forming resist pattern	UTSUMI YOSHIYUKI (JP); SESHIMO TAKEHIRO (JP); SHIMIZU HIROAKI (JP); MOTOIKE NAOTO (JP)	US861 47410A	23-Aug-2010
US9105921B2	11-Aug-2015	Porous amorphous silicon—carbon nanotube composite based electrodes for battery applications	PUSHPARAJ VICTOR L (US); NALAMASU OMKARAM (US); VERHAVERBEKE STEVEN (US)	US201 314016 879A	3-Sep-2013
US8216914B2	10-Jul-2012	Method for manufacturing SOI substrate and method for manufacturing semiconductor device	KOYAMA MASAKI (JP); NEI KOSEI (JP); HASEGAWA TORU (JP); MOMO JUNPEI (JP); HIGA EIJI (JP)	US872 22210A	31-Aug-2010
US8454850B2	4-Jun-2013	Method for the removal of surface oxides by electron attachment	DONG CHUN CHRISTINE (US); GHOSH RANAJIT (US); ARSLANIAN GREGORY KHOSROV (US)	US857 15610A	16-Aug-2010
US9018096B2	28-Apr-2015	Structures comprising planar electronic devices	PRICE RICHARD DAVID (GB); BARTON IAN (GB)	US201 013393 811A	2-Sep-2010
US2012156504A1	21-Jun-2012	COATING MATERIAL COMPOSITION FOR LIQUID IMMERSION EXPOSURE APPARATUS, LAMINATE, METHOD FOR FORMING LAMINATE, AND LIQUID IMMERSION EXPOSURE APPARATUS	TAKEBE YOKO (JP); YOKOKOJI OSAMU (JP)	US201 213408 963A	29-Feb-2012
US2012156615A1	21-Jun-2012	CYCLIC COMPOUND, PROCESS FOR PRODUCTION OF THE CYCLIC COMPOUND, RADIATION-SENSITIVE COMPOSITION, AND METHOD FOR FORMATION OF RESIST PATTERN	ECHIGO MASATOSHI (JP); HAYASHI HIROMI (JP)	US201 013392 254A	27-Aug-2010
US8889919B2	18-Nov-2014	Cyclic compound, process for production of the cyclic compound, radiation-sensitive composition, and method for formation of resist pattern	ECHIGO MASATOSHI (JP); HAYASHI HIROMI (JP)	US201 013392 263A	26-Aug-2010

US8360129B2	29-Jan-2013	Peeling device	EBATA KENICHI (JP); ITO YASUNORI (JP)	US201 113096 006A	28-Apr-2011
US9397050B2	19-Jul-2016	Semiconductor device and method of forming pre-molded semiconductor die having bumps embedded in encapsulant	SHIN HANGIL (KR); CHI HEEJO (KR); CHO NAMJU (KR)	US551 27009A	31-Aug-2009
US9450140B2	20-Sep-2016	Thin film deposition apparatus and method of manufacturing organic light-emitting display apparatus using the same	JO CHANG MOG (KR); KIM JONG HEON (KR); CHOI YONG SUP (KR); KIM SANG SOO (KR); KANG HEE CHEOL (KR); CHOI YOUNG MOOK (KR)	US869 83010A	27-Aug-2010
US8062972B2	22-Nov-2011	Semiconductor process	LIU AN CHI (TW); HUANG CHIH CHIEN (TW); LAN TIEN CHENG (TW)	US547 78009A	26-Aug-2009
US9177761B2	3-Nov-2015	Plasma CVD apparatus, method for forming microcrystalline semiconductor film and method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US860 11810A	20-Aug-2010
US9177901B2	3-Nov-2015	Semiconductor device and method of stacking die on leadframe electrically connected by conductive pillars	PAGAILA REZA A (SG); DO BYUNG TAI (SG); CHUA LINDA PEI EE (SG)	US201 213430 538A	26-Mar-2012
US8896068B2	25-Nov-2014	Semiconductor device including source/drain regions and a gate electrode, and having contact portions	MAYUZUMI SATORU (JP)	US854 61310A	11-Aug-2010
US9318346B2	19-Apr-2016	CMP polishing liquid and polishing method	KANAMARU MAMIKO (JP); SHIMADA TOMOKAZU (JP); SHINODA TAKASHI (JP)	US201 414468 688A	26-Aug-2014
US9379064B2	28-Jun-2016	Semiconductor device and method of mounting semiconductor die to heat spreader on temporary carrier and forming polymer layer and conductive layer over the die	OH JIHOON (KR); LEE SINJAE (KR); KIM JINGWAN (KR)	US201 514697 950A	28-Apr-2015
US10522382B2	31-Dec-2019	Method of manufacturing a semiconductor device	LU YUNG JEAN (TW); CHEN MING FA (TW); CHEN CHEN SHIEN (TW); HUANG JAO SHENG (TW)	US201 715715 839A	26-Sep-2017
US9137902B2	15-Sep-2015	Process to form highly conductive feature from silver nanoparticles with reduced processing temperature	WU YILIANG (CA); LIU PING (CA); HU NAN XING (CA)	US541 64409A	14-Aug-2009
US2012217445A1	30-Aug-2012	POLYMER COMPOUND AND METHOD FOR PRODUCING THE SAME	FUKUSHIMA DAISUKE (JP); ISHII YUSUKE (JP); SETO MARI (JP); OHUCHI KAZUEI (JP)	US201 013389 945A	11-Aug-2010
US2012196444A1	2-Aug-2012	METHOD FOR THE SELECTIVE DELIVERY OF MATERIAL TO A SUBSTRATE	LENNON ALISON JOAN (AU); WENHAM STUART ROSS (AU)	US201 013389 735A	6-Aug-2010
US8759156B2	24-Jun-2014	Method of producing laminated device	STANDING MARTIN (AT)	US201 213618 280A	14-Sep-2012
US10068843B2	4-Sep-2018	Semiconductor device and method of forming cavity in build-up interconnect structure for short signal path between die	PAGAILA REZA A (ID)	US201 213726 467A	24-Dec-2012

US9954005B2	24-Apr-2018	Semiconductor device comprising oxide semiconductor layer	KIMURA HAJIME (JP); OHARA HIROKI (JP); KAYAMA MASAYO (JP)	US201 514883 706A	15-Oct-2015
US2011033974A1	10-Feb-2011	METHOD FOR FABRICATING HOLLOW NANOTUBE STRUCTURE	WANG SHUI JINN (TW); KUO DER MING (TW); ISAI WEI CHIH (TW); TSENG CHIH REN (TW)	US851 80410A	6-Aug-2010
US2012208012A1	16-Aug-2012	SEMICONDUCTOR PROCESSING SHEET	WATANABE KEISUKE (JP); MORIMOTO MASAKAZU (JP); MORI JUNKI (JP); NATSUME MASAYOSHI (JP)	US201 013388 879A	20-Jul-2010
US9343680B2	17-May-2016	Printed electronic device	SIRRINGHAUS HENNING (GB); CARIONI MARIO (IT); GILI ENRICO (GB)	US201 013388 665A	29-Jul-2010
US9741779B2	22-Aug-2017	Oxide semiconductor device	YAMAZAKI SHUNPEI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP); KUWABARA HIDEAKI (JP)	US201 615161 363A	23-May-2016
US11257714B2	22-Feb-2022	Method of making a pillar structure having a non-metal sidewall protection structure and integrated circuit including the same	HWANG CHIEN LING (TW); WU YI WEN (TW); WANG CHUN CHIEH (TW); LIU CHUNG SHI (TW)	US201 514804 813A	21-Jul-2015
US10954591B2	23-Mar-2021	Method for producing a structured coating on a substrate, coated substrate, and semi-finished product having a coated substrate	LEIB JURGEN (DE); HANSEN ULLI (DE); MAUS SIMON (DE)	US201 013386 642A	22-Jul-2010
US9443828B2	13-Sep-2016	Semiconductor device and method of embedding thermally conductive layer in interconnect structure for heat dissipation	PAGAILA REZA A (ID); DO BYUNG TAI (SG); CHUA LINDA PEI EE (SG)	US201 514694 811A	23-Apr-2015
US7943511B2	17-May-2011	Semiconductor process	FANG CHUN CHIEH (TW); CHEN PO JONG (TW); KUO TSUNG MIN (TW)	US504 92909A	17-Jul-2009
US8258050B2	4-Sep-2012	Method of making light trapping crystalline structures	CHO HANS S (US); KAMINS THEODORE I (US)	US505 37709A	17-Jul-2009
US8277894B2	2-Oct-2012	Selenium ink and methods of making and using same	MOSLEY DAVID (US); CALZIA KEVIN (US)	US504 06209A	16-Jul-2009
US9576937B2	21-Feb-2017	Back-to-back stacked integrated circuit assembly	STUBER MICHAEL A (CA); MOLIN STUART B (CA)	US201 615130 721A	15-Apr-2016
US2016284671A1	29-Sep-2016	Integrated Circuit Assembly and Method of Making	STUBER MICHAEL A (US); MOLIN STUART B (US); DRUCKER MARK (US); FOWLER PETER (US)	US201 615173 251A	3-Jun-2016
US8148230B2	3-Apr-2012	Method of making damascene diodes using selective etching methods	DUNTON VANCE (US); MAKALA RAGHUVeer S (US); CHAN MICHAEL (US)	US656 30610A	25-Jan-2010
US11855194B2	26-Dec-2023	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); HOSOBATA MIYUKI (JP); NODA KOSEI (JP); OHARA HIROKI (JP); SASAKI TOSHINARI (JP); SAKATA JUNICHIRO (JP)	US202 117500 149A	13-Oct-2021

US2016307925A1	20-Oct-2016	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THE SAME	YAMAZAKI SHUNPEI (JP); OHARA HIROKI (JP); SAKATA JUNICHIRO (JP); SASAKI TOSHINARI (JP); HOSOB A MIYUKI (JP)	US201 24-Jun-2016 615191 644A
US2012103860A1	3-May-2012	SUBSTRATE-STORING CONTAINER	MASUKO HIDEHIRO (JP); MIMURA HIROSHI (JP); OGAWA OSAMU (JP)	US201 28-Jun-2010 013382 439A
US2012108012A1	3-May-2012	FILM FOR SEMICONDUCTOR AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD	YASUDA HIROYUKI (JP); HIRANO TAKASHI (JP); ODA NAOYA (JP)	US201 31-May-2010 013382 593A
US2012100697A1	26-Apr-2012	FILM FOR SEMICONDUCTOR AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD	YASUDA HIROYUKI (JP); HIRANO TAKASHI (JP)	US201 31-May-2010 013382 596A
US8933324B2	13-Jan-2015	Thermally mounting electronics to a photovoltaic panel	OLDENKAMP HENDRIK (NL); DE JONG IRENE JOHANNA (NL)	US201 5-Jan-2012 213343 872A
US8846838B2	30-Sep-2014	Fluorine-containing block copolymeric compound	MATSUMIYA TASUKU (JP); SHIONO DAIJU (JP); HIRANO TOMOYUKI (JP); DAZAI TAKAHIRO (JP)	US201 26-Oct-2012 213661 518A
US8241972B2	14-Aug-2012	Method for manufacturing flexible semiconductor device	WANG XUE SHEN (CN); LI QUN QING (CN)	US781 17-May-2010 03610A
US2013328044A1	12-Dec-2013	MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP); SASAKI TOSHINARI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP)	US201 13-Aug-2013 313965 309A
US12272698B2	8-Apr-2025	Semiconductor device comprising driver circuit	SAKATA JUNICHIRO (JP); SASAKI TOSHINARI (JP); HOSOB A MIYUKI (JP)	US202 26-Mar-2024 418616 403A
US10297679B2	21-May-2019	Method for manufacturing semiconductor device	OIKAWA YOSHI AKI (JP); OKAZAKI KENICHI (JP); MARUYAMA HOTAKA (JP)	US201 5-Feb-2018 815888 316A
US10066164B2	4-Sep-2018	Semiconductor nanocrystals used with LED sources	QIAO TIECHENG (US); BATTAGLIA DAVID (US); SUNDERRAJAN SURESH (US); ZHANG QIANG (US); ZHU HAOGUO (US)	US201 30-Jun-2010 013381 577A
US2019035641A1	31-Jan-2019	METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE	SASAKI TOSHINARI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP); YAMAZAKI SHUNPEI (JP)	US201 1-Oct-2018 816148 294A
US10332743B2	25-Jun-2019	Method for manufacturing semiconductor device	SASAKI TOSHINARI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP); YAMAZAKI SHUNPEI (JP)	US201 1-Aug-2017 715665 689A
US2025062121A1	20-Feb-2025	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME	SASAKI TOSHINARI (JP); SAKATA JUNICHIRO (JP); OHARA HIROKI (JP); YAMAZAKI SHUNPEI (JP)	US202 1-Nov-2024 418934 417A
US2010327285A1	30-Dec-2010	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND DISPLAY DEVICE AND MANUFACTURING METHOD OF DISPLAY DEVICE	YAMAMOTO KAZUTO (JP); MOROSAWA KATSUHIKO (JP)	US820 22-Jun-2010 36210A

US8394571B2	12-Mar-2013	Methods of forming electronic devices	BAE YOUNG CHEOL (US); CARDOLACCIA THOMAS (US); LIU YI (US)	US825 28-Jun-2010 16610A
US8507185B2	13-Aug-2013	Methods of forming electronic devices	BAE YOUNG CHEOL (US); CARDOLACCIA THOMAS (US); LIU YI (US)	US825 28-Jun-2010 17010A
US8431329B2	30-Apr-2013	Self-aligned spacer multiple patterning methods	BAE YOUNG CHEOL (US); CARDOLACCIA THOMAS (US); LIU YI (US)	US825 28-Jun-2010 11710A
US8338077B2	25-Dec-2012	Photoacid generators and photoresists comprising same	LI MINGQI (US); XU CHENG BAI (US); AQAD EMAD (US); LIU CONG (US)	US820 22-Jun-2010 33110A
US8981568B2	17-Mar-2015	Simulated wirebond semiconductor package	RATHBURN JAMES (US)	US201 7-Jun-2010 013319 120A
US2010314782A1	16-Dec-2010	DICING TAPE-INTEGRATED FILM FOR SEMICONDUCTOR BACK SURFACE	OONISHI KENJI (JP); TAKAMOTO NAOHIDE (JP)	US814 14-Jun-2010 74510A
US8912665B2	16-Dec-2014	Dicing tape-integrated film for semiconductor back surface	HAYASHI MIKI (JP); TAKAMOTO NAOHIDE (JP)	US201 21-Dec-2012 213725 278A
US8890328B2	18-Nov-2014	Semiconductor device and method of forming vertical interconnect structure between non-linear portions of conductive layers	CAMACHO ZIGMUND R (SG); MERILO DIOSCORO A (SG); PISIGAN JAIRUS L (SG); DAHILIG FREDERICK R (SG)	US201 6-Dec-2011 113312 852A
US2013009312A1	10-Jan-2013	INTERCONNECT STRUCTURE FABRICATED WITHOUT DRY PLASMA ETCH PROCESSING	DARNON MAXIME (US); GAMBINO JEFFREY P (US); HUANG ELBERT E (US); LIN QINGHUANG (US)	US201 4-Sep-2012 213603 017A
US10703917B2	7-Jul-2020	Coating compositions suitable for use with an overcoated photoresist	AMARA JOHN P (US); CAMERON JAMES F (US); SUNG JIN WUK (US); PROKOPOWICZ GREGORY P (US)	US201 17-Jul-2017 715652 192A
US9054083B2	9-Jun-2015	Semiconductor device and method of making TSV interconnect structures using encapsulant for structural support	SUTHIWONGSUNTHORN NATHAPONG (SG); MARIMUTHU PANDI C (SG); KU JAE HUN (SG); OMANDAM GLENN (SG); GOH HIN HWA (SG); HENG KOCK LIANG (SG); CAPARAS JOSE A (SG)	US201 30-Dec-2013 314143 891A
US10180627B2	15-Jan-2019	Processes for photolithography	WANG DEYAN (US); BARCLAY GEORGE G (US); ESTELLE THOMAS A (US); SPIZUOCO KENNETH J (US); KANG DORIS (US)	US795 8-Jun-2010 99710A
US8961853B2	24-Feb-2015	Silicon pen nanolithography	MIRKIN CHAD A (US); SHIM WOYOUNG (US); BRAUNSCHWEIG ADAM B (US); LIAO XING (US); CHAI JINAN (US); LIM JONG KUK (KR); ZHENG GENGFENG (US); ZHENG ZIJIAN (CN)	US201 4-Jun-2010 013375 361A
US2012073655A1	29-Mar-2012	PACKAGE BODY FOR STORING OR TRANSPORTING SOLAR CELL SEALING FILM AND METHOD FOR STORING OR TRANSPORTING SOLAR CELL SEALING FILM	MORI HIROSHI (JP); MUROFUSHI TAKANOBU (JP); IKENAGA SHIGENOBU (JP); HAKUTA TAKASHI (JP); ZENKOH HIROFUMI (JP)	US201 4-Jun-2010 013376 049A
US8304924B2	6-Nov-2012	Composition for sealing semiconductor, semiconductor device, and process for producing semiconductor device	ONO SHOKO (JP); KOHMURA KAZUO (JP)	US201 28-May-2010 013131 895A

US9419113B2	16-Aug-2016	Semiconductor device and manufacturing method thereof	ASANO YUJI (JP); KOEZUKA JUNICHI (JP)	US201 13-Oct-2015 514881 578A
US10283627B2	7-May-2019	Semiconductor device and manufacturing method thereof	SASAKI TOSHINARI (JP); OHARA HIROKI (JP); SAKATA JUNICHIRO (JP)	US201 10-Jul-2014 414328 060A
US8987886B2	24-Mar-2015	Copper pillar full metal via electrical circuit structure	RATHBURN JAMES (US)	US201 7-Mar-2012 213413 724A
US9613841B2	4-Apr-2017	Area array semiconductor device package interconnect structure with optional package-to-package or flexible circuit to package connection	RATHBURN JAMES (US)	US201 2-Mar-2012 213410 943A
US9232654B2	5-Jan-2016	High performance electrical circuit structure	RATHBURN JAMES (US)	US201 18-Oct-2011 113879 783A
US8970031B2	3-Mar-2015	Semiconductor die terminal	RATHBURN JAMES (US)	US201 15-Jun-2010 013319 145A
US9054097B2	9-Jun-2015	Compliant printed circuit area array semiconductor device package	RATHBURN JAMES (US)	US201 27-May-2010 013266 573A
US9136196B2	15-Sep-2015	Compliant printed circuit wafer level semiconductor package	RATHBURN JAMES (US)	US201 27-May-2010 013318 200A
US8955216B2	17-Feb-2015	Method of making a compliant printed circuit peripheral lead semiconductor package	RATHBURN JAMES (US)	US201 25-May-2010 013318 181A
US2015174726A1	25-Jun-2015	POLISHING PAD, COMPOSITION FOR THE MANUFACTURE THEREOF, AND METHOD OF MAKING AND USING	LITKE BRIAN (US); KOSS MICHELE K (US)	US201 5-Mar-2015 514639 463A
US9093190B2	28-Jul-2015	Synthesis of multinary chalcogenide nanoparticles comprising Cu, Zn, Sn, S, and Se	AGRAWAL RAKESH (US); HILLHOUSE HUGH W (US); GUO QIJIE (US)	US201 26-May-2010 013321 835A
US2012115312A1	10-May-2012	THIN FILMS FOR PHOTOVOLTAIC CELLS	AGRAWAL RAKESH (US); HILLHOUSE HUGH W (US); GUO QIJIE (US); KAR MAHAPRASAD (US)	US201 26-May-2010 013321 834A
US8432021B2	30-Apr-2013	Manufacturing method of SOI substrate	MORIWAKA TOMOAKI (JP)	US786 25-May-2010 57410A
US9030002B2	12-May-2015	Semiconductor device having IPD structure with smooth conductive layer and bottom-side conductive layer	LIN YAOJIAN (SG)	US201 20-Apr-2011 113090 590A
US9040113B2	26-May-2015	Atomic layer deposition of metal sulfide thin films using non-halogenated precursors	MARTINSON ALEX B F (US); ELAM JEFFREY W (US); PELLIN MICHAEL J (US)	US780 14-May-2010 66410A

US8114306B2	14-Feb-2012	Method of forming sub-lithographic features using directed self-assembly of polymers	CHENG JOY (US); LAI KAFAI (US); LI WAI KIN (US); NA YOUNG HYE (US); RETTNER CHARLES (US); SANDERS DANIEL P (US); YANG DA (US)	US470 22-May-2009 76009A
US9112094B2	18-Aug-2015	Copper tin sulfide and copper zinc tin sulfide ink compositions	JOHNSON LYNDIA KAYE (US); CATRON JR JOHN W (US); RADU DANIELA RODICA (US)	US201 21-May-2010 013319 819A
US2010294352A1	25-Nov-2010	METAL PATTERNING FOR ELECTRICALLY CONDUCTIVE STRUCTURES BASED ON ALLOY FORMATION	SRINIVASAN UMA (US); PAKALA NEERAJ (US); SANDERS WILLIAM A (US); HIESLMAIR HENRY (US)	US469 20-May-2009 10109A
US2014106551A1	17-Apr-2014	BACK CONTACT SOLAR CELLS WITH EFFECTIVE AND EFFICIENT DESIGNS AND CORRESPONDING PATTERNING PROCESSES	SRINIVASAN UMA (US); ZHOU XIN (US); HIESLMAIR HENRY (US); PAKALA NEERAJ (US)	US201 16-Dec-2013 314107 780A
US9244352B2	26-Jan-2016	Coating compositions for use with an overcoated photoresist	ZAMPINI ANTHONY (US); WAYTON GERALD B (US); JAIN VIPUL (US); LIU CONG (US); COLEY SUZANNE (US); ONGAYI OWENDI (US)	US782 18-May-2010 39710A
US8501383B2	6-Aug-2013	Coating compositions for use with an overcoated photoresist	ZAMPINI ANTHONY (US); JAIN VIPUL (US); LIU CONG (US); COLEY SUZANNE (US); ONGAYI OWENDI (US)	US782 18-May-2010 35010A
US2010295138A1	25-Nov-2010	METHODS AND SYSTEMS FOR FABRICATION OF MEMS CMOS DEVICES	MONTANYA SILVESTRE JOSEP (ES); VALLE FRAGA JUAN JOSE (ES); LLAMAS MOROTE MARCO ANTONIO (ES); SABIR TAYYIB (GB)	US784 20-May-2010 02410A
US2011039210A1	17-Feb-2011	NOVEL RESINS AND PHOTORESIST COMPOSITIONS COMPRISING SAME	XU CHENG BAI (US); ZAMPINI ANTHONY (US)	US782 18-May-2010 52810A
US2010297851A1	25-Nov-2010	COMPOSITIONS AND METHODS FOR MULTIPLE EXPOSURE PHOTOLITHOGRAPHY	BAE YOUNG CHEOL (US); LIU YI (US); CARDOLACCIA THOMAS (US); TREFONAS III PETER (US)	US781 17-May-2010 48610A
US8398868B2	19-Mar-2013	Directed self-assembly of block copolymers using segmented prepatterns	CHENG JOY (US); LAI KAFAI (US); LI WAI KIN (US); NA YOUNG HYE (US); RETTNER CHARLES (US); SANDERS DANIEL P (US)	US468 19-May-2009 39109A
US9721925B2	1-Aug-2017	Semiconductor device and method of forming overlapping semiconductor die with coplanar vertical interconnect structure	BATHAN HENRY D (SG); CAMACHO ZIGMUND R (SG); PISIGAN JAIRUS L (SG)	US201 14-Oct-2014 414514 190A
US2011204472A1	25-Aug-2011	Semiconductor Device and Method of Forming 3D Inductor from Prefabricated Pillar Frame	PAGAILA REZA A (SG); LIN YAOJIAN (SG)	US201 30-Apr-2011 113098 419A
US8164171B2	24-Apr-2012	System-in packages	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW)	US779 13-May-2010 86310A
US8757177B2	24-Jun-2014	Multi-stage substrate cleaning method and apparatus	KHOLODENKO ARNOLD (US); MIKHAYLICHENKO KATRINA (US); LIN CHENG YU SEAN (US); WILCOXSON MARK (US); GINZBURG LEON (US); KAWAGUCHI MARK (US)	US201 6-Nov-2012 213670 006A
US10546841B2	28-Jan-2020	Printed assemblies of ultrathin, microscale inorganic light emitting diodes for deformable and semitransparent displays	ROGERS JOHN A (US); NUZZO RALPH (US); KIM HOON SIK (US); BRUECKNER ERIC (US); PARK SANG IL (US); KIM RAK HWAN (US)	US201 27-Mar-2017 715470 780A

US9130189B2	8-Sep-2015	Optoelectronic component and method for the production thereof	SCHLENKER TILMAN (DE); PAETZOLD RALPH (DE)	US201 414152 608A	10-Jan-2014
US8070546B2	6-Dec-2011	Laser irradiation apparatus for bonding and method of manufacturing display device using the same	JOO YOUNG CHEOL (KR); LEE KWAN HEE (KR); SONG SEUNG YONG (KR); CHOI YOUNG SEO (KR); JUNG SUN YOUNG (KR); KWON OH JUNE (KR)	US662 36310A	13-Apr-2010
US2010273279A1	28-Oct-2010	PRODUCTION LINE FOR THE PRODUCTION OF MULTIPLE SIZED PHOTOVOLTAIC DEVICES	SU TZAY FA (US); MORISHIGE DAVID (US)	US430 75509A	27-Apr-2009
US2010266955A1	21-Oct-2010	POSITIVE RESIST COMPOSITION AND METHOD OF FORMING RESIST PATTERN	UTSUMI YOSHIYUKI (JP); IRIE MAKIKO (JP)	US758 65010A	12-Apr-2010
US8642416B2	4-Feb-2014	Method of forming three dimensional integrated circuit devices using layer transfer technique	OR BACH ZVI (US); SEKAR DEEPAK (US); CRONQUIST BRIAN (US); WURMAN ZE EV (US)	US201 113635 436A	28-Jun-2011
US9219005B2	22-Dec-2015	Semiconductor system and device	OR BACH ZVI (US); SEKAR DEEPAK (US); CRONQUIST BRIAN (US); WURMAN ZE EV (US)	US201 213623 756A	20-Sep-2012
US8476145B2	2-Jul-2013	Method of fabricating a semiconductor device and structure	OR BACH ZVI (US); CRONQUIST BRIAN (US); BEINGLASS ISREAL (US); DE JONG JAN LODEWIJK (US); SEKAR DEEPAK C (US)	US904 11910A	13-Oct-2010
US9136153B2	15-Sep-2015	3D semiconductor device and structure with back-bias	OR BACH ZVI (US); SEKAR DEEPAK C (US); CRONQUIST BRIAN (US); BEINGLASS ISRAEL (US); WURMAN ZE EV (US); LIM PAUL (US)	US201 213492 395A	8-Jun-2012
US8987079B2	24-Mar-2015	Method for developing a custom device	OR BACH ZVI (US)	US201 213683 344A	21-Nov-2012
US9711407B2	18-Jul-2017	Method of manufacturing a three dimensional integrated circuit by transfer of a mono-crystalline layer	OR BACH ZVI (US); CRONQUIST BRIAN (US); BEINGLASS ISRAEL (US); DE JONG J L (US); SEKAR DEEPAK C (US); LIM PAUL (US)	US970 60210A	16-Dec-2010
US9309128B2	12-Apr-2016	Zinc oxide nanostructures and sensors using zinc oxide nanostructures	KENNEDY JOHN VEDAMUTHU (NZ); FUTTER RICHARD JOHN (NZ); FANG FANG (NZ); MARKWITZ ANDREAS (NZ)	US201 013264 225A	14-Apr-2010
US2010260977A1	14-Oct-2010	CHEMICAL MECHANICAL FABRICATION (CMF) FOR FORMING TILTED SURFACE FEATURES	SINGH RAJIV K (US); KUMAR PURUSHOTTAM (US); SINGH DEEPIKA (US); ARJUNAN ARUL CHAKKARAVARTHI (US)	US759 30710A	13-Apr-2010
US8313976B2	20-Nov-2012	Method and apparatus for controllable sodium delivery for thin film photovoltaic materials	MACKIE NEIL M (US); CORSON JOHN (US)	US201 113228 872A	9-Sep-2011
US2012064302A1	15-Mar-2012	PATTERNING METHOD	SHIMODA TATSUYA (JP); MATSUKI YASUO (JP); KAWAJIRI RYO (JP); MASUDA TAKASHI (JP); KANEDA TOSHIHIKO (JP)	US201 013263 805A	9-Apr-2010
US9536633B2	3-Jan-2017	Metallic composite and composition thereof	HIGASHIMURA HIDEYUKI (JP); IJIMA TAKAYUKI (JP); FUJIOKA MASAHIRO (JP); TANAKA KENTA (JP)	US201 013263 220A	6-Apr-2010

US2013284256A1	31-Oct-2013	LEAD-FREE CONDUCTIVE PASTE COMPOSITION AND SEMICONDUCTOR DEVICES MADE THEREWITH	LAUGHLIN BRIAN J (US); TORARDI CARMINE (US); VERNOOY PAUL DOUGLAS (US)	US201 24-Oct-2012 213659 314A
US8236599B2	7-Aug-2012	Solution-based process for making inorganic materials	CHANG CHIH HUNG (US); WANG WEI (US)	US798 9-Apr-2010 75510A
US2010258165A1	14-Oct-2010	GLASS COMPOSITIONS USED IN CONDUCTORS FOR PHOTOVOLTAIC CELLS	CARROLL ALAN FREDERICK (US); LAUGHLIN BRIAN J (US); HANG KENNETH WARREN (US); WANG YUELI (US)	US756 8-Apr-2010 41910A
US2010258184A1	14-Oct-2010	GLASS COMPOSITIONS USED IN CONDUCTORS FOR PHOTOVOLTAIC CELLS	LAUGHLIN BRIAN J (US); CARROLL ALAN FREDERICK (US); HANG KENNETH WARREN (US); WANG YUELI (US)	US756 8-Apr-2010 41610A
US8871640B2	28-Oct-2014	Method of manufacturing semiconductor chip	YONEHARA TAKAO (JP); SAKAGUCHI KIYOFUMI (JP); KAWASE NOBUO (JP); NAKAGAWA KENJI (JP)	US201 2-Apr-2010 013262 830A
US7855123B2	21-Dec-2010	Method of integrating an air gap structure with a substrate	LEE ERIC M (US); LIU JUNJUN (US); TOMA DOREL I (US)	US415 31-Mar-2009 02209A
US8173518B2	8-May-2012	Method of wafer bonding	LIU MARTIN (TW); HSU ALEX (TW); YU CHUNG YI (TW); TSAI CHIA SHIUNG (TW)	US414 31-Mar-2009 91009A
US8685856B2	1-Apr-2014	Solid-state imaging device, fabrication method thereof, imaging apparatus, and fabrication method of anti-reflection structure	MAEDA KENSAKU (JP); KOIKE KAORU (JP); SASAKI TOHRU (JP); TATSUMI TETSUYA (JP)	US728 22-Mar-2010 44810A
US9612615B2	4-Apr-2017	Integrated circuit chip using top post-passivation technology and bottom structure technology	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW); LO HSIN JUNG (TW); YANG PING JUNG (TW); LIU TE SHENG (TW)	US201 1-May-2013 313874 983A
US2012205817A1	16-Aug-2012	MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE	ASAMI HIROSHI (JP); HATANO MASAKI (JP); MORIMOTO AKIHIRO (JP)	US201 24-Apr-2012 213454 139A
US8916338B2	23-Dec-2014	Processes and compositions for removing substances from substrates	QUILLEN MICHAEL WAYNE (US); O DELL DALE EDWARD (US); LEE ZACHARY PHILIP (US); MOORE JOHN CLEAON (US); MCENTIRE EDWARD ENNS (US); HOCHSTETLER SPENCER ERICH (US); PETERS RICHARD DALTON (US); ARMENTROUT RODNEY SCOTT (US); MUCK DARRYL W (US)	US201 19-Nov-2013 314084 027A
US9117828B2	25-Aug-2015	Method of handling a thin wafer	WU WENG JIN (TW); YANG KU FENG (TW); CHIOU WEN CHIH (TW)	US717 4-Mar-2010 57310A
US8896127B2	25-Nov-2014	Via structure and via etching process of forming the same	CHANG HUNG PIN (TW); CHIOU WEN CHIH (TW); YU CHEN HUA (TW)	US201 8-Nov-2012 213671 711A
US9131610B2	8-Sep-2015	Buffer layer for sintering	YANIV ZVI (US); YANG MOHSHI (US); LAXTON PETER B (US)	US201 7-Nov-2013 314073 986A

US8450144B2	28-May-2013	Semiconductor device and method for manufacturing the same	SAKATA JUNICHIRO (JP); KISHIDA HIDEYUKI (JP); OHARA HIROKI (JP); SASAKI TOSHINARI (JP); YAMAZAKI SHUNPEI (JP)	US722 12-Mar-2010 79510A
US9583446B2	28-Feb-2017	Semiconductor device and method of forming a shielding layer between stacked semiconductor die	PAGAILA REZA A (ID); DO BYUNG TAI (SG); SUTHIWONGSUNTHORN NATHAPONG (SG)	US201 25-Nov-2014 414553 358A
US8905823B2	9-Dec-2014	Corrosion-resistant CMP conditioning tools and methods for making and using same	WU JIANHUI (US); HWANG TAEWOOK (US); VEDANTHAM RAMANUJAM (US); DINH NGOC CHARLES (US); PUTHANANGADY THOMAS K (US); SCHULZ ERIC M (US); RAMANATH SRINIVASAN (US)	US791 1-Jun-2010 39110A
US9524955B2	20-Dec-2016	Semiconductor device and method of forming no-flow underfill material around vertical interconnect structure	HUANG RUI (SG); KUAN HEAP HOE (SG); LIN YAOJIAN (SG); CHOW SENG GUAN (SG)	US201 19-Mar-2012 213423 782A
US9406619B2	2-Aug-2016	Semiconductor device including pre-fabricated shielding frame disposed over semiconductor die	PAGAILA REZA A (SG); DO BYUNG TAI (SG); MERILO DIOSCORO A (SG)	US201 13-Jan-2012 213350 692A
US2010240167A1	23-Sep-2010	Quantum confinement solar cell fabricated by atomic layer deposition	DASGUPTA NEIL (US); LEE WON YOUNG (US); HOLME TIMOTHY P (US); PRINZ FRIEDRICH B (US)	US661 23-Mar-2010 77810A
US8426256B2	23-Apr-2013	Method of forming stacked-die packages	HSIAO C W (TW); LEE BO I (TW); WANG TSUNG DING (TW); CHING KAI MING (TW); CHEN CHEN SHIEN (TW); LEE CHIEN HSIUN (TW); CHAO CLINTON (US)	US700 5-Feb-2010 92910A
US8268085B2	18-Sep-2012	Methods for forming metal gate transistors	YEH MATT (TW); LIN SHUN WU (TW); OUYANG HUI (TW)	US719 8-Mar-2010 53210A
US2010264566A1	21-Oct-2010	RAPID FABRICATION OF A MICROELECTRONIC TEMPORARY SUPPORT FOR INORGANIC SUBSTRATES	MOORE JOHN (US); HERMANOWSKI JAMES (US)	US725 16-Mar-2010 35110A
US9768281B2	19-Sep-2017	Method for manufacturing semiconductor device	OHARA HIROKI (JP); SASAKI TOSHINARI (JP)	US201 24-Mar-2015 514666 753A
US9209397B2	8-Dec-2015	Process for forming an electroactive layer	CHESTERFIELD REID JOHN (US); BUTLER JUSTIN (US); SANT PAUL ANTHONY (US)	US201 9-Mar-2010 013202 416A
US9263623B2	16-Feb-2016	Plasma spray deposition of photovoltaic thin films with grain boundary minimization	BARTHOLOMEUSZ BRIAN JOSEF (US); BARTHOLOMEUSZ MICHAEL (US)	US201 15-Dec-2014 414570 440A
US2015353373A1	10-Dec-2015	AIR STABLE ORGANIC-INORGANIC NANOPARTICLES HYBRID SOLAR CELLS	QIAN LEI (US); YANG JIHUA (US); XUE JIANGENG (US); HOLLOWAY PAUL H (US)	US201 18-Aug-2015 514828 890A
US11715801B2	1-Aug-2023	Semiconductor device and method for manufacturing the same	SAKATA JUNICHIRO (JP); HIROHASHI TAKUYA (JP); KISHIDA HIDEYUKI (JP)	US202 7-Mar-2022 217687 817A
US8376207B2	19-Feb-2013	Micro-fluidic injection molded solder (IMS)	BUCHWALTER STEPHEN L (US); GRUBER PETER A (US); LAURO PAUL A (US); NAH JAE WOONG (US)	US201 7-Feb-2012 213367 466A

US2024222464A1	4-Jul-2024	SEMICONDUCTOR DEVICE	KIMURA HAJIME (JP)	US202 418604 713A	14-Mar-2024
US8378462B2	19-Feb-2013	Semiconductor device having through substrate vias	MATSUMOTO SUSUMU (JP)	US201 113214 759A	22-Aug-2011
US9034570B2	19-May-2015	Methods of forming patterns	SILLS SCOTT E (US); SANDHU GURTEJ S (US); SMYTHE JOHN (US); ZHANG MING (US)	US201 414192 410A	27-Feb-2014
US2014363936A1	11-Dec-2014	THIN FILM TRANSISTOR, METHOD OF FABRICATING THE SAME, AND ORGANIC LIGHT EMITTING DIODE DISPLAY DEVICE INCLUDING THE SAME	PARK BYOUNG KEON (US); YANG TAE HOON (KR); SEO JIN WOOK (KR); LEE KI YONG (KR); LISACHENKO MAXIM (KR); CHOI BO KYUNG (KR); LEE DAE WOO (KR); LEE KIL WON (KR); LEE DONG HYUN (KR); PARK JONG RYUK (KR); AHN JI SU (KR); KIM YOUNG DAE (KR); NA HEUNG YEOL (KR); JEONG MIN JAE (KR); CHUNG YUN MO (KR); HONG JONG WON (KR); KANG EU GENE (KR); CHANG SEOK RAK (KR); JUNG JAE WAN (KR); YOON SANG YON (KR)	US201 414303 233A	12-Jun-2014
US9997638B2	12-Jun-2018	Semiconductor device and manufacturing method thereof	GODO HIROMICHI (JP); AKIMOTO KENGO (JP); YAMAZAKI SHUNPEI (JP)	US201 715598 683A	18-May-2017
US8362592B2	29-Jan-2013	Tiled substrates for deposition and epitaxial lift off processes	HE GANG (US); HEGEDUS ANDREAS (US)	US715 24310A	1-Mar-2010
US8841661B2	23-Sep-2014	Staggered oxide semiconductor TFT semiconductor device and manufacturing method thereof	AKIMOTO KENGO (JP); TSUBUKU MASASHI (JP)	US700 75810A	5-Feb-2010
US8822266B2	2-Sep-2014	Integrated circuit micro-module	SMEYS PETER (US); JOHNSON PETER (US); DEANE PETER (US); RAZOUK REDA R (US)	US201 113013 563A	25-Jan-2011
US8252686B2	28-Aug-2012	Method for forming copper wiring in a semiconductor device	PARK HYUNG SOON (KR); KWAK NOH JUNG (KR); YEOM SEUNG JIN (KR); RYU CHOON KUN (KR); JUNG JONG GOO (KR); KIM SUNG JUN (KR)	US427 87009A	22-Apr-2009
US2010248419A1	30-Sep-2010	SOLAR CELL ABSORBER LAYER FORMED FROM EQUILIBRIUM PRECURSOR(S)	WOODRUFF JACOB (US); VAN DUREN JEROEN K J (US); ROBINSON MATTHEW R (US); SAGER BRIAN M (US)	US706 70910A	16-Feb-2010
US8350261B2	8-Jan-2013	Semiconductor device including a transistor, and manufacturing method of the semiconductor device	SAKATA JUNICHIRO (JP); GODO HIROMICHI (JP); SHIMAZU TAKASHI (JP)	US699 97610A	4-Feb-2010
US10074555B2	11-Sep-2018	Non-contact substrate processing	KOELMEL BLAKE (US); MYO NYI O (US)	US201 313786 189A	5-Mar-2013
US8084186B2	27-Dec-2011	Hardmask process for forming a reverse tone image using polysilazane	ABDALLAH DAVID (US); DAMMEL RALPH R (US); TAKANO YUSUKE (JP); LI JIN (JP); KUROSAWA KAZUNORI (JP)	US368 72009A	10-Feb-2009

US9726977B2	8-Aug-2017	Coating compositions suitable for use with an overcoated photoresist	CAMERON JAMES F (US); SUNG JIN WUK (US); AMARA JOHN P (US); PROKOPOWICZ GREGORY P (US); VALERI DAVID A (US); VYKICKY LIBOR (US); HUANG WU SONG S (US); LI WENJIE (US); VARANASI PUSHKARA R (US); POPOVA IRENE Y (US)	US658 8-Feb-2010 61510A
US10539873B2	21-Jan-2020	Coating compositions suitable for use with an overcoated photoresist	CAMERON JAMES F (US); SUNG JIN WUK (US); AMARA JOHN P (US); PROKOPOWICZ GREGORY P (US); VALERI DAVID A (US)	US201 26-Jan-2015 514605 465A
US2016343740A1	24-Nov-2016	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SEMICONDUCTOR DEVICE	OIKAWA YOSHIKI (JP); MARUYAMA HOTAKA (JP); GODO HIROMICHI (JP); KAWAE DAISUKE (JP); YAMAZAKI SHUNPEI (JP)	US201 4-Aug-2016 615228 457A
US2016305025A1	20-Oct-2016	GROUND RETURN FOR PLASMA PROCESSES	CHOI SOO YOUNG (US); TINEER ROBIN L (US); KURITA SHINICHI (US); WHITE JOHN M (US); SORENSEN CARL A (US); KHO JEFFREY A (US); ANWAR SUHAIL (US); INAGAWA MAKOTO (US); FURUTA GAKU (US)	US201 29-Jun-2016 615196 751A
US8704375B2	22-Apr-2014	Barrier structures and methods for through substrate vias	LIU MAX (TW); HSU CHAO SHUN (TW); TSENG YA WEN (TW); CHIOU WEN CHIH (TW); WU WENG JIN (TW)	US613 5-Nov-2009 41709A
US9178072B2	3-Nov-2015	Thin film transistor and display device	MOROSAWA NARIHIRO (JP); FUJIMORI TAKASHIGE (JP)	US201 31-Oct-2012 213665 487A
US7977235B2	12-Jul-2011	Method for manufacturing a semiconductor device with metal-containing cap layers	ISHIZAKA TADAHIRO (US)	US363 2-Feb-2009 86809A
US2010193969A1	5-Aug-2010	DICING TAPE-INTEGRATED WAFER BACK SURFACE PROTECTIVE FILM	TAKAMOTO NAOHIDE (JP)	US696 29-Jan-2010 17410A
US8841780B2	23-Sep-2014	Dicing tape-integrated wafer back surface protective film	TAKAMOTO NAOHIDE (JP); MATSUMURA TAKESHI (JP)	US201 3-Dec-2013 314095 164A
US8685846B2	1-Apr-2014	Technique for processing a substrate	LOW RUSSELL J (US); WEAVER WILLIAM T (US); BATEMAN NICHOLAS P T (US); GUPTA ATUL (US)	US695 28-Jan-2010 72910A
US9892947B2	13-Feb-2018	Sensor system for semiconductor manufacturing apparatus	SCHAUER RONALD VERN (US); DASCOLI RAPHAEL (FR); BHARGAVA SHIVAN (FR)	US201 12-Jan-2016 614993 596A
US8901207B2	2-Dec-2014	Adhesive for electronic components	HAYAKAWA AKINOBU (JP); ISHIZAWA HIDEAKI (JP); TAKEDA KOHEI (JP); MASUI RYOHEI (JP)	US201 29-Jan-2010 013146 571A
US2011281025A1	17-Nov-2011	CURABLE COMPOSITION FOR TRANSFER MATERIALS, AND (METH) ACRYLOYL GROUP-CONTAINING UREA COMPOUND	ARAI YOSHIKAZU (JP); UCHIDA HIROSHI (JP)	US201 26-Jan-2010 013146 538A
US9162341B2	20-Oct-2015	Chemical-mechanical planarization pad including patterned structural domains	LEFEVRE PAUL (US); MATHEW ANOOP (US); QIAO SCOTT XIN (US); WU GUANGWEI (US); WELLS DAVID ADAM (US); HSU OSCAR K (US)	US201 6-May-2013 313887 805A

US8518820B2	27-Aug-2013	Methods for forming contacts in semiconductor devices	SCHIWON ROBERTO (US); HEROLD KLAUS (US); LIAN JENNY (US); MAROKKEY SAJAN (US); OSTERMAYR MARTIN (US)	US201 113301 196A	21-Nov-2011
US8836130B2	16-Sep-2014	Light emitting semiconductor element bonded to a base by a silver coating	KURAMOTO MASAFUMI (JP); OGAWA SATORU (JP); KUNIMUNE TEPPEI (JP)	US201 113333 569A	21-Dec-2011
US8927341B2	6-Jan-2015	Semiconductor device and production method therefor	KURAMOTO MASAFUMI (JP); OGAWA SATORU (JP); NIWA MIKI (JP)	US201 414166 540A	28-Jan-2014
US8325457B2	4-Dec-2012	Electrostatic chuck and device of manufacturing organic light emitting diode having the same	PARK SANG YOUNG (KR); MUN JU EEL (KR); CHA YOU MIN (KR); JUNG WON WOONG (KR)	US585 89509A	28-Sep-2009
US8791574B2	29-Jul-2014	Semiconductor device and manufacturing method of the same	AKIBA TOSHIHIKO (JP); KIMURA MINORU (JP); ODAGIRI MASAO (JP)	US201 213613 031A	13-Sep-2012
US7824948B2	2-Nov-2010	Method and structure for reducing cross-talk in image sensor devices	WANG CHING CHUN (TW); HSU TZU HSUAN (TW); LIU HAN CHI (TW); SU CHUN MING (TW)	US357 22309A	21-Jan-2009
US2010183851A1	22-Jul-2010	Photoresist Image-forming Process Using Double Patterning	CAO YI (US); THIYAGARAJAN MUTHIAH (US); HONG SUNGEUN (US); LEE DONGKWAN (US); LI MENG (US); MIKRUT DAVID (US)	US356 56809A	21-Jan-2009
US7989325B2	2-Aug-2011	Method for manufacturing crystalline semiconductor film and method for manufacturing thin film transistor	YOKOI TOMOKAZU (JP); TAJIMA RYOTA (JP)	US646 37309A	23-Dec-2009
US11600551B2	7-Mar-2023	Through-silicon via with low-K dielectric liner	CHEN MING FA (TW)	US202 016921 561A	6-Jul-2020
US8361704B2	29-Jan-2013	Method for reducing tip-to-tip spacing between lines	COLBURN MATTHEW E (US); LI WAI KIN (US); YANG HAINING S (US)	US352 05109A	12-Jan-2009
US8673682B2	18-Mar-2014	High order silane composition and method of manufacturing a film-coated substrate	SHIMODA TATSUYA (JP); MATSUKI YASUO (JP); MASUDA TAKASHI (JP)	US201 013143 854A	7-Jan-2010
US2011278772A1	17-Nov-2011	PHOTO-CURABLE TRANSFER SHEET AND METHOD FOR FORMING CONCAVE-CONVEX PATTERN USING THE SAME	INAMIYA TAKATO (JP); HASHIMOTO MASASHI (JP); KAIDA EIZOU (JP)	US201 013143 865A	8-Jan-2010
US10361258B2	23-Jul-2019	Light emitting device and electronic device	YAMAZAKI SHUNPEI (JP); KATAYAMA MASAHIRO (JP); EGUCHI SHINGO (JP); OIKAWA YOSHIKI (JP); NAKAMURA AMI (JP); SEO SATOSHI (JP); HATANO KAORU (JP)	US201 815927 436A	21-Mar-2018
US2013008380A1	10-Jan-2013	APPARATUS FOR FABRICATING IB-IIIA-VIA2 COMPOUND SEMICONDUCTOR THIN FILMS	CHUANG CHIA CHIH (TW); HUANG YU (TW)	US201 213610 798A	11-Sep-2012
US9796063B2	24-Oct-2017	Multi-layered chemical-mechanical planarization pad	LEFEVRE PAUL (US); MATHEW ANOOP (US); WU GUANGWEI (US); QIAO SCOTT XIN (US); HSU OSCAR K (US); WELLS DAVID ADAM (US); ALDEBORGH JOHN ERIK (US); JIN MARC C (US)	US201 414318 894A	30-Jun-2014

US8860197B2	14-Oct-2014	Integrated circuits secure from invasion and methods of manufacturing the same	CLARK LAWRENCE T (US); ALLEE DAVID R (US)	US200 29-Dec-2009 913139 955A
US8697577B2	15-Apr-2014	Method and composition for chemical mechanical planarization of a metal or a metal alloy	SHI XIAOBO (US); PALMER BENTLEY J (US); SAWAYDA REBECCA A (US)	US201 30-Jul-2012 213561 398A
US7846756B2	7-Dec-2010	Nanoimprint enhanced resist spacer patterning method	YEN BING K (US); WANG CHUN MING (US); CHEN YUNG TIN (US); MAXWELL STEVEN (US)	US318 31-Dec-2008 59008A
US9274427B2	1-Mar-2016	Compositions and processes for photolithography	WANG DEYAN (US); WU CHUNYI (US)	US201 10-Jun-2014 414301 177A
US8702202B2	22-Apr-2014	Apparatus and method for preventing splatter for continuous printing	TREMEL JAMES DANIEL (US); STAINER MATTHEW (US); HUBERT MATTHEW DEWEY (US)	US647 28-Dec-2009 81809A
US8461699B2	11-Jun-2013	Positive-type photosensitive resin composition, method for producing resist pattern, semiconductor device, and electronic device	MATSUTANI HIROSHI (JP); UENO TAKUMI (JP); NICOLAS ALEXANDRE (JP); YAMASHITA YUKIHIKO (JP); NANAUMI KEN (JP); TANIMOTO AKITOSHI (JP)	US200 16-Dec-2009 913142 057A
US2011262697A1	27-Oct-2011	FLEXIBLE SUBSTRATE AND ELECTRONIC DEVICE	KATSURAYAMA SATORU (JP); MAEJIMA KENZOU (JP); FUJII TOMOE (JP)	US200 22-Dec-2009 913142 056A
US2025159939A1	15-May-2025	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	YAMAZAKI SHUNPEI (JP); SAKATA JUNICHIRO (JP); KOYAMA JUN (JP)	US202 14-Jan-2025 519020 084A
US8592540B2	26-Nov-2013	Fluorine-containing compound, fluorine-containing polymer compound, resist composition and patterning method using same	MORI KAZUNORI (JP); HAGIWARA YUJI (JP); ISONO YOSHIMI (JP); NARIZUKA SATORU (JP); MAEDA KAZUHIKO (JP)	US200 15-Dec-2009 913141 945A
US2012153508A1	21-Jun-2012	THERMOSETTING DIE-BONDING FILM	HAYASHI MIKI (JP); TAKAMOTO NAOHIDE (JP); OONISHI KENJI (JP)	US200 22-Dec-2009 913141 765A
US9070399B2	30-Jun-2015	Polishing liquid composition for magnetic-disk substrate	HAMAGUCHI TAKESHI (JP); DOI HARUHIKO (JP)	US200 18-Dec-2009 913133 736A
US8710355B2	29-Apr-2014	Compositions and processes for forming photovoltaic devices	BORLAND WILLIAM J (US); GLICKSMAN HOWARD DAVID (US); MARIA JON PAUL (US)	US617 13-Nov-2009 92909A
US10439050B2	8-Oct-2019	Method for manufacturing transistor	SAKATA JUNICHIRO (JP)	US201 17-Mar-2017 715461 767A
US8394703B2	12-Mar-2013	Manufacturing method of SOI substrate and manufacturing method of semiconductor device	OHNUMA HIDETO (JP); MOMO JUNPEI (JP); YAMAZAKI SHUNPEI (JP)	US634 9-Dec-2009 10709A
US9847324B2	19-Dec-2017	Semiconductor device and method of forming a vertical interconnect structure for 3-D FO-WLCSP	LIN YAOJIAN (SG); CHEN KANG (SG)	US201 3-Jun-2015 514730 030A

US8871119B2	28-Oct-2014	Composite oxide sintered body and sputtering target comprising same	YANO KOKI (JP); KAWASHIMA HIROKAZU (JP)	US201 213729 535A	28-Dec-2012
US2010148229A1	17-Jun-2010	INSULATING RESIN COMPOSITION	JEONG EUN JEONG (KR); SEON JONG BAEK (KR)	US511 41109A	29-Jul-2009
US2010147369A1	17-Jun-2010	SOLAR CELL HAVING NANODIAMOND QUANTUM WELLS	SUNG CHIEN MIN (TW)	US619 48709A	16-Nov-2009
US9478486B2	25-Oct-2016	Semiconductor device and method of forming topside and bottom-side interconnect structures around core die with TSV	KIM SUN MI (KR); KIM OHHAN (KR); LEE KYUNGHOON (KR)	US201 414267 777A	1-May-2014
US8124457B2	28-Feb-2012	Manufacturing method of transferring a wiring circuit layer on a metal support substrate to a semiconductor element	ODA TAKASHI (JP); MORITA SHIGENORI (JP); YOSHIDA NAKO (JP)	US634 35009A	9-Dec-2009
US2013295334A1	7-Nov-2013	Method for Removal of Carbon from an Organosilicate Material	WU AIPING (US); WEIGEL SCOTT JEFFREY (US); BRAYMER THOMAS ALBERT (US)	US201 313936 557A	8-Jul-2013
US8530583B2	10-Sep-2013	Thermo- and/or photo-sensitive material and insulator film made thereof	WADA KENJI (JP); WATANABE KATSUYUKI (JP); YAMAMOTO KEIJI (JP)	US200 913133 827A	10-Nov-2009
US9029193B2	12-May-2015	Semiconductor device and method of forming an interconnect structure for 3-D devices using encapsulant for structural support	MARIMUTHU PANDI CHELVAM (SG); SUTHIWONGSUNTHORN NATHAPONG (SG); HENG KOCK LIANG (SG)	US775 17010A	6-May-2010
US2010144096A1	10-Jun-2010	METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE IN WHICH BOTTOM SURFACE AND SIDE SURFACE OF SEMICONDUCTOR SUBSTRATE ARE COVERED WITH RESIN PROTECTIVE FILM	KOROKU TAISUKE (JP); OKADA OSAMU (JP); KUWABARA OSAMU (JP); SHIOTA JUNJI (JP); FUJII NOBUMITSU (JP)	US632 03309A	7-Dec-2009
US10192801B2	29-Jan-2019	Semiconductor device and method of forming vertical interconnect structure in substrate for IPD and baseband circuit separated by high-resistivity molding compound	LIN YAOJIAN (SG); FANG JIANMIN (SG); CHEN KANG (SG); CAO HAIJING (SG)	US201 213424 484A	20-Mar-2012
US9515016B2	6-Dec-2016	Semiconductor package and method of forming z-direction conductive posts embedded in structurally protective encapsulant	HUANG RUI (SG); SHIM IL KWON (SG); CHOW SENG GUAN (SG); KUAN HEAP HOE (SG)	US201 213682 281A	20-Nov-2012
US8637396B2	28-Jan-2014	Dielectric barrier deposition using oxygen containing precursor	MATZ LAURA M (US); VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); SINATORE DINO (US)	US623 99809A	23-Nov-2009
US8710491B2	29-Apr-2014	Forming agent for gate insulating film of thin film transistor	MAEDA SHINICHI (JP); KISHIOKA TAKAHIRO (JP)	US200 913131 807A	26-Nov-2009
US9722054B2	1-Aug-2017	Semiconductor device and method for manufacturing the same	AKIMOTO KENGO (JP); SASAKI TOSHINARI (JP); KUWABARA HIDEAKI (JP)	US201 314043 925A	2-Oct-2013
US10221496B2	5-Mar-2019	Copper filling of through silicon vias	RICHARDSON THOMAS B (US); SHAO WENBO (US); LIN XUAN (US); WANG CAI (US); PANECCASIO JR VINCENT (US); ABYS JOSEPH A (US); ZHANG YUN (US); HURTUBISE RICHARD (US); WANG CHEN (US)	US201 113699 910A	24-May-2011

US2010129986A1	27-May-2010	DICING DIE-BONDING FILM AND PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE	KAMIYA KATSUHIKO (JP); OOTAKE HIRONAO (JP); MATSUMURA TAKESHI (JP); MURATA SHUUHEI (JP)	US625 25-Nov-2009 68009A
US8871646B2	28-Oct-2014	Methods of forming a masking pattern for integrated circuits	DEVILLIERS ANTON (US)	US201 22-Jul-2013 313947 792A
US2015137322A1	21-May-2015	Semiconductor Device and Method of Forming WLCSP Using Wafer Sections Containing Multiple Die	PAGAILA REZA A (ID); LIN YAOJIAN (SG)	US201 10-Dec-2014 414565 731A
US9023711B2	5-May-2015	Methods for forming a conductive material and methods for forming a conductive structure	MARSH EUGENE P (US)	US201 14-May-2014 414277 507A
US8506867B2	13-Aug-2013	Printing semiconductor elements by shear-assisted elastomeric stamp transfer	MENARD ETIENNE (US)	US621 19-Nov-2009 80409A
US9204839B2	8-Dec-2015	Miniaturized implantable sensor platform having multiple devices and sub-chips	JAIN FAQUIR (US); PAPADIMITRAKOPOULOS FOTIOS (US)	US201 18-Aug-2014 414462 192A
US8389987B2	5-Mar-2013	Switching element and method for fabricating same	TOGUCHI SATORU (JP); ENDOH HIROYUKI (JP)	US200 9-Nov-2009 913127 761A
US12324189B2	3-Jun-2025	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP); AKIMOTO KENGO (JP); KAWAE DAISUKE (JP)	US202 24-Jan-2022 217582 038A
US8117983B2	21-Feb-2012	Directional extruded bead control	FORK DAVID K (US); SOLBERG SCOTT E (US)	US267 7-Nov-2008 06908A
US2010112807A1	6-May-2010	METHOD OF FORMING METAL WIRING OF SEMICONDUCTOR DEVICE	KIM SANG CHUL (KR)	US608 29-Oct-2009 05209A
US2010108096A1	6-May-2010	Liquid processing method and apparatus	MINAMI TERUOMI (JP); YABUTA TAKASHI (JP); KOSAI KAZUKI (JP)	US320 28-Jan-2009 53609A
US2013049225A1	28-Feb-2013	STACKED INTEGRATED CIRCUIT PACKAGES THAT INCLUDE MONOLITHIC CONDUCTIVE VIAS	KANG PIL KYU (KR); KIM JUNG HO (KR); LEE JONG WOOK (KR); CHOI SEUNG WOO (KR); BAE DAE LOK (KR)	US201 25-Oct-2012 213660 177A
US8080443B2	20-Dec-2011	Method of making pillars using photoresist spacer mask	CHEN YUNG TIN (US); WANG CHUN MING (US); RADIGAN STEVEN J (US)	US289 27-Oct-2008 39608A
US10770670B2	8-Sep-2020	Inverted organic photosensitive devices	FORREST STEPHEN R (US); BAILEY SALZMAN RHONDA F (US)	US201 24-Oct-2016 615332 062A
US12477781B2	18-Nov-2025	Semiconductor device and method for manufacturing the same	MIYAIRI HIDEKAZU (JP); OSADA TAKESHI (JP); YAMAZAKI SHUNPEI (JP)	US202 7-Jun-2024 418736 777A

US8772921B2	8-Jul-2014	Interposer for semiconductor package	TOH CHIN HOCK (SG); HUANG YAO HUANG (SG); KOLAN RAVI KANTH (SG); YUAN WEI LIANG (SG); TANARY SUSANTO (SG); SUN YI SHENG ANTHONY (SG)	US201 213347 683A	10-Jan-2012
US10211240B2	19-Feb-2019	Method for manufacturing semiconductor device	SUZAWA HIDEOMI (JP); SASAGAWA SHINYA (JP); MURAOKA TAIGA (JP)	US201 715837 552A	11-Dec-2017
US8324712B2	4-Dec-2012	Metal capacitor and method of making the same including dielectric layer of different mechanical strength regions	YANG CHIN SHENG (TW)	US201 213342 106A	1-Jan-2012
US2010096569A1	22-Apr-2010	ULTRAVIOLET-TRANSMITTING MICROWAVE REFLECTOR COMPRISING A MICROMESH SCREEN	NGUYEN TUAN ANH (US); YANG YAO HUNG (US); BALUJA SANJEEV (US); NOWAK THOMAS (US); ROCHA ALVAREZ JUAN CARLOS (US)	US255 57808A	21-Oct-2008
US2010096110A1	22-Apr-2010	METHODS AND APPARATUS FOR RECOVERING HEAT FROM PROCESSING SYSTEMS	NEUBER ANDREAS (DE); CLARK DANIEL O (US)	US579 47209A	15-Oct-2009
US8436479B2	7-May-2013	Semiconductor device having a chip bonding using a resin adhesive film and method of manufacturing the same	SASAKI AKITSUGU (JP)	US200 913122 034A	16-Jul-2009
US2014035115A1	6-Feb-2014	SEMICONDUCTOR DEVICE	ZENBUTSU SHIN ICHI (JP); ITOH SHINGO (JP)	US201 314043 877A	2-Oct-2013
US2014186521A1	3-Jul-2014	NICKEL-GOLD PLATEABLE THICK FILM SILVER PASTE, AND PLATING PROCESS FOR LOW TEMPERATURE CO FIRED CERAMIC DEVICES AND LTCC DEVICES MADE THEREFROM	NAIR KUMARAN MANIKANTAN (US); SKURSKI MICHAEL A (US); VOULTOS JOHN D (US)	US201 314100 195A	9-Dec-2013
US2010080989A1	1-Apr-2010	PRESSURE-SENSITIVE ADHESIVE SHEET FOR LASER PROCESSING AND METHOD FOR LASER PROCESSING	ASAI FUMITERU (JP); TAKAHASHI TOMOKAZU (JP); MAEKAWA KEIKO (JP); AOYAGI KAZUHIRO (JP)	US571 61809A	1-Oct-2009
US8617929B2	31-Dec-2013	On-Chip RF shields with front side redistribution lines	BARTH HANS JOACHIM (DE); MEYER THORSTEN (DE); BRUNNBAUER MARKUS (DE); SNEZANA JENEI (DE)	US201 213456 331A	26-Apr-2012
US2010081274A1	1-Apr-2010	METHOD FOR FORMING RUTHENIUM METAL CAP LAYERS	ISHIZAKA TADAHIRO (US); MIZUNO SHIGERU (US); CERIO JR FRANK M (US)	US240 89408A	29-Sep-2008
US2011233820A1	29-Sep-2011	MOLD FOR NANOIMPRINT	WATANABE JUNJI (JP); NISHIMURA SUZUSHI (JP); SEKI TAKASHI (JP); HIRAI TOMOO (JP)	US200 913120 720A	24-Sep-2009
US8598690B2	3-Dec-2013	Semiconductor device having conductive vias in peripheral region connecting shielding layer to ground	CHANDRA HARRY (US); CARSON FLYNN (US)	US201 213360 549A	27-Jan-2012
US2010072542A1	25-Mar-2010	SEMICONDUCTOR DEVICE, METHOD FOR MANUFACTURING THE SAME, AND DATA PROCESSING SYSTEM	KADOYA TOMOHIRO (JP); SHIMAMOTO KAZUMA (JP)	US585 36109A	14-Sep-2009
US8252687B2	28-Aug-2012	Barrier slurry for low-k dielectrics	LI SHOUTIAN (US); GRUMBINE STEVEN (US); DYSARD JEFFREY (US); SINGH PANKAJ (US)	US584 34309A	3-Sep-2009

US8158335B2	17-Apr-2012	High etch resistant material for double patterning	YEH HSIAO WEI (TW); CHANG CHING YU (TW); CHEN JIAN HONG (TW); LIN CHIH AN (TW)	US210 73708A	15-Sep-2008
US8409990B2	2-Apr-2013	Chemical-mechanical polishing compositions and methods of making and using the same	KRAFT BRADLEY M (US)	US673 83409A	25-Aug-2009
US2011061812A1	17-Mar-2011	Apparatus and Methods for Cyclical Oxidation and Etching	GANGULY UDAYAN (US); YOKOTA YOSHITAKA (US); OLSEN CHRISTOPHER S (US); SCOTNEY CASTLE MATTHEW D (US); NGUYEN VICKY (US); SRINIVASAN SWAMINATHAN (US); LIU WEI (US); SWENBERG JOHANES F (US); MARIN JOSE A (US); BALAKRISHNA AIJIT (US); NEWMAN JACOB (US); HICKERSON STEPHEN C (US)	US720 92610A	10-Mar-2010
US8698049B2	15-Apr-2014	Rapid thermal processing lamphead with improved cooling	RANISH JOSEPH M (US); SORABJI KHURSHED (US); SANGAM KEDARNATH (US); LERNER ALEXANDER (US)	US201 213657 935A	23-Oct-2012
US8293626B2	23-Oct-2012	Method for manufacturing semiconductor device	OHNUMA HIDETO (JP); OKUNO NAOKI (JP)	US552 49309A	2-Sep-2009
US9269598B2	23-Feb-2016	Semiconductor device and method of forming an IPD over a high-resistivity encapsulant separated from other IPDS and baseband circuit	LIN YAOJIAN (SG); FANG JIANMIN (SG); CHEN KANG (SG); CAO HAIJING (SG)	US201 213569 105A	7-Aug-2012
US2015053860A1	26-Feb-2015	MANUFACTURING NANOWIRE PHOTO-DETECTOR GROWN ON A BACK-SIDE ILLUMINATED IMAGE SENSOR	DUANE PETER (US); YU YOUNG JUNE (US); WOBER MUNIB (US)	US201 414501 983A	30-Sep-2014
US2024162351A1	16-May-2024	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP); AKIMOTO KENGO (JP)	US202 318509 825A	15-Nov-2023
US2010304092A1	2-Dec-2010	METHOD OF MANUFACTURING DICING DIE-BONDING FILM	AMANO YASUHIRO (JP); MATSUMURA TAKESHI (JP); INOUE KOUICHI (JP)	US744 11309A	12-Aug-2009
US8900953B2	2-Dec-2014	Crystal manufacturing apparatus, semiconductor device manufactured using the same, and method of manufacturing semiconductor device using the same	HIGASHI SEIICHIRO (JP); KOBAYASHI NAOTO (JP)	US200 913061 221A	28-Aug-2009
US8372756B2	12-Feb-2013	Selective etching of silicon dioxide compositions	MITCHELL GLENN MICHAEL (US); MOTIKA STEPHEN ANDREW (US); JOHNSON ANDREW DAVID (US)	US504 06409A	16-Jul-2009
US9023137B2	5-May-2015	Electroless deposition of platinum on copper	KONG BOB (US); IVANOV IGOR (US); SUN ZHI WEN (US); TONG JINHONG (US)	US201 314013 760A	29-Aug-2013
US2011143095A1	16-Jun-2011	MICROFINE STRUCTURE AND PROCESS FOR PRODUCING SAME	TADA YASUHIKO (JP); YOSHIDA HIROSHI (JP)	US200 913059 751A	12-Aug-2009

US2011159238A1	30-Jun-2011	PHOTOSENSITIVE ADHESIVE COMPOSITION, PHOTOSENSITIVE FILM ADHESIVE, ADHESIVE PATTERN, SEMICONDUCTOR WAFER WITH ADHESIVE, SEMICONDUCTOR DEVICE AND ELECTRONIC COMPONENT	KAWAMORI TAKASHI (JP); MITSUKURA KAZUYUKI (JP); MASUKO TAKASHI (JP); KATO GI SHIGEKI (JP)	US200 26-Aug-2009 913060 679A
US2021020784A1	21-Jan-2021	SEMICONDUCTOR FILM COMPRISING AN OXIDE CONTAINING IN ATOMS, Sn ATOMS AND Zn ATOMS	YANO KOKI (JP); KAWASHIMA HIROKAZU (JP); INOUE KAZUYOSHI (JP)	US202 24-Sep-2020 017030 618A
US8962448B2	24-Feb-2015	Computer readable medium encoded with a program for fabricating 3D integrated circuit device using interface wafer as permanent carrier	FAROOQ MUKTA G (US); HANNON ROBERT (US); IYER SUBRAMANIAN S (US); KOESTER STEVEN J (US); LIU FEI (US); PURUSHOTHAMAN SAMPATH (US); YOUNG ALBERT M (US); YU ROY R (US)	US201 10-Aug-2012 213572 004A
US8283260B2	9-Oct-2012	Process for restoring dielectric properties	WEIGEL SCOTT JEFFREY (US); O NEILL MARK LEONARD (US); HAAS MARY KATHRYN (US); MATZ LAURA M (US); MITCHELL GLENN MICHAEL (US); WU AIPING (US); VRTIS RAYMOND NICHOLAS (US); LANGAN JOHN GILES (US)	US540 13-Aug-2009 39509A
US8110342B2	7-Feb-2012	Method for forming an opening	LIU FENG (SG); BAI SHI JIE (SG); MA HONG (SG); NG CHUN PENG (SG); WANG YE (SG)	US193 18-Aug-2008 05208A
US7928433B2	19-Apr-2011	Electronic device comprising semiconducting polymers	LI YUNING (CA)	US193 18-Aug-2008 18908A
US2010041862A1	18-Feb-2010	ELECTRONIC DEVICE COMPRISING SEMICONDUCTING POLYMERS	LI YUNING (CA)	US193 18-Aug-2008 16408A
US7928181B2	19-Apr-2011	Semiconducting polymers	LI YUNING (CA)	US193 18-Aug-2008 15208A
US2010040838A1	18-Feb-2010	Hardmask Process for Forming a Reverse Tone Image	ABDALLAH DAVID J (US); DAMMEL RALPH R (US); NEISSER MARK (US)	US192 15-Aug-2008 62108A
US8772074B2	8-Jul-2014	Organic light emitting display and manufacturing method of the same	PARK JAEHEE (KR); YANG HEESEOK (KR); CHOI HOWON (KR)	US461 12-Aug-2009 47609A
US8129745B2	6-Mar-2012	Method of manufacturing an instant pulse filter using anodic oxidation and instant pulse filter manufactured by said method	MOON HAK BEOM (KR); CHO JIN HYUNG (KR); BANG SUC HYUN (KR); KIM CHEOL HWAN (KR); JANG YOON HYUNG (KR)	US200 3-Apr-2009 913057 493A
US9028242B2	12-May-2015	Template and method of making high aspect ratio template for lithography and use of the template for perforating a substrate at nanoscale	MUHAMMAD AMIN SALEEM (SE); BRUD DAVID (SE); BERG JONAS (SE); KABIR MOHAMMAD SHAFIQU L (SE); DESMARIS VINCENT (SE)	US200 23-Jul-2009 913057 508A
US8835909B2	16-Sep-2014	Hybrid dielectric material for thin film transistors	HAN LIN (US); MANDLIK PRASHANT (US); WAGNER SIGURD (US)	US200 30-Jul-2009 913056 704A
US8804360B2	12-Aug-2014	System-in packages	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW)	US201 3-Jul-2013 313935 135A

USRE50741E	6-Jan-2026	Semiconductor module and portable apparatus provided with semiconductor module	KOBAYASHI HAJIME (JP); NAKASATO MAYUMI (JP); USUI RYOSUKE (JP); YANASE YASUYUKI (JP); SAITO KOICHI (JP)	US200 29-Jul-2009 917954 718A
US2024371985A1	7-Nov-2024	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME	YAMAZAKI SHUNPEI (JP); MIYAIRI HIDEKAZU (JP); AKIMOTO KENGO (JP); SHIRAISHI KOJIRO (JP)	US202 18-Jul-2024 418776 570A
US10326025B2	18-Jun-2019	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP); MIYAIRI HIDEKAZU (JP); AKIMOTO KENGO (JP); SHIRAISHI KOJIRO (JP)	US201 11-Dec-2014 414567 309A
US2024145599A1	2-May-2024	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	YAMAZAKI SHUNPEI (JP); MIYAIRI HIDEKAZU (JP); MIYANAGA AKIHARU (JP); AKIMOTO KENGO (JP); SHIRAISHI KOJIRO (JP)	US202 9-Jan-2024 418407 630A
US9859441B2	2-Jan-2018	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); MIYAIRI HIDEKAZU (JP); AKIMOTO KENGO (JP); SHIRAISHI KOJIRO (JP)	US201 5-Aug-2016 615229 363A
US8597540B2	3-Dec-2013	Compositions for polishing silicon-containing substrates	DE REGE THESAURO FRANCESCO (US); CHEN ZHAN (US)	US201 20-Jul-2012 213554 829A
US2010022091A1	28-Jan-2010	METHOD FOR PLASMA ETCHING POROUS LOW-K DIELECTRIC LAYERS	LI SIYI (US); ZHOU QINGJUN (US); PATZ RYAN (US); ZHOU YIFENG (US); PENDER JEREMIAH (US); ARMACOST MICHAEL D (US)	US180 25-Jul-2008 36708A
US2010022078A1	28-Jan-2010	Aluminum Inks and Methods of Making the Same, Methods for Depositing Aluminum Inks, and Films Formed by Printing and/or Depositing an Aluminum Ink	ROCKENBERGER JOERG (US); ZUERCHER FABIO (US); GUO WENZHUO (US)	US509 24-Jul-2009 35109A
US7863750B2	4-Jan-2011	Semiconductor device capable of suppressing warping in a wafer state and manufacturing method thereof	SHIOTA JUNJI (JP); KOROKU TAISUKE (JP); FUJII NOBUMITSU (JP); KUWABARA OSAMU (JP); OKADA OSAMU (JP)	US507 22-Jul-2009 18809A
US7927976B2	19-Apr-2011	Reinforced composite stamp for dry transfer printing of semiconductor elements	MENARD ETIENNE (US)	US177 23-Jul-2008 96308A
US7579232B1	25-Aug-2009	Method of making a nonvolatile memory device including forming a pillar shaped semiconductor device and a shadow mask	PING ER XUAN (US); THAKUR RANDHIR (US); SCHEUGRAF KLAUS (US)	US216 11-Jul-2008 92408A
US2010007021A1	14-Jan-2010	Methods of Fabricating Semiconductor Devices Including Porous Insulating Layers	CHOO JAE OUK (KR); YOON IL YOUNG (KR); LEE TAE HOON (KR); LEE KYOUNG WOO (KR)	US499 8-Jul-2009 19909A
US11453956B2	27-Sep-2022	Method for growth of a merged crystal by bonding at least a first and second crystal to an adhesion layer to form a tiled substrate and growing a crystalline composition over said tiled substrate	D EVELYN MARK P (US); SPECK JAMES S (US); KAMBER DERRICK S (US); POCIUS DOUGLAS W (US)	US201 26-Aug-2019 916550 947A
US8349672B2	8-Jan-2013	Display element manufacturing method and manufacturing apparatus, thin film transistor manufacturing method and manufacturing apparatus, and circuit forming apparatus	NARA KEI (JP); HAMADA TOMOHIDE (JP)	US978 27-Dec-2010 77910A
US2009321932A1	31-Dec-2009	Coreless substrate package with symmetric external dielectric layers	GONZALEZ JAVIER SOTO (US); WU TAO (US); ALUR PALLAVI (US); ROY MIHIR (US); LI SHENG (US); OLMEDO REYNALDO (US)	US217 30-Jun-2008 06808A

US7781269B2	24-Aug-2010	Triangle two dimensional complementary patterning of pillars	WANG CHUN MING (US); CHEN YUNG TIN (US); SCHEUERLEIN ROY E (US)	US216 30-Jun-2008 10908A
US7923361B2	12-Apr-2011	Method for manufacturing a semiconductor integrated circuit device	SHIBUYA KATSUHISA (JP); WAKI HIROMICHI (JP); AIDA NAOTO (JP)	US474 29-May-2009 52909A
US7971347B2	5-Jul-2011	Method of interconnecting workpieces	ARANA LEONEL (US); NICKERSON ROB (US); SIM LIM CHONG (MY); PRACK EDWARD (US); TOMITA YOSHIHIRO (JP)	US215 27-Jun-2008 55008A
US2013260560A1	3-Oct-2013	Patterning Processes Comprising Amplified Patterns	MAYERS BRIAN T (US); CARBECK JEFFREY (US); SAADI WAJEEH (US); WHITESIDES GEORGE M (US)	US201 30-May-2013 313905 675A
US8795554B2	5-Aug-2014	Sputtering target for oxide semiconductor, comprising InGaO3(ZnO) crystal phase and process for producing the sputtering target	YANO KOKI (JP); KAWASHIMA HIROKAZU (JP)	US200 26-Jun-2009 913001 511A
US8852969B2	7-Oct-2014	Fabrication of compact opto-electronic component packages	KUHMANN JOCHEN (DE)	US938 3-Nov-2010 51210A
US8680634B2	25-Mar-2014	Method and apparatus providing an imager module with a permanent carrier	BORTHAKUR SWARNAL (US); LAKE RICK (US); PERKINS ANDY (US); CHURCHWELL SCOTT (US); OLIVER STEVE (US)	US201 29-Apr-2011 113097 085A
US7955890B2	7-Jun-2011	Methods for forming an amorphous silicon film in display devices	CHOI SOO YOUNG (US); CHEN JRIYAN JERRY (US); WON TAE KYUNG (US); YIM DONG KIL (KR)	US486 17-Jun-2009 43509A
US9398699B2	19-Jul-2016	Dual epoxy dielectric and photosensitive solder mask coatings, and processes of making same	JOMAA HOUSSAM (US); BCHIR OMAR (US)	US201 27-Aug-2012 213595 149A
US7811924B2	12-Oct-2010	Air gap formation and integration using a patterning cap	CUI ZHENJIANG (US); NAIK MEHUL (US); BENCHER CHRISTOPHER D (US); MACWILLIAMS KENNETH (US)	US336 17-Dec-2008 88408A
US2011258938A1	27-Oct-2011	Aluminum oxide particle and polishing composition containing the same	MORINAGA HITOSHI (JP); TAHARA MUNEAKI (JP); MATSUNAMI YASUSHI (JP)	US997 12-Jun-2009 45509A
US8791173B2	29-Jul-2014	Ink composition for forming insulating film and insulating film formed from the ink composition	KOTAKE MASAYOSHI (JP); ETORI HIDEKI (JP); EBINE TOSHIHIRO (JP); ISOZUMI HIROSHI (JP); KASAI MASANORI (JP)	US737 3-Jun-2009 14509A
US10083916B2	25-Sep-2018	Semiconductor device and method of forming stress relief layer between die and interconnect structure	SHIM IL KWON (SG); CHOW SENG GUAN (SG); YAOJIAN YAOJIAN (SG)	US201 3-Mar-2015 514637 054A
USRE47923E	31-Mar-2020	Semiconductor device and method of forming PIP with inner known good die interconnected with conductive bumps	CAMACHO ZIGMUND R (SG); DAHILIG FREDERICK R (SG); TAY LIONEL CHIEN HUI (SG); TRASPORTO ARNEL SENOSA (SG); BATHAN HENRY DESCALZO (SG)	US201 1-Mar-2016 615058 005A
US9123663B2	1-Sep-2015	Semiconductor device and method of forming shielding layer grounded through metal pillars formed in peripheral region of the semiconductor	KIM OHHAN (KR); KIM SEUNGWON (KR); PARK JOUNGUN (KR)	US136 10-Jun-2008 68208A

US8394282B2	12-Mar-2013	Adaptive nanotopography sculpting	PANGA AVINASH (US); SREENIVASAN SIDLGATA V (US)	US479 5-Jun-2009 20009A
US8420409B2	16-Apr-2013	Method for manufacturing semiconductor device	GOTO YUUGO (JP); FUJII TERUYUKI (JP)	US201 3-Nov-2011 113288 207A
US8623511B2	7-Jan-2014	Sputtering target for oxide thin film and process for producing the sputtering target	KAWASHIMA HIROKAZU (JP); YANO KOKI (JP); UTSUNO FUTOSHI (JP); INOUE KAZUYOSHI (JP)	US996 5-Jun-2009 59809A
US8815743B2	26-Aug-2014	Through substrate via semiconductor components and methods of formation thereof	BIRNER ALBERT (DE); HOECKELE UWE (DE); KUNSTMANN THOMAS (DE); SEIDEL UWE (DE)	US201 14-Mar-2013 313830 185A
US8709317B2	29-Apr-2014	Mold for nanoimprinting, its production process, and processes for producing molded resin having fine concavo-convex structure on its surface and wire-grid polarizer	KAIDA YURIKO (JP); SAKAMOTO HIROSHI (JP); MIYAGI TAKAHIRA (JP); TAKAYAMA KOSUKE (JP); SHIDOJI EIJI (JP)	US201 8-May-2012 213467 010A
US2009305490A1	10-Dec-2009	METHOD FOR PRODUCING SEMICONDUCTOR DEVICE	SERA HIROSHI (JP)	US425 16-Apr-2009 01609A
US8685500B2	1-Apr-2014	Method for depositing a thin-film polymer in a low-pressure gas phase	GERSDORFF MARKUS (DE)	US995 14-May-2009 43909A
US9224885B2	29-Dec-2015	Conductive compositions and processes for use in the manufacture of semiconductor devices—organic medium components	AKIMOTO HIDEKI (JP); KONNO TAKUYA (JP); LAUDISIO GIOVANNA (GB); OLLIVIER PATRICIA J (US); ROSE MICHAEL (GB); SMITH JEROME DAVID (US); YOUNG RICHARD JOHN SHEFFIELD (GB)	US201 13-Mar-2013 313800 333A
US9543258B2	10-Jan-2017	Semiconductor device and method of forming holes in substrate to interconnect top shield and ground shield	KIM OHHAN (KR); KIM SUNMI (KR); LEE KYUNGHOON (KR)	US201 29-Jan-2016 615011 311A
US2011076416A1	31-Mar-2011	METHOD OF MAKING POROUS MATERIALS AND POROUS MATERIALS PREPARED THEREOF	KLIPP ANDREAS (DE); WAGNER NORBERT (DE); ZAGAR CYRILL (CN); FECHTENKOETTER ANDREAS (SG); PENG CHIH CHENG (SG); SHIH CHIEN HSUEH STEVE (TW); SUJANDI SUJANDI (SG)	US993 20-May-2009 87109A
US8551560B2	8-Oct-2013	Methods for improving selectivity of electroless deposition processes	TONG JINHONG (US); SUN ZHI WEN (US); LANG CHI I (US); KUMAR NITIN (US); KONG BOB (US); FRESCO ZACHARY (US)	US471 22-May-2009 31009A
US2011147060A1	23-Jun-2011	DIELECTRIC FILM, DIELECTRIC ELEMENT, AND PROCESS FOR PRODUCING THE DIELECTRIC ELEMENT	OSADA MINORU (JP); SASAKI TAKAYOSHI (JP)	US993 25-May-2009 95209A
US9136338B2	15-Sep-2015	Sputtering target, method for forming amorphous oxide thin film using the same, and method for manufacturing thin film transistor	YANO KOKI (JP); KAWASHIMA HIROKAZU (JP); INOUE KAZUYOSHI (JP)	US201 25-Apr-2013 313870 847A
US2011067733A1	24-Mar-2011	METHOD FOR CLEANING WITH FLUORINE COMPOUND	OKAMOTO HIDEKAZU (JP); NAMATSU HIDEO (JP)	US951 22-Nov-2010 24110A
US8823179B2	2-Sep-2014	Electronic device package and method for fabricating the same	TSAI CHIA LUN (TW); CHIEN WEN CHENG (TW); LEE PO HAN (TW); CHEN WEI MING (TW); LIU CHIEN HUNG (TW); WEN YING NAN (TW)	US667 13-Jun-2008 38308A

US7960840B2	14-Jun-2011	Double wafer carrier process for creating integrated circuit die with through-silicon vias and micro-electro-mechanical systems protected by a hermetic cavity created at the wafer level	BONIFIELD THOMAS DYER (US); WINTER THOMAS W (US); MORRISON WILLIAM R (US); WINTERTON GREGORY D (US); HAIDER ASAD M (US)	US463 83009A	11-May-2009
US9048277B2	2-Jun-2015	Semiconductor device and method for manufacturing semiconductor device	OIKAWA YOSHIKI (JP); EGUCHI SHINGO (JP); YAMAZAKI SHUNPEI (JP)	US201 313759 251A	5-Feb-2013
US8410354B2	2-Apr-2013	Photoelectric conversion device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP)	US435 13309A	4-May-2009
US2009278126A1	12-Nov-2009	METAL LINE SUBSTRATE, THIN FILM TRANSISTOR SUBSTRATE AND METHOD OF FORMING THE SAME	YANG DONG JU (KR); KIM SANG GAB (KR); LEE KI YEUP (KR); YEO YUN JONG (KR); CHOI SHIN IL (KR); CHIN HONG KEE (KR); JEONG YU GWANG (KR); CHOI SEUNG HA (KR)	US431 96909A	29-Apr-2009
US8119542B2	21-Feb-2012	Method of preparing an electrically insulating film and application for the metallization of vias	MEVELLEC VINCENT (FR); GONZALEZ JOSE (FR); SUHR DOMINIQUE (FR)	US495 13709A	30-Jun-2009
US7786015B2	31-Aug-2010	Method for fabricating self-aligned complementary pillar structures and wiring	CHEN YUNG TIN (US); WANG CHUN MING (US); RADIGAN STEVEN J (US); PETTI CHRISTOPHER J (US); MAXWELL STEVEN (US)	US149 15108A	28-Apr-2008
US8388398B2	5-Mar-2013	Method of manufacturing substrate and organic emitting display device having the substrate	KWON OH JUNE (KR); LEE KWAN HEE (KR); SONG SEUNG YONG (KR); CHOI YOUNG SEO (KR); JUNG SUN YOUNG (KR); JOO YOUNG CHEOL (KR); RYU JI HUN (KR)	US201 113101 107A	4-May-2011
US8546919B2	1-Oct-2013	Die stacking with an annular via having a recessed socket	PRATT DAVE (US)	US201 213556 026A	23-Jul-2012
US8398833B2	19-Mar-2013	Use of DC magnetron sputtering systems	LEE EAL H (US); KIM JAEYEON (US)	US988 01609A	14-Apr-2009
US2011027997A1	3-Feb-2011	POLISHING LIQUID FOR CMP AND POLISHING METHOD	SHINODA TAKASHI (JP); TANAKA TAKAAKI (JP); KANAMARU MAMIKO (JP); AMANOKURA JIN (JP)	US937 46309A	16-Apr-2009
US8734204B2	27-May-2014	Polishing solution for metal films and polishing method using the same	HAGA KOUJI (JP); FUKASAWA MASATO (JP); NAKAGAWA HIROSHI (JP); MISHIMA KOUJI (JP)	US937 77309A	13-Apr-2009
US7968871B2	28-Jun-2011	Organic thin film transistor	WU YILIANG (CA); PAN HUALONG (CA); LIU PING (CA); LI YUNING (CA)	US101 94208A	11-Apr-2008
US2011315218A1	29-Dec-2011	CONDUCTIVE COMPOSITIONS AND PROCESSES FOR USE IN THE MANUFACTURE OF SEMICONDUCTOR DEVICES	CARROLL ALAN FREDERICK (US)	US201 113223 712A	1-Sep-2011
US7960247B2	14-Jun-2011	Die thinning processes and structures	THOMPSON JEFFREY C (US); TEPOLT GARY B (US); RACZ LIVIA M (US)	US628 6408A	4-Apr-2008
US8470701B2	25-Jun-2013	Printable, flexible and stretchable diamond for thermal management	ROGERS JOHN A (US); KIM TAE HO (KR); CHOI WON MOOK (KR); KIM DAE HYEONG (US); MEITL MATTHEW (US); MENARD ETIENNE (US); CARLISLE JOHN (US)	US418 07109A	3-Apr-2009
US9324611B2	26-Apr-2016	Corrosion resistant via connections in semiconductor substrates and methods of making same	BORTHAKUR SWARNAL (US)	US623 6908A	3-Apr-2008

US9646828B2	9-May-2017	Reacted particle deposition (RPD) method for forming a compound semi-conductor thin-film	BRUCE ALLAN JAMES (US); FROLOV SERGEY (US); CYRUS MICHAEL (US)	US185 4-Aug-2008 36908A
US8603588B2	10-Dec-2013	Composition and method for production thereof, porous material and method for production thereof, interlayer insulating film, semiconductor material, semiconductor device, and low-refractive-index surface protection film	KOHMURA KAZUO (JP); TANAKA HIROFUMI (JP)	US934 30-Mar-2009 76709A
US8431430B2	30-Apr-2013	Method for forming a compound semi-conductor thin-film	BRUCE ALLAN JAMES (US); FROLOV SERGEY (US); CYRUS MICHAEL (US)	US201 23-May-2012 213478 851A
US8173908B2	8-May-2012	Device interconnects	ALTEBAEUMER THOMAS HEINZ HELMUT (GB); DAY STEPHEN (GB); LANG CHRISTIAN (GB); HEFFERNAN JONATHAN (GB)	US413 30-Mar-2009 66009A
US2011018127A1	27-Jan-2011	Multilayer UV-Curable Adhesive Film	LEE BYOUNGCHUL (US)	US894 30-Sep-2010 81610A
US7709291B2	4-May-2010	Si substrate has on the surface a first region, a second region, and a third region, the first region being hydrophilic (glass, ceramics), the second region being coated with a hydrocarbon group(hexadecane) and the third region being coated with a fluorocarbon group (trifluoroethanol/2,2,2-)	NAKAGAWA TOHRU (JP)	US627 30-Nov-2009 80109A
US9029184B2	12-May-2015	Photoelectric conversion device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); SHIMOMURA AKIHISA (JP)	US405 17-Mar-2009 46509A
US2012252214A1	4-Oct-2012	POLISHING LIQUID AND POLISHING METHOD	KAMIMURA TETSUYA (JP)	US201 14-Jun-2012 213517 619A
US8940636B2	27-Jan-2015	Through hole vias at saw streets including protrusions or recesses for interconnection	PAGAILA REZA A (SG); CAMACHO ZIGMUND R (SG); TAY LIONEL CHIEN HUI (SG); DO BYUNG TAI (SG)	US201 14-Oct-2011 113273 537A
US8440545B2	14-May-2013	Method of manufacturing semiconductor device with spraying fluid	FUKAYA HIRONORI (JP); SHIMOBEPPE YUZO (JP); YOSHIMOTO KAZUHIRO (JP); SHINJO YOSHIAKI (JP); TESHIOGI KAZUO (JP); SAKAMOTO MIKA (JP)	US273 18-Nov-2008 00908A
US8921691B2	30-Dec-2014	Solar cell and manufacturing method thereof	ISHIZUKA SHOGO (JP); NIKI SHIGERU (JP); KIDO NOBUAKI (JP); HONMOTO HIROYUKI (JP)	US922 19-Mar-2009 99609A
US8546067B2	1-Oct-2013	Material assisted laser ablation	JAIN KANTI (US); CHAE JUNGHUN (US)	US529 21-Mar-2008 8008A
US8623767B2	7-Jan-2014	Method for polishing aluminum/copper and titanium in damascene structures	BRUSIC VLASTA (US); THOMPSON CHRISTOPHER (US); DYSARD JEFFREY (US)	US201 18-Mar-2013 313846 126A
US9209000B2	8-Dec-2015	Gas flow distribution receptacles, plasma generator systems, and methods for performing plasma stripping processes	QIU HUATAN (US); CHUNG WOODY (US); GUHA ANIRBAN (US); CHEUNG DAVID (US)	US201 3-Jan-2012 213342 757A
US7888300B2	15-Feb-2011	Cleaning liquid for semiconductor device and cleaning method	SEKI HIROYUKI (JP); NUKUI KATSUYUKI (JP); INABA TADASHI (JP); FUSHIMI HIDEO (JP)	US585 16-Sep-2009 48609A

US9048445B2	2-Jun-2015	Gate insulating material, gate insulating film and organic field-effect transistor	MURASE SEIICHIRO (JP); FUJIWARA TAKENORI (JP); JO YUKARI (JP); TSUKAMOTO JUN (JP)	US933 41709A	27-Feb-2009
US2015187572A1	2-Jul-2015	INTERLAYER DESIGN FOR EPITAXIAL GROWTH OF SEMICONDUCTOR LAYERS	GIRT EROL (US); MUNTEANU MARIANA RODICA (US)	US201 514658 972A	16-Mar-2015
US8247315B2	21-Aug-2012	Plasma processing apparatus and method for manufacturing semiconductor device	FURUNO MAKOTO (JP); SUGIYAMA TETSUO (JP); NOZAWA TAICHI (JP); ICHIJO MITSUHIRO (JP); TAJIMA RYOTA (JP); YAMAZAKI SHUNPEI (JP)	US400 84409A	10-Mar-2009
US8420412B2	16-Apr-2013	Method of forming a photovoltaic cell module	CROFOOT STEVEN D (US); HOULE KEVIN R (US); JOHNSON DAVID C (US); KETOLA BARRY M (US)	US922 39009A	13-Mar-2009
US7687447B2	30-Mar-2010	Semi-aqueous stripping and cleaning composition containing aminobenzenesulfonic acid	EGBE MATTHEW I (US); LEGENZA MICHAEL WALTER (US); DURHAM DANA L (US)	US476 5508A	13-Mar-2008
US7942716B2	17-May-2011	Frit sealing system and method of manufacturing organic light emitting display device	LEE JUNG MIN (KR); YOON SEOK JOON (KR); LEE CHOONG HO (KR); JEONG HEE SEONG (KR); KANG TAE WOOK (KR); CHOE WON KYU (KR)	US378 46309A	13-Feb-2009
US8404502B2	26-Mar-2013	Water-barrier encapsulation method	WON TAE K (US); CAMPO JOSE MANUEL DIEGUEZ (DE); WHITE JOHN M (US); YADAV SANJAY (US)	US201 113117 947A	27-May-2011
US2011014443A1	20-Jan-2011	ADHESIVE TAPE FOR ELECTRONIC COMPONENT FABRICATION	YOKOI HIROTOKI (JP); SUDA AKIRA (JP); YANO SYOUZOU (JP); ISHIWATA SHINICHI (JP)	US921 44108A	10-Dec-2008
US8900399B2	2-Dec-2014	Integrated method and system for manufacturing monolithic panels of crystalline solar cells	RAVI TIRUNELVELI S (US); KUMAR ANANDA H (US); ASTHANA ASHISH (US); TANTIWONG KYLE ROSS (US); SIVARAMAKRISHNAN VISWESWAREN (US)	US201 113050 807A	17-Mar-2011
US8247030B2	21-Aug-2012	Void-free copper filling of recessed features using a smooth non-agglomerated copper seed layer	SUZUKI KENJI (US); GOMI ATSUSHI (JP); JOMEN MIHO (US)	US441 9108A	7-Mar-2008
US10292261B2	14-May-2019	Stretchable and foldable electronic devices	ROGERS JOHN A (US); HUANG YONGGANG (US); KO HEUNG CHO (US); STOYKOVICH MARK (US); CHOI WON MOOK (US); SONG JIZHOU (US); AHN JONG HYUN (KR); KIM DAE HYEONG (US)	US201 514706 733A	7-May-2015
US2009226708A1	10-Sep-2009	PRESSURE-SENSITIVE ADHESIVE COMPOSITION AND PRESSURE-SENSITIVE ADHESIVE SHEET	NAGANAWA SATOSHI (JP); KASHIO MIKIHIRO (JP)	US396 90209A	3-Mar-2009
US2009223551A1	10-Sep-2009	Process for making solar cells	REDDY DAMODER (US); LEIDHOLM CRAIG (US)	US380 63809A	2-Mar-2009
US8003305B2	23-Aug-2011	Method for patterning a semiconductor wafer	SCHEER STEVEN (US); SCHROEDER UWE PAUL (US)	US415 0008A	3-Mar-2008
US8273601B2	25-Sep-2012	Method of fabricating multi-chip package structure	WANG CHIEN HAO (TW)	US201 113110 228A	18-May-2011
US8350391B2	8-Jan-2013	Sheet structure, semiconductor device and method of growing carbon structure	KONDO DAIYU (JP); IWAI TAISUKE (JP); YAMAGUCHI YOSHITAKA (JP); SOGA IKUO (JP)	US201 213562 782A	31-Jul-2012

US8652350B2	18-Feb-2014	Chemical mechanical polishing aqueous dispersion, chemical mechanical polishing method using the same, and method of recycling chemical mechanical polishing aqueous dispersion	NISHIMOTO KAZUO (JP); SHINODA TOMOTAKA (JP)	US919 6-Feb-2009 89709A
US2018155824A1	7-Jun-2018	METHOD OF GROWING NANOSTRUCTURES	BERG JONAS S T (SE); DESMARIS VINCENT (SE); KABIR MOHAMMAD SHAFIQL (SE); SALEEM MUHAMMAD AMIN (SE); BRUD DAVID (SE)	US201 2-Nov-2017 715801 734A
US2009211525A1	27-Aug-2009	MULTIPLE AMPOULE DELIVERY SYSTEMS	SARI GIANNIS DEMETRIUS (US); HOOVER CYNTHIA A (US); KRAUSE MICHAEL JOSEPH (US); PRYOR EDWARD (US); CHESTERS STEPHEN (US); SPOHN RONALD (US)	US369 12-Feb-2009 79909A
US11392037B2	19-Jul-2022	Resist underlayer film forming composition containing silicone having cyclic amino group	NAKAJIMA MAKOTO (JP); SHIBAYAMA WATARU (JP); KANNO YUTA (JP)	US867 16-Feb-2009 58709A
US8809247B2	19-Aug-2014	Cleaning composition and method for cleaning substrate for electronic device	HIDAKA MAKOTO (JP); OGURA TAKU (JP)	US867 13-Feb-2009 46809A
US8421326B2	16-Apr-2013	Electrode, method of preparing the same, and electronic device including the electrode	KIM WON JONG (KR); KIM YONG TAK (KR); LEE JONG HYUK (KR); YOON DAE HO (KR); YOON SEOK GYU (KR); HIDEO HOSONO (JP)	US369 11-Feb-2009 27209A
US7935604B2	3-May-2011	Method of making small geometry features	ADKISSON JAMES WILLIAM (US); GAMBINO JEFFREY PETER (US); LEIDY ROBERT KENNETH (US); LEPUSCHENKO WALTER VICTOR (US); MEATYARD DAVID ALAN (US); MONGEON STEPHEN A (US); RASSEL RICHARD JOHN (US)	US288 11-Feb-2008 4708A
US9627420B2	18-Apr-2017	Method for forming an electronic device on a flexible substrate supported by a detachable carrier	KERR ROGER STANLEY (US); TREDWELL TIMOTHY JOHN (US)	US281 8-Feb-2008 9408A
US8506359B2	13-Aug-2013	Aqueous dispersion for chemical mechanical polishing and chemical mechanical polishing method	SHIDA HIROTAKA (JP); SHIMIZU TAKAFUMI (JP); IKEDA MASATOSHI (JP); KUBOUCHI SHOU (JP); SHIBATA YOUSUKE (JP); UCHIKURA KAZUHITO (JP); TAKEMURA AKIHIRO (JP)	US866 16-Jan-2009 57109A
US8273659B2	25-Sep-2012	Method for patterned etching of selected material	LENNON ALISON JOAN (AU); WENHAM STUART ROSS (AU); HO BAILLIE ANITA WING YI (AU)	US847 30-Jul-2010 06110A
US2015228823A1	13-Aug-2015	APPARATUS AND METHODS OF MIXING AND DEPOSITING THIN FILM PHOTOVOLTAIC COMPOSITIONS	BRITT JEFFREY S (US); WIEDEMAN SCOTT (US)	US201 16-Apr-2015 514688 776A
US9673348B2	6-Jun-2017	Buffer layer deposition for thin-film solar cells	BRITT JEFFREY S (US); ALBRIGHT SCOT (US); SCHOOP URS (US)	US201 27-Jun-2016 615193 921A
US8277869B2	2-Oct-2012	Heating for buffer layer deposition	BRITT JEFFREY S (US); ALBRIGHT SCOT (US); SCHOOP URS (US)	US397 4-Mar-2009 87309A
US8110911B2	7-Feb-2012	Semiconductor chip package with post electrodes	ISHIHARA MASAMICHI (JP); UEDA HIROTAKA (JP)	US864 16-Jan-2009 12509A
US2010330300A1	30-Dec-2010	SYSTEM AND METHOD FOR PRE-IONIZATION OF SURFACE WAVE LAUNCHED PLASMA DISCHARGE SOURCES	STOWELL MICHAEL W (US)	US865 30-Jan-2008 31708A

US10297469B2	21-May-2019	Method for producing an electronic component and electronic component	SCHMID CHRISTIAN (DE); SCHLENKER TILMAN (DE); ZULL HERIBERT (DE); PAETZOLD RALPH (DE); KLEIN MARKUS (DE); HEUSER KARSTEN (DE)	US201 414540 670A	13-Nov-2014
US8501394B2	6-Aug-2013	Superfine-patterned mask, method for production thereof, and method employing the same for forming superfine-pattern	TAKANO YUSUKE (JP); LI JIN (JP); ISHIKAWA TOMONORI (JP); NOYA GO (JP)	US864 52909A	27-Jan-2009
US9111981B2	18-Aug-2015	Method for reversibly mounting a device wafer to a carrier substrate	FLAIM TONY D (US); MCCUTCHEON JEREMY (US)	US358 95109A	23-Jan-2009
US7963435B2	21-Jun-2011	Method of forming bonded body and bonded body	SATO MITSURU (JP); YAMAMOTO TAKATOSHI (JP)	US358 68909A	23-Jan-2009
US8617928B2	31-Dec-2013	Dicing/die bonding film	KAMIYA KATSUHIKO (JP); MATSUMURA TAKESHI (JP); MURATA SHUUHEI (JP); OOTAKE HIRONAO (JP)	US863 06308A	16-Dec-2008
US7781232B2	24-Aug-2010	Method to recover underfilled modules by selective removal of discrete components	ARVIN CHARLES L (US); FASANO BENJAMIN V (US); INTERRANTE MARIO J (US); POMERANTZ GLENN A (US)	US157 5408A	17-Jan-2008
US7629307B2	8-Dec-2009	Ternary azeotropic-like compositions with 1,1,1,2,3,3-hexafluoro-3-methoxy-propane and trans-1,2-dichloroethylene	OWENS JOHN G (US)	US158 2608A	17-Jan-2008
US8985173B2	24-Mar-2015	Manufacturing method and manufacturing apparatus of semiconductor substrate	OMATA TAKATSUGU (JP); MORIWAKA TOMOAKI (JP); OHNUMA HIDETO (JP)	US201 113110 950A	19-May-2011
US7994495B2	9-Aug-2011	Organic thin film transistors	WU YILIANG (CA); ONG BENG S (CN)	US148 8408A	16-Jan-2008
US8987119B2	24-Mar-2015	Pillar devices and methods of making thereof	DUNTON VANCE (US); HERNER S BRAD (US); POON PAUL WAI KIE (US); PAN CHUANBIN (US); CHAN MICHAEL (US); KONEVECKI MICHAEL (US); RAGHURAM USHA (US)	US201 113026 381A	14-Feb-2011
US8741782B2	3-Jun-2014	Charging-free electron beam cure of dielectric material	DIMITRAKOPOULOS CHRISTOS D (US); LEE KAM L (US); WISNIEFF ROBERT L (US)	US201 213561 240A	30-Jul-2012
US7585754B2	8-Sep-2009	Method of forming bonding pad opening	LO WEN SHUN (TW); NI CHIH JUNG (TW); LIN YI TUNG (TW)	US972 30308A	10-Jan-2008
US8283644B2	9-Oct-2012	Measuring in-situ UV intensity in UV cure tool	SMARGIASSI EUGENE (US); KENANE BOAZ (US); LEE JAMES (US); CHEN XIAOLAN (US)	US201 113070 306A	23-Mar-2011
US2009176381A1	9-Jul-2009	METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING APPARATUS	HIYAMA SHIN (JP); KAKUDA TORU (JP); HIROCHI YUKITOMO (JP)	US344 89908A	29-Dec-2008
US8551565B2	8-Oct-2013	Film forming method and film forming apparatus	GUNJI ISAO (JP); MIYOSHI HIDENORI (JP); ITOH HITOSHI (JP)	US811 18508A	25-Dec-2008
US2014077126A1	20-Mar-2014	METHOD OF ETCHING A HIGH ASPECT RATIO CONTACT	BENSON RUSSELL A (US); TAYLOR THEODORE M (US); KIEHLBAUCH MARK W (US)	US201 314084 854A	20-Nov-2013

US8999818B2	7-Apr-2015	Semiconductor device and method of manufacturing semiconductor device	TAKAHASHI HIDEKAZU (JP); YAMADA DAIKI (JP); MONMA YOHEI (JP); ADACHI HIROKI (JP); YAMAZAKI SHUNPEI (JP)	US342 23-Dec-2008 15308A
US9525080B2	20-Dec-2016	Semiconductor device with optical sensor and method of forming interconnect structure on front and backside of the device	CAMACHO ZIGMUND R (SG); BATHAN HENRY D (SG); TAY LIONEL CHIEN HUI (SG); TRASPORTO ARNEL SENOSA (SG)	US201 23-Jul-2012 213555 353A
US8703605B2	22-Apr-2014	High yield and high throughput method for the manufacture of integrated circuit devices of improved integrity, performance and reliability	YANG BYUNG CHUN (US)	US831 7-Jul-2010 48210A
US8207060B2	26-Jun-2012	High yield and high throughput method for the manufacture of integrated circuit devices of improved integrity, performance and reliability	YANG BYUNG CHUN (US)	US339 18-Dec-2008 03308A
US8951849B2	10-Feb-2015	Method for manufacturing semiconductor device including layer containing yttria-stabilized zirconia	TAKAYAMA TORU (JP); AKIMOTO KENGO (JP)	US201 17-Mar-2011 113050 002A
US10998248B2	4-May-2021	Semiconductor device and method of forming sacrificial adhesive over contact pads of semiconductor die	PAGAILA REZA A (ID); LIN YAOJIAN (SG); KOO JUN MO (SG)	US201 11-Mar-2016 615068 290A
US9472452B2	18-Oct-2016	Semiconductor device and method of forming repassivation layer with reduced opening to contact pad of semiconductor die	LIN YAOJIAN (SG); CHEN KANG (SG); FANG JIANMIN (SG); FENG XIA (SG)	US201 22-May-2014 414284 752A
US8163090B2	24-Apr-2012	Methods structures and apparatus to provide group VIA and IA materials for solar cell absorber formation	BASOL BULENT M (US)	US953 10-Dec-2007 82207A
US2011065224A1	17-Mar-2011	METHODS AND DEVICES FOR PROCESSING A PRECURSOR LAYER IN A GROUP VIA ENVIRONMENT	BOLLMAN BRENT (US); LEIDHOLM CRAIG (US)	US813 11-Jun-2010 50810A
US9281241B2	8-Mar-2016	Methods for forming interconnects in microelectronic workpieces and microelectronic workpieces formed using such methods	SULFRIDGE MARC (US)	US201 21-Aug-2012 213590 862A
US9460951B2	4-Oct-2016	Semiconductor device and method of wafer level package integration	LIN YAOJIAN (SG)	US201 29-Jun-2011 113172 680A
US8187956B2	29-May-2012	Method for manufacturing microcrystalline semiconductor film, thin film transistor having microcrystalline semiconductor film, and photoelectric conversion device having microcrystalline semiconductor film	JINBO YASUHIRO (JP); MIYAIRI HIDEKAZU (JP); DAIRIKI KOJI (JP)	US277 25-Nov-2008 37808A
US8211780B2	3-Jul-2012	Method for manufacturing SOI substrate	YAMAZAKI SHUNPEI (JP)	US325 1-Dec-2008 48808A
US10074553B2	11-Sep-2018	Wafer level package integration and method	LIN YAOJIAN (SG)	US949 3-Dec-2007 28207A
US8343821B2	1-Jan-2013	Method for manufacturing a thin film transistor	YAMAZAKI SHUNPEI (JP)	US201 22-Sep-2011 113239 617A

US8558236B2	15-Oct-2013	Semiconductor device	YAMAZAKI SHUNPEI (JP); MIYAIRI HIDEKAZU (JP); JINBO YASUHIRO (JP)	US201 113196 926A	3-Aug-2011
US8007334B2	30-Aug-2011	Display panel and manufacturing method of display panel	TOHYAMA TADAHISA (JP); OZAKI TSUYOSHI (JP)	US323 79008A	26-Nov-2008
US2011030901A1	10-Feb-2011	METHOD FOR MANUFACTURING SEMICONDUCTOR SUBSTRATE AND SEMICONDUCTOR SUBSTRATE MANUFACTURING APPARATUS	SHIMOMURA AKIHISA (JP); KOYAMA MASAKI (JP); OKAMOTO SATOHIRO (JP)	US903 52710A	13-Oct-2010
US8242562B2	14-Aug-2012	Film deposition apparatus	YAMAZAKI SHUNPEI (JP); FURUNO MAKOTO (JP)	US201 113094 886A	27-Apr-2011
US8129212B2	6-Mar-2012	Surface cleaning and texturing process for crystalline solar cells	WIJEKON KAPILA (US); MISHRA ROHIT (US); STEWART MICHAEL P (US); WEIDMAN TIMOTHY (US); PONNEKANTI HARI (US); HOLTAM TRISTAN R (US)	US383 35009A	23-Mar-2009
US8642361B2	4-Feb-2014	Method and system for large scale manufacture of thin film photovoltaic devices using multi-chamber configuration	LEE HOWARD W H (US); FARRIS III CHESTER A (US)	US201 213456 095A	25-Apr-2012
US8597769B2	3-Dec-2013	Etching mask, base material having etching mask, finely processed article, and method for production of finely processed article	TAKAYA YOSHIKI (JP); SATSUKA TAKURO (JP); HAYASHIDA YOSHIHISA (JP); KUSUURA TAKAHISA (JP); MITRA ANUPAM (JP)	US742 38108A	13-Nov-2008
US2017144152A1	25-May-2017	PROCESSES FOR RAPID MICROFABRICATION USING THERMOPLASTICS AND DEVICES THEREOF	KHINE MICHELLE (US); CHEN CHI SHUO (US); GRIMES ANTHONY (US); BRESLAUER DAVID NATE (US); LEE LUKE (US); DUNLAP MICHAEL (US); GOPINATHAN AJAY (US); GHOSH SAYANTANI (US)	US201 615380 954A	15-Dec-2016
US2010239866A1	23-Sep-2010	DICING DIE-BONDING FILM	MATSUMURA TAKESHI (JP); KAMIYA KATSUHIKO (JP); MURATA SHUUHEI (JP)	US741 85908A	30-Oct-2008
US2009130414A1	21-May-2009	Preparation of A Metal-containing Film Via ALD or CVD Processes	KIM MIN KYUNG (KR); KIM MOO SUNG (KR); LEI XINJIAN (US); YANG SANG HYUN (KR); HAN YANG SUK (KR)	US255 12808A	21-Oct-2008
US7816234B2	19-Oct-2010	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); ARAI YASUYUKI (JP)	US262 75308A	31-Oct-2008
US8253138B2	28-Aug-2012	Thin film transistor and display device having the thin film transistor	YAMAZAKI SHUNPEI (JP); KOBAYASHI SATOSHI (JP); KUOKAWA YOSHIYUKI (JP); GODO HIROMICHI (JP)	US263 70208A	3-Nov-2008
US10222699B2	5-Mar-2019	Compositions and processes for immersion lithography	WANG DEYAN (US); XU CHENG BAI (US); BARCLAY GEORGE G (US)	US201 414525 044A	27-Oct-2014
US8232209B2	31-Jul-2012	Processes for forming electronic devices including polishing metal-containing layers	BRANNON CHRISTOPHER E (US); WEDLAKE MICHAEL (US); NAUERT CHRIS A (US)	US201 113025 979A	11-Feb-2011
US2010330805A1	30-Dec-2010	METHODS FOR FORMING HIGH ASPECT RATIO FEATURES ON A SUBSTRATE	DOAN KENNY LINH (US); KESWICK KATHRYN (US); DESHMUKH SUBHASH (US); WEGE STEPHAN (DE); LEE WONSEOK (US)	US934 58907A	2-Nov-2007

US8481393B2	9-Jul-2013	Semiconductor substrate and method for manufacturing the same, and method for manufacturing semiconductor device	KOYAMA MASAKI (JP); ISAKA FUMITO (JP); SHIMOMURA AKIHISA (JP); MOMO JUNPEI (JP)	US844 22410A	27-Jul-2010
US8183319B2	22-May-2012	Film forming additive formulations of conductive polymers	HAN ADEBEKUN GANG CHRIS (US); MARKLEY THOMAS JOHN (US); LOWRY MICHAEL SCOTT (US)	US248 09808A	9-Oct-2008
US8435871B2	7-May-2013	Method for manufacturing semiconductor device, and semiconductor device and electronic device	SHIMOMURA AKIHISA (JP); MOMO JUNPEI (JP); ISAKA FUMITO (JP)	US259 24108A	27-Oct-2008
US8853868B2	7-Oct-2014	Semiconductor structures including sub-resolution alignment marks	PRATT DAVID S (US); SULFRIDGE MARC A (US)	US201 314059 548A	22-Oct-2013
US2014017893A1	16-Jan-2014	CMP POLISHING LIQUID AND METHOD FOR POLISHING SUBSTRATE USING THE SAME	MINAMI HISATAKA (JP); ONO HIROSHI (JP); AMANOKURA JIN (JP)	US201 314030 903A	18-Sep-2013
US8110478B2	7-Feb-2012	Method for manufacturing semiconductor substrate, display panel, and display device	YAMAZAKI SHUNPEI (JP); OHNUMA HIDETO (JP); KOYAMA JUN (JP)	US253 30108A	17-Oct-2008
US8835797B2	16-Sep-2014	Method and device for the plasma treatment of running metal substrates	VANDENBRANDE PIERRE (CH)	US739 30508A	6-Oct-2008
US7666754B2	23-Feb-2010	Method and system for forming an air gap structure	TOMA DOREL I (US); LIU JUNJUN (US)	US874 46107A	18-Oct-2007
US7998371B2	16-Aug-2011	Conductive compositions and processes for use in the manufacture of semiconductor devices: Mg-containing additive	YOUNG RICHARD JOHN SHEFFIELD (GB); ROSE MICHAEL (GB); MIKESKA KURT RICHARD (US); CARROLL ALAN FREDERICK (US); HANG KENNETH WARREN (US); PRINCE ALISTAIR GRAEME (GB)	US839 65310A	20-Jul-2010
US8226856B2	24-Jul-2012	Lead-free conductive compositions and processes for use in the manufacture of semiconductor devices: flux materials	CARROLL ALAN FREDERICK (US); HANG KENNETH WARREN (US)	US254 29708A	20-Oct-2008
US8631757B2	21-Jan-2014	Solution deposition assembly	ROUSSILLON YANN (US); SCHOLZ JEREMY H (US); SHELTON ADDISON (US); GREEN GEOFF T (US); UTTACHOO PIYAPHANT (US)	US369 52409A	11-Feb-2009
US7820531B2	26-Oct-2010	Method of manufacturing semiconductor device, method of manufacturing display apparatus, apparatus of manufacturing semiconductor device, and display apparatus	MATSUNOBU GOH (JP); TATSUKI KOICHI (JP); INAGAKI YOSHIO (JP); UMEZU NOBUHIKO (JP); TSUKIHARA KOICHI (JP)	US247 37008A	8-Oct-2008
US2009096106A1	16-Apr-2009	ANTIREFLECTIVE COATINGS	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); JOHNSON ANDREW DAVID (US)	US244 42608A	2-Oct-2008
US8298839B2	30-Oct-2012	Manufacturing method of a thin film active element	KASAHARA KENJI (JP)	US681 99508A	9-Oct-2008
US8772128B2	8-Jul-2014	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); MOMO JUNPEI (JP); ISAKA FUMITO (JP); HIGA EIJI (JP); KOYAMA MASAKI (JP); SHIMOMURA AKIHISA (JP)	US246 57708A	7-Oct-2008

US8101501B2	24-Jan-2012	Method of manufacturing semiconductor device	OHNUMA HIDETO (JP); IIKUBO YOICHI (JP); YAMAZAKI SHUNPEI (JP)	US240 29-Sep-2008 18608A
US8409966B2	2-Apr-2013	Method for manufacturing SOI substrate	OHNUMA HIDETO (JP); YAMAZAKI SHUNPEI (JP)	US201 7-Jul-2011 113177 584A
US8455331B2	4-Jun-2013	Manufacturing method of semiconductor device	YAMAZAKI SHUNPEI (JP); SHICHI TAKESHI (JP); SUZUKI NAOKI (JP)	US246 7-Oct-2008 64008A
US7851332B2	14-Dec-2010	Semiconductor device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); KOEZUKA JUNICHI (JP); KAKEHATA TETSUYA (JP)	US237 25-Sep-2008 60608A
US9695347B2	4-Jul-2017	Slurry composition for chemical mechanical polishing of metal and polishing method using the same	CHOU HOMER (KR); KIM WON LAE (KR); NOH JONG IL (KR); LEE IN KYUNG (KR); LEE TAE YOUNG (KR)	US965 27-Dec-2007 45307A
US8771419B2	8-Jul-2014	Roll to roll evaporation tool for solar absorber precursor formation	PINARBASI MUSTAFA (US); BASOL BULENT M (US)	US868 5-Oct-2007 44307A
US2011011447A1	20-Jan-2011	Method of Forming A Ceramic Silicon Oxide Type Coating, Method of Producing An Inorganic Base Material, Agent For Forming A Ceramic Silicon Oxide Type Coating, and Semiconductor Device	HARIMOTO YUKINARI (JP); MICHINO TETSUYUKI (JP); KATSOLIS DIMITRIS ELIAS (US); KUSHIBIKI NOBUO (JP); SUTO MICHITAKA (JP)	US681 3-Oct-2008 52108A
US2009093124A1	9-Apr-2009	Method of manufacturing semiconductor device	HIYAMA SHIN (JP)	US230 3-Sep-2008 67608A
US7846793B2	7-Dec-2010	Plasma surface treatment for Si and metal nanocrystal nucleation	OLSEN CHRISTOPHER S (US); SEUTTER SEAN (US); LI MING (US); KRAUS PHILLIP ALLAN (US)	US866 3-Oct-2007 62507A
US8759671B2	24-Jun-2014	Thin film metal oxide bearing semiconductor material for single junction solar cell devices	LEE HOWARD W H (US)	US237 24-Sep-2008 36908A
US9964848B2	8-May-2018	Positive photosensitive resin composition and cured film forming method using the same	TAKITA SATOSHI (JP)	US201 13-Apr-2015 514684 812A
US2009087988A1	2-Apr-2009	POLISHING LIQUID AND POLISHING METHOD	SAIE TOSHIYUKI (JP)	US235 22-Sep-2008 47508A
US8030212B2	4-Oct-2011	Process for selective area deposition of inorganic materials	YANG CHENG (US); IRVING LYN M (US); LEVY DAVID H (US); COWDERY CORVAN PETER J (US); FREEMAN DIANE C (US)	US861 26-Sep-2007 65807A
US7701040B2	20-Apr-2010	Semiconductor package and method of reducing electromagnetic interference between devices	HUANG RUI (SG); LIN YAOJIAN (SG); CHOW SENG GUAN (SG)	US860 24-Sep-2007 37707A
US11034862B2	15-Jun-2021	Polishing composition and method utilizing abrasive particles treated with an aminosilane	GRUMBINE STEVEN (US); LI SHOUTIAN (US); WARD WILLIAM (US); SINGH PANKAJ (US); DYSARD JEFFREY (US)	US201 25-Oct-2019 916664 235A

US7994057B2	9-Aug-2011	Polishing composition and method utilizing abrasive particles treated with an aminosilane	DYSARD JEFFREY (US); ANJUR SRIRAM (US); GRUMBINE STEVEN (US); WHITE DANIELA (US); WARD WILLIAM (US)	US234 19-Sep-2008 17308A
US8309429B2	13-Nov-2012	Method for manufacturing semiconductor substrate and semiconductor device	YAMAZAKI SHUNPEI (JP)	US211 17-Sep-2008 93308A
US9640478B2	2-May-2017	Semiconductor device having low dielectric insulating film and manufacturing method of the same	MIZUSAWA AIKO (JP); OKADA OSAMU (JP); WAKABAYASHI TAKESHI (JP); MIHARA ICHIRO (JP)	US201 25-Jun-2015 514750 665A
US8597973B2	3-Dec-2013	Ink for forming thin film of solar cells and method for preparing the same, CIGS thin film solar cell using the same and manufacturing method thereof	CHOE YOUNG HO (KR); LEE YOUNG HEE (KR); CHOI YONG WOO (KR); KIM HYUNG SEOK (KR); KIM HO GYOUNG (KR)	US201 27-Dec-2011 113338 136A
US10192781B2	29-Jan-2019	Interconnect structures incorporating air gap spacers	NITTA SATYA V (US); PONOTH SHOM (US)	US201 26-Feb-2016 615055 451A
US8323516B2	4-Dec-2012	Etching processes used in MEMS production	BITA ION (US); GOUSEV EVGENI (US); LONDERGAN ANA (US); YAN XIAOMING (US)	US210 12-Sep-2008 04208A
US8308991B2	13-Nov-2012	Low temperature bonding electronic adhesives	LARSON ERIC G (US); ZENNER ROBERT L D (US); MURRAY CAMERON T (US); SURA RAVI K (US)	US206 9-Sep-2008 94208A
US2009203215A1	13-Aug-2009	METAL POLISHING SLURRY AND CHEMICAL MECHANICAL POLISHING METHOD	YOSHIKAWA MASARU (JP); INABA TADASHI (JP); INADA HIROSHI (JP); TOMIGA TAKAMITSU (JP)	US368 9-Feb-2009 03809A
US9666745B2	30-May-2017	Method for manufacturing a compound film	RUDMANN DOMINIK (CH); KAEIN MARC (CH); STUDER THOMAS (SA); BUDDE FELIX (CH)	US201 26-Jul-2013 313952 420A
US8426112B2	23-Apr-2013	Resist underlayer film forming composition containing polymer having nitrogen-containing silyl group	NAKAJIMA MAKOTO (JP); SHIBAYAMA WATARU (JP); KANNO YUTA (JP)	US676 10-Sep-2008 68708A
US2010203713A1	12-Aug-2010	METHOD OF MANUFACTURING ELECTRONIC DEVICE	OHMI TADAHIRO (JP); FUJIMURA MAKOTO (JP); KOIKE TADASHI (JP); BAMBA AKINORI (JP); KOBAYASHI AKIHIRO (JP); WATANUKI KOHEI (JP)	US733 5-Sep-2008 59508A
US8601973B2	10-Dec-2013	Solution deposition assembly	ROUSSILLON YANN (US); UTTACHOO PIYAPHANT (US)	US203 2-Sep-2008 11708A
US7908743B2	22-Mar-2011	Method for forming an electrical connection	LI ZHIYONG (US); LUU CHUCK (US); PRABHU GOPALAKRISHNA B (US); LU DANNY CAM TOAN (US); KWONG GARRY (US); TANNER DAVID (US)	US430 27-Apr-2009 80709A
US8049521B2	1-Nov-2011	Solar parametric testing module and processes	LU DANNY CAM TOAN (US); MARRIOTT MICHEL (US); SVIDENKO VICKY (US); WANG DAPENG (US); FREI MICHEL R (US)	US409 24-Mar-2009 73209A

US8231431B2	31-Jul-2012	Solar panel edge deletion module	GAJARIA DHRUV (US); LI ZHIYONG (US); PRABHU GOPALAKRISHNA B (US); ELGAR YACOV (US); VISITACION JOHN (US); LIU YONG (US); SULLIVAN JEFFREY S (US); UMOTOY SALVADOR (US); NGO TAI T (US); MARRIOTT MICHAEL (US); CRUNDWELL PETER (GB); SHAH VINAY (US); CHOI HO GENE (US); PIERCE DENNIS C (US)	US358 23-Jan-2009 81409A
US8225496B2	24-Jul-2012	Automated integrated solar cell production line composed of a plurality of automated modules and tools including an autoclave for curing solar devices that have been laminated	BACHRACH ROBERT Z (US); CHAE YONG KEE (US); CHOI SOO YOUNG (US); DE VRIES NICHOLAS G J (US); ELGAR YACOV (US); ENGLHARDT ERIC A (US); FREI MICHEL R (US); GAY CHARLES (US); HAWKINS PARRIS (US); HO CHOI GENE (US); HUNTER JAMES CRAIG (US); KANKANALA PENCHALA N (US); LI LIWEI (US); LO WING HOO HENDRICK (US); LU DANNY CAM TOAN (US); MEI FANG (US); MURPHY STEPHEN P (US); PATEL SRUJAL STEVE (US); SAUNDERS MATTHEW J B (US); SCHLEZINGER ASAF (US); SHENG SHURAN (US); SU TZAY FA JEFF (US); SULLIVAN JEFFREY S (US); TANNER DAVID (US); TROWBRIDGE TERESA (US); WALKER BRICE (US); WHITE JOHN M (US); WON TAE K (US)	US202 29-Aug-2008 19908A
US2009061630A1	5-Mar-2009	Method for Chemical Mechanical Planarization of A Metal-containing Substrate	PALMER BENTLEY J (US); MEYERS ANN MARIE (US); SHRAUTI SURESH (US); ZHANG GUANGYING (US); ZUTSHI AJOY (US)	US195 21-Aug-2008 84008A
US7678605B2	16-Mar-2010	Method for chemical mechanical planarization of chalcogenide materials	SCHLUETER JAMES ALLEN (US); PALMER BENTLEY J (US)	US190 13-Aug-2008 88208A
US8030775B2	4-Oct-2011	Wirebond over post passivation thick metal	LIN MOU SHIUNG (TW)	US198 27-Aug-2008 89908A
US8114722B2	14-Feb-2012	Manufacturing method of semiconductor device	KAKEHATA TETSUYA (JP)	US190 12-Aug-2008 05908A
US8268701B2	18-Sep-2012	Manufacturing of semiconductor device	YAMAZAKI SHUNPEI (JP)	US939 4-Nov-2010 50010A
US8043901B2	25-Oct-2011	Method for manufacturing display device	YAMAZAKI SHUNPEI (JP); ARAI YASUYUKI (JP); SUZUKI YUKIE (JP); KUOKAWA YOSHIYUKI (JP)	US222 14-Aug-2008 68608A
US8309406B2	13-Nov-2012	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); FURUNO MAKOTO (JP)	US201 28-Dec-2011 113338 340A
US9054206B2	9-Jun-2015	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); TEDUKA SACHIYUKI (JP); TORIUMI SATOSHI (JP); FORUNO MAKOTO (JP); JINBO YASUHIRO (JP); DAIRIKI KOJI (JP); KUWABARA HIDEAKI (JP)	US222 1-Aug-2008 10908A

US7611930B2	3-Nov-2009	Method of manufacturing display device	YAMAZAKI SHUNPEI (JP); TEDUKA SACHIaki (JP); FURUNO MAKOTO (JP); TORIUMI SATOSHI (JP); JINBO YASUHIRO (JP); DAIRIKI KOJI (JP)	US186 00108A	5-Aug-2008
US8535119B2	17-Sep-2013	Chemical mechanical polishing pad and methods of making and using same	PALAPARTHI RAVICHANDRA V (US); HREHA RICHARD D (US); VINING BENJAMIN JOHN (US)	US201 213494 575A	12-Jun-2012
US7458885B1	2-Dec-2008	Chemical mechanical polishing pad and methods of making and using same	PALAPARTHI RAVICHANDRA V (US)	US838 95407A	15-Aug-2007
US8702919B2	22-Apr-2014	Target designs and related methods for coupled target assemblies, methods of production and uses thereof	FERRASSE STEPHANE (US); HORT WERNER H (US); KIM JAEYEON (US); ALFORD FRANK C (US)	US838 16607A	13-Aug-2007
US2010255429A1	7-Oct-2010	FINE PATTERN FORMING METHOD AND COAT FILM FORMING MATERIAL	ISHIKAWA KIYOSHI (JP); KOSHIYAMA JUN (JP); WAKIYA KAZUMASA (JP)	US671 80508A	3-Jul-2008
US9190362B2	17-Nov-2015	Image sensor package with trench insulator and fabrication method thereof	CHIEN WEN CHENG (TW); HUANG WEN KEN (TW); LIU CHIEN HUNG (TW); LAI JOEY (TW)	US201 414325 812A	8-Jul-2014
US8922026B2	30-Dec-2014	Chip package and fabrication method thereof	LIU CHIEN HUNG (TW); CHOU CHENG TE (TW)	US201 213553 331A	19-Jul-2012
US2010247906A1	30-Sep-2010	HEAT-RESISTANT ADHESIVE SHEET	LEE JUN HO (KR); JEUN HAE SANG (KR); MOON KI JEONG (KR); SIM CHANG HOON (KR)	US159 83907A	22-Aug-2007
US7875502B2	25-Jan-2011	Semiconductor chips with crack stop regions for reducing crack propagation from chip edges/comers	BROFMAN PETER J (US); CASEY JON ALFRED (US); MELVILLE IAN D (US); QUESTAD DAVID L (US); SAUTER WOLFGANG (US); WASSICK THOMAS ANTHONY (US)	US788 52110A	27-May-2010
US8703276B2	22-Apr-2014	Apparatus, system, and method for DNA shadow nanolithography	GARCIA HECTOR ALEJANDRO BECERRIL (US); WOOLLEY ADAM T (US)	US184 13108A	31-Jul-2008
US8288282B2	16-Oct-2012	Polishing liquid for metal and method of polishing	NOMURA YUTAKA (JP); FUKASAWA MASATO (JP); NAKAGAWA HIROSHI (JP)	US670 29208A	28-Jul-2008
US10610620B2	7-Apr-2020	Method and devices for preventing restenosis in cardiovascular stents	JOHNSON ALFRED DAVID (US)	US201 113220 522A	29-Aug-2011
US8963292B2	24-Feb-2015	Semiconductor device having backside redistribution layers and method for fabricating the same	OLIVER STEVE (US); FARNWORTH WARREN (US)	US201 313789 305A	7-Mar-2013
US7696062B2	13-Apr-2010	Method of batch integration of low dielectric substrates with MMICs	CHANG CHIEN PATTY PEI LING (US); CHEUNG CHI KONG (US); YAJIMA MELANIE SACHIKO (US); ZENG XIANGLIN (US)	US828 14707A	25-Jul-2007
US8968583B2	3-Mar-2015	Cleaning process for microelectronic dielectric and metal structures	ROTHWELL MARY BETH (US); YU ROY RONGQING (US)	US782 99607A	25-Jul-2007

US8263476B2	11-Sep-2012	Manufacturing method of SOI substrate	OHNUMA HIDETO (JP)	US176 21-Jul-2008 61708A
US8872335B2	28-Oct-2014	Electronic device and method of manufacturing same	HUEBNER HOLGER (DE); FRANOSCH MARTIN (DE)	US781 23-Jul-2007 28207A
US9142632B2	22-Sep-2015	Liquid crystal display device	YAMAZAKI SHUNPEI (JP)	US201 26-Mar-2014 414225 469A
US8455333B2	4-Jun-2013	Method for reuse of wafers for growth of vertically-aligned wire arrays	SPURGEON JOSHUA M (US); PLASS KATHERINE E (US); LEWIS NATHAN S (US); ATWATER HARRY A (US)	US201 16-Jul-2012 213550 395A
US2014134404A1	15-May-2014	METHOD FOR FABRICATING DUAL DAMASCENE PROFILES USING SUB PIXEL-VOTING LITHOGRAPHY AND DEVICES MADE BY SAME	JAIN KANTI (US); REDDY UTTAM (US)	US201 16-Jan-2014 414157 407A
US7829431B2	9-Nov-2010	Method for manufacturing a SOI with plurality of single crystal substrates	TANAKA KOICHIRO (JP)	US216 8-Jul-2008 55308A
US7741224B2	22-Jun-2010	Plasma treatment and repair processes for reducing sidewall damage in low-k dielectrics	JIANG PING (US); MATZ LAURA M (US); OROZCO TERAN ROSA A (US)	US776 11-Jul-2007 13007A
US7875486B2	25-Jan-2011	Solar cells and methods and apparatuses for forming the same including I-layer and N-layer chamber cleaning	CHOI SOO YOUNG (US); LI LIWEI (US)	US170 9-Jul-2008 38708A
US8349705B2	8-Jan-2013	Method of manufacturing semiconductor device	SHIMOMURA AKIHISA (JP); MIZOI TATSUYA (JP); MIYAIRI HIDEKAZU (JP); TANAKA KOICHIRO (JP)	US201 21-Jul-2011 113187 754A
US7670497B2	2-Mar-2010	Oxidant and passivant composition and method for use in treating a microelectronic structure	FITZSIMMONS JOHN A (US); RATH DAVID L (US); PONOTH SHOM (US); BECK MICHAEL (DE)	US774 6-Jul-2007 04107A
US8901002B2	2-Dec-2014	Polishing slurry for metal films and polishing method	TANAKA TAKAAKI (JP); FUKASAWA MASATO (JP); NOBE SHIGERU (JP); SAKURADA TAKAFUMI (JP); SHINODA TAKASHI (JP)	US201 13-Nov-2013 314079 152A
US7678668B2	16-Mar-2010	Manufacturing method of SOI substrate and manufacturing method of semiconductor device	SHIMOMURA AKIHISA (JP); OHNUMA HIDETO (JP); KAKEHATA TETSUYA (JP); MAKINO KENICHIRO (JP)	US213 17-Jun-2008 27108A
US8143617B2	27-Mar-2012	Semiconductor device, semiconductor device manufacturing method and image display device	YAMASHITA YOSHIHISA (JP); NAKATANI SEIICHI (JP)	US667 1-Jul-2008 29708A
US9176353B2	3-Nov-2015	Liquid crystal display device	YAMAZAKI SHUNPEI (JP); SUZUKI YUKIE (JP); KUWABARA HIDEAKI (JP); KIMURA HAJIME (JP); MIYAIRI HIDEKAZU (JP); KUROKAWA YOSHIYUKI (JP); KOBAYASHI SATOSHI (JP)	US213 24-Jun-2008 72808A
US8324077B2	4-Dec-2012	Semiconductor device and manufacturing method thereof	TANADA YOSHIFUMI (JP)	US201 10-Feb-2011 113024 808A

US8361873B2	29-Jan-2013	Method of manufacturing an SOI substrate and method of manufacturing a semiconductor device	OHNUMA HIDETO (JP); IMAHAYASHI RYOTA (JP); IIKUBO YOICHI (JP); MAKINO KENICHIRO (JP); NAGAMATSU SHO (JP)	US762 60010A	19-Apr-2010
US8283238B2	9-Oct-2012	Layer transfer process for semiconductor device	SHIMOMURA AKIHISA (JP); MIZOI TATSUYA (JP); MIYAIRI HIDEKAZU (JP); TANAKA KOICHIRO (JP)	US213 73408A	24-Jun-2008
US7867873B2	11-Jan-2011	Manufacturing method of a semiconductor substrate using a damaged region	MURAKAMI SATOSHI (JP); GODO HIROMICHI (JP); ISOBE ATSUO (JP)	US213 03708A	13-Jun-2008
US7842539B2	30-Nov-2010	Zinc oxide semiconductor and method of manufacturing the same	PARK SEONG JU (KR); OH MIN SUK (KR); HWANG DAE KYU (KR); KWON MIN KI (KR)	US145 37108A	24-Jun-2008
US8590145B2	26-Nov-2013	Method of fabricating a circuit structure	EICHELBERGER CHARLES W (US); KOHL JAMES E (US)	US580 53709A	16-Oct-2009
US8273611B2	25-Sep-2012	Method for manufacturing semiconductor substrate	KAKEHATA TETSUYA (JP); KURIKI KAZUTAKA (JP)	US840 37910A	21-Jul-2010
US9620714B2	11-Apr-2017	Method for forming pattern, method for manufacturing light emitting device, and light emitting device	FUJII GEN (JP); TAKAHASHI ERIKA (JP)	US201 113213 255A	19-Aug-2011
US8850700B2	7-Oct-2014	Wiring board and method for making the same	SUMIDA TAKAYUKI (JP)	US128 23808A	28-May-2008
US2008314872A1	25-Dec-2008	Chemical-Mechanical Polishing Compositions Containing Aspartame And Methods Of Making And Using The Same	LIU YUE (US); SANTORA BRIAN (US)	US104 79808A	17-Apr-2008
US2010183853A1	22-Jul-2010	STRIPPING AGENT FOR RESIST FILM ON/ABOVE CONDUCTIVE POLYMER, METHOD FOR STRIPPING RESIST FILM, AND SUBSTRATE HAVING PATTERNED CONDUCTIVE POLYMER	IHARA TAKASHI (JP)	US663 14208A	27-May-2008
US7927913B2	19-Apr-2011	Electrolyte pattern and method for manufacturing an electrolyte pattern	KUGLER THOMAS (GB)	US155 70808A	9-Jun-2008
US8123976B2	28-Feb-2012	Alkaline aqueous solution composition used for washing or etching substrates	ISHIKAWA NORIO (JP)	US134 40908A	6-Jun-2008
US8143144B2	27-Mar-2012	Semiconductor nanowire and its manufacturing method	KAWASHIMA TAKAHIRO (JP); SAITOH TOHRU (JP)	US451 89808A	4-Jun-2008
US8207010B2	26-Jun-2012	Method for manufacturing photoelectric conversion device	YAMAZAKI SHUNPEI (JP); ARAI YASUYUKI (JP)	US153 72108A	23-May-2008
US8932800B2	13-Jan-2015	Positive photosensitive resin composition and method for forming cured film using the same	TAKITA SATOSHI (JP)	US201 213674 275A	12-Nov-2012

US7863155B2	4-Jan-2011	Manufacturing method of semiconductor substrate and semiconductor device	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP)	US155 29-May-2008 05308A
US8053333B2	8-Nov-2011	Manufacturing method of semiconductor device	MIYAIRI HIDEKAZU (JP)	US781 18-May-2010 87310A
US2010279092A1	4-Nov-2010	MULTIPLE-LAYER FILM AND METHOD FOR MANUFACTURING THE SAME	HWANG JANG YEON (KR); KIM DONG RYUL (KR); KIM GI CHEUL (KR); RYU SANG UK (KR); LEE HO JUN (KR); LEE EUN SIL (KR); MA SEUNG LAC (KR); KO MYEONG GEUN (KR)	US451 2-Jun-2008 77808A
US9362348B2	7-Jun-2016	Method of manufacturing a light emitting, power generating or other electronic apparatus	LOWENTHAL MARK DAVID (US); RAY WILLIAM JOHNSTONE (US); SHOTTON NEIL O (US); BLANCHARD RICHARD A (US); ORAW BRAD (US); LEWANDOWSKI MARK ALLAN (US); BALDRIDGE JEFFREY (US); PEROZZIELLO ERIC ANTHONY (US)	US201 27-Aug-2014 414469 664A
US9349928B2	24-May-2016	Method of manufacturing a printable composition of a liquid or gel suspension of diodes	LOWENTHAL MARK DAVID (US); RAY WILLIAM JOHNSTONE (US); SHOTTON NEIL O (US); BLANCHARD RICHARD A (US); ORAW BRAD (US); LEWANDOWSKI MARK ALLAN (US); BALDRIDGE JEFFREY (US); PEROZZIELLO ERIC ANTHONY (US)	US201 28-Aug-2014 414471 739A
US7825406B2	2-Nov-2010	Organic EL device	YOSHIDA HIDEHIRO (JP); MORI KIYOTAKA (GB); ONO SHINYA (JP); YAMAMURO KEISEI (JP)	US375 30-May-2008 78208A
US8436339B2	7-May-2013	Gate insulating film forming agent for thin-film transistor	MAEDA SHINICHI (JP); KISHIOKA TAKAHIRO (JP)	US451 28-May-2008 73008A
US10873044B2	22-Dec-2020	Method and apparatus for light absorption and charged carrier transport	XUE JIANGENG (US)	US201 5-Sep-2018 816122 511A
US8334338B2	18-Dec-2012	Composition for forming resist lower layer film	YOSHIMURA NAKAATSU (JP); KONNO YOUSUKE (JP)	US599 21-May-2008 69408A
US8110534B2	7-Feb-2012	Cleaning solution for substrate for semiconductor device and process for producing substrate for semiconductor device	KAWASE YASUHIRO (JP); IKEMOTO MAKOTO (JP); ITOU ATSUSHI (JP); ISHIKAWA MAKOTO (JP)	US600 16-May-2008 54508A
US8471272B2	25-Jun-2013	Semiconductor device having a display portion	YAMAZAKI SHUNPEI (JP)	US877 8-Sep-2010 38810A
US2008284048A1	20-Nov-2008	Alignment mark, semiconductor chip including the same, semiconductor package including the chip and methods of fabricating the same	KIM SUNG JAE (KR); PARK YONG BOK (KR); NAM JUNG SOO (KR); LEE IN JUNG (KR); KIM SUNG JUN (KR)	US153 14-May-2008 08808A
US7786494B2	31-Aug-2010	Thin film transistor, method of manufacturing the same, organic light emitting display apparatus comprising the thin film transistor, and method of manufacturing the same	LEE HUN JUNG (KR); JEONG JAE KYEONG (KR); MO YEON GON (KR)	US149 9-May-2008 94408A
US8896071B2	25-Nov-2014	Reducing defects in electronic switching devices	VON WERNE TIMOTHY (GB); RAMSDALE CATHERINE MARY (GB); SIRRINGHAUS HENNING (GB)	US599 12-May-2008 55308A

US7759244B2	20-Jul-2010	Method for fabricating an inductor structure or a dual damascene structure	WANG JENG HO (TW)	US747 21407A	10-May-2007
US8057602B2	15-Nov-2011	Apparatus and method for supporting, positioning and rotating a substrate in a processing chamber	KOELMEL BLAKE (US); LERNER ALEXANDER N (US); RANISH JOSEPH M (US); SANGAM KEDARNATH (US); SORABJI KHURSHED (US)	US172 9308A	21-Jan-2008
US2008277787A1	13-Nov-2008	METHOD AND PAD DESIGN FOR THE REMOVAL OF BARRIER MATERIAL BY ELECTROCHEMICAL MECHANICAL PROCESSING	LIU FENG Q (US); DUBOUST ALAIN (US); WANG YAN (US); HSU WEI YUNG (US); DU TIANBO (US)	US746 13507A	9-May-2007
US8084765B2	27-Dec-2011	Electronic device having a dielectric layer	QI YU (CA); WU YILIANG (CA); LI YUNING (CA); ONG BENG S (CA)	US745 30807A	7-May-2007
US7936567B2	3-May-2011	Wiring board with built-in component and method for manufacturing the same	TAKASHIMA TSUNEAKI (JP); OTSUKA JUN (JP); ORIGUCHI MAKOTO (JP); NAGAO YUKINOBU (JP); NARITH CHY (JP); YAMASAKI KOZO (JP)	US107 97108A	23-Apr-2008
US8822301B2	2-Sep-2014	Profile engineered thin film devices and structures	KAMATH ARVIND (US); SCHER ERIK (US); SMITH PATRICK (US); CHANDRA ADITI (US); MOLESA STEVEN (US)	US201 313791 721A	8-Mar-2013
US9045653B2	2-Jun-2015	Print processing for patterned conductor, semiconductor and dielectric materials	SCHER ERIK (US); MOLESA STEVEN (US); ROCKENBERGER JOERG (US); KAMATH ARVIND (US); MORI IKUO (US); GUO WENZHUO (US); KARSHTEDT DMITRY (US); DIOUMAEV VLADIMIR K (US)	US201 313975 231A	23-Aug-2013
US9153491B2	6-Oct-2015	Methods for forming conductive elements and vias on substrates and for forming multi-chip modules	LAKE RICKIE C (US)	US201 414483 510A	11-Sep-2014
US8426742B2	23-Apr-2013	Connecting terminal, semiconductor package using connecting terminal and method for manufacturing semiconductor package	EJIRI YOSHINORI (JP); HATAKEYAMA SHUICHI (JP); ARIKE SHIGEHARU (JP); HASEGAWA KIYOSHI (JP)	US597 83508A	23-Apr-2008
US9130045B2	8-Sep-2015	Thin film transistor and method for preparing the same	LEE JUNG HYOUNG (KR)	US201 213566 833A	3-Aug-2012
US9732253B2	15-Aug-2017	Polyimide precursor, polyimide, and coating solution for under layer film for image formation	MAEDA SHINICHI (JP); IINUMA YOSUKE (JP)	US201 414175 236A	7-Feb-2014
US8119500B2	21-Feb-2012	Wafer bonding	YANG KU FENG (TW); WU WENG JIN (TW); CHIOU WEN CHIH (TW); YU CHEN HUA (TW)	US740 17807A	25-Apr-2007
US8441472B2	14-May-2013	Method of driving display panel	PARK JAE GUN (KR); LEE GON SUB (KR); LEE SU HWAN (KR); SEO SUNG HO (KR); NAM WOO SIK (KR); SHIN DONG WON (KR); KIM DAL HO (KR); SEUNG HYUN MIN (KR); LEE JONG DAE (KR)	US451 06608A	24-Apr-2008
US2009311474A1	17-Dec-2009	ADHESIVE SHEET FOR WATER JET LASER DICING	TAKAHASHI TOMOKAZU (JP); ASAI FUMITERU (JP); SHINTANI TOSHIO (JP); SASAKI TAKATOSHI (JP); YAMAMOTO AKIYOSHI (JP); MIKI TSUBASA (JP)	US307 88208A	15-Apr-2008
US8551808B2	8-Oct-2013	Methods of patterning a substrate including multilayer antireflection coatings	MARSH EUGENE P (US); MILLWARD DAN B (US)	US201 213613 358A	13-Sep-2012

US2011210441A1	1-Sep-2011	CHIP PACKAGE	LEE JIN YUAN (TW); LO HSIN JING (TW)	US201 11-May-2011 113105 866A
US8003300B2	23-Aug-2011	Methods for fabricating complex micro and nanoscale structures and electronic devices and components made by the same	JAIN KANTI (US); REDDY UTTAM (US)	US734 12-Apr-2007 60007A
US8541299B2	24-Sep-2013	Electrical interconnect forming method	BUCHWALTER STEPHEN LESLIE (US); FURMAN BRUCE K (US); GRUBER PETER A (US); NAH JAE WOONG (US); SHIH DA YUAN (US)	US787 26-May-2010 52710A
US2008248648A1	9-Oct-2008	DEPOSITION PRECURSORS FOR SEMICONDUCTOR APPLICATIONS	THOMPSON DAVID M (US); GEARY JOAN ELIZABETH (US)	US603 1-Apr-2008 3608A
US8642379B2	4-Feb-2014	Thin film transistor	HOTTA SADAYOSHI (JP); BURROUGHS JEREMY HENLEY (GB); WHITING GREGORY LEWIS (US)	US524 3-Apr-2008 02308A
US8048725B2	1-Nov-2011	Method of forming pattern and method of producing electronic element	FUKUDA TOSHIO (JP); NOMOTO AKIHIRO (JP)	US593 21-Dec-2007 84107A
US8083964B2	27-Dec-2011	Using amino acid derivative and surfactant as polishing mixture	YAMADA TORU (JP); KIKUCHI MAKOTO (JP); INABA TADASHI (JP); MATSUNO TAKAHIRO (JP); TOMIGA TAKAMITSU (JP); TAKAHASHI KAZUTAKA (JP)	US559 26-Mar-2008 3008A
US2008242091A1	2-Oct-2008	METAL-POLISHING LIQUID AND POLISHING METHOD	KATO TOMOO (JP); TOMIGA TAKAMITSU (JP); TAKAMIYA SUMI (JP)	US437 6-Mar-2008 2908A
US7585778B2	8-Sep-2009	Method of etching an organic low-k dielectric material	HSIEH CHANG LIN (US); GU BINXI (US)	US691 27-Mar-2007 93007A
US8524607B2	3-Sep-2013	Anisotropically conductive member and method of manufacture	HOTTA YOSHINORI (JP); TOUMA TAKASHI (JP); HATANAKA YUSUKE (JP)	US201 14-Nov-2011 113295 871A
US8206788B2	26-Jun-2012	Method for treating a damaged porous dielectric	SINAPI FABRICE (BE); VAN HOEYMISSSEN JAN ALFONS B (BE)	US824 3-Jul-2007 81807A
US8902123B2	2-Dec-2014	Semiconductor device with wireless communication	DAIRIKI KOJI (JP); IZUMI KONAMI (JP)	US201 28-Dec-2012 213729 270A
US7972935B2	5-Jul-2011	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); KAWAMATA IKUKO (JP); ARAI YASUYUKI (JP)	US858 18-Aug-2010 52510A
US7897505B2	1-Mar-2011	Method for enhancing adhesion between layers in BEOL fabrication	KO CHUNG CHI (TW); LI LIH PING (TW); LU YUNG CHENG (TW); CHANG HUI LIN (TW); LIN CHIH HSIEN (TW)	US727 23-Mar-2007 13307A
US2014290858A1	2-Oct-2014	METHODS OF FORMING A POLYMERIC MATERIAL VIA SELF- ASSEMBLY OF AMPHIPHILIC MATERIAL AND RELATED TEMPLATE STRUCTURES	MILLWARD DAN B (US)	US201 10-Jun-2014 414300 404A
US2010218894A1	2-Sep-2010	Method of Removing Metallic, Inorganic and Organic Contaminants From Chip Passivation Layer Surfaces	BLAIS CLAUDE (CA); DUCHESNE ERIC (CA); LEE KANG WOOK (US); OUI MET SYLVAIN (CA); SCILLA GERALD J (US)	US780 14-May-2010 33910A

US8211543B2	3-Jul-2012	Cushion for polishing pad and polishing pad using the cushion	KATO MITSURU (JP); KIKUCHI HIROFUMI (JP); KATO SHINYA (JP)	US531 64708A	19-Mar-2008
US7563719B2	21-Jul-2009	Dual damascene process	CHEN PO ZEN (TW); WENG TZU CHAN (TW); CHEN CHIEN CHUNG (TW)	US724 28407A	15-Mar-2007
US2010098856A1	22-Apr-2010	METHOD FOR FABRICATING I -III-VI2 COMPOUND THIN FILM USING SINGLE METAL-ORGANIC CHEMICAL VAPOR DEPOSITION PROCESS	CHOI IN HWAN (KR)	US530 88108A	22-Feb-2008
US9130051B2	8-Sep-2015	Semiconductor device including semiconductor layer over insulating layer and manufacturing method thereof	OHNUMA HIDETO (JP); ISOBE ATSUO (JP); GODO HIROMICHI (JP)	US201 213402 212A	22-Feb-2012
US8075945B2	13-Dec-2011	Discharging nanoparticles of a conductive material dispersed in a solvent, drawing a wiring pattern; drying the composition; exposing the composition in which the solvent has been vaporized , to active oxygen, baking; a baking temperature can be reduced	YOSHIZUMI KENSUKE (JP); HARIMA NORIKO (JP); YAMADA TOMOKO (JP)	US384 5308A	27-Feb-2008
US7772690B2	10-Aug-2010	Insulating film	MORITA KENSUKE (JP); WARIISHI KOJI (JP); ASANO AKIRA (JP); MURAMATSU MAKOTO (JP)	US409 8808A	3-Mar-2008
US2008214761A1	4-Sep-2008	INSULATING FILM FORMING COMPOSITION	MORITA KENSUKE (JP); MURAMATSU MAKOTO (JP)	US410 6308A	3-Mar-2008
US7972943B2	5-Jul-2011	Manufacturing method of semiconductor device	MORIWAKA TOMOAKI (JP)	US346 7708A	21-Feb-2008
US8013077B2	6-Sep-2011	Insulating film forming composition and production method of insulating film	MORITA KENSUKE (JP)	US409 5108A	3-Mar-2008
US7470617B2	30-Dec-2008	Treating a liner layer to reduce surface oxides	CHEBIAM RAMANAN (US); CHENG CHIN CHANG (US); WHITNEY DAMIAN (US); SIMKA HARSONO (US)	US712 67407A	1-Mar-2007
US7611926B2	3-Nov-2009	Thermosetting die bonding film	TAKAMOTO NAOHIDE (JP); MISUMI SADAHITO (JP); MATSUMURA TAKESHI (JP); AMANO YASUHIRO (JP); OIKAWA MASAMI (JP); MIKI TSUBASA (JP)	US407 7508A	29-Feb-2008
US8821750B2	2-Sep-2014	Metal polishing slurry and polishing method	AMANOKURA JIN (JP); SAKURADA TAKAFUMI (JP); ANZAI SOU (JP); SHINODA TAKASHI (JP); NOBE SHIGERU (JP)	US527 60708A	22-Feb-2008
US8642246B2	4-Feb-2014	Compositions, coatings and films for tri-layer patterning applications and methods of preparation thereof	KENNEDY JOSEPH (US); XIE SONGYUAN (US); DO KIM (US); MUKHOPADHYAY SUDIP (US)	US838 85407A	14-Aug-2007
US7605062B2	20-Oct-2009	Doped nanoparticle-based semiconductor junction	KAHEN KEITH B (US)	US678 73407A	26-Feb-2007
US2014145264A1	29-May-2014	METHODS OF FORMING WIRING TO TRANSISTOR AND RELATED TRANSISTOR	FRANK DAVID J (US); LATULIPE JR DOUGLAS C (US); STEEN STEVEN E (US); TOPOL ANNA W (US)	US201 414167 298A	29-Jan-2014
US7375011B1	20-May-2008	Ex-situ doped semiconductor transport layer	KAHEN KEITH B (US)	US677 79407A	22-Feb-2007

US2010216299A1	26-Aug-2010	SUBSTRATE PREPARATION FOR ENHANCED THIN FILM FABRICATION FROM GROUP IV SEMICONDUCTOR NANOPARTICLES	POPLAVSKYY DMITRY (US); TERRY MASON (US)	US450 93808A	29-Feb-2008
US7500397B2	10-Mar-2009	Activated chemical process for enhancing material properties of dielectric films	WEIGEL SCOTT JEFFREY (US); O NEILL MARK LEONARD (US); VRTIS RAYMOND NICHOLAS (US); SINATORE DINO (US)	US235 5208A	31-Jan-2008
US9437431B2	6-Sep-2016	Electronic device manufacture	TREFONAS III PETER (US); CHUNG DONG WON (US)	US698 5708A	13-Feb-2008
US2011061687A1	17-Mar-2011	Apparatus for Contained Chemical Surface Treatment	MIKHAYLICHENKO KATRINA (US); RAVKIN MIKE (US); REDEKER FRITZ (US); DE LARIOS JOHN M (US); FREER ERIK M (US); KOROLIK MIKHAIL (US)	US949 76210A	18-Nov-2010
US8274082B2	25-Sep-2012	Electronic semiconductor device based on copper nickel and gallium-tin-zinc-copper-titanium p and n-type oxides, their applications and corresponding manufacture process	FERRA DE PAIVA MARTINS RODRIGO (PT); CORREIA FORTUNATO ELVIRA MARIA (PT)	US525 70307A	5-Feb-2007
US9184221B2	10-Nov-2015	Method of manufacturing semiconductor device	JINBO YASUHIRO (JP); ISA TOSHIYUKI (JP); HONDA TATSUYA (JP)	US201 514669 722A	26-Mar-2015
US8440775B2	14-May-2013	Curable liquid composition, method of coating, inorganic substrate, and semiconductor device	HARIMOTO YUKINARI (JP); ITOH MAKI (JP); KATSOU LIS DIMITRIS ELIAS (US)	US525 42908A	1-Feb-2008
US8441002B2	14-May-2013	Organic semiconductor composite, organic transistor material and organic field effect transistor	MURASE SEIICHIRO (JP); JO YUKARI (JP); TSUKAMOTO JUN (JP); MATA JUNJI (JP)	US524 71408A	25-Jan-2008
US8349714B2	8-Jan-2013	Method of crystallizing semiconductor film and method of manufacturing semiconductor device	TANAKA KOICHIRO (JP); MORIWAKA TOMOAKI (JP); OMATA TAKATSUGU (JP); MOMO JUNPEI (JP)	US972 02908A	10-Jan-2008
US2008206995A1	28-Aug-2008	METAL-POLISHING LIQUID AND POLISHING METHOD THEREWITH	TOMIGA TAKAMITSU (JP); KATO TOMOO (JP)	US184 5608A	23-Jan-2008
US8038972B2	18-Oct-2011	Higher order silane composition, method for manufacturing film-coated substrate, electro-optical device and electronic device	MASUDA TAKASHI (JP); KATO MAKOTO (JP); TANAKA HIDEKI (JP)	US972 30608A	10-Jan-2008
US12136620B2	5-Nov-2024	Optical systems fabricated by printing-based assembly	ROGERS JOHN A (US); NUZZO RALPH (US); MEITL MATTHEW (US); MENARD ETIENNE (US); BACA ALFRED (US); MOTALA MICHAEL (US); AHN JONG HYUN (KR); PARK SANG IL (US); YU CHANG JAE (US); KO HEUNG CHO (KR); STOYKOVICH MARK (US); YOON JONGSEUNG (US)	US202 217690 952A	9-Mar-2022
US8247905B2	21-Aug-2012	Formation of vertical devices by electroplating	DELIGIANNI HARIKLIA (US); HUANG QIANG (US); HUMMEL JOHN P (US); ROMANKIW LUBOMYR T (US); ROTHWELL MARY B (US)	US538 78209A	10-Aug-2009
US7910919B2	22-Mar-2011	Organic light emitting display and fabricating method thereof	YANG TAEHOON (KR); SEO JINWOOK (KR); PARK BYOUNGKEON (KR); LEE KIYONG (KR); JUNG SEIHWAN (KR)	US961 21307A	20-Dec-2007
US7845073B2	7-Dec-2010	Method of manufacturing circuit board embedding thin film capacitor	LEE IN HYUNG (KR); CHUNG YUL KYO (KR); KIM BAE KYUN (KR); LEE SEUNG EUN (KR); LEE JUNG WON (KR)	US125 07A	10-Dec-2007

US8617994B2	31-Dec-2013	Polishing liquid composition	SHIROTA MAMI (JP); YONEDA YASUHIRO (JP)	US201 213717 589A	17-Dec-2012
US8017519B2	13-Sep-2011	Semiconductor device and manufacturing method thereof	ISHIKAWA HIRAKU (JP)	US521 39707A	26-Dec-2007
US2008160204A1	3-Jul-2008	Spontaneous copper seed deposition process for metal interconnects	LAVOIE ADRIEN R (US); BLACKWELL JAMES M (US); MORRISON DARRYL J (CA); SHARMA MANISH (US)	US648 00606A	28-Dec-2006
US8184426B2	22-May-2012	Dielectric element and method for producing the dielectric element	OSADA MINORU (JP); EBINA YASUO (JP); SASAKI TAKAYOSHI (JP)	US448 52807A	20-Dec-2007
US7615483B2	10-Nov-2009	Printed metal mask for UV, e-beam, ion-beam and X-ray patterning	DANIEL JURGEN H (US); ARIAS ANA C (US)	US644 25006A	22-Dec-2006
US7438636B2	21-Oct-2008	Chemical mechanical polishing pad	KULP MARY JO (US); JAMES DAVID B (US); ANTRIM ROBERT F (US)	US644 49306A	21-Dec-2006
US2008148652A1	26-Jun-2008	Compositions for chemical mechanical planarization of copper	SIDDQUI JUNAID AHMED (US); MCCONNELL RACHEL DIANNE (US); USMANI SAIFI (US)	US643 30906A	21-Dec-2006
US2012024230A1	2-Feb-2012	APPARATUSES AND SYSTEMS FOR FABRICATING THREE DIMENSIONAL INTEGRATED CIRCUITS	LI SHIJIAN (US); REDEKER FRITZ (US); DORDI YEZDI (US)	US201 113253 829A	5-Oct-2011
US2008149273A1	26-Jun-2008	PLASMA PROCESSING APPARATUS	GOMI KAZUHIRO (JP)	US959 81807A	19-Dec-2007
US8405225B2	26-Mar-2013	Three-dimensional integrated circuits with protection layers	YU CHEN HUA (TW); CHIOU WEN CHIH (TW); WU WENG JIN (TW); TU HUNG JUNG (TW); YANG KU FENG (TW)	US201 213437 533A	2-Apr-2012
US7977244B2	12-Jul-2011	Semiconductor manufacturing process	LAI YU TSUNG (TW); HUANG CHUN JEN (TW); YAU JYH CHERNG (TW); LIAO JIUNN HSIUNG (TW)	US611 89006A	18-Dec-2006
US2011306203A1	15-Dec-2011	INTERCONNECT STRUCTURE AND METHOD OF MANUFACTURING A DAMASCENE STRUCTURE	DORDI YEZDI (US); BOYD JOHN M (US); REDEKER FRITZ C (US); THIE WILLIAM (US); ARUNAGIRI TIRUCHIRAPALLI (US); YOON HYUNGSUK ALEXANDER (US)	US201 113218 035A	25-Aug-2011
US8471172B2	25-Jun-2013	Elimination of short circuits between conductors by laser ablation	WATTS JIM (GB); CAIN PAUL A (GB); BANACH MIKE J (GB)	US518 59907A	6-Dec-2007
US7927966B2	19-Apr-2011	Method of manufacturing openings in a substrate, a via in substrate, and a semiconductor device comprising such a via	NGUYEN HOANG VIET (BE); BENNEBROEK MARTINUS T (NL)	US518 68407A	10-Dec-2007
US7952170B2	31-May-2011	System including semiconductor components having through interconnects and back side redistribution conductors	PRATT DAVID S (US)	US837 55110A	16-Jul-2010

US2008199814A1	21-Aug-2008	Device manufacturing process utilizing a double patterning process	BRZOWY DAVE (US); SARUBBI THOMAS R (US); MALIK SANJAY (US); SPAZIANO GREGORY (US)	US999 10407A	4-Dec-2007
US9343330B2	17-May-2016	Compositions for polishing aluminum/copper and titanium in damascene structures	BRUSIC VLASTA (US); ZHOU RENJIE (US); FEENEY PAUL (US); THOMPSON CHRISTOPHER (US)	US634 57606A	6-Dec-2006
US7763901B2	27-Jul-2010	Electronic device, method of producing the same, light-emitting diode display unit, and method of producing the same	TOMODA KATSUHIRO (JP)	US877 49207A	23-Oct-2007
US7994503B2	9-Aug-2011	Cu alloy wiring film, TFT element for flat-panel display using the Cu alloy wiring film, and Cu alloy sputtering target for depositing the Cu alloy wiring film	HINO AYA (JP); TOMIHISA KATSUFUMI (JP); GOTOU HIROSHI (JP); ONISHI TAKASHI (JP)	US517 36207A	4-Dec-2007
US8507180B2	13-Aug-2013	Chemically amplified positive-type photoresist composition for thick film, chemically amplified dry film for thick film, and method for production of thick film resist pattern	WASHIO YASUSHI (JP); OHGAKE MITSUAKI (JP); UNO KAZUhide (JP); MISUMI KOICHI (JP); SENZAKI TAKAHIRO (JP); SAITO KOJI (JP)	US515 87207A	18-Oct-2007
US9562179B2	7-Feb-2017	Adhesive composition, adhesive sheet and production process for semiconductor device	SAIKI NAOYA (JP); ICHIKAWA ISAO (JP); SHIZUHATA HIRONORI (JP); YAMAZAKI OSAMU (JP)	US201 514868 421A	29-Sep-2015
US2008124917A1	29-May-2008	Method of manufacturing a semiconductor device having air gaps	OH JUN HWAN (KR); CHUNG JU HYUCK (KR); KIM IL GOO (KR); KIM HYOUNG SIK (KR)	US986 23607A	20-Nov-2007
US8895960B2	25-Nov-2014	Electrode covering material, electrode structure and semiconductor device	MURATA MASAKI (JP); YONEYA NOBUHIDE (JP); KIMURA NORIO (JP)	US515 58507A	21-Nov-2007
US8004293B2	23-Aug-2011	Plasma processing chamber with ground member integrity indicator and method for using the same	WHITE JOHN M (US); SORENSEN CARL (US)	US561 46306A	20-Nov-2006
US9360509B2	7-Jun-2016	Nanoscale sensors with nanoporous material	NAUGHTON MICHAEL J (US); CAI DONG (US); RIZAL BINOD (US); CHILES THOMAS (US); ZHAO HUAIZHOU (US)	US201 214005 205A	21-Mar-2012
US7959738B2	14-Jun-2011	Method of removing photoresist and method of manufacturing a semiconductor device	KANG DAE HYUK (KR); LEE HYO SAN (KR); HAN DONG GYUN (KR); HONG CHANG KI (KR); LEE KUN TACK (KR)	US984 34007A	16-Nov-2007
US7838197B2	23-Nov-2010	Photosensitive composition	SHIBASAKI YOKO (JP); KATO KENJI (JP); ARIMA MASAO (JP)	US939 93307A	14-Nov-2007
US9263361B2	16-Feb-2016	Semiconductor device having a vertical interconnect structure using stud bumps	PAGAILA REZA A (SG); DO BYUNG TAI (SG); HUANG SHUANGWU (SG); PENDSE RAJENDRA D (US)	US201 213446 863A	13-Apr-2012
US7589018B2	15-Sep-2009	Method of forming contact hole, method of manufacturing wiring board, method of manufacturing semiconductor device, and method of manufacturing electro-optical device	MORIYA SOICHI (JP); KAWASE TAKEO (JP); HARADA MITSUAKI (JP); SAEKI TAKEHISA (JP); OKUYAMA TOMOYUKI (JP); HOKARI HIROFUMI (JP); AOKI TAKASHI (JP)	US973 19307A	5-Oct-2007
US2008122078A1	29-May-2008	Systems and methods to passivate on-die redistribution interconnects	HE JUN (US); LEE KEVIN J (US); GADRE KAUSTABH (US); JOSHI SUBHASH (US)	US595 64506A	8-Nov-2006

US2008125342A1	29-May-2008	FORMULATIONS FOR CLEANING MEMORY DEVICE STRUCTURES	VISINTIN PAMELA M (US); KORZENSKI MICHAEL B (US)	US935 6-Nov-2007 83807A
US8242002B2	14-Aug-2012	Method for manufacturing semiconductor device	SHIMOMURA AKIHISA (JP); MIYAIRI HIDEKAZU (JP); JINBO YASUHIRO (JP)	US201 31-Aug-2011 113222 076A
US2008108262A1	8-May-2008	ADHESIVE SHEET FOR WATER JET LASER DICING	ASAI FUMITERU (JP); SASAKI TAKATOSHI (JP); SHINTANI TOSHIO (JP); TAKAHASHI TOMOKAZU (JP); MIKI TSUBASA (JP); YAMAMOTO AKIYOSHI (JP)	US931 31-Oct-2007 12407A
US2008182095A1	31-Jul-2008	ADHESIVE SHEET FOR WATER JET LASER DICING	ASAI FUMITERU (JP); SASAKI TAKATOSHI (JP); MIKI TSUBASA (JP); TAKAHASHI TOMOKAZU (JP); SHINTANI TOSHIO (JP); YAMAMOTO AKIYOSHI (JP)	US931 31-Oct-2007 16807A
US2010028588A1	4-Feb-2010	Heat-peelable pressure-sensitive adhesive sheet and method of recovering adherend	KIUCHI KAZUYUKI (JP)	US311 18-Oct-2007 97407A
US8206892B2	26-Jun-2012	Solution processed thin films and laminates, devices comprising such thin films and laminates, and method for their use and manufacture	KESZLER DOUGLAS A (US); ANDERSON JEREMY (US); STOWERS JASON K (US)	US836 14-Jul-2010 49210A
US7476615B2	13-Jan-2009	Deposition process for iodine-doped ruthenium barrier layers	HAN JOSEPH H (US); SIMKA HARSONO S (US); LAVOIE ADRIEN R (US); DOMINGUEZ JUAN E (US); PLOMBON JOHN J (US)	US591 1-Nov-2006 79206A
US8105747B2	31-Jan-2012	Positive resist composition and method of forming resist pattern	UTSUMI YOSHIYUKI (JP); SHIMIZU HIROAKI (JP); OHSHITA KYOKO (JP); YOSHII YASUHIRO (JP)	US447 15-Oct-2007 43207A
US8795549B2	5-Aug-2014	Printable medium for etching oxidic, transparent and conductive layers	STOCKUM WERNER (DE); KUEBELBECK ARMIN (DE)	US447 5-Oct-2007 76307A
US9244355B2	26-Jan-2016	Compositions and processes for immersion lithography	CAPOREALE STEFAN J (US); BARCLAY GEORGE G (US); WANG DEYAN (US); JIA LI (US)	US978 30-Oct-2007 91007A
US2011259627A1	27-Oct-2011	Circuit board with buried circuit pattern	JUNG HOE KU (KR); YOO JE GWANG (KR); KANG MYUNG SAM (KR); KIM JI EUN (KR); PARK JEONG WOO (KR); PARK JUNG HYUN (KR)	US201 1-Jul-2011 113067 883A
US7767595B2	3-Aug-2010	Manufacturing method of semiconductor device	TANAKA KOICHIRO (JP); YAMAZAKI SHUNPEI (JP)	US876 23-Oct-2007 98107A
US8687407B2	1-Apr-2014	Semiconductor device including storage device and method for driving the same	TOKUNAGA HAJIME (JP); SAITO TOSHIHIKO (JP)	US201 30-Aug-2012 213599 272A
US8105998B2	31-Jan-2012	Liquid composition for removing photoresist residue and polymer residue	OHWADA TAKUO (JP)	US311 24-Oct-2007 95107A
US8859187B2	14-Oct-2014	Method of forming resist pattern and negative resist composition	TANAKA KEN (JP); ABE SHO (JP); YOKOI SHIGERU (JP)	US438 19-Oct-2007 90607A

US2008118764A1	22-May-2008	ADHESIVE SHEET FOR PROCESSING SEMICONDUCTOR WAFERS AND/OR SUBSTRATES	SHINTANI TOSHIO (JP); YAMAMOTO AKIYOSHI (JP); ASAI FUMITERU (JP); HASHIMOTO KOUICHI (JP)	US875 16907A	19-Oct-2007
US7902610B2	8-Mar-2011	Semiconductor device and method for manufacturing same	TAI KAORI (JP); TSUKAMOTO MASANORI (JP); NAKATA MASASHI (JP); OSHIYAMA ITARU (JP)	US712 80910A	25-Feb-2010
US7534628B2	19-May-2009	Method for forming semiconductor device and method for forming photovoltaic device	TAKAI YASUYOSHI (JP); SAWAYAMA TADASHI (JP); MORIYAMA KOICHIRO (JP)	US871 53407A	12-Oct-2007
US7842620B2	30-Nov-2010	Method for manufacturing semiconductor device using quadruple-layer laminate	TAKEI SATOSHI (JP); NAKAJIMA MAKOTO (JP); SAKAIDA YASUSHI (JP); IMAMURA HIKARU (JP); HASHIMOTO KEISUKE (JP); KISHIOKA TAKAHIRO (JP)	US311 74207A	12-Oct-2007
US8227172B2	24-Jul-2012	Method of producing semiconductor device using resist underlayer film by photo-crosslinking curing	HORIGUCHI YUSUKE (JP); TAKEI SATOSHI (JP); SHINJO TETSUYA (JP)	US311 74507A	10-Oct-2007
US7968453B2	28-Jun-2011	Method for manufacturing display device, and etching apparatus	TANAKA KOICHIRO (JP); MORISUE MASAFUMI (JP)	US870 53007A	11-Oct-2007
US8822814B2	2-Sep-2014	Composition for electrode formation and method for forming electrode by using the composition	HAYASHI TOSHIHARU (JP); YAMASAKI KAZUHIKO (JP); TAKATA YOSHIAKI (JP)	US444 72007A	10-Oct-2007
US2008083427A1	10-Apr-2008	POST ETCH RESIDUE REMOVAL FROM SUBSTRATES	BLOCK JOY (US); SCRANTON DANA (US); MEUCHEL CRAIG (US)	US869 09607A	9-Oct-2007
US7982322B2	19-Jul-2011	Liquid resin composition for electronic part sealing, and electronic part apparatus utilizing the same	TSUCHIDA SATORU (JP); HAGIWARA SHINSUKE (JP); TENDOU KAZUYOSHI (JP)	US444 44907A	28-Sep-2007
US7928001B2	19-Apr-2011	Electronic device and method of manufacturing the same	KURITA YOICHIRO (JP); SOEJIMA KOJI (JP); KAWANO MASAYA (JP)	US865 75007A	2-Oct-2007
US8685796B2	1-Apr-2014	Electronic device and method of manufacturing the same	KURITA YOICHIRO (JP); SOEJIMA KOJI (JP); KAWANO MASAYA (JP)	US856 73007A	18-Sep-2007
US7989361B2	2-Aug-2011	Composition for dielectric thin film, metal oxide dielectric thin film using the same and preparation method thereof	SEON JONG BAEK (KR); JEONG HYUN DAM (KR); LEE SANG YOON (KR)	US831 38007A	31-Jul-2007
US7713836B2	11-May-2010	Method for forming conductive layer and substrate having the same, and method for manufacturing semiconductor device	AOKI TOMOYUKI (JP); TSURUME TAKUYA (JP); YAMADA DAIKI (JP)	US902 79907A	25-Sep-2007
US8618580B2	31-Dec-2013	Integrated circuit chips with fine-line metal and over-passivation metal	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW); CHOU CHIEN KANG (TW)	US201 313735 987A	7-Jan-2013
US8120113B2	21-Feb-2012	Metal line in semiconductor device	CHOI YOUNG SOO (KR); KIM GYU HYUN (KR)	US688 73810A	15-Jan-2010

US8206768B2	26-Jun-2012	Oxide material, patterning substrate, method of forming a pattern, method of producing an imprint transfer mold, method of producing a recording medium, imprint transfer mold, and recording medium	FUJIMURA MEGUMI (JP); HOSODA YASUO (JP)	US443 03907A	28-Sep-2007
US2008078424A1	3-Apr-2008	METHODS TO ACCELERATE PHOTOIMAGEABLE MATERIAL STRIPPING FROM A SUBSTRATE	GOUK ROMAN (US); PETERS PHILLIP (US); CHEN HAN WEN (US); PAPANU JAMES S (US)	US536 29206A	28-Sep-2006
US7473634B2	6-Jan-2009	Method for integrated substrate processing in copper metallization	SUZUKI KENJI (US)	US536 16106A	28-Sep-2006
US2011121243A1	26-May-2011	ANISOTROPIC CONDUCTIVE ADHESIVE COMPOSITION, ANISOTROPIC CONDUCTIVE FILM, CIRCUIT MEMBER CONNECTING STRUCTURE AND METHOD FOR MANUFACTURING COATED PARTICLES	TAKANE NOBUAKI (JP)	US201 113021 924A	7-Feb-2011
US8028649B2	4-Oct-2011	Liquid ejection apparatus and resist pattern forming method	INOUE SEIICHI (JP)	US902 31307A	20-Sep-2007
US2009278134A1	12-Nov-2009	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SEMICONDUCTOR DEVICE	OHMI TADAHIRO (JP); SUGITANI KOICHI (JP)	US442 33007A	21-Sep-2007
US8372762B2	12-Feb-2013	Manufacturing method of semiconductor device and laser processing apparatus	OISHI HIROTADA (JP); TANAKA KOICHIRO (JP)	US793 22910A	3-Jun-2010
US2010029057A1	4-Feb-2010	SILICONE RESIN COMPOSITION AND METHOD OF FORMING A TRENCH ISOLATION	IWASAWA HARUO (JP); SAKAI TATSUYA (JP); MATSUKI YASUO (JP); TAMAKI KENTARO (JP)	US442 40507A	21-Sep-2007
US9349900B2	24-May-2016	Release strategies for making transferable semiconductor structures, devices and device components	ROGERS JOHN A (US); NUZZO RALPH G (US); MEITL MATTHEW (US); KO HEUNG CHO (US); YOON JONGSEUNG (US); MENARD ETIENNE (US); BACA ALFRED J (US)	US201 414246 962A	7-Apr-2014
USRE46136E	6-Sep-2016	Heating apparatus with enhanced thermal uniformity and method for making thereof	MARINER JOHN (US); SANE AJIT (US); EBATA TOSHIKI (JP); SCHAEPKENS MARC (US); LIU XIANG (US); FAN WEI (US)	US201 313790 423A	8-Mar-2013
US7553758B2	30-Jun-2009	Method of fabricating interconnections of microelectronic device using dual damascene process	PARK WAN JAE (KR); CHOI HYUNG YOON (KR); LIN YI HSIUNG (TW); CHEN TONG QING (CN)	US532 71906A	18-Sep-2006
US2008070340A1	20-Mar-2008	Image sensor using thin-film SOI	BORRELLI NICHOLAS FRANCIS (US); BRADY MICHAEL DONAVON (US); BURT RONALD LEE (US); GADKAREE KISHOR PURUSHOTTAM (US)	US520 95806A	14-Sep-2006
US8008767B2	30-Aug-2011	Semiconductor device	WADA MASAHIRO (JP); TANAKA HIROYUKI (JP); HIROSE HIROSHI (JP); ITOH TEPPEI (JP); TACHIBANA KENYA (JP)	US947 7507A	5-Sep-2007
US7466027B2	16-Dec-2008	Interconnect structures with surfaces roughness improving liner and methods for fabricating the same	KO CHUNG CHI (TW); LIN KENG CHU (TW); CHOU CHIA CHENG (TW)	US531 30406A	13-Sep-2006
US2010019365A1	28-Jan-2010	DICING/DIE BONDING FILM	MATSUMURA TAKESHI (JP); MISUMI SADAHITO (JP)	US440 49509A	9-Mar-2009

US8975759B2	10-Mar-2015	Manufacturing method of semiconductor device, adhesive sheet used therein, and semiconductor device obtained thereby	MISUMI SADAHITO (JP); MATSUMURA TAKESHI (JP); HOSOKAWA KAZUHITO (JP); KONDO HIROYUKI (JP)	US201 213615 221A	13-Sep-2012
US9129907B2	8-Sep-2015	Onium-containing CMP compositions and methods of use thereof	WHITE MICHAEL L (US); CHEN ZHAN (US)	US517 90906A	8-Sep-2006
US8857805B2	14-Oct-2014	Method, apparatus for holding and treatment of a substrate	LACKNER GERALD (AT); MAIER CHRISTIAN (AT); SANTOS RODRIGUEZ FRANCISCO JAVIER (AT)	US851 97607A	7-Sep-2007
US2011091731A1	21-Apr-2011	SEMICONDUCTOR THIN FILMS FORMED FROM GROUP IV NANOPARTICLES	KELMAN MAXIM (US); YU PINGRONG (US); JAYARAMAN MANIKANDAN (US); POPLAVSKYY DMITRY (US); JURBERGS DAVID (US); LEMMI FRANCESCO (US); ANTONIADIS HOMER (US)	US967 37810A	14-Dec-2010
US2010183818A1	22-Jul-2010	APPARATUS AND METHOD OF DEPOSITING FILMS USING BIAS AND CHARGING BEHAVIOR OF NANOPARTICLES FORMED DURING CHEMICAL VAPOR DEPOSITION	HWANG NONG MOON (KR); KIM CHAN SOO (KR); LEE JAE IK (KR); CHUNG YUNG BIN (KR); YOUN WOONG KYU (KR)	US440 30407A	6-Sep-2007
US7662703B2	16-Feb-2010	Method for manufacturing crystalline semiconductor film and semiconductor device	MORIWAKA TOMOAKI (JP); TANAKA KOICHIRO (JP)	US892 96807A	28-Aug-2007
US8216892B2	10-Jul-2012	Method for manufacturing crystalline semiconductor film	MORIWAKA TOMOAKI (JP); TANAKA KOICHIRO (JP)	US201 113092 173A	22-Apr-2011
US8212254B2	3-Jul-2012	Thin film transistor, manufacturing method thereof, and semiconductor device	MIYAIRI HIDEKAZU (JP)	US896 00507A	29-Aug-2007
US8293593B2	23-Oct-2012	Method for manufacturing semiconductor device and method for manufacturing display device	MORISUE MASAFUMI (JP); TANAKA KOICHIRO (JP)	US777 58010A	11-May-2010
US7985621B2	26-Jul-2011	Method and apparatus for making semiconductor packages	CHAN VINCENT K (CA); MCLELLAN NEIL (CA); TOPACIO RODEN (CA)	US469 25606A	31-Aug-2006
US8012875B2	6-Sep-2011	Method and apparatus for workpiece surface modification for selective material deposition	VASILEV VLADISLAV (RU)	US757 65210A	9-Apr-2010
US8409905B2	2-Apr-2013	Method of forming display device that includes removing mask to form opening in insulating film	TANAKA KOICHIRO (JP)	US201 113270 271A	11-Oct-2011
US2008057253A1	6-Mar-2008	Adhesive sheet for water jet laser dicing	SASAKI TAKATOSHI (JP); MIKI TSUBASA (JP); ASAI FUMITERU (JP); TAKAHASHI TOMOKAZU (JP); SHINTANI TOSHIO (JP); YAMAMOTO AKIYOSHI (JP)	US892 56707A	24-Aug-2007
US8481247B2	9-Jul-2013	Resist underlayer film forming composition containing liquid additive	HORIGUCHI YUSUKE (JP); SHINJO TETSUYA (JP); TAKEI SATOSHI (JP)	US310 32807A	20-Aug-2007
US7927991B2	19-Apr-2011	Method for manufacturing semiconductor device	MIYAIRI HIDEKAZU (JP); JINBO YASUHIRO (JP); HIGA EIJI (JP); YAMAZAKI SHUNPEI (JP)	US839 34907A	15-Aug-2007

US8043969B2	25-Oct-2011	Method for manufacturing semiconductor device	MIYAIRI HIDEKAZU (JP); TANAKA KOICHIRO (JP); SHOJI HIRONOBU (JP); YAMAZAKI SHUNPEI (JP)	US827 30-Jun-2010 34710A
US7482289B2	27-Jan-2009	Methods and apparatus for depositing tantalum metal films to surfaces and substrates	YONKER CLEMENT R (US); MATSON DEAN W (US); BAYS JOHN T (US)	US511 25-Aug-2006 54806A
US7727847B2	1-Jun-2010	Method for manufacturing display device	TANAKA KOICHIRO (JP); ARAI YASUYUKI (JP)	US840 16-Aug-2007 04307A
US8796774B2	5-Aug-2014	Printed non-volatile memory	KAMATH ARVIND (US); SMITH PATRICK (US); CLEEVES JAMES MONTAGUE (US)	US201 14-Aug-2012 213585 673A
US8664047B2	4-Mar-2014	Integrated circuit tampering protection and reverse engineering prevention coatings and methods	LOWER NATHAN P (US); BOONE ALAN P (US); WILCOXON ROSS K (US)	US201 16-Dec-2011 113329 068A
US2008057306A1	6-Mar-2008	Adhesive sheet for laser processing	SASAKI TAKATOSHI (JP); TAKAHASHI TOMOKAZU (JP); ASAI FUMITERU (JP); YAMAMOTO AKIYOSHI (JP); SHINTANI TOSHIO (JP)	US892 21-Aug-2007 21607A
US8603318B2	10-Dec-2013	Method of selectively removing conductive material	KLEIN RITA J (US); COLLINS DALE W (US); MORGAN PAUL (US); GREELEY JOSEPH N (US); SINHA NISHANT (US)	US201 2-May-2011 113098 572A
US2008045016A1	21-Feb-2008	CLEANING COMPOSITION, CLEANING METHOD, AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE	ANDOU MICHIAKI (JP); KONNO TOMOHISA (JP); SHIDA HIROTAKA (JP); UCHIKURA KAZUHITO (JP); KURASHIMA NOBUYUKI (JP); MINAMIHABA GAKU (JP); TATEYAMA YOSHIKUNI (JP); YANO HIROYUKI (JP)	US833 3-Aug-2007 53407A
US2008182413A1	31-Jul-2008	SELECTIVE CHEMISTRY FOR FIXED ABRASIVE CMP	MENK GREGORY E (US); JACKSON ROBERT L (US); LEUNG GARLEN C (US); PRABHU GOPALAKRISHNA B (US); MCREYNOLDS PETER (US); IYER ANAND N (US)	US839 15-Aug-2007 04807A
US9196641B2	24-Nov-2015	Printed dopant layers	KAMATH ARVIND (US); CLEEVES JAMES MONTAGUE (US); ROCKENBERGER JOERG (US); SMITH PATRICK (US); ZURCHER FABIO (US)	US201 2-Oct-2012 213633 816A
US8304780B2	6-Nov-2012	Printed dopant layers	KAMATH ARVIND (US); CLEEVES JAMES MONTAGUE (US); ROCKENBERGER JOERG (US); SMITH PATRICK (US); ZUERCHER FABIO (US)	US797 9-Jun-2010 27410A
US11031310B2	8-Jun-2021	Chip package	LIN MOU SHIUNG (TW)	US201 11-Jan-2018 815868 715A
US2008038467A1	14-Feb-2008	Nanostructured pattern method of manufacture	JAGANNATHAN RAMESH (US); RAO YUANQIAO (US); MI XIANG DONG (US)	US502 11-Aug-2006 76406A
US2015364350A1	17-Dec-2015	HEATING AND COOLING OF SUBSTRATE SUPPORT	WHITE JOHN M (US); TINER ROBIN L (US)	US201 24-Aug-2015 514834 324A
US9166123B2	20-Oct-2015	Light emitting device package and method for manufacturing the same	KIM GEUN HO (KR); WON YU HO (KR); PARK CHIL KEUN (KR); SONG KI CHANG (KR)	US755 7-Apr-2010 82210A

US7867888B2	11-Jan-2011	Flip-chip package substrate and a method for fabricating the same	WANG HSIEN SHOU (TW)	US808 02807A	6-Jun-2007
US7989030B2	2-Aug-2011	Silicone resin and silicone composition	BOISVERT RONALD (US); BUJALSKI DUANE (US); LI ZHONGTAO (US); SU KAI (US)	US375 43607A	23-Jul-2007
US7569469B2	4-Aug-2009	Dielectric nanostructure and method for its manufacture	KIM HO CHEOL (US); MILLER ROBERT D (US)	US499 13206A	3-Aug-2006
US7815815B2	19-Oct-2010	Method and apparatus for processing the peripheral and edge portions of a wafer after performance of a surface treatment thereon	MIYATA KOJI (US)	US497 14306A	1-Aug-2006
US8349543B2	8-Jan-2013	Pattern-forming method, metal oxide film-forming material and method for using the metal oxide film-forming material	MATSUMARU SHOGO (JP); WATANABE RYOJI (JP); OGATA TOSHIYUKI (JP)	US373 71407A	18-Jun-2007
US8703579B2	22-Apr-2014	Method of manufacturing semiconductor device	MIYAIRI HIDEKAZU (JP); SHOJI HIRONOBU (JP); SHIMOMURA AKIHISA (JP); HIGA EIJI (JP); MORIWAKA TOMOAKI (JP); YAMAZAKI SHUNPEI (JP)	US201 113186 803A	20-Jul-2011
US8173543B2	8-May-2012	Method of forming hole in semiconductor device using mask	SEKI KATSUYUKI (JP); SUZUKI AKIRA (JP); KAMEYAMA KOUJIRO (JP); OIKAWA TAKAHIRO (JP)	US878 79607A	26-Jul-2007
US7501346B2	10-Mar-2009	For chemical-mechanical planarization of silicon dioxide-containing substrates; condensation-polymerized silica, gallium nitrate, biocides, water	GRUMBINE STEVEN K (US)	US491 05506A	21-Jul-2006
US9257562B2	9-Feb-2016	Semiconductor device	SHIMOMURA AKIHISA (JP); MIYAIRI HIDEKAZU (JP); ISAKA FUMITO (JP); JINBO YASUHIRO (JP); MARUYAMA JUNYA (JP)	US201 514636 589A	3-Mar-2015
US7553730B2	30-Jun-2009	Methods of fabrication employing nanoscale mandrels	BARTH PHILLIP W (US); KOPLEY THOMAS EDWARD (US); MOLL NICOLAS J (US); CHANG YING LAN (US)	US487 55006A	14-Jul-2006
US2010003827A1	7-Jan-2010	METHOD AND DEVICE FOR ETCHING A SUBSTRATE BY MEANS OF PLASMA	KESSELS WILHELMUS MATHIJS MARIE (NL); VAN DE SANDEN MAURITIUS CORNELIS (NL); BLAUW MICHIEL ALEXANDER (NL); ROOZEBOOM FREDDY (NL)	US373 39407A	12-Jul-2007
US8778217B2	15-Jul-2014	Polishing slurry for CMP, and polishing method	KIMURA TADAHIRO (JP)	US307 44007A	4-Jul-2007
US8916230B2	23-Dec-2014	Method for manufacturing display device	YAMAZAKI SHUNPEI (JP); SHOJI HIRONOBU (JP); KAWAMATA IKUKO (JP)	US201 113284 584A	28-Oct-2011
US2008020582A1	24-Jan-2008	Method of forming an opening in a semiconductor device and method of manufacturing a semiconductor device using the same	BAI KEUN HEE (KR)	US822 05807A	2-Jul-2007
US2008001528A1	3-Jan-2008	Color conversion substrate and color display	EIDA MITSURU (JP)	US488 72406A	19-Jul-2006

US8021964B2	20-Sep-2011	Method of producing segmented chips	AKIYAMA RYOTA (JP); SAITO KAZUTA (JP)	US303 81307A	18-Jun-2007
US8618561B2	31-Dec-2013	Methods for depositing nanomaterial, methods for fabricating a device, and methods for fabricating an array of devices	COE SULLIVAN SETH (US)	US317 25008A	19-Dec-2008
US7718995B2	18-May-2010	Nanowire, method for fabricating the same, and device having nanowires	KAWASHIMA TAKAHIRO (JP); SAITOH TOHRU (JP); HARADA KENJI (JP)	US812 35707A	18-Jun-2007
US9064827B2	23-Jun-2015	Method for manufacturing semiconductor device	FUJII TERUYUKI (JP)	US806 72007A	4-Jun-2007
US8422289B2	16-Apr-2013	Fabrication method of nanoparticles by chemical curing	KIM YOUNG HO (KR); DONG WENGUO (KR); KIM GUN HONG (KR); YOON JUN RO (KR)	US303 07907A	5-Jun-2007
US8394457B2	12-Mar-2013	Precursor composition for porous thin film, method for preparation of the precursor composition, porous thin film, method for preparation of the porous thin film, and semiconductor device	FUJII NOBUTOSHI (JP); NAKAYAMA TAKAHIRO (JP); KOHMURA KAZUO (JP); TANAKA HIROFUMI (JP)	US303 24007A	16-May-2007
US2007278453A1	6-Dec-2007	Electrically conductive polymers and method of making electrically conductive polymers	ZAHN STEFFEN (US); FORD MICHAEL EDWARD (US)	US446 00006A	2-Jun-2006
US7682972B2	23-Mar-2010	Advanced multilayer coreless support structures and method for their fabrication	HURWITZ DROR (IL); FARKASH MORDECHAY (IL); IGNER EVA (IL); STATNIKOV BORIS (IL); MICHAELI BENNY (IL)	US421 60006A	1-Jun-2006
US2007277736A1	6-Dec-2007	Method for manufacturing substrate, and vapor deposition apparatus used for the same	OTANI MINORU (JP); MORINAGA YUKARI (JP)	US807 80707A	30-May-2007
US2007284758A1	13-Dec-2007	Electronics package and associated method	ZHANG JIAN (US); SIMONE DAVIDE L (US); CARTER CHRISTOPHER M (US); MEYER LAURA J (US); BECKER CHARLES A (US); SCHATTENMANN FLORIAN J (US); TONAPI SANDEEP S (US); RUBINSZTAJN SLAWOMIR (US); KEIMEL CHRISTOPHER F (US)	US438 65706A	22-May-2006
US7566661B2	28-Jul-2009	Electroless treatment of noble metal barrier and adhesion layer	LAVOIE ADRIEN R (US)	US438 79306A	22-May-2006
US7781267B2	24-Aug-2010	Enclosed nanotube structure and method for forming	GAMBINO JEFFREY PETER (US); NGUYEN SON VAN (US)	US419 32906A	19-May-2006
US8669183B2	11-Mar-2014	Manufacturing method of semiconductor device	SUZUKI AKIRA (JP); SEKI KATSUYUKI (JP); KAMEYAMA KOUJIRO (JP); OIKAWA TAKAHIRO (JP)	US802 10707A	18-May-2007
US7960245B2	14-Jun-2011	Dual wired integrated circuit chips	BERNSTEIN KERRY (US); DALTON TIMOTHY JOSEPH (US); GAMBINO JEFFREY PETER (US); JAFFE MARK DAVID (US); KARTSCHOKE PAUL DAVID (US); STAMPER ANTHONY KENDALL (US)	US295 7508A	12-Feb-2008

US2007264814A1	15-Nov-2007	METHOD FOR FORMING METAL WIRING LINE, METHOD FOR MANUFACTURING ACTIVE MATRIX SUBSTRATE, DEVICE, ELECTRO-OPTICAL DEVICE, AND ELECTRONIC APPARATUS	HIRAI TOSHIMITSU (JP); MORIYA KATSUYUKI (JP)	US737 16507A	19-Apr-2007
US9054146B2	9-Jun-2015	Substrate transfer equipment and high speed substrate processing system using the same	WI SOON IM (KR)	US298 97207A	1-May-2007
US2007257261A1	8-Nov-2007	METHOD FOR FORMING METAL WIRING, METHOD FOR MANUFACTURING ACTIVE MATRIX SUBSTRATE, DEVICE, ELECTRO-OPTICAL DEVICE, AND ELECTRONIC APPARATUS	HIRAI TOSHIMITSU (JP); MORIYA KATSUYUKI (JP)	US741 92507A	30-Apr-2007
US7834293B2	16-Nov-2010	Method and apparatus for laser processing	WILE DONALD E (US); JOHANSEN BRIAN C (US)	US417 26906A	2-May-2006
US7388178B2	17-Jun-2008	Rapid thermal response induction heating system for platen embossing	HENNESSEY MICHAEL (US)	US415 03206A	1-May-2006
US8900970B2	2-Dec-2014	Method for manufacturing a semiconductor device using a flexible substrate	MARUYAMA JUNYA (JP); JINBO YASUHIRO (JP); SHOJI HIRONOBU (JP); KUWABARA HIDEAKI (JP); YAMAZAKI SHUNPEI (JP)	US735 00907A	13-Apr-2007
US8288856B2	16-Oct-2012	Semiconductor integrated circuit, manufacturing method thereof, and semiconductor device using semiconductor integrated circuit	YAMAGUCHI MAYUMI (JP); IZUMI KONAMI (JP)	US201 113298 505A	17-Nov-2011
US8582962B2	12-Nov-2013	Substrate processing chamber with dielectric barrier discharge lamp assembly	RANISH JOSEPH MICHAEL (US); SINGH KAUSHAL KISHORE (US); ADAMS BRUCE (US)	US201 113175 452A	1-Jul-2011
US8741009B2	3-Jun-2014	Polishing composition containing polyether amine	DYSARD JEFFREY M (US); FEENEY PAUL M (US); ANJUR SRIRAM P (US); JOHNS TIMOTHY P (US); XIN YUN BIAO (US); WANG LI (US)	US462 06709A	29-Jul-2009
US7659624B2	9-Feb-2010	Simplification of selectively forming catalyst in a layer with an opening exposing the substrate; contacting the substrate with a catalytic material, where the exposed area of the substrate has a property that attracts the catalytic material, and the first layer has a second property that repels it	MAYYA KOLAKE SUBRAMANYA (KR); LEE SUN WOO (KR); YEO IN SEOK (KR)	US785 16407A	16-Apr-2007
US8299403B2	30-Oct-2012	Heat resisting vacuum insulating material and heating device	OHMI TADAHIRO (JP); SHIRAI YASUYUKI (JP); KOBAYASHI SADA O (JP); WAKAYAMA YOSHIHIDE (JP); UEKADO KAZUTAKA (JP)	US298 19207A	20-Apr-2007
US2007249098A1	25-Oct-2007	Bonding plate mechanism for use in anodic bonding	CADY RAYMOND CHARLES (US); LAKOTA ALEXANDER (US); LOCK WILLIAM EDWARD (US); THOMAS JOHN CHRISTOPHER (US); COSTELLO JOHN JOSEPH (US)	US786 30707A	11-Apr-2007
US2007249167A1	25-Oct-2007	CMP method for copper-containing substrates	ZHANG JIAN (US); CARTER PHILLIP W (US); LI SHOUTIAN (US)	US408 33406A	21-Apr-2006
US8975111B2	10-Mar-2015	Wafer level die integration and method therefor	LIN YAOJIAN (SG); CAO HAIJING (CN)	US201 113170 116A	27-Jun-2011

US7767504B2	3-Aug-2010	Methods for forming film patterns by disposing a liquid within a plural-level partition structure	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US689 22-Mar-2007 53307A
US2008286979A1	20-Nov-2008	Method of controlling sidewall profile by using intermittent, periodic introduction of cleaning species into the main plasma etching species	SHIN TAEHO (US); LIU JINGBAO (US); JOSHI AJEY M (US); KIM JONG MUN (US); WU WEI TE (US)	US220 24-Jul-2008 50308A
US9293361B2	22-Mar-2016	Materials and methods of forming controlled void	VRTIS RAYMOND NICHOLAS (US); WU DINGJUN (US); O NEILL MARK LEONARD (US); BITNER MARK DANIEL (US); VINCENT JEAN LOUISE (US); KARWACKI EUGENE JOSEPH (US); LUKAS AARON SCOTT (US)	US201 3-Jul-2014 414323 008A
US10754249B2	25-Aug-2020	Coating compositions for photolithography	ZAMPINI ANTHONY (US); GALLAGHER MICHAEL K (US); ONGAYI OWENDI (US)	US201 23-Jun-2017 715631 958A
US9390920B2	12-Jul-2016	Composition including material, methods of depositing material, articles including same and systems for depositing material	COE SULLIVAN SETH (US); ANC MARIA J (US); KIM LEEANN (US); RITTER JOHN E (US); COX MARSHALL (US); BREEN CRAIG (US); BULOVIC VLADIMIR (US); KYMISSIS IOANNIS (US); PRAINO JR ROBERT F (US); KAZLAS PETER T (US)	US201 8-Dec-2014 414563 571A
US8686551B2	1-Apr-2014	Substrate for a microelectronic package and method of fabricating thereof	HABA BELGACEM (US); MITCHELL CRAIG S (US); ALVAREZ JR APOLINAR (US)	US201 5-Jun-2012 213488 828A
US7820067B2	26-Oct-2010	Halide anions for metal removal rate control	LI SHOUTIAN (US)	US388 23-Mar-2006 08506A
US8551202B2	8-Oct-2013	Iodate-containing chemical-mechanical polishing compositions and methods	LI SHOUTIAN (US); CARTER PHILLIP W (US); ZHANG JIAN (US)	US387 23-Mar-2006 55806A
US2012071005A1	22-Mar-2012	HEAT TREATING APPARATUS, HEAT TREATING METHOD AND STORAGE MEDIUM	SHIMIZU MASAHIRO (JP)	US201 28-Nov-2011 113305 379A
US7381651B2	3-Jun-2008	Processes for monitoring the levels of oxygen and/or nitrogen species in a substantially oxygen and nitrogen-free plasma ashing process	SAKTHIVEL PALANIKUMARAN (US); BUCKLEY THOMAS J (US); BECKNELL ALAN F (US)	US386 22-Mar-2006 32706A
US8278739B2	2-Oct-2012	Crystalline semiconductor film, semiconductor device, and method for manufacturing thereof	MORIWAKA TOMOAKI (JP)	US715 8-Mar-2007 47307A
US2007215480A1	20-Sep-2007	Pattern transfer by solid state electrochemical stamping	FANG NICHOLAS X (US); FERREIRA PLACID M (US); HSU KENG H (US); RAPA K VENKATA K (US)	US376 16-Mar-2006 90806A
US7892954B2	22-Feb-2011	Interconnection of electronic devices with raised leads	BALUCANI MARCO (IT)	US293 16-Mar-2007 27307A
US8119449B2	21-Feb-2012	Method of manufacturing an electronic part mounting structure	SAKURAI DAISUKE (JP); YAGI YOSHIHIKO (JP)	US278 6-Mar-2007 48107A

US7528004B2	5-May-2009	Method for mounting anisotropically-shaped members	TORII HIDEO (JP)	US129 29-May-2008 33108A
US9107303B2	11-Aug-2015	Warp compensated electronic assemblies	LYTLE WILLIAM H (US); HAYES SCOTT M (US); LEAL GEORGE R (US)	US201 29-Aug-2014 414474 063A
US2009305437A1	10-Dec-2009	FABRICATION OF INORGANIC MATERIALS USING TEMPLATES WITH LABILE LINKAGE	ALLEMAND PIERRE MARC (US); HEIDECKER MANFRED (US); KIRK GREGORY L (US); QUAN XINA (US); WANG CHENG I (US)	US282 8-Mar-2007 16007A
US10261418B2	16-Apr-2019	Coating compositions for use with an overcoated photoresist	ZAMPINI ANTHONY (US); WAYTON GERALD B (US)	US201 29-Aug-2016 615250 302A
US2010330809A1	30-Dec-2010	POLISHING LIQUID FOR METALS	INABA TADASHI (JP); MATSUNO TAKAHIRO (JP); KIKUCHI MAKOTO (JP)	US877 7-Sep-2010 01010A
US2007224768A1	27-Sep-2007	Method and apparatus for delivery of pulsed laser radiation	CHAPLICK VICTORIA M (US); HARTE KENNETH J (US); MILLMAN RONALD P JR (US); ELLIOTT DAVID J (US)	US710 23-Feb-2007 09407A
US8097120B2	17-Jan-2012	Process tuning gas injection from the substrate edge	DHINDSA RAJINDER (US); SRINIVASAN MUKUND (US)	US359 21-Feb-2006 30006A
US7830012B2	9-Nov-2010	Polycarbosilane substituted with a benzyl or diazo group and/or a polysilazane having a substituent capable of absorbing light; blocks ultraviolet light applied to a porous insulating film	OZAKI SHIROU (JP); NAKATA YOSHIHIRO (JP)	US728 22-Mar-2010 48010A
US7691736B2	6-Apr-2010	Minimizing low-k dielectric damage during plasma processing	BECK MICHAEL (US); FITZSIMMONS JOHN A (US); HORNIK KARL (DE); RESTAINO DARRYL (US)	US352 10-Feb-2006 04706A
US7695567B2	13-Apr-2010	Water vapor passivation of a wall facing a plasma	FU XINYU (US)	US351 10-Feb-2006 67606A
US2010178432A1	15-Jul-2010	Method of Forming Pattern Film, and Pattern Film Forming Apparatus	KONDO YOSHIKAZU (JP); NISHIWAKI AKIRA (JP)	US223 18-Jan-2007 19407A
US8324100B2	4-Dec-2012	Methods of forming conductive vias	AKRAM SALMAN (US); HIATT WILLIAM MARK (US); OLIVER STEVEN (US); WOOD ALAN G (US); RIGG SIDNEY B (US); WARK JAMES M (US); KIRBY KYLE K (US)	US201 17-Feb-2011 113029 950A
US2007179072A1	2-Aug-2007	Cleaning formulations	RAO MADHUKAR B (US); WIEDER THOMAS M (US); MARSELLA JOHN A (US); LISTEMANN MARK L (US)	US342 30-Jan-2006 41406A
US7982318B2	19-Jul-2011	Device including contact structure and method of forming the same	HEO JANG EUN (KR); CHOI YOUNG MOON (KR); LEE SUN WOO (KR); YOON HONG SIK (KR); BYUN KYUNG RAE (KR)	US655 19-Jan-2007 11607A
US9171778B2	27-Oct-2015	Dual-damascene process to fabricate thick wire structure	COOLBAUGH DOUGLAS D (US); DOWNES KEITH E (US); LINDGREN PETER J (US); STAMPER ANTHONY K (US)	US201 28-Jan-2014 414166 274A

US8618013B2	31-Dec-2013	Method of producing particles by physical vapor deposition in an ionic liquid	FINLEY JAMES J (US)	US201 313740 369A	14-Jan-2013
US7851923B2	14-Dec-2010	Low resistance and inductance backside through vias and methods of fabricating same	ERTURK METE (US); GROVES ROBERT A (US); JOHNSON JEFFREY BOWMAN (US); JOSEPH ALVIN JOSE (US); LIU QIZHI (US); SPROGIS EDMUND JURIS (US); STAMPER ANTHONY KENDALL (US)	US410 72809A	25-Mar-2009
US7534753B2	19-May-2009	pH buffered aqueous cleaning composition and method for removing photoresist residue	WU AIPING (US); ROVITO ROBERTO JOHN (US)	US330 81506A	12-Jan-2006
US7462940B2	9-Dec-2008	Semiconductor component comprising flip chip contacts with polymer cores and method of producing the same	BAUER MICHAEL (DE); HAIMERL ALFRED (DE); KESSLER ANGELA (DE); MAHLER JOACHIM (DE); SCHOBBER WOLFGANG (DE)	US620 78407A	8-Jan-2007
US2009203216A1	13-Aug-2009	PHOTOLITHOGRAPHIC SYSTEMS AND METHODS FOR PRODUCING SUB-DIFFRACTION-LIMITED FEATURES	MACKEY JEFFREY L (US)	US424 44909A	15-Apr-2009
US10046584B2	14-Aug-2018	Layered structures on thin substrates	WOLKIN MICHAL V (US); ARIAS ANA C (US)	US201 615380 467A	15-Dec-2016
US7579259B2	25-Aug-2009	Simplified method of producing an epitaxially grown structure	FOURNEL FRANK (FR); MORICEAU HUBERT (FR)	US158 19106A	4-Dec-2006
US2010143744A1	10-Jun-2010	Systems and Methods of Laser Texturing of Material Surfaces and their Applications	GUPTA MOOL C (US); NAYAK BARADA K (US)	US530 31308A	6-Mar-2008
US2014273535A1	18-Sep-2014	Systems and Methods of Laser Texturing and Crystallization of Material Surfaces	GUPTA MOOL C (US); NAYAK BARADA K (US)	US201 414291 585A	30-May-2014
US2010136785A1	3-Jun-2010	DIRECT PATTERNING METHOD FOR MANUFACTURING A METAL LAYER OF A SEMICONDUCTOR DEVICE	HSIAO MING NAN (TW); CHIANG SHIN CHUANG (TW); CHUANG BOR CHUAN (TW)	US699 42910A	3-Feb-2010
US9384979B2	5-Jul-2016	Apparatus for the deposition of a conformal film on a substrate and methods therefor	CHOI DAE HAN (US); KIM JISOO (US); HUDSON ERIC (US); LEE SANGHEON (US); CHIANG CONAN (US); SADJADI S M REZA (US)	US201 213631 414A	28-Sep-2012
US7543374B2	9-Jun-2009	Method of manufacturing wiring substrate	NAKAMURA JUNICHI (JP)	US595 91606A	13-Nov-2006
US8048615B2	1-Nov-2011	Silicon-containing resist underlayer coating forming composition for forming photo-crosslinking cured resist underlayer coating	TAKEI SATOSHI (JP); HORIGUCHI YUSUKE (JP); HASHIMOTO KEISUKE (JP); NAKAJIMA MAKOTO (JP)	US861 6706A	1-Dec-2006
US8030644B2	4-Oct-2011	Organic insulator composition, organic insulating film having the same, organic thin film transistor having the same and electronic device having the same and methods of forming the same	SHIN JUNG HAN (KR); LEE EUN KYUNG (KR); JEONG EUN JEONG (KR); KIM JOO YOUNG (KR); MOON HYUN SIK (KR); LEE SANG YOON (KR)	US481 84306A	7-Jul-2006
US7989811B2	2-Aug-2011	Manufacturing method of semiconductor device	YAMADA DAIKI (JP)	US201 113010 887A	21-Jan-2011

US7638439B2	29-Dec-2009	Peripheral processing method and method of manufacturing a semiconductor device	KUBOTA TAKEO (JP); SHIGETA ATSUSHI (JP); YOMOGIHARA KAORI (JP); HONDA MAKOTO (JP); EZAWA HIROKAZU (JP)	US604 28-Nov-2006 78606A
US8172980B2	8-May-2012	Device with self aligned gaps for capacitance reduction	SADJADI S M REZA (US); HUANG ZHI SONG (US)	US202 29-Aug-2008 04308A
US8866202B2	21-Oct-2014	Device with gaps for capacitance reduction	SADJADI S M REZA (US); HUANG ZHI SONG (US)	US201 26-Apr-2012 213457 147A
US8679587B2	25-Mar-2014	Solution deposition of inorganic materials and electronic devices made comprising the inorganic materials	CHANG CHIH HUNG (US); LEE DO HYOUNG (US); CHANG YU JEN (US)	US564 29-Nov-2006 75906A
US8153890B2	10-Apr-2012	Low area screen printed metal contact structure and method	WENHAM STUART ROSS (AU); MAI LY (AU); SHI ZHENG RONG (CN); JI JINGJIA (CN)	US125 22-May-2008 81708A
US7887609B2	15-Feb-2011	Polishing slurry for polishing aluminum film and polishing method for polishing aluminum film using the same	ONO HIROSHI (JP); ASHIZAWA TORANOSUKE (JP); KAMIGATA YASUO (JP)	US602 21-Nov-2006 50306A
US7658802B2	9-Feb-2010	Apparatus and a method for cleaning a dielectric film	FU XINYU (US); FORSTER JOHN (US); WANG WEI W (US)	US284 22-Nov-2005 77505A
US7728511B2	1-Jun-2010	Organic thin film transistor, method of manufacturing the same, and flat display apparatus comprising the same	SHIN HYUN SOO (KR); SUH MIN CHUL (KR); MO YEON GON (KR)	US603 21-Nov-2006 36206A
US7410884B2	12-Aug-2008	3D integrated circuits using thick metal for backside connections and offset bumps	RAMANATHAN SHRIRAM (US); KIM SARAH E (KR); MORROW PATRICK R (US)	US284 21-Nov-2005 51905A
US7498662B2	3-Mar-2009	Dielectric media including surface-treated metal oxide particles	NAPIERALA MARK E (US)	US282 18-Nov-2005 92305A
US9441309B2	13-Sep-2016	Electrode and method of forming the master electrode	FREDENBERG MIKAEL (SE); MOLLER PATRIK (SE); WIWEN NILSSON PETER (SE); ARONSSON CECILIA (SE); DAINESE MATTEO (SE)	US201 20-Dec-2013 314135 745A
US7670948B2	2-Mar-2010	Semiconductor device having diffusion barriers and a method of preventing diffusion of copper in a metal interconnection of a semiconductor device	LEE JAE SUK (KR)	US559 14-Nov-2006 72406A
US2007175104A1	2-Aug-2007	Polishing slurry for silicon oxide, additive liquid and polishing method	NISHIYAMA MASAYA (JP); ENOMOTO KAZUHIRO (JP); FUKASAWA MASATO (JP); AKUTSU TOSHIKI (JP); OTSUKI YUUTO (JP); ASHIZAWA TORANOSUKE (JP)	US594 9-Nov-2006 98806A
US2007167029A1	19-Jul-2007	THERMAL PROCESSING SYSTEM, COMPONENTS, AND METHODS	KOWALSKI JEFFREY M (US); KOWALSKI JEFFREY E (US)	US559 13-Nov-2006 31506A
US8642526B2	4-Feb-2014	Composition and method for recycling semiconductor wafers having low-k dielectric materials thereon	VISINTIN PAMELA M (US); JIANG PING (US); KORZENSKI MICHAEL B (US); KING MACKENZIE (US)	US201 9-May-2011 113103 536A

US10068765B2	4-Sep-2018	Multi-step system and method for curing a dielectric film	LIU JUNJUN (US); LEE ERIC M (US); TOMA DOREL I (US)	US201 615204 279A	7-Jul-2016
US7704881B2	27-Apr-2010	Producing a covered through substrate via using a temporary cap layer	KLOOTWIJK JOHAN H (NL); KEMMEREN ANTONIUS L A M (NL); DEKKER RONALD (NL); VAN GRUNSVEN ERIC CORNELIS EGBERTUS (NL); ROOZEBOOM FREDDY (NL)	US926 0506A	3-Nov-2006
US9032906B2	19-May-2015	Apparatus and process for plasma-enhanced atomic layer deposition	MA PAUL (US); SHAH KAVITA (US); WU DIEN YEH (US); GANGULI SESHADRI (US); MARCADAL CHRISTOPHE (US); WU FREDERICK C (US); CHU SCHUBERT S (US)	US873 12907A	16-Oct-2007
US7803515B2	28-Sep-2010	Film pattern forming method, device, electro-optical apparatus, and electronic appliance	HIRAI TOSHIMITSU (JP); MORIYA KATSUYUKI (JP)	US556 38406A	3-Nov-2006
US7504018B2	17-Mar-2009	Electrochemical method for Ecmp polishing pad conditioning	WANG YOU (US); TSAI STAN D (US); KARUPPIAH LAKSHMANAN (US); DIAO JIE (US); JIA RENHE (US); YILMAZ ALPAY (US)	US554 92806A	31-Oct-2006
US7244660B2	17-Jul-2007	Method for manufacturing a semiconductor component	HIGGINS SR KELLEY KYLE (US); WISEMAN JOSEPH WILLIAM (US)	US264 19405A	31-Oct-2005
US7265055B2	4-Sep-2007	CMP of copper/ruthenium substrates	THOMPSON CHRISTOPHER C (US); BRUSIC VLASTA (US); ZHOU RENJIE (US)	US259 64505A	26-Oct-2005
US8557567B2	15-Oct-2013	Method for fabricating nanogap and nanogap sensor	CHUNG BONG HYUN (KR); KIM SANG KYU (KR); PARK HYE JUNG (KR)	US887 97806A	5-Sep-2006
US7969520B2	28-Jun-2011	Liquid crystal display device and dielectric film usable in the liquid crystal display device	RYUZAKI DAISUKE (JP); TORII KAZUYOSHI (JP); HATANO MUTSUOKO (JP); SONODA DAISUKE (JP); KANEKO TOSHIKI (JP)	US500 63909A	10-Jul-2009
US8211993B2	3-Jul-2012	Inorganic substrate with a thin silica type glass layer, method of manufacturing the aforementioned substrate, coating agent, and a semiconductor device	HARIMOTO YUKINARI (JP); ITOH MAKI (JP); KATSOUKIS DIMITRIS ELIAS (US)	US906 9406A	23-Oct-2006
US2007128553A1	7-Jun-2007	METHOD FOR FORMING FEATURE DEFINITIONS	LINZ JOERG (DE)	US551 11006A	19-Oct-2006
US8058709B2	15-Nov-2011	Semiconductor device and manufacturing method thereof	MORIWAKA TOMOAKI (JP)	US725 48310A	17-Mar-2010
US7705691B2	27-Apr-2010	Capacitor interconnection	LU CHEE WAI ALBERT (MY); LOK BOON KENG (MY); WONG CHEE KHUEN STEPHEN (SG); CHUA KAI MENG (SG); WAI LAI LAI (SG); VASUDIVAN SUNNAPPAN (SG)	US253 03905A	18-Oct-2005
US8772214B2	8-Jul-2014	Aqueous cleaning composition for removing residues and method using same	WU AIPING (US); ROVITO ROBERTO JOHN (US)	US250 25005A	14-Oct-2005
US8058219B2	15-Nov-2011	Metals compatible post-etch photoresist remover and/or sacrificial antireflective coating etchant	RATH MELISSA K (US); BERNHARD DAVID D (US); BAUM THOMAS H (US); JIANG PING (US); ZHOU RENJIE (US); KORZENSKI MICHAEL B (US)	US902 1306A	12-Oct-2006

US8932682B2	13-Jan-2015	Method for manufacturing a light emitting device	ARAI YASUYUKI (JP)	US545 10-Oct-2006 34406A
US2017267895A9	21-Sep-2017	POLISHING SLURRY FOR CMP AND POLISHING METHOD	SHINODA TAKASHI (JP); NOBE SHIGERU (JP); SAKURADA TAKAFUMI (JP); OOMORI YOSHIKAZU (JP); KIMURA TADAHIRO (JP)	US201 15-Jul-2015 514799 971A
US2009130463A1	21-May-2009	Coated Substrates and Methods for their Preparation	ALBAUGH JOHN DEAN (US); AMAKO MASAACKI (JP); CAMILLETTI ROBERT CHARLES (US); CHOI DONG (US); WEIDNER WILLIAM (US); ZAMBOV LUDMIL (US)	US992 18-Sep-2006 87106A
US12183832B2	31-Dec-2024	Semiconductor device and manufacturing method thereof	AKIMOTO KENGO (JP); HONDA TATSUYA (JP); SONE NORIHITO (JP)	US202 8-Nov-2021 117521 021A
US7435673B2	14-Oct-2008	Methods of forming integrated circuit devices having metal interconnect structures therein	LEE KYOUNG WOO (US); KU JA HUM (US); HONG DUK HO (US); PARK WAN JAE (US)	US237 28-Sep-2005 98705A
US8349202B2	8-Jan-2013	Methods for controlling bevel edge etching in a plasma chamber	FANG TONG (US); KIM YUNSANG (US); BAILEY III ANDREW D (US); RIGOUTAT OLIVIER (US); STOJAKOVIC GEORGE (US)	US201 18-Nov-2011 113300 483A
US9564308B2	7-Feb-2017	Methods for processing bevel edge etching	SEXTON GREGORY S (US); BAILEY III ANDREW D (US); KUTHI ANDRAS (US); KIM YUNSANG (US)	US201 10-Nov-2015 514937 716A
US8574397B2	5-Nov-2013	Bevel edge plasma chamber with top and bottom edge electrodes	SEXTON GREGORY S (US); BAILEY III ANDREW D (US); KUTHI ANDRAS (US)	US201 12-Jul-2012 213547 700A
US8926789B2	6-Jan-2015	Apparatus for the removal of a fluorinated polymer from a substrate	YOON HYUNGSUK ALEXANDER (US); BOYD JOHN (US); KUTHI ANDRAS (US); BAILEY III ANDREW D (US)	US750 30-Mar-2010 61210A
US8883027B2	11-Nov-2014	Methods for removing a metal oxide from a substrate	YOON HYUNGSUK ALEXANDER (US); THIE WILLIAM (US); DORDI YEZDI (US); BAILEY III ANDREW D (US)	US683 7-Jan-2010 99510A
US7906038B2	15-Mar-2011	Aqueous polishing liquid and chemical mechanical polishing method	KATO TOMO (JP)	US525 25-Sep-2006 86406A
US8298433B2	30-Oct-2012	Methods for removing an edge polymer from a substrate	YOON HYUNGSUK ALEXANDER (US); KIM YUNSANG (US); RYDER JASON A (US); BAILEY III ANDREW D (US)	US648 28-Dec-2009 26409A
US7642195B2	5-Jan-2010	Hydrogen treatment to improve photoresist adhesion and rework consistency	YEH WENDY H (US)	US235 26-Sep-2005 29805A
US8637404B2	28-Jan-2014	Metal cations for initiating polishing	CARTER PHILLIP W (US); LI SHOUTIAN (US)	US952 23-Nov-2010 24210A
US8101941B2	24-Jan-2012	Interface conditioning to improve efficiency and lifetime of organic electroluminescence devices	CHOULIS STELIOS A (US); MATHAI MATHEW (US); CHOONG VI EN (US)	US236 26-Sep-2005 17605A
US9321142B2	26-Apr-2016	Polymer material, foam obtained from same, and polishing pad using those	OKAMOTO CHIIHIRO (JP); KATO SHINYA (JP); KANEDA SHUNJI (JP); KIKUCHI HIROFUMI (JP)	US672 21-Sep-2006 9706A

US7955454B2	7-Jun-2011	Method for forming wiring on insulating resin layer	YAMANO TAKAHARU (JP); HARAYAMA KOSAKU (JP); KATO HIROYUKI (JP); KOYAMA TETSUYA (JP)	US516 7-Sep-2006 73706A
US7435989B2	14-Oct-2008	Semiconductor device with layer containing polysiloxane compound	NAKAYAMA TOMONARI (JP); MASUMOTO AKANE (JP); GO SHINTETSU (JP); OHNISHI TOSHINOBU (JP)	US514 5-Sep-2006 92206A
US7700463B2	20-Apr-2010	Method for manufacturing semiconductor device	SHIMOMURA AKIHISA (JP)	US506 21-Aug-2006 85506A
US8736028B2	27-May-2014	Semiconductor device structures and printed circuit boards comprising semiconductor devices	TUTTLE MARK E (US)	US201 22-Mar-2013 313848 914A
US7956454B2	7-Jun-2011	Wiring board and ceramic chip to be embedded	YAMAMOTO HIROSHI (JP); SEKI TOSHITAKE (JP); YURI SHINJI (JP); MURAMATSU MASAKI (JP); SATO MOTOHIKO (JP); TOSA AKIFUMI (JP)	US475 1-Jun-2009 64809A
US8637962B2	28-Jan-2014	Semiconductor dice including at least one blind hole, wafers including such semiconductor dice, and intermediate products made while forming at least one blind hole in a substrate	AKRAM SALMAN (US); RIGG SIDNEY B (US)	US201 14-Sep-2012 213620 065A
US7833894B2	16-Nov-2010	Devices and systems having at least one dam structure	HIATT W MARK (US)	US781 23-Jul-2007 74607A
US7452743B2	18-Nov-2008	Microelectronic imaging units and methods of manufacturing microelectronic imaging units at the wafer level	OLIVER STEVEN D (US); VELICKY LU (US); HIATT WILLIAM MARK (US); HEMBREE DAVID R (US); TUTTLE MARK E (US); RIGG SIDNEY B (US); WARK JAMES M (US); FARNWORTH WARREN M (US); KIRBY KYLE K (US)	US217 1-Sep-2005 87705A
US7473988B2	6-Jan-2009	Wiring board construction including embedded ceramic capacitors(s)	URASHIMA KAZUHIRO (JP); YURI SHINJI (JP); SATO MANABU (JP); OTSUKA JUN (JP)	US513 31-Aug-2006 24906A
US7678702B2	16-Mar-2010	CMP composition of boron surface-modified abrasive and nitro-substituted sulfonic acid and method of use	COMPTON TIMOTHY FREDERICK (US); SIDDIQUI JUNAID AHMED (US); ZUTSHI AJOY (US)	US509 24-Aug-2006 22306A
US7820521B2	26-Oct-2010	Conductive through via structure and process for electronic device carriers	ANDRY PAUL S (US); PATEL CHIRAG S (US); SPROGIS EDMUND J (US); TSANG CORNELIA K (US)	US335 16-Dec-2008 60508A
US11158796B2	26-Oct-2021	Resistance variable memory device with nanoparticle electrode and method of fabrication	LIU JUN (US); CAMPBELL KRISTY A (US)	US202 3-Jun-2020 016892 091A
US8956430B2	17-Feb-2015	Polishing composition	YAMAGUCHI NORIHITO (JP)	US285 2-Oct-2008 32908A
US7432184B2	7-Oct-2008	Integrated PVD system using designated PVD chambers	HOSOKAWA AKIHIRO (US); INAGAWA MAKOTO (US); LE HIENMINH HUU (US); WHITE JOHN M (US)	US213 26-Aug-2005 66205A
US2007048451A1	1-Mar-2007	Substrate movement and process chamber scheduling	WHITE JOHN (US); TAKEHARA TAKAKO (US); HUANG INCHEN (US)	US213 26-Aug-2005 34905A

US8888229B2	18-Nov-2014	Method for forming a layer, method for manufacturing an active matrix substrate, and method for manufacturing a multilayered wiring substrate	SHINTATE TSUYOSHI (JP); MIZUGAKI KOICHI (JP); SAKURADA KAZUAKI (JP); WADA KENJI (JP)	US467 25-Aug-2006 29506A
US7233048B2	19-Jun-2007	MEMS device trench plating process and apparatus for through hole vias	RYBNICEK KIMON (US)	US211 26-Aug-2005 62405A
US8101013B2	24-Jan-2012	Film-forming material and method of forming pattern	MATSUMARU SHOGO (JP); HADA HIDEO (JP); FUJIKAWA SHINGENORI (JP); KUNITAKE TOYOKI (JP)	US997 24-Aug-2006 30006A
US8431816B2	30-Apr-2013	Apparatus and methods for solar energy conversion using nanoscale cometal structures	KEMPA KRZYSZTOF J (US); NAUGHTON MICHAEL J (US); REN ZHIFENG (US); RYBCZYNSKI JAKUB A (US)	US201 22-Apr-2011 113092 512A
US7316977B2	8-Jan-2008	For silicon based semiconductor devices, such as integrated circuits and memory devices; tunability of removal rates for metal, barrier material, and dielectric layer materials in metal CMP	SIDDIQUI JUNAID AHMED (US); COMPTON TIMOTHY FREDERICK (US)	US508 23-Aug-2006 42706A
US9978681B2	22-May-2018	Semiconductor device	SU HUNG WEN (TW); CHOU SHIH WEI (TW); TSAI MING HSING (TW)	US201 27-Aug-2015 514837 458A
US8975192B2	10-Mar-2015	Method for manufacturing semiconductor device	KOJIMA YASUNORI (JP); ITABASHI TOSHIAKI (JP)	US645 22-Aug-2006 1106A
US8080286B2	20-Dec-2011	Low dielectric constant silicon coating, method for the preparation and application thereof to integrated circuits	GIRAUD YVES (FR); VERGELATTI CAROL (FR); TUPINIER DIDIER (FR); ODONI LUDOVIC (FR); BASIRE CHARLOTTE (FR); TROUILLET LISE (FR)	US640 16-Aug-2006 6206A
US7964964B2	21-Jun-2011	Method of packaging and interconnection of integrated circuits	SHEATS JAMES (US)	US582 21-Oct-2009 94009A
US7646012B2	12-Jan-2010	Organic thin film transistor and manufacturing method thereof	KIM SUNG JIN (KR); AHN TAEK (KR); SUH MIN CHUL (KR); LEE SIN DOO (KR)	US505 18-Aug-2006 91206A
US2007039926A1	22-Feb-2007	Abrasive-free polishing system	CHERIAN ISAAC K (US); MOEGGENBORG KEVIN J (US)	US205 17-Aug-2005 42805A
US2013143359A1	6-Jun-2013	SEMICONDUCTOR DEVICE AND A MANUFACTURING METHOD OF THE SAME	HIGASHINO TOMOKO (JP); MIYAZAKI CHUICHI (JP); ABE YOSHIYUKI (JP)	US201 24-Jan-2013 313748 928A
US8497503B2	30-Jul-2013	Manufacture of photovoltaic devices	MEYERS PETER V (US)	US201 13-Sep-2011 113231 090A
US7880307B2	1-Feb-2011	Semiconductor device including through-wafer interconnect structure	FARNWORTH WARREN M (US); WOOD ALAN G (US)	US186 6-Aug-2008 91308A
US9006043B2	14-Apr-2015	Manufacturing method of semiconductor device	OHNUMA HIDETO (JP); SAKAKURA MASAYUKI (JP)	US201 18-Apr-2012 213449 383A

US2017084630A1	23-Mar-2017	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	TSURUME TAKUYA (JP); DOZEN YOSHITAKA (JP)	US201 615255 602A	2-Sep-2016
US7655566B2	2-Feb-2010	Method for manufacturing semiconductor device	FUJII GEN (JP)	US488 14306A	18-Jul-2006
US7902002B2	8-Mar-2011	Semiconductor device	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP)	US631 54505A	25-Jul-2005
US7511936B2	31-Mar-2009	Method and apparatus for dynamic plasma treatment of bipolar ESC system	HUANG CUKER (TW); LEE SHING LONG (TW); LU YI JOU (TW); LEE CHIA LING (TW)	US425 00606A	19-Jun-2006
US2007015338A1	18-Jan-2007	Substrate applicable to both wire bonding and flip chip bonding, smart card modules having the substrate and methods for fabricating the same	LEE SEOK WON (JP); CHOI KYOUNG SEI (KR); KIM DONG HAN (KR); RO YOUNG HOON (KR)	US487 48406A	17-Jul-2006
US7564672B2	21-Jul-2009	Transfer-ESC based on a wafer	RETZLAFF UDO HEINZ (DE)	US455 20806A	19-Jun-2006
US7348663B1	25-Mar-2008	Integrated circuit package and method for fabricating same	KIRLOSKAR MOHAN (US); WAGENHOFFER KATHERINE (US); HIGGINS III LEO M (US)	US183 29005A	15-Jul-2005
US8088297B2	3-Jan-2012	Combined etching and doping media for silicon dioxide layers and underlying silicon	KUEBELBECK ARMIN (DE); STOCKUM WERNER (DE)	US995 44906A	13-Jun-2006
US8124239B2	28-Feb-2012	Silica film forming material, silica film and method of manufacturing the same, multilayer wiring structure and method of manufacturing the same, and semiconductor device and method of manufacturing the same	NAKATA YOSHIHIRO (JP); YANO EI (JP)	US640 36209A	17-Dec-2009
US8673539B2	18-Mar-2014	Photosensitive adhesive composition, and obtained using the same, adhesive film, adhesive sheet, semiconductor wafer with adhesive layer, semiconductor device and electronic part	KAWAMORI TAKASHI (JP); MASUKO TAKASHI (JP); KATO GI SHIGEKI (JP); YASUDA MASA AAKI (JP)	US201 213672 847A	9-Nov-2012
US2007000523A1	4-Jan-2007	Cleaning composition and related methods	KIM SE YEON (KR); JUN PIL KWON (KR); PARK JUNG DAE (KR); HAN MYOUNG OK (KR); KIM JEA WOOK (KR); CHAE SEUNG KI (KR); KIM KOOK JOO (KR); LEE JAE SEOK (KR); KO YONG KYUN (KR); LIM KWANG SHIN (KR); LEE YANG KOO (KR)	US454 82906A	19-Jun-2006
US8062096B2	22-Nov-2011	Use of CMP for aluminum mirror and solar cell fabrication	BRUSIC VLASTA (US); JENKINS RICHARD JON (US); THOMPSON CHRISTOPHER C (US)	US173 51805A	30-Jun-2005
US7335587B2	26-Feb-2008	Post polish anneal of atomic layer deposition barrier layers	JOHNSTON STEVEN W (US); O BRIEN KEVIN P (US); BALAKRISHNAN SRIDHAR (US)	US173 85805A	30-Jun-2005
US8558227B2	15-Oct-2013	Semiconductor device and manufacturing method of the same	FUJII GEN (JP)	US201 213567 235A	6-Aug-2012

US8441118B2	14-May-2013	Electromigration-resistant and compliant wire interconnects, nano-sized solder compositions, systems made thereof, and methods of assembling soldered packages	HUA FAY (US)	US589 40909A	22-Oct-2009
US2006292362A1	28-Dec-2006	Bilayer anode	HSU CHE HSIUNG (US); SKULASON HJALTI (US)	US476 48806A	28-Jun-2006
US7687916B2	30-Mar-2010	Semiconductor substrates including vias of nonuniform cross-section and associated structures	LAKE RICKIE C (US)	US174 94108A	17-Jul-2008
US7932013B2	26-Apr-2011	Pattern coating material and pattern forming method	MATSUMARU SHOGO (JP); OGATA TOSHIYUKI (JP); ISHIKAWA KIYOSHI (JP); HADA HIDEO (JP); FUJIKAWA SHIGENORI (JP); KUNITAKE TOYOKI (JP)	US993 44406A	16-Jun-2006
US7700533B2	20-Apr-2010	Composition for removal of residue comprising cationic salts and methods using same	EGBE MATTHEW I (US); LEGENZA MICHAEL WALTER (US)	US452 29006A	14-Jun-2006
US7943519B2	17-May-2011	Etchant, method for fabricating interconnection line using the etchant, and method for fabricating thin film transistor substrate using the etchant	PARK HONG SICK (KR); KIM SHI YUL (KR); CHOUNG JONG HYUN (KR); SHIN WON SUK (KR)	US473 60706A	22-Jun-2006
US8044441B2	25-Oct-2011	Electrode patterning layer comprising polyamic acid or polyimide, and electronic device employing it	MAEDA SHINICHI (JP); ONO GO (JP)	US993 24306A	19-Jun-2006
US2009192065A1	30-Jul-2009	DENSE FLUID COMPOSITIONS FOR REMOVAL OF HARDENED PHOTORESIST, POST-ETCH RESIDUE AND/OR BOTTOM ANTI-REFLECTIVE COATING	KORZENSKI MICHAEL B (US); VISINTIN PAMELA M (US); BAUM THOMAS H (US); MINSEK DAVID W (US); XU CHONGYING (US)	US917 65406A	16-Jun-2006
US2010120197A1	13-May-2010	METHODS OF MAKING THIN FILM TRANSISTORS COMPRISING ZINC-OXIDE-BASED SEMICONDUCTOR MATERIALS	LEVY DAVID H (US); SCUDERI ANDREA C (US); IRVING LYN M (US)	US690 12910A	20-Jan-2010
US8643186B2	4-Feb-2014	Processed wafer via	TREZZA JOHN (US)	US846 49510A	29-Jul-2010
US7986085B2	26-Jul-2011	Light emitting apparatus and electronic equipment provided with the light emitting apparatus	SHINOHARA YUJI (JP); NAKAGAWA TETSUO (JP)	US922 00206A	24-May-2006
US7781886B2	24-Aug-2010	Electronic chip contact structure	TREZZA JOHN (US); CALLAHAN JOHN (US); DUDOFF GREGORY (US)	US329 88506A	10-Jan-2006
US7998335B2	16-Aug-2011	Controlled electrochemical polishing method	FEENEY PAUL M (US); BRUSIC VLASTA (US)	US150 94405A	13-Jun-2005
US7629606B2	8-Dec-2009	Functional molecular element, method for producing functional molecular element, and functional molecular device	MATSUI ERIKO (JP)	US422 48506A	6-Jun-2006
US8722135B2	13-May-2014	Method for discharging chemical solution	TATEISHI FUMINORI (JP)	US842 58510A	23-Jul-2010

US8586447B2	19-Nov-2013	Semiconductor device and manufacturing method of the same	NOGUCHI JUNJI (JP); MATSUMOTO TAKASHI (JP); OSHIMA TAKAYUKI (JP); ONOZUKA TOSHIHIKO (JP)	US201 213541 229A	3-Jul-2012
US2006278614A1	14-Dec-2006	Polishing composition and method for defect improvement by reduced particle stiction on copper surface	WANG YUCHUN (US); SUN FRED F (US); HAWKINS JOSEPH D (US)	US147 53105A	8-Jun-2005
US7517815B2	14-Apr-2009	Spin-on glass composition, method of preparing the spin-on glass composition and method of forming a porous silicon oxide layer using the spin-on glass composition	CHO JUN HYUN (KR); CHOI JUNG SIK (KR); LEE JUNG HO (KR); KIM MI AE (KR)	US446 15206A	5-Jun-2006
US2006273366A1	7-Dec-2006	Methods of manufacturing ferroelectric capacitors and semiconductor devices	KO HWA YOUNG (KR); JOO SUK HO (KR); BAE BYOUNG JAE (KR); KIM HEE SEOK (KR); BYUN KYUNG RAE (KR); HAM JIN HWAN (KR)	US447 54506A	6-Jun-2006
US2006275952A1	7-Dec-2006	Method for making electronic devices	GOWDA ARUN V (US); TONAPI SANDEEP S (US); MILLS RYAN C (US); ESLER DAVID R (US); LATHAM STEPHEN A (US); CAMPBELL JOHN R (US)	US146 83805A	7-Jun-2005
US7638859B2	29-Dec-2009	Interconnects with harmonized stress and methods for fabricating the same	LU YUNG CHENG (TW); TSAI MING HSING (TW)	US144 74205A	6-Jun-2005
US2008218063A1	11-Sep-2008	Organic Electroluminescent Light Source	GREINER HORST (DE)	US915 74806A	30-May-2006
US7214611B2	8-May-2007	Imprinting-damascene process for metal interconnection	LIU JEN FU (TW); HSU YUNG JEN (TW); CHEN JIANN HENG (TW); HUANG FON SHAN (TW)	US208 62405A	23-Aug-2005
US2006291833A1	28-Dec-2006	Switchable reflector wall concept	TIMANS PAUL J (US)	US441 81006A	26-May-2006
US8062984B2	22-Nov-2011	Laser ablation of electronic devices	CALN PAUL A (GB); HAYTON CARL (GB)	US657 2206A	31-Aug-2006
US2016111667A1	21-Apr-2016	LAYER-SELECTIVE LASER ABLATION PATTERNING	HAYTON CARL (GB); BROWN THOMAS MEREDITH (IT); CAIN PAUL A (GB)	US201 514919 056A	21-Oct-2015
US8227851B2	24-Jul-2012	Semiconductor device	AOKI TOMOYUKI (JP); DAIRIKI KOJI (JP); GOTO YUUGO (JP)	US952 76610A	23-Nov-2010
US2006270241A1	30-Nov-2006	METHOD OF REMOVING A PHOTORESIST PATTERN AND METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE USING THE SAME	KIM KYOUNG CHUL (KR); KANG DAE KEUN (KR); CHA SE HO (KR); HWANG IN SEAK (KR); LEE KEUM JOO (KR)	US420 94306A	30-May-2006
US8455287B2	4-Jun-2013	Method for manufacturing semiconductor device including microstructure	IZUMI KONAMI (JP); YAMAGUCHI MAYUMI (JP)	US201 113219 784A	29-Aug-2011
US8011296B2	6-Sep-2011	Supercritical fluid-assisted direct write for printing integrated circuits	SANDHU GURTEJ (US); BASCERI CEM (US)	US232 91308A	25-Sep-2008
US7678255B2	16-Mar-2010	Mask and method for electrokinetic deposition and patterning process on substrates	KHASELEV OSCAR (US); LEWIS BRIAN G (US); MARCZI MICHAEL (US); SINGH BAWA (US)	US419 12806A	18-May-2006

US7947907B2	24-May-2011	Electronics structures using a sacrificial multi-layer hardmask scheme	COLBURN MATTHEW EARL (US); DONATON RICARDO ALVES (US); MURRAY CONAL E (US); NITTA SATYANARAYANA VENKATA (US); PURUSHOTHAMAN SAMPATH (US); SANKARAN SUJATHA (US); STANDAERT THEDORUS EDUARDOS (US); LIU XIAO HU (US)	US988 7-Apr-2008 9508A
US7799407B2	21-Sep-2010	Bank structure, wiring pattern forming method, device, electro-optical device, and electronic apparatus	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US382 12-May-2006 95006A
US2006255735A1	16-Nov-2006	METHOD OF FORMING BANK, METHOD OF FORMING FILM PATTERN, SEMICONDUCTOR DEVICE, ELECTRO OPTIC DEVICE, AND ELECTRONIC APPARATUS	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US381 5-May-2006 83406A
US7199450B2	3-Apr-2007	Materials and method to seal vias in silicon substrates	CASEY JON A (US); BERGER MICHAEL (US); BUCHWALTER LEENA P (US); CANAPERI DONALD F (US); HORTON RAYMOND R (US); JAIN ANURAG (US); PERFECTO ERIC D (US); TORNELLO JAMES A (US)	US908 13-May-2005 48005A
US7462570B2	9-Dec-2008	Method for forming high-resolution pattern and substrate having prepattern formed thereby	SHIN DONG YOUN (KR); KIM TAE SU (KR)	US431 11-May-2006 92306A
US7510951B2	31-Mar-2009	Method for forming high-resolution pattern with direct writing means	SHIN DONG YOUN (KR); SHIN BU GON (KR)	US431 11-May-2006 92206A
US8884433B2	11-Nov-2014	Circuitry component and method for forming the same	LIN MOU SHIUNG (TW); CHOU CHIEN KANG (TW); CHEN KE HUNG (TW)	US545 24-Aug-2009 88009A
US8318554B2	27-Nov-2012	Method of forming gate insulating film for thin film transistors using plasma oxidation	ARAI YASUYUKI (JP); YAMAZAKI SHUNPEI (JP)	US410 25-Apr-2006 08306A
US7514772B2	7-Apr-2009	Method of manufacturing a semiconductor apparatus	KOBAYASHI TOMOKI (JP); SHIMADA TOSHIJI (JP); INOUE AKINOBU (JP); KAJIKI ATSUNORI (JP); KATO HIROYUKI (JP); SHIMIZU HIROSHI (JP)	US380 25-Apr-2006 12806A
US8415787B2	9-Apr-2013	Integrated circuits having interconnects and heat dissipators based on nanostructures	KABIR MOHAMMAD SHAFIQUL (SE)	US201 21-May-2012 213476 417A
US7317253B2	8-Jan-2008	Cobalt tungsten phosphate used to fill voids arising in a copper metallization process	NOGAMI TAKESHI (US)	US113 25-Apr-2005 93405A
US9134610B2	15-Sep-2015	Resist underlayer coating forming composition for forming photo-crosslinking cured resist underlayer coating	TAKEI SATOSHI (JP); SHINJO TETSUYA (JP); HIDAKA MOTOHIKO (JP)	US201 12-Mar-2013 313797 009A
US7368388B2	6-May-2008	Cerium oxide abrasives for chemical mechanical polishing	SMALL ROBERT J (US); HAYDEN CHRISTOPHER G (US)	US106 15-Apr-2005 49005A
US7812343B2	12-Oct-2010	Multilayer composite body having an electronic function	ULLMANN ANDREAS (DE); KNOBLOCH ALEXANDER (DE); WELKER MERLIN (DE); FIX WALTER (DE)	US911 31-Mar-2006 42906A

US8741442B2	3-Jun-2014	Modified electrodes using functional organic materials and electronic devices therefrom	CELLA JAMES ANTHONY (US); HELLER CHRISTIAN MARIA ANTON (US); LIU JIE (US)	US107 50105A	15-Apr-2005
US8460414B2	11-Jun-2013	Polishing slurry and polishing material using same	ETOH AKINORI (JP); OIKE SETSUKO (JP); ISHIZUKA TOMOKAZU (JP); FUJII SHIGEHARU (JP); SHINDO KIYOTAKA (JP)	US918 22606A	14-Apr-2006
US8557721B2	15-Oct-2013	Rapid thermal processing using energy transfer layers	TIMANS PAUL J (US)	US201 213372 082A	13-Feb-2012
US8053909B2	8-Nov-2011	Semiconductor component having through wire interconnect with compressed bump	HEMBREE DAVID R (US)	US201 113007 743A	17-Jan-2011
US2008245304A1	9-Oct-2008	SYSTEM FOR SELECTIVE DEPOSITIONS OF MATERIALS TO SURFACES AND SUBSTRATES	YONKER CLEMENT R (US); MATSON DEAN W (US); GASPAR DANIEL J (US); DEVERMAN GEORGE S (US)	US139 97208A	16-Jun-2008
US7399708B2	15-Jul-2008	Method of treating a composite spin-on glass/anti-reflective material prior to cleaning	SCHILLING PAUL (US)	US949 3905A	30-Mar-2005
US2006219268A1	5-Oct-2006	Neutralization of systemic poisoning in wafer processing	JACOBSON GUNILLA (US)	US949 3805A	30-Mar-2005
US7311856B2	25-Dec-2007	Chemical-mechanical polishing of a polishing pad, and/or abrasive; surfactant with an azole group of 1,2,3-triazole, 1,2,4-triazole, pyrazole, imidazole, indazole, tetrazole, benzimidazole, and/or benzotriazole having a polymer chain attached; not polyvinylimidazole; and liquid carrier	ZHOU RENJIE (US); GRUMBINE STEVEN K (US); ZHANG JIAN (US); CHERIAN ISAAC K (US)	US938 0605A	30-Mar-2005
US2008200361A1	21-Aug-2008	AQUEOUS CLEANER WITH LOW METAL ETCH RATE	WALKER ELIZABETH L (US); BARNES JEFFREY A (US); NAGHSHINEH SHAHRIAR (US); YANDERS KEVIN P (US)	US111 46908A	29-Apr-2008
US8142688B2	27-Mar-2012	Conductivity variable composition, conductivity variable laminated body, and conductive pattern formed body	KOBAYASHI YOSHIHIRO (JP); ITOH KIYOSHI (JP)	US390 66306A	28-Mar-2006
US2008210664A1	4-Sep-2008	Method of Surface Treatment and Surface-Treated Article	UENISHI MASAMOTO (JP); NOMURA SHINFUKU (JP); TOYOTA HIROMICHI (JP)	US909 65806A	24-Mar-2006
US7560821B2	14-Jul-2009	Area mount type semiconductor device, and die bonding resin composition and encapsulating resin composition used for the same	OSUGA HIRONORI (JP); YAGISAWA TAKASHI (JP); YASUDA HIROYUKI (JP)	US386 21606A	22-Mar-2006
US2006213868A1	28-Sep-2006	Low-dishing composition and method for chemical-mechanical planarization with branched-alkylphenol-substituted benzotriazole	SIDDIQUI JUNAID A (US); COMPTON TIMOTHY F (US)	US374 71406A	14-Mar-2006
US2009053503A1	26-Feb-2009	Precursor composition for porous film and method for preparing the composition, porous film and method for preparing the porous film, and semiconductor device	FUJII NOBUTOSHI (JP); NAKAYAMA TAKAHIRO (JP); KANAYAMA TOSHIHIKO (JP); KOHMURA KAZUO (JP); TANAKA HIROFUMI (JP)	US886 95206A	17-Mar-2006
US9436084B2	6-Sep-2016	Positive-working photoresist composition for thick film formation	MISUMI KOICHI (JP); OKUI TOSHIKI (JP)	US792 75206A	22-Mar-2006

US7884474B2	8-Feb-2011	Method for fabricating semiconductor device and semiconductor device	KOJIMA AKIHIRO (JP)	US232 45308A	17-Sep-2008
US7678712B2	16-Mar-2010	Vapor phase treatment of dielectric materials	BHANAP ANIL S (US); ROTH ROBERT R (US); BURNHAM KIKUE S (US); DANIELS BRIAN J (US); ENDISCH DENIS H (US); GOLECKI ILAN (US)	US860 1005A	22-Mar-2005
US8461628B2	11-Jun-2013	MOS transistor with laser-patterned metal gate, and method for making the same	CHOI CRISWELL (US); ROCKENBERGER JOERG (US); MACKENZIE J DEVIN (US); GUDEMAN CHRISTOPHER (US)	US203 56305A	11-Aug-2005
US7635524B2	22-Dec-2009	Coating composition for dielectric insulating film, dielectric insulating film prepared therefrom, and electric or electronic device comprising the same	KO MIN JIN (KR); LEE KI YOUL (KR); CHOI BUM GYU (KR); MOON MYUNG SUN (KR); KANG DAE HO (KR); SON JEONG MAN (KR)	US222 12008A	1-Aug-2008
US2006237392A1	26-Oct-2006	Polymer remover	AUGER ROBERT L (US); LACHOWSKI JOSEPH F (US)	US374 24506A	13-Mar-2006
US2006199037A1	7-Sep-2006	Light emitting element, display unit and electronic apparatus	MORII KATSUYUKI (CH)	US336 77506A	23-Jan-2006
US2006220023A1	5-Oct-2006	Thin-film device	HOFFMAN RANDY (US); HERMAN GREGORY (US); NELSON CURT (US)	US729 4705A	3-Mar-2005
US2008150118A1	26-Jun-2008	Method of Manufacturing a Semiconductor Packages and Packages Made	VAN VEEN NICOLAAS JOHANNES ANT (NL); DEKKER RONALD (NL); TAK COEN C (NL)	US816 75006A	27-Feb-2006
US2011073483A1	31-Mar-2011	APPARATUS AND METHOD FOR IMPROVING UNIFORMITY IN ELECTROPLATING	HAFEZI HOOMAN (US); ROSENFELD ARON (US)	US962 60110A	7-Dec-2010
US7439193B2	21-Oct-2008	Patterning method for fabricating high resolution structures	LI SHUNPU (GB); NEWSOME CHRISTOPHER (GB); RUSSELL DAVID (GB); KUGLER THOMAS (GB)	US320 58205A	30-Dec-2005
US7553386B2	30-Jun-2009	Adhesive with differential optical properties and its application for substrate processing	LU DAOQIANG (US); LI ERIC J (US)	US125 68708A	22-May-2008
US8236614B2	7-Aug-2012	Semiconductor device manufacturing method	MISUMI SADAHITO (JP); MATSUMURA TAKESHI (JP)	US816 69606A	20-Feb-2006
US7906206B2	15-Mar-2011	Organic insulator composition comprising high dielectric constant insulator dispersed in hyperbranched polymer and organic thin film transistor using the same	PARK JONG JIN (KR); PARK HYUN JUNG (KR); KOO BON WON (KR); LEE SANG YOON (KR); PU LYONG SUN (KR); MASAOKI KAKIMOTO (JP)	US204 10205A	16-Aug-2005
US2006183055A1	17-Aug-2006	Method for defining a feature on a substrate	O NEILL MARK L (US); WEIGEL SCOTT J (US); RENNIE DAVID B (US); ROBERTS DAVID A (US); KARWACKI EUGENE J JR (US); MAC DOUGALL JAMES E (US)	US350 32206A	8-Feb-2006
US7745736B2	29-Jun-2010	Interconnecting substrate and semiconductor device	OGAWA KENTA (JP); TSUKANO JUN (JP); MAEDA TAKEHIKO (JP); SHIMOTO TADANORI (JP); YAMAMICHI SHINTARO (JP); BABA KAZUHIRO (JP)	US341 44506A	30-Jan-2006

US7815968B2	19-Oct-2010	Centrifugal method for filling high aspect ratio blind micro vias powdered materials for circuit formation	HOUGHAM GARETH (US); BUCHWALTER LEENA PAIVIKKI (US); BUCHWALTER STEPHEN L (US); CASEY JON (US); FEGER CLAUDIUS (US); FLOTTA MATTEO (US); GELMORE JEFFREY D (US); HINGE KATHLEEN C (US); JAIN ANURAG (US); KANG SUNG K (US); KNICKERBOCKER JOHN U (US)	US247 8-Oct-2008 89408A
US7135402B2	14-Nov-2006	Sealing pores of low-k dielectrics using CxHy	LIN KENG CHU (TW); CHENG SHWANG MING (TW); YEH MING LING (TW); BAO TIEN I (TW)	US485 1-Feb-2005 1805A
US7341908B2	11-Mar-2008	Semiconductor device and method of manufacturing the same	SUH BONG SEOK (KR); CHOI SEUNG MAN (KR); SHIN HONG JAE (KR); WEE YOUNG JIN (KR)	US344 30-Jan-2006 55006A
US8137821B2	20-Mar-2012	Substituted ethynyl gold-nitrogen containing heterocyclic carbene complex and organic electroluminescent device using the same	FUJIMURA OSAMU (JP); FUKUNAGA KENJI (JP); HONMA TAKASHI (JP); MACHIDA TOSHIKAZU (JP); TAKAHASHI TAKESHI (JP)	US883 31-Jan-2006 32006A
US8324018B2	4-Dec-2012	Semiconductor device, electronic device, and method of manufacturing semiconductor device	ISA TOSHIYUKI (JP); FUJII GEN (JP); MORISUE MASAFUMI (JP); KAWAMATA IKUKO (JP)	US641 18-Dec-2009 70109A
US7915058B2	29-Mar-2011	Substrate having pattern and method for manufacturing the same, and semiconductor device and method for manufacturing the same	AOKI TOMOYUKI (JP); DAIRIKI KOJI (JP)	US334 19-Jan-2006 47406A
US7638252B2	29-Dec-2009	Dielectric layer; photoreceptors; electrostatic latent imaging	STASIAK JAMES WILLIAM (US); MCCLELLAND PAUL (US)	US459 28-Jan-2005 2105A
US7922823B2	12-Apr-2011	Compositions for processing of semiconductor substrates	WALKER ELIZABETH (US); NAGHSHINEH SHAHRI (US); BARNES JEFFREY A (US); OLDAK EWA (US); PETERS DARRYL W (US); YANDERS KEVIN P (US)	US814 26-Jan-2006 71406A
US2008149137A1	26-Jun-2008	Method For Cleaning Surfaces	STEINBRENNER ULRICH (DE); MOCK CHRISTOF (DE); SCHORNICK GUNNAR (DE); FRENZEL STEFAN (DE); EHRENSTEIN MORITZ (DE); FECHTENKOTTER ANDREAS (DE); ZIEMER ANTJE (DE); MICHL KATHRIN (DE); WEIDL CHRISTIAN HUBERT (DE)	US814 19-Jan-2006 57706A
US2012126226A1	24-May-2012	SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME, AND ELECTRIC DEVICE	KUWABARA HIDEAKI (JP); YAMAMOTO HIROKO (JP)	US201 3-Feb-2012 213365 498A
US8835907B2	16-Sep-2014	Memory device and semiconductor device	MORIYA YOSHITAKA (JP); WATANABE YASUKO (JP); ARAI YASUYUKI (JP)	US793 20-Jan-2006 81006A
US7436009B2	14-Oct-2008	Via structures and trench structures and dual damascene structures	HUANG YI CHEN (TW); FU CHIEN CHUNG (TW); HSIEH MING HONG (TW); OUYANG HUI (TW); SU YI NIEN (TW); TAO HUN JAN (TW)	US732 4-Apr-2007 88307A
US7837890B2	23-Nov-2010	Selectivity; pastes; doped glass; semiconductors; solar cells	STOCKUM WERNER (DE); KUEBELBECK ARMIN (DE); KLEIN SYLKE (DE)	US813 19-Dec-2005 63205A
US7700411B2	20-Apr-2010	Semiconductor device package and manufacturing method	YANG JUN YOUNG (TW); JOO YOU OCK (TW); JUNG DONG PIL (TW)	US852 7-Sep-2007 07907A

US7282394B2	16-Oct-2007	Printed circuit board including embedded chips and method of fabricating the same using plating	CHO SUK HYEON (KR); RYU CHANG SUP (KR); LEE DOO HWAN (KR)	US179 86405A	11-Jul-2005
US7256120B2	14-Aug-2007	Method to eliminate plating copper defect	TSAO JUNG CHIN (TW); LIU CHI WEN (TW); FENG HSIEN PING (TW); CHENG HSI KUEI (TW); LIN STEVEN (TW); CHENG MIN YUAN (TW)	US249 1704A	28-Dec-2004
US7405167B2	29-Jul-2008	Method of manufacturing nonvolatile organic memory device and nonvolatile organic memory device manufactured by the same	KANG YOON SOK (KR); LEE SANG KYUN (KR); JOO WON JAE (KR); LEE KWANG HEE (KR)	US214 72405A	31-Aug-2005
US7297452B2	20-Nov-2007	Alkali-soluble resin; a quinone diazide; and a mixture of surfactants including a 3-(perfluoroalkyl)-1,2-epoxypropane, reaction product between methylhydrobis(trimethylsiloxy)silane and polyalkylene glycol monoallyl ether preferably having a molecular weight from 200 to 500 and a 2nd ether silicone	LEE HI KUK (KR); YUKO YAKO (JP); KIM KYU YOUNG (KR)	US318 15705A	23-Dec-2005
US2008260956A1	23-Oct-2008	Film, Silica Film and Method of Forming the Same, Composition for Forming Silica Film, and Electronic Part	SAKURAI HARUAKI (JP); YOSHIKAWA TAKAHIRO (JP)	US793 59305A	21-Dec-2005
US7528476B2	5-May-2009	Semiconductor device, method for manufacturing semiconductor device, circuit board, and electronic instrument	ITO HARUKI (JP)	US305 47105A	16-Dec-2005
US7368336B2	6-May-2008	Organic insulator, organic thin film transistor array panel including organic insulator, and manufacturing method therefor	LEE YONG UK (KR); CHUNG KYUHA (KR); HONG MUN PYO (KR); YOON DO YEUNG (KR); HONG JONG IN (KR); KIM GIA (KR)	US313 43105A	20-Dec-2005
US7202173B2	10-Apr-2007	Systems and methods for electrical contacts to arrays of vertically aligned nanorods	HANTSCHER THOMAS (US); JOHNSON NOBLE M (US); KIESEL PETER (US); VAN DE WALLE CHRISTIAN G (US); WONG WILLIAM S (US)	US156 6504A	20-Dec-2004
US9607889B2	28-Mar-2017	Forming structures using aerosol jet® deposition	RENN MICHAEL J (US); KING BRUCE H (US)	US201 414449 811A	1-Aug-2014
US7871309B2	18-Jan-2011	Polishing pad	OGAWA KAZUYUKI (JP); SHIMOMURA TETSUO (JP); KAZUNO ATSUSHI (JP); NAKAI YOSHIYUKI (JP); WATANABE MASAHIRO (JP); YAMADA TAKATOSHI (JP); NAKAMORI MASAHIKO (JP)	US720 96405A	8-Dec-2005
US7309652B2	18-Dec-2007	Method for removing photoresist layer and method for forming metal line in semiconductor device using the same	RYU SANG WOOK (KR)	US146 53805A	6-Jun-2005
US9123625B2	1-Sep-2015	Display device	YOSHIDA YASUNORI (JP); KIMURA HAJIME (JP); MAEKAWA SHINJI (JP); NAKAMURA OSAMU (JP); YAMAZAKI SHUNPEI (JP)	US201 414260 533A	24-Apr-2014
US9985207B2	29-May-2018	Electronic devices	HAYTON CARL (GB); SIRRINGHAUS HENNING (GB); VON WERNE TIMOTHY (GB); NORVAL SHANE (GB)	US720 97905A	6-Dec-2005
US7682703B2	23-Mar-2010	Microfabrication using patterned topography and self-assembled monolayers	FREY MATTHEW H (US); NGUYEN KHANH P (US)	US564 58206A	29-Nov-2006

US2012264977A1	18-Oct-2012	TRIARYLAMINE CONTAINING POLYMERS AND ELECTRONIC DEVICES	WANG CHUN (US); INBASEKARAN MICHAEL (US); YU WANGLIN (US); CHENG YANG (US)	US201 213537 908A	29-Jun-2012
US2006121717A1	8-Jun-2006	Bonding structure and fabrication thereof	YU CHEN HUA (TW); LIU CHUNG SHI (TW)	US100 304A	2-Dec-2004
US2006112969A1	1-Jun-2006	WET CLEANING OF ELECTROSTATIC CHUCKS	SHIH HONG (US); HUANG TUOCHUAN (US); ZHOU CATHERINE (US); MOREL BRUNO (US); MCMILLIN BRIAN (US); MULGREW PAUL (US); AVOYAN ARMEN (US)	US388 04A	1-Dec-2004
US9397250B2	19-Jul-2016	Releasing apparatus for separating a semiconductor substrate from a semiconductor template	MOSLEHI MEHRDAD M (US); WANG DAVID XUAN QI (US); TOR SAM TONE (US); KRAMER KARL JOSEF (US)	US201 213463 757A	3-May-2012
US7732349B2	8-Jun-2010	Manufacturing method of insulating film and semiconductor device	YAMAMOTO HIROKO (JP)	US283 81205A	22-Nov-2005
US8058172B2	15-Nov-2011	Polishing process of a semiconductor substrate	YONEDA YASUHIRO (JP); SHIROTA MAMI (JP)	US406 44009A	18-Mar-2009
US2006112971A1	1-Jun-2006	Method of eliminating galvanic corrosion in copper CMP	KUO HAN HSIN (TW); LU HSIN HSIEN (TW); CHEN YING HO (TW); JANG SYUN MING (TW)	US999 27704A	30-Nov-2004
US7495881B2	24-Feb-2009	Chucking method and processing method using the same	KAMEYAMA KOJIRO (JP); SUZUKI AKIRA (JP); OKAYAMA YOSHIO (US); UMEMOTO MITSUO (JP)	US287 48405A	28-Nov-2005
US7547335B2	16-Jun-2009	Chemical mechanical polishing, and forming a wiring pattern of semiconductor devices; minimizing defects such as corrosion, scratches, thinning, and erosion; for polishing wafers	SEKI HIROYUKI (JP); YAMASHITA KATSUHIRO (JP); AKATSUKA TOMOHIKO (JP); INABA TADASHI (JP)	US287 38605A	28-Nov-2005
US2009008792A1	8-Jan-2009	Three-dimensional chip-stack package and active component on a substrate	KO CHENG TA (TW); LU SU TSAI (TW)	US232 01908A	10-Sep-2008
US2006255315A1	16-Nov-2006	Selective removal chemistries for semiconductor applications, methods of production and uses thereof	YELLOWAGA DEBORAH L (US); PALMER BEN (US); STARZYNSKI JOHN S (US); MCFARLAND JOHN A (US); LOWE MARIE (US)	US352 12406A	10-Feb-2006
US7294566B2	13-Nov-2007	Method for forming wiring pattern, method for manufacturing device, device, electro-optic apparatus, and electronic equipment	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US250 37005A	17-Oct-2005
US8033655B2	11-Oct-2011	Pressure-regulating valve, functional liquid supplying apparatus, imaging apparatus, method of manufacturing electro-optic device, electro-optic device, and electronic apparatus	NAKAMURA TOMONORI (JP)	US258 51608A	27-Oct-2008
US7736949B2	15-Jun-2010	Device and method for fabricating double-sided SOI wafer scale package with optical through via connections	CHEN HOWARD HAO (US); HSU LOUIS LU CHEN (US)	US199 06308A	27-Aug-2008
US2006118973A1	8-Jun-2006	Sheet for optical-semiconductor-element encapsulation and process for producing optical semiconductor device with the sheet	HARADA NORIAKI (JP); HOTTA YUJI (JP); SUEHIRO ICHIRO (JP); SADAYORI NAOKI (JP)	US273 08205A	15-Nov-2005

US7704872B2	27-Apr-2010	Ultraviolet assisted pore sealing of porous low k dielectric films	WALDFRIED CARLO (US); ESCORCIA ORLANDO (US); BERRY IVAN (US)	US702 5-Feb-2007 46507A
US9997568B2	12-Jun-2018	Semiconductor device	YAMAZAKI SHUNPEI (JP); ABE HIROKO (JP); NEMOTO YUKIE (JP); NOMURA RYOJI (JP); YUKAWA MIKIO (JP)	US201 6-Jun-2016 615174 293A
US8178397B2	15-May-2012	Field effect transistor	ARAMAKI SHINJI (JP); YOSHIYAMA RYUICHI (JP); OHNO AKIRA (JP); SAKAI YOSHIMASA (JP)	US719 10-Nov-2005 09605A
US7684868B2	23-Mar-2010	Microfabricated devices for wireless data and power transfer	TAI YU CHONG (US); RODGER DAMIEN C (US); LI WEN (US); HUMAYUN MARK (US); WEILAND JAMES D (US)	US272 10-Nov-2005 38205A
US7687223B2	30-Mar-2010	photoresists; semiconductors	TAKEI SATOSHI (JP); SHINJO TETSUYA (JP); HASHIMOTO KEISUKE (JP)	US666 25-Oct-2005 34205A
US2009127692A1	21-May-2009	METHOD OF CONNECTING A SEMICONDUCTOR PACKAGE TO A PRINTED WIRING BOARD	KAWATE KOHICHIRO (JP); SATO YOSHIAKI (JP); MONMA MIWA (JP); KAWATE YOSHIHISA (JP)	US577 14-Oct-2005 92105A
US7524347B2	28-Apr-2009	CMP composition comprising surfactant	SUN TAO (US); MEDSKER ROBERT (US)	US975 28-Oct-2004 58504A
US7622385B2	24-Nov-2009	Wiring pattern forming method, film pattern forming method, semiconductor device, electro-optical device, and electronic equipment	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US242 4-Oct-2005 00905A
US8038752B2	18-Oct-2011	Metal ion-containing CMP composition and method for using the same	CARTER PHILLIP W (US)	US974 27-Oct-2004 46004A
US8174094B2	8-May-2012	Bonded structures formed by plasma enhanced bonding	CHEN CHIEN HUA (US); SNYDER BARRY C (US); HELLEKSON RONALD A (US)	US488 21-Jun-2009 57109A
US8143706B2	27-Mar-2012	Method of forming a component having dielectric sub-layers	MARDILOVICH PETER (US); KRAMER LAURA (US); HERMAN GREGORY S (US); HOFFMAN RANDY (US); PUNSALAN DAVID (US)	US778 16-Jul-2007 20107A
US10225906B2	5-Mar-2019	Light emitting device including semiconductor nanocrystals	COE SULLIVAN SETH (US); STECKEL JONATHAN S (US); KIM LEEANN (US); BAWENDI MOUNGI G (US); BULOVIC VLADIMIR (US)	US253 20-Oct-2005 59505A
US2006088702A1	27-Apr-2006	Pattern formation method and functional film	SAKAI SHINRI (JP); HIRAI TOSHIMITSU (JP)	US244 6-Oct-2005 80405A
US7445809B2	4-Nov-2008	Using a droplet discharge method; useful for formation of fine wiring patterns, such as those used in semiconductor integrated circuits	SAKAI SHINRI (JP); HIRAI TOSHIMITSU (JP)	US561 20-Nov-2006 54806A
US2006084271A1	20-Apr-2006	Systems, methods and slurries for chemical mechanical polishing	YANG ANDY C (CN); YU CHRIS C (CN)	US970 20-Oct-2004 54704A

US8921461B2	30-Dec-2014	Epoxy resin composition and semiconductor device	KOTANI TAKAHIRO (JP); SEKI HIDETOSHI (JP); MAEDA MASAKATSU (JP); SHIGENO KAZUYA (JP); NISHITANI YOSHINORI (JP)	US201 213667 318A	2-Nov-2012
US2008200002A1	21-Aug-2008	Plasma Sputtering Film Deposition Method and Equipment	SUZUKI KENJI (US); IKEDA TARO (JP); HATANO TATSUO (JP); MIZUSAWA YASUSHI (US)	US577 53505A	18-Oct-2005
US8889332B2	18-Nov-2014	Low-K dielectric functional imprinting materials	XU FRANK Y (US); CHUN JUN SUNG (US); WATTS MICHAEL P C (US)	US201 113172 350A	29-Jun-2011
US2006084206A1	20-Apr-2006	Thin-film pattern forming method, semiconductor device, electro-optic device, and electronic apparatus	MORIYA KATSUYUKI (JP); HIRAI TOSHIMITSU (JP)	US244 80505A	6-Oct-2005
US8156646B2	17-Apr-2012	Method for manufacturing printed wiring board	IWAI TSUTOMU (JP); KODERA YOSHIHIRO (JP); MAEDA SHINYA (JP); WATANABE HIROYUKI (JP); SUZUKI KAZUNARI (JP); TSUKADA KIYOTAKA (JP)	US494 94809A	30-Jun-2009
US7244311B2	17-Jul-2007	Heat transfer system for improved semiconductor processing uniformity	FISCHER ANDREAS (US)	US962 56804A	13-Oct-2004
US2008076253A1	27-Mar-2008	Adhesive Sheet,Semiconductor Device,and Process for Producing Semiconductor Device	FUKADA HIROSHI (JP)	US576 26707A	29-Mar-2007
US2006068091A1	30-Mar-2006	Method for manufacturing functional film and method for manufacturing thin film transistor	DENDA ATSUSHI (JP)	US213 97205A	30-Aug-2005
US7399668B2	15-Jul-2008	Method for making electronic devices having a dielectric layer surface treatment	DUNBAR TIMOTHY D (US); KELLEY TOMMIE W (US)	US954 41304A	30-Sep-2004
US7335991B2	26-Feb-2008	Pattern forming structure, pattern forming method, device, electro-optical device, and electronic apparatus	HIRAI TOSHIMITSU (JP); MORIYA KATSUYUKI (JP)	US213 86405A	30-Aug-2005
US2007287362A1	13-Dec-2007	POLISHING COMPOSITION AND METHOD OF POLISHING WITH THE SAME	TAKENOUCHI KENJI (JP)	US830 52507A	30-Jul-2007
US7316974B2	8-Jan-2008	Wiring pattern formation method, manufacturing method for multi layer wiring substrate, and electronic device	UEHARA NOBORU (JP); SHINTATE TSUYOSHI (JP); SAKURADA KAZUAKI (JP)	US235 63405A	26-Sep-2005
US7432137B2	7-Oct-2008	Method of manufacturing thin film transistor	DENDA ATSUSHI (JP)	US197 32005A	5-Aug-2005
US7332445B2	19-Feb-2008	chemical vapor deposition method for forming a porous organosilicate glass film on a substrate; organosilane and/or organosiloxane precursor and a porogen precursor; insulating layers in electronic devices	LUKAS AARON SCOTT (US); O NEILL MARK LEONARD (US); KARWACKI JR EUGENE JOSEPH (US); VRTIS RAYMOND NICHOLAS (US); VINCENT JEAN LOUISE (US)	US228 22305A	19-Sep-2005
US2014113451A1	24-Apr-2014	METHOD FOR FORMING A PATTERN	SAKURAI NAOAKI (JP)	US201 314058 798A	21-Oct-2013

US7205244B2	17-Apr-2007	Patterning substrates employing multi-film layers defining etch-differential interfaces	STACEY NICHOLAS A (US); SREENIVASAN SIDLGATA V (US); MILLER MICHAEL N (US)	US946 21-Sep-2004 57404A
US2014315332A1	23-Oct-2014	System and Method for Increasing Productivity of Combinatorial Screening	PINTO GUSTAVO A (US); CHIANG TONY P (US); WEINER KURT H (US)	US201 1-Jul-2014 414321 663A
US2015287616A1	8-Oct-2015	Methods for Discretized Processing and Process Sequence Integration of Regions of a Substrate	BOUSSIE THOMAS R (US); CHIANG TONY P (US); GORER ALEXANDER (US); LAZOVSKY DAVID E (US)	US201 29-May-2015 514725 192A
US2015056723A1	26-Feb-2015	Processing Substrates Using Site-Isolated Processing	LAZOVSKY DAVID E (US); CHIANG TONY P (US); MALHOTRA SANDRA G (US)	US201 6-Oct-2014 414507 209A
US9362231B2	7-Jun-2016	Molecular self-assembly in substrate processing	CHIANG TONY P (US); KESHAVARZ MAJID (US); LAZOVSKY DAVID E (US)	US201 16-Oct-2015 514885 002A
US8587093B2	19-Nov-2013	Multilayer device with organic and inorganic dielectric material	MARDILOVICH PETER (US); HOFFMAN RANDY (US); HERMAN GREGORY (US)	US855 14-Sep-2007 42507A
US7282801B2	16-Oct-2007	Microelectronic device chip including hybrid Au bump, package of the same, LCD apparatus including microelectronic device chip and method of fabricating microelectronic device chip	PARK HYUNG KEUN (KR); JANG WOO JIN (KR); KIM YOUNG HO (KR); MOON TAE SUNG (KR)	US226 14-Sep-2005 79705A
US8698262B2	15-Apr-2014	Wireless chip and manufacturing method of the same	TSURUME TAKUYA (JP); DAIRIKI KOJI (JP); KUSUMOTO NAOTO (JP)	US213 30-Aug-2005 99705A
US2007254490A1	1-Nov-2007	Method of Making a Microelectronic and/or Optoelectronic Circuitry Sheet	JAIN AJAYKUMAR R (US)	US776 11-Jul-2007 06107A
US2008110748A1	15-May-2008	Selective High Dielectric Constant Material Etchant	STARZYNSKI JOHN (US)	US662 18-Mar-2005 24505A
US2006051500A1	9-Mar-2006	Method of forming wiring pattern, and method of forming source electrode and drain electrode for TFT	HIRAI TOSHIMITSU (JP); SAKAI SHINRI (JP)	US207 22-Aug-2005 88905A
US7196005B2	27-Mar-2007	Dual damascene process with dummy features	HO BANG CHING (TW)	US933 3-Sep-2004 58904A
US7432218B2	7-Oct-2008	Method for producing porous body	IMADA AYA (JP); DEN TOHRU (JP)	US211 26-Aug-2005 52705A
US7629250B2	8-Dec-2009	Method for creating electrically conductive elements for semiconductor device structures using laser ablation processes and methods of fabricating semiconductor device assemblies	BENSON PETER A (US); WATKINS CHARLES M (US)	US601 17-Nov-2006 34106A
US10448509B2	15-Oct-2019	Electronic device assemblies including conductive vias having two or more conductive elements	CORISIS DAVID J (US); LEE CHOON KUAN (SG); CHONG CHIN HUI (SG)	US201 13-Jul-2015 514797 721A

US2010317179A1	16-Dec-2010	METHOD FOR MAKING INTEGRATED CIRCUIT DEVICE	RANTALA JUHA T (FI); PAULASAARI JYRI (FI); KYLMA JANNE (FI); TORMANEN TURO T (FI); PIETIKAINEN JARKKO (FI); HACKER NIGEL (US); HADZIC ADMIR (FI)	US382 41909A	16-Mar-2009
US7495316B2	24-Feb-2009	Methods of forming conductive vias and methods of forming multichip modules including such conductive vias	KIRBY KYLE K (US); FARNWORTH WARREN M (US)	US868 89907A	8-Oct-2007
US7528491B2	5-May-2009	Semiconductor components and assemblies including vias of varying lateral dimensions	KIRBY KYLE K (US); FARNWORTH WARREN M (US)	US516 42406A	5-Sep-2006
US7994547B2	9-Aug-2011	Semiconductor devices and assemblies including back side redistribution layers in association with through wafer interconnects	BENSON PETER A (US); AKRAM SALMAN (US)	US178 06608A	23-Jul-2008
US7732334B2	8-Jun-2010	Method for manufacturing semiconductor device	MORISUE MASAFUMI (JP); FUJII GEN (JP)	US195 72505A	3-Aug-2005
US2006265868A1	30-Nov-2006	Inter-metal dielectric fill	RUEGER NEAL R (US); HILL CHRIS W (US); BIAN ZAILONG (US); SMYTHE JOHN A III (US)	US487 02706A	14-Jul-2006
US7785948B2	31-Aug-2010	Semiconductor element and process for producing the same	KAMATA TOSHIHIDE (JP); KOZASA TAKEHITO (JP)	US659 10505A	19-Aug-2005
US8338228B2	25-Dec-2012	Method of detaching a thin semiconductor circuit from its base	GAKIS ANDREAS (DE); SCHNITT WOLFGANG (DE)	US574 01405A	9-Aug-2005
US7736728B2	15-Jun-2010	Coated substrates and methods for their preparation	LOBODA MARK (US); SNOW STEVEN (US); WEIDNER WILLIAM (US); ZAMBOV LUDMIL (US)	US629 06505A	12-Aug-2005
US7622193B2	24-Nov-2009	Coated substrates and methods for their preparation	LOBODA MARK (US); SNOW STEVEN (US); WEIDNER WILLIAM (US); ZAMBOV LUDMIL (US)	US631 57905A	12-Aug-2005
US7375946B2	20-May-2008	Method and apparatus for dechucking a substrate	WHITE JOHN M (US); BLONIGAN WENDELL T (US)	US919 45704A	16-Aug-2004
US7723207B2	25-May-2010	Three dimensional integrated circuit and method of design	ALAM SYED M (US); ELFADEL IBRAHIM M (US); GUARINI KATHRYN W (US); IEONG MEIKEI (US); KUDVA PRABHAKAR N (US); KUNG DAVID S (US); LAVIN MARK A (US); RAHMAN ARIFUR (US)	US737 59807A	19-Apr-2007
US2006072281A1	6-Apr-2006	Methods of forming a layer utilizing a liquid-phase lanthanum precursor and methods of manufacturing a capacitor using the same	NAM GAB JIN (KR); PARK YOUNG GEUN (KR); KIM YOUNG SUN (KR); CHOI HAN MEI (KR); LEE SEUNG HWAN (KR); PARK KI YEON (KR); YOU CHA YOUNG (KR)	US196 94305A	4-Aug-2005
US7323407B2	29-Jan-2008	Method of fabricating dual damascene interconnections of microelectronic device using diffusion barrier layer against base material	LEE KYOUNG WOO (KR); MAENG JAE YEOL (KR); KIM JAE HAK (KR); OH IL WHAN (KR); SHIN HONG JAE (KR)	US195 40405A	2-Aug-2005
US7564058B2	21-Jul-2009	Display device, manufacturing method thereof, and television set	YAMAZAKI SHUNPEI (JP); SHOJI HIRONOBU (JP); MAEKAWA SHINJI (JP); NAKAMURA OSAMU (JP); HONDA TATSUYA (JP); FUJII GEN (JP); SUZUKI YUKIE (JP); KAWAMATA IKUKO (JP)	US187 98805A	25-Jul-2005

US8821742B2	2-Sep-2014	Plasma etching method	YOSHIDA RYOICHI (JP); YOSHIDA TETSUO (JP); SAITO MICHISHIGE (JP); WAKAKI TOSHIKATSU (JP); AOYAMA HAYATO (JP); OBI AKIRA (JP); SUZUKI HIROSHI (JP)	US700 4-Feb-2010 57110A
US9941115B2	10-Apr-2018	Method for manufacturing semiconductor device	TAMURA TOMOKO (JP); SUGIYAMA EIJI (JP); DOZEN YOSHITAKA (JP); DAIRIKI KOJI (JP); TSURUME TAKUYA (JP)	US201 25-Jul-2013 313950 957A
US7176126B2	13-Feb-2007	Method of fabricating dual damascene interconnection	OH HYEOK SANG (KR); CHUNG JU HYUCK (KR); KIM IL GOO (KR)	US157 21-Jun-2005 36305A
US8552559B2	8-Oct-2013	Very thick metal interconnection scheme in IC chips	LIN MOU SHIUNG (TW); CHOU CHIU MING (TW); CHOU CHIEN KANG (TW)	US879 23-Mar-2005 5505A
US7795736B2	14-Sep-2010	Interconnects with interlocks	SIR JIUN HANN (MY); GOH ENG HUAT (MY)	US715 8-Mar-2007 62407A
US7581549B2	1-Sep-2009	Method for removing carbon-containing residues from a substrate	JOHNSON ANDREW DAVID (US); SUBAWALLA HOSHANG (US); JI BING (US); VRTIS RAYMOND NICHOLAS (US); KARWACKI JR EUGENE JOSEPH (US); RIDGEWAY ROBERT GORDON (US); MAROULIS PETER JAMES (US); O NEILL MARK LEONARD (US); LUKAS AARON SCOTT (US); MOTIKA STEPHEN ANDREW (US)	US178 12-Jul-2005 54505A
US9217929B2	22-Dec-2015	Composition for removing photoresist and/or etching residue from a substrate and use thereof	EGBE MATTHEW I (US); GEITZ DENISE (US)	US896 22-Jul-2004 58904A
US7402503B2	22-Jul-2008	Dicing sheet, manufacturing method thereof, and manufacturing method of semiconductor apparatus	HARA KAZUMI (JP)	US159 22-Jun-2005 04705A
US7508078B2	24-Mar-2009	Electronic device, method for manufacturing electronic device, contact hole of electronic device, method for forming contact hole of electronic device	KONDO HIROSHI (JP); TOMONO HIDENORI (JP); TANO TAKANORI (JP); KONDOH HITOSHI (JP)	US319 28-Dec-2005 06305A
US7250681B2	31-Jul-2007	Semiconductor device and a method of manufacturing the semiconductor device	MATSUNAGA NORIAKI (JP)	US939 14-Sep-2004 41404A
US8911927B2	16-Dec-2014	Compositions and processes for immersion lithography	GALLAGHER MICHAEL K (US); WAYTON GERALD B (US); PROKOPOWICZ GREGORY P (US); ROBERTSON STEWART A (US)	US862 24-Aug-2010 63910A
US8575040B2	5-Nov-2013	Low temperature process for polysilazane oxidation/densification	FUCSKO JANOS (US); SMYTHE III JOHN A (US); LI LI (US); WALDO GRADY S (US)	US497 6-Jul-2009 79109A
US7384871B2	10-Jun-2008	Polishing copper metal interconnects on a semiconductor wafer, oxidizer, copper inhibitor, copper complexing agent, modified cellulose, acrylic acid-methacrylic acid copolymer and water; preventing excessive dishing; time for clearing residual copper from the wafer is less than thirty seconds.	KELLEY FRANCIS J (US); QUANCI JOHN (US); SO JOSEPH K (US); WANG HONGYU (US)	US882 1-Jul-2004 56704A
US8440599B2	14-May-2013	Composition for stripping and cleaning and use thereof	EGBE MATTHEW I (US); LEGENZA MICHAEL WALTER (US); WEIDER THOMAS MICHAEL (US); RIEKER JENNIFER MAY (US)	US201 25-Aug-2011 113217 994A

US7485612B2	3-Feb-2009	Electronic parts cleaning solution	TAKASHIMA MASAYUKI (JP)	US174 30-Jun-2005 06105A
US7560134B2	14-Jul-2009	Nanoparticle implantation	YANIV ZVI (US); FINK RICHARD LEE (US); YANG MOHSHI (US)	US570 28-Jun-2005 91205A
US7829976B2	9-Nov-2010	Microelectronic devices and methods for forming interconnects in microelectronic devices	KIRBY KYLE K (US); AKRAM SALMAN (US); HEMBREE DAVID R (US); RIGG SIDNEY B (US); FARNWORTH WARREN M (US); HIATT WILLIAM M (US)	US419 6-Apr-2009 02909A
US7312152B2	25-Dec-2007	Lactate-containing corrosion inhibitor	STEPHENSON ADAM R (US); CHIANG HUE D (US)	US879 28-Jun-2004 46204A
US2007178658A1	2-Aug-2007	Patterning and aligning semiconducting nanoparticles	KELLEY TOMMIE W (US); DUNBAR TIMOTHY D (US)	US156 20-Jun-2005 80005A
US7645556B2	12-Jan-2010	Photo-patternable composition for forming an organic insulating film which includes a functional group-containing monomer, an initiator generating an acid or a radical upon light irradiation, and an organic or inorganic polymer; simplified process; high charge carrier mobility	SHIN JUNG HAN (KR); LEE TAE WOO (KR); KOO BON WON (KR); LEE BANG LIN (KR); LEE SANG YOON (KR)	US156 21-Jun-2005 48905A
US2011215469A1	8-Sep-2011	METHOD FOR FORMING A DOUBLE EMBOSSING STRUCTURE	LO HSIN JUNG (TW); LIN MOU SHIUNG (TW); CHOU CHIU MING (TW); CHOU CHIEN KANG (TW)	US201 16-May-2011 113108 811A
US7709814B2	4-May-2010	Apparatus and process for treating dielectric materials	WALDFRIED CARLO (US); GARMER CHRISTOPHER (US); ESCORCIA ORLANDO (US); BERRY III IVAN (US); SAKTHIVEL PALANI (US); JANOS ALAN C (US)	US155 17-Jun-2005 52505A
US7459786B2	2-Dec-2008	Semiconductor device	SHIMAZU HIROMI (JP); IWASAKI TOMIO (JP); OHTA HIROYUKI (JP); ISHIKAWA KENSUKE (JP); INOUE OSAMU (JP); OSHIMA TAKAYUKI (JP)	US155 17-Jun-2005 27205A
US7611319B2	3-Nov-2009	Methods and apparatus for identifying small lot size substrate carriers	SHAH VINAY (US); ELLIOTT MARTIN R (US); HUDGENS JEFFREY C (US); ENGLHARDT ERIC ANDREW (US)	US154 16-Jun-2005 93205A
US7390704B2	24-Jun-2008	Laser process apparatus, laser irradiation method, and method for manufacturing semiconductor device	TANAKA KOICHIRO (JP)	US137 26-May-2005 49405A
US2006003910A1	5-Jan-2006	Composition and method comprising same for removing residue from a substrate	HSU JIUN Y (US); WU AIPING (US); EGBE MATTHEW I (US)	US142 2-Jun-2005 45005A
US7696031B2	13-Apr-2010	Method for manufacturing semiconductor device	SHIMOMURA AKIHISA (JP); SHOJI HIRONOBU (JP)	US150 13-Jun-2005 28505A
US7504327B2	17-Mar-2009	Method of manufacturing thin film semiconductor device	YAMAZAKI SHUNPEI (JP); ISOBE ATSUO (JP); YAMAGUCHI TETSUJI (JP); GODO HIROMICHI (JP)	US148 9-Jun-2005 42605A
US7385287B2	10-Jun-2008	Preventing damage to low-k materials during resist stripping	LI SIYI (US); ZHU HELEN H (US); DANG HOWARD (US); CHOI THOMAS S (US); LOEWENHARDT PETER (US)	US744 3-May-2007 03507A

US7879742B2	1-Feb-2011	Laser annealing method wherein reflected beams are minimized	TANAKA KOICHIRO (JP)	US596 58305A	6-Jun-2005
US8871623B2	28-Oct-2014	Methods and devices for forming nanostructure monolayers and devices including such monolayers	CHEN JIAN (US); CRUDEN KAREN CHU (US); DUAN XIANGFENG (US); LIU CHAO (US); PARCE J WALLACE (US)	US201 414251 092A	11-Apr-2014
US8143703B2	27-Mar-2012	Methods and devices for forming nanostructure monolayers and devices including such monolayers	HEALD DAVID L (US); CRUDEN KAREN CHU (US); DUAN XIANGFENG (US); LIU CHAO (US); PARCE J WALLACE (US)	US291 10108A	5-Nov-2008
US10355113B2	16-Jul-2019	Controlled buckling structures in semiconductor interconnects and nanomembranes for stretchable electronics	ROGERS JOHN A (US); MEITL MATTHEW (US); SUN YUGANG (US); KO HEUNG CHO (KR); CARLSON ANDREW (US); CHOI WON MOOK (KR); STOYKOVICH MARK (US); JIANG HANQING (US); HUANG YONGGANG (US); NUZZO RALPH G (US); ZHU ZHENGTAO (US); MENARD ETIENNE (US); KHANG DAHL YOUNG (KR)	US201 615084 112A	29-Mar-2016
US12074213B2	27-Aug-2024	Methods and devices for fabricating and assembling printable semiconductor elements	NUZZO RALPH G (US); ROGERS JOHN A (US); MENARD ETIENNE (FR); LEE KEON JAE (KR); KHANG DAHL YOUNG (KR); SUN YUGANG (US); MEITL MATTHEW (US); ZHU ZHENGTAO (US)	US202 117357 697A	24-Jun-2021
US7807482B2	5-Oct-2010	Method for transferring wafers	ASPAR BERNARD (FR); LAGAHE BLANCHARD CHRYSTELLE (FR)	US628 61505A	2-Jun-2005
US7399703B2	15-Jul-2008	Process for patterning nanocarbon material, semiconductor device, and method for manufacturing semiconductor device	KAWAKAMI SOICHIRO (JP)	US138 33105A	27-May-2005
US2005263719A1	1-Dec-2005	Ultraviolet ray generator, ultraviolet ray irradiation processing apparatus, and semiconductor manufacturing system	OHDAIRA TOSHIYUKI (JP); SHIOYA YOSHIMI (JP)	US852 3105A	22-Mar-2005
US7157789B2	2-Jan-2007	Semiconductor device and method for manufacturing the same	HIRANO KOICHI (JP); YAMAMOTO YOSHIYUKI (JP); NAKATANI SEIICHI (JP); KOJIMA TOSHIYUKI (JP); KOMATSU SHINGO (JP)	US136 11005A	24-May-2005
US2007240366A1	18-Oct-2007	Composition for Polishing	OTA ISAO (JP); TANIMOTO KENJI (JP); TAKAKUMA NORIYUKI (JP)	US596 38905A	16-May-2005
US2006287208A1	21-Dec-2006	Methods of Forming Corrosion-Inhibiting Cleaning Compositions for Metal Layers and Patterns on Semiconductor Substrates	LEE KWANG WOOK (KR); HWANG IN SEAK (KR); LEE KEUM JOO (KR); SONG CHANG LYONG (KR); KO YONG SUN (KR); BAEK KUI JONG (KR); HAN WOONG (KR)	US467 73606A	28-Aug-2006
US7316976B2	8-Jan-2008	Polishing method to reduce dishing of tungsten on a dielectric	NOJO HARUKI (JP); SUZUKI YOSHIBUMI (JP)	US132 31505A	19-May-2005
US2005252526A1	17-Nov-2005	Single wafer cleaning apparatus and cleaning method thereof	OGAWA NAOKI (JP); IWAMOTO HAYATO (JP); ASADA KAZUMI (JP); YOKOTA MARI (JP); HIEI YASUHIRO (JP); NISHIMATSU TSUYOSHI (JP)	US116 35305A	28-Apr-2005
US7008808B2	7-Mar-2006	Method of manufacturing LCOS spacers	JEN CHUNG KUEI (TW)	US840 11704A	5-May-2004

US8007631B2	30-Aug-2011	System and method for imprint lithography to facilitate dual damascene integration with two imprint acts	DAKSHINA MURTHY SRIKANTESWARA (US); SINGH BHANWAR (US); SUBRAMANIAN RAMKUMAR (US)	US741 99107A	30-Apr-2007
US7608856B2	27-Oct-2009	Electronic devices comprising organic semiconductors	BECKER HEINRICH (DE); STREY REINHARD (DE); MEERHOLZ KLAUS (DE); MUELLER DAVID CHRISTOPH (DE)	US587 46205A	3-May-2005
US7608909B2	27-Oct-2009	Suspended transmission line structures in back end of line processing	CHINTHAKINDI ANIL K (US); GROVES ROBERT A (US); TRETIKOV YOURI V (US); VAED KUNAL (US); VOLANT RICHARD P (US)	US164 76505A	5-Dec-2005
US2005241671A1	3-Nov-2005	Method for removing a substance from a substrate using electron attachment	DONG CHUN C (US); JI BING (US)	US955 8005A	1-Apr-2005
US8669663B2	11-Mar-2014	Wiring over substrate, semiconductor device, and methods for manufacturing thereof	SASAGAWA SHINYA (JP); OKAMOTO SATORU (JP); MONOE SHIGEHARU (JP)	US201 113187 746A	21-Jul-2011
US7544586B2	9-Jun-2009	Method of fabricating chips and an associated support	GHYSELEN BRUNO (FR); RAYSSAC OLIVIER (FR)	US136 25205A	23-May-2005
US7265053B2	4-Sep-2007	Trench photolithography rework for removal of photoresist residue	HSU JYH SHIOU (TW)	US831 94304A	26-Apr-2004
US2005239286A1	27-Oct-2005	TWO-STEP STRIPPING METHOD FOR REMOVING VIA PHOTORESIST DURING THE FABRICATION OF PARTIAL-VIA DUAL DAMASCENE FEATURES	WU CHIH NING (TW); LIEN WEN LIANG (TW); LEE CHARLIE C (TW); LI MEILING (TW)	US904 15104A	27-Oct-2004
US10263041B2	16-Apr-2019	Quantum dot optical devices with enhanced gain and sensitivity and methods of making same	SARGENT EDWARD HARTLEY (CA); CLIFFORD JASON PAUL (US); KONSTANTATOS GERASIMOS (ES); HOWARD IAN (DE); KLEM ETHAN J D (US); LEVINA LARISSA (CA)	US201 815987 951A	24-May-2018
US8213212B2	3-Jul-2012	Methods of making quantum dot films	SARGENT EDWARD (CA); KONSTANTATOS GERASIMOS (ES); LEVINA LARISSA (CA); HOWARD IAN (DE); KLEM ETHAN J D (US); CLIFFORD JASON (US)	US201 113242 397A	23-Sep-2011
US8284586B2	9-Oct-2012	Electronic and optoelectronic devices with quantum dot films	SARGENT EDWARD (CA); LEVINA LARISSA (CA); KONSTANTATOS GERASIMOS (ES); HOWARD IAN (DE); KLEM ETHAN J D (US); CLIFFORD JASON (US)	US201 113226 533A	7-Sep-2011
US7445810B2	4-Nov-2008	Creating a tantalum layer disposed on a first layer region of a first layer and on a second layer region of a second layer; tantalum layer has a substantially body-centered-cubic (bcc)-phase tantalum region on the first layer region, and a non-bcc-phase tantalum region on the second layer region	FARTASH ARJANG (US)	US825 84104A	15-Apr-2004
US7709959B2	4-May-2010	Article with a metal layer on a substrate	WATKINS JAMES J (US); ZONG YINFENG (US)	US363 40306A	24-Feb-2006
US8230807B2	31-Jul-2012	Coatings, and methods and devices for the manufacture thereof	ALCOTT GREGORY ROBERT (GB); CREATORE MARIADRIANA (NL); LINDEN JOANNES LEONARD (NL); SANDEN MAURITIUS CORNELIS MARIA VAN DE (NL)	US578 49105A	14-Apr-2005
US7378349B2	27-May-2008	Chemical mechanical polishing aqueous dispersion and chemical mechanical polishing method	KONNO TOMOHISA (JP); SHIDA HIROTAKA (JP); KUBOTA KIYONOBU (JP); HATTORI MASAYUKI (JP); KAWAHASHI NOBUO (JP)	US102 63905A	11-Apr-2005

US7078723B2	18-Jul-2006	Microelectronic device with depth adjustable sill	LIN CHUAN YI (TW); LEE WEN CHIN (TW); CHANG SUN JAY (TW); WU SHIEN YANG (TW)	US819 25004A	6-Apr-2004
US2006252358A1	9-Nov-2006	POLISHING PAD AND METHOD OF MAKING SAME	PRESTON SPENCER (US); HUTCHINS DOUG (US); HYMES STEVE (US)	US459 60106A	24-Jul-2006
US2005227382A1	13-Oct-2005	In-situ surface treatment for memory cell formation	HUI ANGELA T (US)	US817 13104A	2-Apr-2004
US7429789B2	30-Sep-2008	Fluoropolymer dielectric composition for use in circuitized substrates and circuitized substrate including same	JAPP ROBERT M (US); MARKOVICH VOYA R (US); PAPATHOMAS KOSTAS I (US)	US390 38606A	28-Mar-2006
US2005218480A1	6-Oct-2005	Device mounting board and semiconductor apparatus using device mounting board	USUI RYOSUKE (JP); NAKAMURA TAKESHI (JP); MIZUHARA HIDEKI (JP)	US881 3705A	23-Mar-2005
US2005217722A1	6-Oct-2005	Organic photoelectric conversion element and method of producing the same, organic photodiode and image sensor using the same, organic diode and method of producing the same	KOMATSU TAKAHIRO (JP); SAKANOUKE KEI (JP); YATSUNAMI RYUICHI (JP); MIZUSAKI MASAKAZU (JP); KITADA TAKASHI (JP); INOUE MASAHIRO (JP)	US927 1605A	30-Mar-2005
US7863760B2	4-Jan-2011	Roll-to-roll fabricated encapsulated semiconductor circuit devices	DANIELS JOHN J (US); NELSON GREGORY VICTOR (US)	US543 70506A	3-Oct-2006
US2006051615A1	9-Mar-2006	Organic electroluminescent element	KANNO HIROSHI (JP); OKUMOTO KENJI (JP); HAMADA YUJI (JP); HASHIMOTO HARUHISA (JP); IYORI MASAHIRO (JP); NISHIMURA KAZUKI (JP)	US852 6805A	22-Mar-2005
US7204742B2	17-Apr-2007	Polishing pad comprising hydrophobic region and endpoint detection port	PRASAD ABANESHWAR (US)	US808 82704A	25-Mar-2004
US8222636B2	17-Jul-2012	Method for forming pattern, thin film transistor, display device, method for manufacturing thereof, and television apparatus	FUJII GEN (JP)	US616 49109A	11-Nov-2009
US7838871B2	23-Nov-2010	Organic field-effect transistor, flat panel display device including the same, and a method of manufacturing the organic field-effect transistor	REDECKER MICHAEL (DE); FISCHER JOERG (DE); MATHEA ARTHUR (DE)	US614 5905A	22-Feb-2005
US8101093B2	24-Jan-2012	Chemical-mechanical polishing composition and method for using the same	DE REGE THESAURO FRANCESCO (US); MOEGGENBORG KEVIN J (US); BRUSIC VLASTA (US); BAYER BENJAMIN P (US)	US393 48909A	26-Feb-2009
US2005215732A1	29-Sep-2005	Composition for film formation, coating solution containing the same and electronic device having insulating film obtained by using the coating solution	WATANABE KATSUYUKI (JP); ADEGAWA YUTAKA (JP)	US842 5105A	21-Mar-2005
US7699684B2	20-Apr-2010	CMP porous pad with component-filled pores	PRASAD ABANESHWAR (US)	US690 94407A	26-Mar-2007
US8058152B2	15-Nov-2011	Method for manufacturing integrated circuit	TSURUME TAKUYA (JP); MARUYAMA JUNYA (JP); DOZEN YOSHITAKA (JP)	US859 87810A	20-Aug-2010

US8486287B2	16-Jul-2013	Methods for fabrication of positional and compositionally controlled nanostructures on substrate	ZHU JI (US); GRUNES JEFF (US); CHOI YANG KYU (US); BOKOR JEFFREY (US); SOMORJAI GABOR (US)	US599 10604A	14-Oct-2004
US7354863B2	8-Apr-2008	Methods of selectively removing silicon	KIRBY KYLE K (US); TOREK KEVIN J (US)	US804 36604A	19-Mar-2004
US2005208769A1	22-Sep-2005	Semiconductor structure	SHARMA MANISH (US)	US805 47104A	19-Mar-2004
US2005205835A1	22-Sep-2005	Alkaline post-chemical mechanical planarization cleaning compositions	TAMBOLI DNYANESH C (US); BANERJEE GAUTAM (US)	US650 8005A	25-Feb-2005
US2010226629A1	9-Sep-2010	ROLL-TO-ROLL PROCESSING AND TOOLS FOR THIN FILM SOLAR CELL MANUFACTURING	BASOL BULENT M (US); ZOLLA HOWARD (US); PINARBASI MUSTAFA (US); NORSWORTHY GREGORY (US)	US721 44610A	10-Mar-2010
US2009183675A1	23-Jul-2009	REACTOR TO FORM SOLAR CELL ABSORBERS	PINARBASI MUSTAFA (US); ZOLLA HOWARD G (US); YU YING (US); NORSWORTHY GREGORY (US); ASHJAE JALAL (US); BASOL BULENT M (US)	US334 42008A	12-Dec-2008
US8008113B2	30-Aug-2011	Technique and apparatus for depositing layers of semiconductors for solar cell and module fabrication	BASOL BULENT M (US)	US816 23610A	15-Jun-2010
US2011011340A1	20-Jan-2011	METHOD AND APPARATUS FOR CONVERTING PRECURSOR LAYERS INTO PHOTOVOLTAIC ABSORBERS	BASOL BULENT M (US)	US843 67410A	26-Jul-2010
US8192594B2	5-Jun-2012	Technique and apparatus for depositing thin layers of semiconductors for solar cell fabrication	BASOL BULENT M (US)	US106 24008A	18-Apr-2008
US2005199586A1	15-Sep-2005	Resist removal method and semiconductor device manufactured by using the same	MATSUSHITA ATSUSHI (JP); MATSUMOTO ISAO (JP); INUKAI KAZUAKI (JP); SHIN HONG J (KR); OHASHI NAOFUMI (JP); SONE SHUJI (JP); MISAWA KAORI (JP)	US529 1105A	9-Feb-2005
US7285795B2	23-Oct-2007	Vertical field-effect transistor, method of manufacturing the same, and display device having the same	REDECKER MICHAEL (DE); FISCHER JOERG (DE); MATHEA ARTHUR (DE)	US738 6705A	8-Mar-2005
US7514291B2	7-Apr-2009	Methods relating to singulating semiconductor wafers and wafer scale assemblies	AKRAM SALMAN (US)	US282 92205A	18-Nov-2005
US7122894B2	17-Oct-2006	Wiring substrate and process for manufacturing the same	SUGIMOTO ATSUHIKO (JP); SAIKI HAJIME (JP)	US712 0305A	4-Mar-2005
US2005196900A1	8-Sep-2005	Substrate protection system, device and method	HUMPHREY ALAN E (US); BROZ JERRY (US)	US794 71804A	5-Mar-2004
US7357879B2	15-Apr-2008	Etching solution, method of etching and printed wiring board	TAKAHASHI TSUNEHISA (JP); SAWA SHIGEKI (JP); MATSUI KAZUHIKO (JP)	US560 42105A	14-Dec-2005
US2009298671A1	3-Dec-2009	Compositions for Preparing Low Dielectric Materials Containing Solvents	WEIGEL SCOTT JEFFREY (US); KHOT SHRIKANT NARENDRA (US); MAC DOUGALL JAMES EDWARD (US); BRAYMER THOMAS ALBERT (US); KIRNER JOHN FRANCIS (US); PETERSON BRIAN KEITH (US)	US538 51009A	10-Aug-2009

US2021225640A1	22-Jul-2021	SUPPORT ASSEMBLY	KAO CHIEN TEH (US); HUSTON JOEL M (US); CHANG MEI (US); YUAN XIAOXIONG (US)	US202 8-Apr-2021 117225 311A
US7767556B2	3-Aug-2010	Adhesive sheet for laser dicing and its manufacturing method	OKAWA YUJI (JP)	US484 15-Jun-2009 93909A
US2005183740A1	25-Aug-2005	Process and apparatus for removing residues from semiconductor substrates	FULTON JOHN L (US); GASPAR DANIEL J (US); YONKER CLEMENT R (US); YOUNG JAMES S (US); LEA ALAN S (US); ENGELHARD MARK H (US)	US783 19-Feb-2004 24904A
US8318601B2	27-Nov-2012	Method for manufacturing thin film transistor and display device	FUJII GEN (JP)	US201 2-May-2011 113098 751A
US2005192409A1	1-Sep-2005	Polymers of polycyclic olefins having a polyhedral oligosilsesquioxane pendant group and uses thereof	RHODES LARRY F (US); SEGER LARRY (US); RAVIKIRAN RAMAKRISHNA (US); ELCE EDMUND (US); SHICK ROBERT (US); LIPIAN JOHN HENRY (US)	US549 10-Feb-2005 6305A
US7416463B2	26-Aug-2008	Panel substrate, display panel, organic EL panel, and method of manufacturing the same	OHSHITA ISAMU (JP); YUKI TOSHINAO (JP)	US450 31-Jan-2005 6905A
US7772113B2	10-Aug-2010	Post metal chemical mechanical polishing dry cleaning	OLLENDORF HEINRICH (US); CABRAL STACEY (US); FULLER ROBERT (US)	US926 29-Oct-2007 57807A
US7498294B2	3-Mar-2009	organic polymer particles (A) having a crosslinked structure and a surfactant (B) and is used after chemical mechanical polishing. The cleaning method of a semiconductor substrate is a method for cleaning semiconductor substrates	KONNO TOMOHISA (JP); KUBOTA KIYONOBU (JP); HATTORI MASAYUKI (JP); KAWAHASHI NOBUO (JP)	US529 9-Feb-2005 1005A
US7541322B2	2-Jun-2009	Comprising organic acid, organic alkaline component, at least one anionic surfactant selected from an alkylsulfonic acid or salt thereof, an alkyldiphenyl ether disulfonic acid or salt thereof, an alkylmethyltaurate, a sulfosuccinic acid diester and water; good water rinsability, removes fine particles	IKEMOTO MAKOTO (JP); MORINAGA HITOSHI (JP)	US500 8-Aug-2006 35606A
US8685835B2	1-Apr-2014	Method for manufacturing thin film integrated circuit, and element substrate	YAMAZAKI SHUNPEI (JP); DAIRIKI KOJI (JP)	US201 5-May-2011 113101 400A
US7598168B2	6-Oct-2009	Method of fabricating dual damascene interconnection and etchant for stripping sacrificial layer	HAN SANG CHEOL (KR); LEE KYOUNG WOO (KR); KIM MI YOUNG (KR)	US332 11-Jan-2005 0805A
US2005173799A1	11-Aug-2005	Interconnect structure and method for its fabricating	JOU JUAN JANN (TW); LEE YU HUA (TW); YANG CHIN TIEN (TW); LAI CHIA HUNG (TW); HSU CONNIE (TW); LIN MU YI (TW); CAO MIN (TW); KU CHIA YU (TW); FAN YUH DA (TW)	US772 5-Feb-2004 73604A
US8634266B2	21-Jan-2014	Semiconductor device	KATO KIYOSHI (JP)	US201 13-Sep-2012 213613 428A

US8343868B2	1-Jan-2013	Device and methodology for reducing effective dielectric constant in semiconductor devices	EDELSTEIN DANIEL C (US); COLBURN MATTHEW E (US); COONEY III EDWARD C (US); DALTON TIMOTHY J (US); FITZSIMMONS JOHN A (US); GAMBINO JEFFREY P (US); HUANG ELBERT E (US); LANE MICHAEL W (US); MCGAHAY VINCENT J (US); NICHOLSON LEE M (US); NITTA SATYANARAYANA V (US); PURUSHOTHAMAN SAMPATH (US); SANKARAN SUJATHA (US); SHAW THOMAS M (US); SIMON ANDREW H (US); STAMPER ANTHONY K (US)	US201 12-Jan-2011 113005 201A
US2006118830A1	8-Jun-2006	MSD raised metal interface features	BRUNNER DENNIS M (US); BUSTER DAVID L (US); GRAFF MICHAEL S (US); LUEBBERT DANIEL K (US); KREUTTER NATHAN P (US); YANG RUI (US)	US326 5-Jan-2006 14006A
US7635645B2	22-Dec-2009	Method for forming interconnection line in semiconductor device and interconnection line structure	LEE KYOUNG WOO (KR); SHIN HONG JAE (KR); KIM JAE HAK (KR); WEE YOUNG JIN (KR); LEE SEUNG JIN (KR); PARK KI KWAN (KR)	US285 4-Jan-2005 1505A
US7691685B2	6-Apr-2010	Method for manufacturing semiconductor device	MAEKAWA SHINJI (JP); YAMAZAKI SHUNPEI (JP); SHOJI HIRONOBU (JP)	US579 24-Jan-2005 80005A
US2005158664A1	21-Jul-2005	Method of integrating post-etching cleaning process with deposition for semiconductor device	TSENG JOSHUA (TW); CHUANG PING (TW); TU HUNG JUNG (TW); WANG CHING YA (TW); LIN YU LIANG (TW); LO HENRY (TW); ZHOU MEI SHENG (SG)	US760 20-Jan-2004 92704A
US8624252B2	7-Jan-2014	Substrate having film pattern and manufacturing method of the same, manufacturing method of semiconductor device, liquid crystal television, and el television	MAEKAWA SHINJI (JP); FUJII GEN (JP); SHIROGUCHI HIROKO (JP); MORISUE MASAFUMI (JP)	US201 12-Sep-2012 213612 146A
US2015221896A1	6-Aug-2015	AMBIPOLAR, LIGHT-EMITTING FIELD-EFFECT TRANSISTORS	ZAUMSEIL JANA (GB); SIRRINGHAUS HENNING (GB); CHUA LAY LAY (SG); HO PETER KIAN HOON (SG); FRIEND RICHARD HENRY (GB)	US201 9-Feb-2015 514616 803A
US7351635B2	1-Apr-2008	Method of fabricating microelectronic device using super critical fluid	HAN SANG CHEOL (KR); OH JUN HWAN (KR)	US337 12-Jan-2005 1205A
US7176571B2	13-Feb-2007	Nitride barrier layer to prevent metal (Cu) leakage issue in a dual damascene structure	CHENG YI LUNG (TW); WANG YING LUNG (TW)	US753 8-Jan-2004 63704A
US7288021B2	30-Oct-2007	Chemical-mechanical polishing of metals in an oxidized form	DE REGE THESAURO FRANCESCO (US); BRUSIC VLASTA (US); BAYER BENJAMIN P (US)	US753 7-Jan-2004 13804A
US2008296510A1	4-Dec-2008	Ion Implantation System and Ion Implantation System	KASAMA YASUHIKO (JP); OMOTE KENJI (JP); YOKOH KUNIYOSHI (JP)	US585 6-Jan-2005 24505A
US2005151273A1	14-Jul-2005	Semiconductor chip package	ARNOLD RICHARD W (US); COWENS MARVIN W (US); ODEGARD CHARLES A (US)	US749 30-Dec-2003 11103A
US7375030B2	20-May-2008	Method to assay sacrificial light absorbing materials and spin on glass materials for chemical origin of defectivity	CHOI HOK KIN (US); MEAGLEY ROBERT P (US)	US440 25-May-2006 93306A
US7608527B2	27-Oct-2009	Laser irradiation method and method for manufacturing crystalline semiconductor film	TANAKA KOICHIRO (JP); YAMAMOTO YOSHIAKI (JP)	US179 22-Dec-2004 0004A

US2005139582A1	30-Jun-2005	Laser irradiation apparatus, laser irradiation method, and method for manufacturing crystalline semiconductor film	TANAKA KOICHIRO (JP)	US178 9904A	22-Dec-2004
US7507617B2	24-Mar-2009	Method for manufacturing semiconductor device	OHNUMA HIDETO (JP); INOUE KOUKI (JP)	US121 7204A	16-Dec-2004
US7517801B1	14-Apr-2009	Method for selectivity control in a plasma processing system	TAKESHITA KENJI (US)	US881 41004A	29-Jun-2004
US7825032B2	2-Nov-2010	Fabricating a set of semiconducting nanowires, and electric device comprising a set of nanowires	BAKKERS ERIK PETRUS ANTONIUS MARIA (NL); FEINER LOUIS FELIX (NL); BALKENENDE ABRAHAM RUDOLF (NL)	US584 03704A	3-Dec-2004
US2007166838A1	19-Jul-2007	Method for patterning a ferroelectric polymer layer	MARSMAN ALBERT W (NL); WILLARD NICOLAAS P (NL)	US584 04004A	7-Dec-2004
US2005136670A1	23-Jun-2005	Compositions and methods for controlled polishing of copper	AMEEN JOSEPH G (US); LAVOIE RAYMOND L JR (US); QUANCI JOHN (US); SO JOSEPH K (US); THOMAS TERENCE M (US); YE QIANQIU (US)	US741 37003A	19-Dec-2003
US7232709B2	19-Jun-2007	Process for producing a semiconductor device	MISUMI SADAHITO (JP); MATSUMURA TAKESHI (JP); HOSOKAWA KAZUHITO (JP); KONDOU HIROYUKI (JP)	US123 7704A	15-Dec-2004
US7731799B2	8-Jun-2010	Substrate processing method, substrate processing apparatus and computer-readable memory medium	TOSHIMA TAKAYUKI (JP); IINO TADASHI (JP); SAITO YUSUKE (JP); NAKAMORI MITSUNORI (JP); UCHIDA NORITAKA (JP); ORII TAKEHIKO (JP)	US579 42304A	7-Dec-2004
US2006240661A1	26-Oct-2006	Method of preventing damage to porous low-K materials during resist stripping	ANNAPRAGADA RAO (US); TAKESHITA KENJI (US)	US449 06006A	7-Jun-2006
US7341924B2	11-Mar-2008	Method for manufacturing semiconductor device	TAKAYAMA TORU (JP); ARAI YASUYUKI (JP); SUZUKI YUKIE (JP)	US452 98706A	15-Jun-2006
US2007117389A1	24-May-2007	Pattern formation method using nanoimprinting and device for carrying out same	TAKAKI YASUHIRO (JP)	US582 10104A	7-Dec-2004
US7256419B2	14-Aug-2007	Composition for forming organic insulating film and organic insulating film formed from the same	JEONG EUN JEONG (KR); KOO BON WON (KR); KIM JOO YOUNG (KR); KANG IN NAM (KR)	US864 46904A	10-Jun-2004
US6849549B1	1-Feb-2005	Method for forming dummy structures for improved CMP and reduced capacitance	CHIOU WEN CHIH (TW); JANG SYUN MING (TW)	US728 99903A	4-Dec-2003
US2006003570A1	5-Jan-2006	Method and apparatus for electroless capping with vapor drying	SHANMUGASUNDRAM ARULKUMAR (US); TOLLES ROBERT D (US); ELLWANGER RUSSEL (US)	US401 404A	2-Dec-2004
US7897968B2	1-Mar-2011	Electronic device and semiconductor device and method for manufacturing the same	KUWABARA HIDEAKI (JP); YAMAZAKI SHUNPEI (JP); MAEKAWA SHINJI (JP); NAKAMURA OSAMU (JP)	US504 84009A	17-Jul-2009
US8619219B2	31-Dec-2013	Thin film transistor, display device and liquid crystal display device and method for manufacturing the same	YAMAZAKI SHUNPEI (JP); MAEKAWA SHINJI (JP); KANNO YOHEI (JP)	US201 213552 845A	19-Jul-2012
US7772130B2	10-Aug-2010	Insulation film forming method, insulation film forming system, and semiconductor device manufacturing method	MIYOSHI HIDENORI (JP); KOMURA KAZUO (JP)	US580 82404A	29-Nov-2004

US7452752B2	18-Nov-2008	Production method of semiconductor chip	NODA KAZUKI (JP); IWASAWA MASARU (JP)	US595 20-Oct-2004 87104A
US7333257B2	19-Feb-2008	Device for contacting patterned electrodes on porous substrates	REYNOLDS JOHN R (US); ARGUN AVNI A (US); AUBERT PIERRE HENRI (FR); BERARD MATHIEU (FR)	US992 19-Nov-2004 82704A
US7166859B2	23-Jan-2007	Organic semiconductor transistor element, semiconductor device using the same, and process for producing the semiconductor device	HIROSE HIDEKAZU (JP); SEKI MIEKO (JP); OKUDA DAISUKE (JP); OZAKI TADAYOSHI (JP); AGATA TAKESHI (JP); ISHII TORU (JP); MASHIMO KIYOKAZU (JP); SATO KATSUHIRO (JP); MORIYAMA HIROAKI (JP); NISHINO YOHEI (JP)	US959 7-Oct-2004 22404A
US7883912B2	8-Feb-2011	Display device and method for manufacturing the same	FUKUCHI KUNIHIKO (JP); FUJII GEN (JP); NAKAMURA OSAMU (JP); MAEKAWA SHINJI (JP)	US552 2-Sep-2009 30509A
US7859187B2	28-Dec-2010	Display device and method for fabricating the same	YAMAZAKI SHUNPEI (JP); MAEKAWA SHINJI (JP); FUJII GEN (JP); KUWABARA HIDEAKI (JP); TACHIMURA YUKO (JP)	US576 5-Nov-2004 49504A
US11177175B2	16-Nov-2021	Microelectronic devices and methods for filling vias in microelectronic devices	HIATT WILLIAM M (US); KIRBY KYLE K (US)	US201 6-Aug-2018 816055 492A
US8057696B2	15-Nov-2011	Compositions and methods for rapidly removing overfilled substrates	CHELLE PHILIPPE H (US); SMALL ROBERT J (US)	US201 29-Aug-2008 45908A
US7264641B2	4-Sep-2007	for use in chemical mechanical polishing; low cost production and compostable	PRASAD ABANESHWAR (US)	US705 10-Nov-2003 53303A
US2005095448A1	5-May-2005	Layer incorporating particles with a high dielectric constant	KATZ HOWARD E (US); MALIAKAL ASHOK J (US)	US700 4-Nov-2003 65103A
US7524709B2	28-Apr-2009	Manufacturing method for a display device	ISHIKAWA AKIRA (JP); YAMAGUCHI TETSUJI (JP)	US698 29-Jan-2007 86207A
US7015504B2	21-Mar-2006	Sidewall formation for high density polymer memory element array	LYONS CHRISTOPHER F (US); CHANG MARK S (US); LOPATIN SERGEY D (US); SUBRAMANIAN RAMKUMAR (US); CHEUNG PATRICK K (US); NGO MINH V (US); OGLESBY JANE V (US)	US699 3-Nov-2003 90303A
US7566385B2	28-Jul-2009	Apparatus adapted for membrane-mediated electropolishing	MAZUR STEPHEN (US); JACKSON JR CHARLES E (US); FOGGIN GARY W (US)	US986 12-Nov-2004 04804A
US7221033B2	22-May-2007	Anti-stiction technique for thin film and wafer-bonded encapsulated microelectromechanical systems	LUTZ MARKUS (US); PARTRIDGE AARON (US)	US172 30-Jun-2005 11805A
US8987068B2	24-Mar-2015	Method for manufacturing display device	YAMAZAKI SHUNPEI (JP); MAEKAWA SHINJI (JP); FURUNO MAKOTO (JP); NAKAMURA OSAMU (JP); IMAI KEITARO (JP)	US201 15-Nov-2013 314080 822A

US7446054B2	4-Nov-2008	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP)	US573 25-Oct-2004 16004A
US9200180B2	1-Dec-2015	Chemical-mechanical planarization composition having benzenesulfonic acid and per-compound oxidizing agents, and associated method for use	BANERJEE GAUTAM (US); COMPTON TIMOTHY FREDERICK (US); SIDDIQUI JUNAID AHMED (US); ZUTSHI AJOY (US)	US419 7-Apr-2009 61909A
US7247566B2	24-Jul-2007	CMP method for copper, tungsten, titanium, polysilicon, and other substrates using organosulfonic acids as oxidizers	CARTER MELVIN K (US); SMALL ROBERT J (US); SHANG XIAOWEI CASS (US); FREY DONALD W (US)	US690 23-Oct-2003 62303A
US7410897B2	12-Aug-2008	Contact plug processing and a contact plug	KANZAWA HIDEYUKI (JP)	US297 9-Dec-2005 34005A
US9034675B2	19-May-2015	Light-emitting device and method for manufacturing light-emitting device	YAMAZAKI SHUNPEI (JP); AKIMOTO KENGO (JP); SAKATA JUNICHIRO (JP); HIRAKATA YOSHIHARU (JP); SONE NORIHITO (JP)	US201 9-Jun-2014 414299 045A
US7498520B2	3-Mar-2009	Semiconductor multilayer wiring board and method of forming the same	OSAKA TETSUYA (JP); YOKOSHIMA TOKIHIKO (JP); SATO ISAO (JP); HASHIMOTO AKIRA (JP); HAGIWARA YOSHIO (JP)	US965 18-Oct-2004 86804A
US7019402B2	28-Mar-2006	Silicon chip carrier with through-vias using laser assisted chemical vapor deposition of conductor	ANDRY PAUL STEPHEN (US); BUCHWALTER LEENA PAIVIKKI (US); BUDD RUSSELL ALAN (US); WASSICK THOMAS ANTHONY (US)	US686 17-Oct-2003 64003A
US8017245B2	13-Sep-2011	Composition for preparing organic insulator	LEE SANG YOON (KR); PARK JONG JIN (KR); LYU YI YEOL (KR); KOO BON WON (KR); BYUN YOUNG HUN (KR); SEO EUN MI (KR)	US128 13-May-2005 30905A
US2009233079A1	17-Sep-2009	Techniques for Layer Transfer Processing	BEDELL STEPHEN W (US); FOGEL KEITH EDWARD (US); FURMAN BRUCE KENNETH (US); PURUSHOTHAMAN SAMPATH (US); SADANA DEVENDRA K (US); TOPOL ANNA WANDA (US)	US472 27-May-2009 94309A
US2008076262A1	27-Mar-2008	METHOD AND SYSTEM FOR TREATING A DIELECTRIC FILM	KEVWITCH ROBERT (US); HANSEN BRANDON (US); TOMA DOREL I (US); ZHU JIANHONG (US)	US947 29-Nov-2007 43207A
US2007026667A1	1-Feb-2007	Composition for forming etching stopper layer	TASHIRO YUJI (JP); AOKI HIROYUKI (JP); ISHIKAWA TOMONORI (JP)	US574 3-Apr-2006 55606A
US7427361B2	23-Sep-2008	Chemical mechanical polishing slurry for semiconductors	SMALL ROBERT J (US); FREY DONALD WILLIAM (US); TREDINNICK BRUCE (US); HAYDEN CHRISTOPHER G (US)	US690 23-Oct-2003 62603A
US2005194563A1	8-Sep-2005	Bicine/tricine containing composition and method for chemical-mechanical planarization	SIDDIQUI JUNAID A (US); COMPTON TIMOTHY F (US); HU BIN (US); RICHARDS ROBIN E (US); USMANI SAIFI (US)	US325 10-Jan-2005 9305A
US2005215183A1	29-Sep-2005	Chemical-mechanical planarization composition having PVNO and associated method for use	SIDDIQUI JUNAID A (US); HU BIN (US)	US101 8-Apr-2005 81505A
US2011252710A1	20-Oct-2011	Abrasive tools made with a self-avoiding abrasive grain array	HALL RICHARD W J (US); MOLTER JENS M (DE); BATEMAN CHARLES A (US)	US201 28-Jun-2011 113170 450A

US7417246B2	26-Aug-2008	Organic thin film transistor enhanced in charge carrier mobility by virtue of surface relief structure	SHIN JUNG HAN (KR); SEO EUN MI (KR); HAN KOOK MIN (KR); BARMATOV EVGENY (RU); SHIBAEV VALERY (RU)	US845 29704A	14-May-2004
US7701039B2	20-Apr-2010	Semiconductor devices and in-process semiconductor devices having conductor filled vias	KIRBY KYLE K (US); FARNWORTH WARREN M (US)	US394 77206A	31-Mar-2006
US7202177B2	10-Apr-2007	Nitrous oxide stripping process for organosilicate glass	ZHU HELEN (US); ANNAPRAGADA RAO (US)	US680 89503A	8-Oct-2003
US8122850B2	28-Feb-2012	Method and apparatus for processing polysilazane film	HISHIYA SHINGO (JP); AOKI KIMIYA (JP); WATANABE MASAHISA (JP)	US496 34909A	1-Jul-2009
US7365894B2	29-Apr-2008	Electrode structure including transparent electrode structure, and applications thereof	FARIS SADEG M (US)	US957 88504A	4-Oct-2004
US2012094412A1	19-Apr-2012	METHOD FOR MANUFACTURING WIRING, THIN FILM TRANSISTOR, LIGHT EMITTING DEVICE AND LIQUID CRYSTAL DISPLAY DEVICE, AND DROPLET DISCHARGE APPARATUS FOR FORMING THE SAME	NAKAMURA OSAMU (JP); OGINO KLYOFUMI (JP)	US201 113334 757A	22-Dec-2011
US7399704B2	15-Jul-2008	Fabrication method of a semiconductor device using liquid repellent film	FUJII GEN (JP); MAEKAWA SHINJI (JP)	US954 28604A	1-Oct-2004
US7795730B2	14-Sep-2010	A first conductive layer of a high-melting point metal is in contact with an insulating layer by droplet discharge; a second conductive layer of silver, gold, copper, or indium tin oxide in contact with the first conductive layer,has improved adhesiveness with the insulating layer; antipeeling agents	NAKAMURA OSAMU (JP); SATO JUNKO (JP)	US934 52807A	2-Nov-2007
US2005115679A1	2-Jun-2005	Surface treatment apparatus	KUROSAWA RYUICHI (JP); TAKAGI FUMIO (JP); KOEDA HIROSHI (JP); OYA KAZUFUMI (JP); ARAKAWA KATSUJI (JP)	US953 87104A	29-Sep-2004
US7238605B2	3-Jul-2007	Circuit structures and methods of forming circuit structures with minimal dielectric constant layers	LU DAOQIANG (US)	US376 79506A	16-Mar-2006
US7446057B2	4-Nov-2008	Fabrication method	BIETSCH ALEXANDER (CH); MICHEL BRUNO (CH)	US574 15004A	23-Aug-2004
US2008032457A1	7-Feb-2008	Structure and method of making sealed capped chips	MCWILLIAMS BRUCE M (US); HUMPSTON GILES (US); HABA BELGACEM (US); TUCKERMAN DAVID B (US)	US904 47707A	27-Sep-2007
US8648472B2	11-Feb-2014	Semiconductor device	ISONO SHUSUKE (JP)	US201 213674 749A	12-Nov-2012
US7767581B2	3-Aug-2010	comprising imine compounds and hydrazine compounds; for polishing tantalum-containing barrier; abrasive free	BIAN JINRU (US)	US437 29906A	19-May-2006

US2005065050A1	24-Mar-2005	Selective silicon etch chemistries, methods of production and uses thereof	STARZYNSKI JOHN S (US)	US827 01104A	19-Apr-2004
US9287207B2	15-Mar-2016	Methods for forming conductive vias in semiconductor device components	SINHA NISHANT (US)	US201 213404 631A	24-Feb-2012
US7195539B2	27-Mar-2007	Polishing pad with recessed window	TURNER KYLE A (US); BEELER JEFFREY L (US); NEWELL KELLY J (US)	US666 79703A	19-Sep-2003
US7393776B2	1-Jul-2008	Method of forming closed air gap interconnects and structures formed thereby	COLBURN MATTHEW E (US); DALTON TIMOTHY J (US); HUANG ELBERT (US); KARECKI LEGAL REPRESENTATIVE A (US); NITTA SATYA V (US); PURUSHOTHAMAN SAMPATH (US); SAENGER KATHERINE L (US); SURENDRA MAHESWARAN (US)	US405 28706A	17-Apr-2006
US8158521B2	17-Apr-2012	Two step post-deposition treatment of ILD layer for a lower dielectric constant and improved mechanical properties	CHANG HUI LIN (TW); KO CHUNG CHI (TW); BAO TIEN I (TW); LU YUN CHEN (TW)	US781 63207A	23-Jul-2007
US7291278B2	6-Nov-2007	Electrode forming method	KANEKO TSUYOSHI (JP); HIRAMATSU TETSUO (JP)	US934 37904A	7-Sep-2004
US7056813B2	6-Jun-2006	Methods of forming backside connections on a wafer stack	MORROW PATRICK (US); LIST R SCOTT (US); KIM SARAH E (US)	US714 3405A	2-Mar-2005
US7545041B2	9-Jun-2009	Techniques for patterning features in semiconductor devices	ALLEN SCOTT D (US); BABICH KATHERINA E (US); HOLMES STEVEN J (US); MAHOROWALA ARPAN P (US); PFEIFFER DIRK (US); WISE RICHARD STEPHAN (US)	US337 41106A	23-Jan-2006
US7754098B2	13-Jul-2010	Chemical-mechanical polishing composition and method for using the same	SCHROEDER DAVID J (US); MOEGGENBORG KEVIN J (US)	US568 72704A	10-Sep-2004
US7186634B2	6-Mar-2007	Method for forming metal single-layer film, method for forming wiring, and method for producing field effect transistors	YONEYA NOBUHIDE (JP)	US923 37204A	20-Aug-2004
US8304289B2	6-Nov-2012	Semiconductor module including circuit component and dielectric film, manufacturing method thereof, and application thereof	USUI RYOSUKE (JP); INOUE YASUNORI (JP)	US603 12209A	21-Oct-2009
US7628840B2	8-Dec-2009	Metal nano-particles and method for preparing the same, dispersion of metal nano-particles and method for preparing the same, and thin metallic wire and metal film and method for preparing these substances	ATSUKI TSUTOMU (JP); ODA MASAOKI (JP); HAYASHI TOSHIHARU (JP); KIYOSHIMA REIKO (JP)	US571 31504A	7-Sep-2004
US7156669B2	2-Jan-2007	Anisotropic conductive film	ASAI FUMITERU (JP); NORO MASATO (JP)	US936 94604A	9-Sep-2004
US2006254052A1	16-Nov-2006	Conductive sheet having conductive layer with improved adhesion and product including the same	MIURA SHIGEKI (JP)	US482 81306A	10-Jul-2006
US2008318030A1	25-Dec-2008	LASER TRANSFER ARTICLES AND METHOD OF MAKING	HANDY ERIK S (US); KUNZE JOSEPH MICHAEL (US); KAZLAS PETER T (US)	US205 26708A	5-Sep-2008

US7217334B2	15-May-2007	Method for forming film, method for forming wiring pattern, method for manufacturing semiconductor device, electro-optical device, and electronic device	TOYODA NAOYUKI (JP)	US933 3-Sep-2004 43804A
US7265447B2	4-Sep-2007	Interconnect with composite layers and method for fabricating the same	YU CHEN HUA (TW); TSENG HORNG HUEI (TW); JANG SYUN MING (TW); HU CHENMING (US)	US240 30-Sep-2005 21605A
US2011003402A1	6-Jan-2011	RECOVERY OF HYDROPHOBICITY OF LOW-K AND ULTRA LOW-K ORGANOSILICATE FILMS USED AS INTER METAL DIELECTRICS	CHAKRAPANI NIRUPAMA (US); COLBURN MATTHEW E (US); DIMITRAKOPOULOS CHRISTOS D (US); PFEIFFER DIRK (US); PURUSHOTHAMAN SAMPATH (US); NITTA SATYANARAYANA V (US)	US749 29-Mar-2010 21310A
US7105264B2	12-Sep-2006	Method for forming patterned conductive film, electrooptical device, and electronic appliance	TOYODA NAOYUKI (JP)	US930 1-Sep-2004 75904A
US7108922B2	19-Sep-2006	Polysilsequioxane copolymer with porogens; ladder polymers; dielectrics with improved solubility, flowability and mechanical properties	LYU YI YEOL (KR); YIM JIN HEONG (KR); SONG KI YONG (KR); JEONG HYUN DAM (KR); RYU JOON SUNG (KR)	US768 2-Feb-2004 05804A
US7180149B2	20-Feb-2007	Semiconductor package with through-hole	YAMAMOTO SATOSHI (JP); SUEMASU TATSUO (JP); HIRAFUNE SAYAKA (JP); ISOKAWA TOSHIHIKO (JP); SHIOTANI KOICHI (JP); MATSUMOTO KAZUYA (JP)	US924 24-Aug-2004 20504A
US2005079338A1	14-Apr-2005	Method of heat treatment, method for forming wiring pattern, method for manufacturing electro-optic device, and electro-optic device and electronic apparatus	TOYODA NAOYUKI (JP)	US922 20-Aug-2004 09804A
US7648820B2	19-Jan-2010	Polycarbosilanes with chromogen and transparent moieties crosslinked by glycouril, alcohols, hydroxybenzyl, phenol, hydroxymethylbenzyl, cyclohexanoyl, propanol, fluorocarbon alcohols, vinyl ethers, and epoxides; semiconductors; lithography	BABICH KATHERINA (US); HUANG ELBERT (US); MAHOROWALA ARPAN P (US); MEDEIROS DAVID R (US); PFEIFFER DIRK (US); TEMPLE KAREN (US)	US614 21-Dec-2006 79906A
US7479509B2	20-Jan-2009	Low dielectric organosilicate polymer composite	REE MOONHOR (KR); OH WEONTAE (KR); HWANG YONG TAEK (KR); LEE BYEONGDU (KR)	US530 8-Apr-2005 81505A
US7921500B2	12-Apr-2011	Flexible formed sheets for treating surfaces	LINZELL GEOFFREY R (GB)	US554 4-Sep-2009 13809A
US7126180B2	24-Oct-2006	Semiconductor device including a capacitor having improved structural stability and enhanced capacitance, and method of manufacturing the semiconductor device	PARK JE MIN (KR)	US916 11-Aug-2004 67204A
US7704893B2	27-Apr-2010	Semiconductor device, method for manufacturing semiconductor device and gas for plasma CVD	KOBAYASHI YASUO (JP); KAWAMURA KOHEI (JP); OHMI TADAHIRO (JP); TERAMOTO AKINOBU (JP); SUGIMOTO TATSUYA (JP); YAMADA TOSHIRO (JP); TANAKA KIMIACHI (JP)	US568 15-Feb-2006 46106A
US7968465B2	28-Jun-2011	Periodic acid compositions for polishing ruthenium/low K substrates	SMALL ROBERT J (US); NOJO HARUKI (JP); ORUI KENICHI (JP); ARAGAKI STEVE MASAMI (JP); HAYASHIDA ATSUSHI (JP)	US568 12-Aug-2004 07704A
US7413991B2	19-Aug-2008	Damascene process at semiconductor substrate level	TSENG HORNG HUEI (TW)	US357 17-Feb-2006 69706A

US7094641B2	22-Aug-2006	Method for forming wiring pattern, method for manufacturing semiconductor device, electro-optic device and electronic equipment	TOYODA NAOYUKI (JP)	US902 10904A	30-Jul-2004
US7172912B2	6-Feb-2007	Pattern forming method and wiring pattern forming method, and electro-optic device and electronic equipment	TOYODA NAOYUKI (JP)	US898 34404A	26-Jul-2004
US2005028837A1	10-Feb-2005	Method and apparatus for manufacturing semiconductor devices	NAM SANG WOO (KR); LEE CHEA GAB (KR)	US761 50004A	20-Jan-2004
US8252116B2	28-Aug-2012	Perimeter partition-valve with protected seals and associated small size process chambers and multiple chamber systems	SNEH OFER (US)	US700 62010A	4-Feb-2010
US7223517B2	29-May-2007	Lithographic antireflective hardmask compositions and uses thereof	BABICH KATHERINA (US); MAHOROWALA ARPAN P (US); MEDEIROS DAVID R (US); PFEIFFER DIRK (US)	US634 66703A	5-Aug-2003
US7867331B2	11-Jan-2011	Coating composition optimization for via fill and photolithography applications and methods of preparation thereof	KENNEDY JOSEPH (US); STUCK JASON (US)	US567 42004A	4-Aug-2004
US2010147220A1	17-Jun-2010	EVAPORATION CONTAINER AND VAPOR DEPOSITION APPARATUS	SAKATA JUNICHIRO (JP); NAKAMURA YASUO (JP); OKAZAKI YUTAKA (JP)	US712 63110A	25-Feb-2010
US9057705B2	16-Jun-2015	Surface-enhanced raman spectroscopy substrate for arsenic sensing in groundwater	YANG PEIDONG (US); MULVIHILL MARTIN (US); TAO ANDREA R (US); SINERMSUKSAKUL PRASERT (US); ARNOLD JOHN (US)	US372 67209A	17-Feb-2009
USRE45468E	14-Apr-2015	Barrier-slurry-free copper CMP process	CHEN YI CHEN (TW); TSAI CHING MING (TW); CHANG RAY TING (TW)	US494 75406A	27-Jul-2006
US2006202334A1	14-Sep-2006	METHOD OF FORMING REDISTRIBUTION BUMP AND SEMICONDUCTOR CHIP AND MOUNT STRUCTURE FABRICATED USING THE SAME	KWON YONG HWAN (KR); KANG SA YOON (KR); LEE CHUNG SUN (KR)	US421 68006A	1-Jun-2006
US2005016465A1	27-Jan-2005	Electrostatic chuck having electrode with rounded edge	RAMASWAMY KARTIK (US); MCCHESENEY JON M (US); KUMAR ANANDA H (US); NOORBAKHSI HAMID (US)	US626 15603A	23-Jul-2003
US8097947B2	17-Jan-2012	Conductive systems and devices including wires coupled to anisotropic conductive film, and methods of forming the same	LUA EDMUND KOON TIAN (SG); LENG NAM YIN (SG)	US394 9708A	28-Feb-2008
US7910223B2	22-Mar-2011	Planarization films for advanced microelectronic applications and devices and methods of production thereof	HUANG WEI (US); KENNEDY JOSEPH (US); KATSANES RONALD (US)	US518 20105A	6-Oct-2005
US7387903B2	17-Jun-2008	Method for manufacturing layer pattern, method for manufacturing wiring, and method for manufacturing electronic equipment	SAKAI HIROFUMI (JP); SAKURADA KAZUAKI (JP)	US887 82204A	12-Jul-2004
US7517802B2	14-Apr-2009	Method for reducing foreign material concentrations in etch chambers	COONEY III EDWARD CRANDAL (US); STAMPER ANTHONY KENDALL (US)	US550 19006A	17-Oct-2006
US7037350B2	2-May-2006	Composition for chemical-mechanical polishing and method of using same	SMALL ROBERT J (US); CHEN ZHEFEI J (US)	US619 90103A	14-Jul-2003

US2007026221A1	1-Feb-2007	Morphological forms of fillers for electrical insulation	STEVENS GARY (GB); SMITH JAMES D B (US); WOOD JOHN W (US)	US529 18106A	28-Sep-2006
US7592045B2	22-Sep-2009	structured polymer hairs formed of liquid crystal epoxy resins with high thermal conductivity (HTC), configured to be sufficiently rigid for ordering such polymer hairs at the density and the chain length effective to reduce entanglements, form phonon channels; impregnated into mica flake or glass fiber	SMITH JAMES D B (US); STEVENS GARY (GB); WOOD JOHN W (US)	US397 00006A	3-Apr-2006
US2006175295A1	10-Aug-2006	Abrasive partilcle for chemical mechanical polishing	CHU JIA NI (DE); PRYOR JAMES N (US)	US564 84204A	9-Jul-2004
US7094651B2	22-Aug-2006	Hydrazine-free solution deposition of chalcogenide films	MITZI DAVID B (US); COPEL MATTHEW W (US)	US801 76604A	16-Mar-2004
US7585549B2	8-Sep-2009	Selective deposition of solder particles over metal interconnect features on electronic device substrate, such as a silicon wafer substrate, to provide electrical interconnection between substrate interconnect features and devices to be attached to substrate, using electrokinetic or electrostatic means	LEWIS BRIAN G (US); SINGH BAWA (US); DETIG ROBERT H (US); MINOGUE GERARD R (US); EBERLEIN DIETMAR C (US); REILLY KENNETH (US); MARCZI MICHAEL (US)	US888 28604A	9-Jul-2004
US6935928B2	30-Aug-2005	Chemical mechanical polishing aqueous dispersion and chemical mechanical polishing method	UCHIKURA KAZUHITO (JP); NISHIMOTO KAZUO (JP); HATTORI MASAYUKI (JP); KAWAHASHI NOBUO (JP); YANO HIROYUKI (JP); MATSUI YUKITERU (JP); MINAMIHABA GAKU (JP); FUKUSHIMA DAI (JP); KURASHIMA NOBUYUKI (JP)	US882 36204A	2-Jul-2004
US7005674B2	28-Feb-2006	Organic thin film transistor comprising multi-layered gate insulator	LEE SANG YOON (KR); PARK JONG JIN (KR); LYU YI YEOL (KR); BYUN YOUNG HUN (JP); KOO BON WON (KR); KANG IN NAM (KR)	US769 81604A	3-Feb-2004
US7635639B2	22-Dec-2009	Method for the interconnection of active and passive components and resulting thin heterogeneous component	VAL CHRISTIAN (FR); LIGNIER OLIVIER (FR)	US562 68504A	30-Jun-2004
US7384862B2	10-Jun-2008	Method for fabricating semiconductor device and display device	YAMAZAKI SHUNPEI (JP)	US878 49804A	29-Jun-2004
US8314055B2	20-Nov-2012	Materials and systems for advanced substrate cleaning	MUI DAVID S L (US); ZHU JI (US); MENDIRATTA ARJUN (US)	US503 48609A	15-Jul-2009
US8758522B2	24-Jun-2014	Method and apparatus for removing contaminants from substrate	ZHU JI (US); MENDIRATTA ARJUN (US); MUI DAVID (US)	US201 113115 649A	25-May-2011
US7521408B2	21-Apr-2009	Semiconductor cleaning solution	VOS RITA (BE); MERTENS PAUL (BE); KOLBESEN BERND (DE); FESTER ALBRECHT (DE); DOLL OLIVER (DE)	US301 13005A	12-Dec-2005
US2009065032A1	12-Mar-2009	Apparatus and method for removing photoresist from a substrate	HAN DONGGYUN (KR); HAN WOOSUNG (KR); HONG CHANGKI (KR); CHOI SANGJUN (KR); KO HYUNGHO (KR); LEE HYOSAN (KR)	US230 29308A	27-Aug-2008

US7326651B2	5-Feb-2008	Method for forming damascene structure utilizing planarizing material coupled with compressive diffusion barrier material	BAKS HEIDI (US); BRUFF RICHARD A (US); CONTI RICHARD A (US); UPHAM ALLAN (US)	US905 06804A	14-Dec-2004
US7361445B2	22-Apr-2008	Mixture of alkali soluble resin, quinonediazide compound and alcohol	BANBA TOSHIO (JP); IKEDA TAKUJI (JP); YANO TATSUYA (JP); HIRANO TAKASHI (JP)	US175 81305A	6-Jul-2005
US7435161B2	14-Oct-2008	Multi-layer polishing pad material for CMP	PRASAD ABANESHWAR (US); LACY MICHAEL S (US)	US113 49805A	25-Apr-2005
US2009215920A1	27-Aug-2009	SILANE POLYMER AND METHOD FOR FORMING SILICON FILM	IWASAWA HARUO (JP); WANG DAOHAI (JP); MATSUKI YASUO (JP); KATO HITOSHI (JP)	US398 45109A	5-Mar-2009
US7364832B2	29-Apr-2008	Wet developable hard mask in conjunction with thin photoresist for micro photolithography	SUN SAM X (US); LI CHENGHONG (US)	US864 78704A	8-Jun-2004
US6924230B2	2-Aug-2005	Method for forming a conductive layer	SUN YU CHANG (TW); TANG CHING HSUAN (TW); LEE CHI SHEN (TW); SHEU CHAI YUAN (TW)	US653 08003A	3-Sep-2003
US8147911B2	3-Apr-2012	Perforated porous resin base material and production process of porous resin base with inner wall surfaces of perforations made conductive.	OKUDA YASUHIRO (JP); HAYASHI FUMIHIRO (JP); HAGA TSUYOSHI (JP); FUJITA TARO (JP); UENOYAMA MAYO (JP); MASUDA YASUHITO (JP); IDOMOTO YUICHI (JP)	US559 58005A	4-Jun-2004
US2010184289A1	22-Jul-2010	SUBSTRATE AND METHOD OF MANUFACTURING THE SAME	OHMI TADAHIRO (JP); MORIMOTO AKIHIRO (JP); SUZUKI TERUHIKO (JP); KATO TAKEYOSHI (JP)	US749 14310A	29-Mar-2010
US7205228B2	17-Apr-2007	Selective metal encapsulation schemes	PADHI DEENESH (US); GANDIKOTA SRINIVAS (US); NAIK MEHUL (US); PARIKH SUKETU A (US); DIXIT GIRISH A (US)	US812 48004A	30-Mar-2004
US9985076B2	29-May-2018	Diode/superionic conductor/polymer memory structure	CAMPBELL KRISTY A (US)	US201 715478 072A	3-Apr-2017
US7713578B2	11-May-2010	Method for fabricating thin film pattern, method for fabricating device, electro-optical apparatus, and electronic apparatus	HIRAI TOSHIMITSU (JP)	US849 23504A	20-May-2004
US7179732B2	20-Feb-2007	Interconnection structure and fabrication method thereof	HSIUNG CHIUNG SHENG (TW); YANG CHIH CHAO (TW); YANG GWO SHIL (TW); YEH MING SHIH (TW); CHEN JEN KON (TW)	US893 63204A	15-Jul-2004
US8137764B2	20-Mar-2012	Mechanical enhancer additives for low dielectric films	VINCENT JEAN LOUISE (US); O NEILL MARK LEONARD (US); VRTIS RAYMOND NICHOLAS (US); LUKAS AARON SCOTT (US); PETERSON BRIAN KEITH (US); BITNER MARK DANIEL (US)	US842 50304A	11-May-2004
US7235415B2	26-Jun-2007	Film pattern formation method, device and method for manufacturing the same, electro-optical device, electronic device, and method for manufacturing active matrix substrate	MIKOSHIBA TOSHIAKI (JP)	US848 60404A	19-May-2004
US2005012068A1	20-Jan-2005	Stable solutions of organic semiconducting compounds	KIRCHMEYER STEPHAN (DE); PONOMARENKO SERGEI ANATOLIEVIC (RU)	US853 84404A	26-May-2004

US7326585B2	5-Feb-2008	Forming process of thin film pattern and manufacturing process of device, electro-optical apparatus and electronic apparatus	HIRAI TOSHIMITSU (JP)	US843 12-May-2004 42604A
US8076005B2	13-Dec-2011	Energy conversion and storage films and devices by physical vapor deposition of titanium and titanium oxides and sub-oxides	DEMARAY RICHARD E (US); ZHANG HONG MEI (US); NARASIMHAN MUKUNDAN (US); MILONOPOULOU VASSILIKI (US)	US726 22-Mar-2007 97207A
US8268181B2	18-Sep-2012	Plasma ashing apparatus and endpoint detection process	SRIVASTAVA ASEEM KUMAR (US); SAKTHIVEL PALANIKUMARAN (US); BUCKLEY THOMAS JAMES (US)	US552 2-Sep-2009 31609A
US7115534B2	3-Oct-2006	Dielectric materials to prevent photoresist poisoning	NGUYEN SON VAN (US); ARMACOST MICHAEL D (US); NAIK MEHUL (US); DIXIT GIRISH A (US); YIEH ELLIE Y (US)	US847 18-May-2004 89104A
US7364769B2	29-Apr-2008	Apparatus and method for formation of a wiring pattern on a substrate, and electronic devices and producing methods thereof	YOSHIDA YOSHIHIRO (JP); SANO TAKESHI (JP); OHKURA HIDEAKI (JP); KOBAYASHI HIROFUMI (JP)	US844 13-May-2004 42804A
US7227252B2	5-Jun-2007	Semiconductor component having stacked, encapsulated dice and method of fabrication	BOLKEN TODD O (US); COBBLEY CHAD A (US)	US205 17-Aug-2005 57205A
US2007194449A1	23-Aug-2007	Pattern and fabricating method therefor, device and fabricating method therefor, electro-optical apparatus, electronic apparatus, and method for fabricating active matrix substrate	HIRAI TOSHIMITSU (JP)	US785 13-Apr-2007 01007A
US7678697B2	16-Mar-2010	Substrate, device, method of manufacturing device, method of manufacturing active matrix substrate, electro-optical apparatus and electronic apparatus	HIRAI TOSHIMITSU (JP)	US562 28-Dec-2007 707A
US7279777B2	9-Oct-2007	Organic polymers, laminates, and capacitors	BAI FENG (US); JONES TODD D (US); LEWANDOWSKI KEVIN M (US); LEE TZU CHEN (US); MUYRES DAWN V (US); KELLEY TOMMIE W (US)	US839 5-May-2004 19304A
US7473652B2	6-Jan-2009	Organic polymers, electronic devices, and methods	BAI FENG (US); JONES TODD D (US); LEWANDOWSKI KEVIN M (US); LEE TZU CHEN (US); MUYRES DAWN V (US); KELLEY TOMMIE W (US)	US428 30-Jun-2006 08406A
US2005008983A1	13-Jan-2005	Wide temperature range chuck system	WANG ALBERT (US)	US840 6-May-2004 50204A
US7479474B2	20-Jan-2009	post-etch resist residue removal using H ₂ SiF ₆ or HBF ₄ ; N-methyl-2-pyrrolidone an organic solvent; an amine e.g. ethanolamine, nitrilotris(methylene phosphonic acid) a corrosion inhibitor and water; pH less than 7; environmental friendly	CERNAT MIHAELA (US); LEE SHIHYING (US)	US836 3-May-2004 25904A
US2006134921A1	22-Jun-2006	Plasma etching process	WU CHIH NING (TW); CHIEN WEN SHENG (TW)	US295 5-Dec-2005 68005A
US7897029B2	1-Mar-2011	Removal of surface oxides by electron attachment	DONG CHUN CHRISTINE (US); PATRICK RICHARD E (US); ARSLANIAN GREGORY KHOSROV (US)	US119 13-May-2008 70108A

US8361340B2	29-Jan-2013	Removal of surface oxides by electron attachment	DONG CHUN CHRISTINE (US); PATRICK RICHARD E (US); ARSLANIAN GREGORY KHOSROV (US); GHOSH RANAJIT (US)	US433 10809A	30-Apr-2009
US8528497B2	10-Sep-2013	Drop discharge apparatus, method for forming pattern and method for manufacturing semiconductor device	NAKAMURA OSAMU (JP); YAMAZAKI SHUNPEI (JP)	US553 27409A	3-Sep-2009
US7794785B2	14-Sep-2010	Cleaning method, storage method, pattern formation method, device manufacturing method, electro-optical device, and electronic apparatus	MORIYAMA HIDEKAZU (JP)	US827 42604A	20-Apr-2004
US7044836B2	16-May-2006	providing a substrate containing at least one metal layer, abrading at least a portion of the metal layer with an abrasive containing a metal oxide (having a surface with a silane compound adhered to a portion of it and a polymer adhered to the silane compound) and a liquid carrier	SUN FRED F (US); LU BIN (US); LIGHTLE ETHAN K (US); WANG SHUMIN (US)	US419 58003A	21-Apr-2003
US7744946B2	29-Jun-2010	Organic siloxane resins and insulating film using the same	CHOI BUM GYU (KR); KO MIN JIN (KR); KO BYUNG RO (KR); MOON MYUNG SUN (KR); KANG JUNG WON (KR); NAM HYE YEONG (KR); KANG GWI GWON (KR)	US541 84404A	16-Apr-2004
US2021296120A1	23-Sep-2021	Method of filling high aspect ratio, small dimension gaps and formulations useful therein	FOSTER KENNETH L (US); GODSCHALX JAMES P (US); SIMMONDS MICHAEL G (BE)	US552 87704A	15-Apr-2004
US2004206307A1	21-Oct-2004	Method and system having at least one thermal transfer station for making OLED displays	BOROSON MICHAEL L (US); PHILLIPS BRADLEY A (US); KAY DAVID B (US); RIVERS ANDREA S (US); BEDZYK MARK D (US); TUTT LEE W (US); CULVER MYRON W (US); PHELAN GIANA M (US)	US414 69903A	16-Apr-2003
US8043968B2	25-Oct-2011	Dielectric barrier layer for increasing electromigration lifetimes in copper interconnect structures	CUI HAO (US); BURKE PETER A (US); CATABAY WILBUR G (US)	US764 00410A	20-Apr-2010
US7443693B2	28-Oct-2008	Electromagnetic interference shielding for a printed circuit board	ARNOLD ROCKY R (US); ZARGANIS JOHN C (US); MONTAUTI FABRIZIO (US)	US825 99904A	15-Apr-2004
US6876027B2	5-Apr-2005	Method of forming a metal-insulator-metal capacitor structure in a copper damascene process sequence	LIEN WAN YIH (TW); WU CHII MING M (TW)	US411 34603A	10-Apr-2003
US6913994B2	5-Jul-2005	Method to form Cu/OSG dual damascene structure for high performance and reliable interconnects	GUO QIANG (SG); KRISHNAMOORTHY AHILA (SG); BU XIAOMEI (SG); BLIZNETSOV VLADIMIR N (SG)	US410 12203A	9-Apr-2003
US7357961B2	15-Apr-2008	Using polysiloxane comprised of such as methyltrimethoxysilane and tetramethoxysilane; adhesion, uniformity, mechanical strength, reduced moisture absorption	IWABUCHI MOTOAKI (JP); YAGIHASHI FUJIO (JP); HAMADA YOSHITAKA (JP); ASANO TAKESHI (JP); NAKAGAWA HIDEO (JP); SASAGO MASARU (JP)	US819 54404A	7-Apr-2004
US7214617B2	8-May-2007	Method of forming thin film pattern, method of manufacturing device, electro-optical apparatus and electronic apparatus	HIRAI TOSHIMITSU (JP)	US803 02704A	18-Mar-2004
US2005260420A1	24-Nov-2005	Low dielectric materials and methods for making same	COLLINS MARTHA J (US); DEIS LISA (US); KIRNER JOHN F (US); MAC DOUGALL JAMES E (US); PETERSON BRIAN K (US); WEIGEL SCOTT J (US)	US404 19503A	1-Apr-2003

US2004197474A1	7-Oct-2004	Method for enhancing deposition rate of chemical vapor deposition films	VRTIS RAYMOND NICHOLAS (US); LUKAS AARON SCOTT (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUISE (US); BITNER MARK DANIEL (US); KARWACKI EUGENE JOSEPH (US); PETERSON BRIAN KEITH (US)	US404 19003A	1-Apr-2003
US2010242270A1	30-Sep-2010	Wiring circuit board, manufacturing method for the wiring circuit board, and circuit module	IJIMA TOMOO (JP); ENDO KIMITAKA (JP); IKENAGA KAZUO (JP); ODAIRA HIROSHI (JP); MINARI NAOTO (JP); KATO TAKASHI (JP)	US658 92610A	16-Feb-2010
US7429778B2	30-Sep-2008	Methods for forming wiring and electrode	YOKOYAMA LEGAL REPRESENTATIVE (JP); SHINODA LEGAL REPRESENTATIVE NAOMI (JP); YOKOYAMA LEGAL REPRESENTATIVE RISA (JP); YONEKURA ISAMU (JP); SATOH TAKASHI (JP); WAKASAKI TAMAKI (JP); TAKEUCHI YASUMASA (JP); ENDO MASAYUKI (JP)	US237 86905A	29-Sep-2005
US2005031836A1	10-Feb-2005	Pattern forming method, pattern forming apparatus, device manufacturing method, conductive film wiring, electro-optical device, and electronic apparatus	HIRAI TOSHIMITSU (JP)	US809 20504A	25-Mar-2004
US6930393B2	16-Aug-2005	Composition for forming porous film, porous film and method for forming the same, interlayer insulator film, and semiconductor device	HAMADA YOSHITAKA (JP); ASANO TAKESHI (JP); NAKAGAWA HIDEO (JP); SASAGO MASARU (JP)	US807 49404A	23-Mar-2004
US6864181B2	8-Mar-2005	Method and apparatus to form a planarized Cu interconnect layer using electroless membrane deposition	REDEKER FRED C (US); BOYD JOHN (US)	US402 60003A	27-Mar-2003
US2006220253A1	5-Oct-2006	Porous film, composition and manufacturing method, interlayer dielectric film, and semiconductor device	HAMADA YOSHITAKA (JP); YAGIHASHI FUJIO (JP); NAKAGAWA HIDEO (JP); SASAO MASARU (JP)	US446 16006A	5-Jun-2006
US6759347B1	6-Jul-2004	Method of forming in-situ SRO HDP-CVD barrier film	CHENG YI LUNG (TW); YOO MING HWA (TW); WU SZE AN (TW); WANG YING LUNG (TW)	US401 71503A	27-Mar-2003
US7052980B2	30-May-2006	Transistor manufacturing method, electrooptical apparatus and electronic apparatus	AOKI TAKASHI (JP)	US804 01304A	19-Mar-2004
US7211502B2	1-May-2007	Method for manufacturing semiconductor device	YAMAZAKI SHUNPEI (JP); YAMAGUCHI TETSUJI (JP); ISOBE ATSUO (JP)	US806 35304A	23-Mar-2004
US7407895B2	5-Aug-2008	Process for producing dielectric insulating thin film, and dielectric insulating material	KUNITAKE TOYOKI (JP); AOKI YOSHITAKA (JP)	US550 01604A	26-Mar-2004
US7166362B2	23-Jan-2007	Film-forming composition, production process therefor, and porous insulating film	KANO TAKEYOSHI (JP)	US807 39104A	24-Mar-2004
US7053315B2	30-May-2006	Junction structure and junction method for conductive projection	ORUI KEN (JP); JINNO HIROKO (JP); NISHITANI YUJI (JP); ASAMI HIROSHI (JP)	US802 18804A	17-Mar-2004
US7018920B2	28-Mar-2006	Composite sacrificial material	MEAGLEY ROBERT P (US); GOODNER MICHAEL D (US)	US985 51004A	10-Nov-2004

US2005254190A1	17-Nov-2005	ESD dissipative structural components	KWON OH HUN (US); SIMPSON MATTHEW A (US)	US187 22-Jul-2005 16705A
US7214615B2	8-May-2007	Method of manufacturing semiconductor device, semiconductor device, circuit substrate and electronic apparatus	MIYAZAWA IKUYA (JP)	US801 16-Mar-2004 95204A
US2006183317A1	17-Aug-2006	Semiconductor device and a method of manufacturing the same	NOGUCHI JUNJI (JP); FUJIWARA TSUYOSHI (JP)	US401 11-Apr-2006 28706A
US8017516B2	13-Sep-2011	Method for stress free conductor removal	BAILEY III ANDREW D (US); LOHOKARE SHRIKANT P (US)	US732 3-Apr-2007 60807A
US2004234678A1	25-Nov-2004	Pattern forming method, pattern forming apparatus, device manufacturing method, conductive film wiring, electro-optical device, and electronic apparatus	HIRAI TOSHIMITSU (JP); HASEI HIRONORI (JP)	US797 10-Mar-2004 71904A
US7582333B2	1-Sep-2009	Arranging liquid drops on surface y/to overlap with central part formed substrate forming the sides;	HIRAI TOSHIMITSU (JP); HASEI HIRONORI (JP)	US797 10-Mar-2004 59104A
US2008096142A1	24-Apr-2008	Baking apparatus, substrate heat treatment method and semiconductor device manufacturing method for using baking apparatus, pattern forming method and semiconductor device manufacturing method for using pattern forming method	SHIBATA TSUYOSHI (JP); KOBAYASHI YUUJI (JP)	US907 11-Oct-2007 35207A
US7932188B2	26-Apr-2011	Mechanical enhancement of dense and porous organosilicate materials by UV exposure	LUKAS AARON SCOTT (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUISE (US); VRTIS RAYMOND NICHOLAS (US); BITNER MARK DANIEL (US); KARWACKI JR EUGENE JOSEPH (US)	US262 31-Oct-2008 87908A
US7456103B2	25-Nov-2008	Etch-resistant film, forming method thereof, surface-modified resist pattern, forming method thereof, semiconductor device and manufacturing method thereof	NOZAKI KOJI (JP); TAKEDA MASAYUKI (JP)	US205 18-Aug-2005 99205A
US7262131B2	28-Aug-2007	Dielectric barrier layer films	NARASIMHAN MUKUNDAN (US); BROOKS PETER (US); DEMARAY RICHARD E (US)	US228 16-Sep-2005 80505A
US6900082B2	31-May-2005	Methods for forming laterally crystallized polysilicon and devices fabricated therefrom	WONG MAN (HK); MA TIANFU (HK); MENG ZHIGUO (HK)	US373 24-Feb-2003 37803A
US6910951B2	28-Jun-2005	Materials and methods for chemical-mechanical planarization	BALIJEPAI SUDHAKAR (US); ALDRICH DALE J (US); GRIER LAURA A (US)	US370 24-Feb-2003 78103A
US2016372672A1	22-Dec-2016	SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP); TAKAYAMA TORU (JP); MARUYAMA JUNYA (JP); GOTO YUUGO (JP); OHNO YUMIKO (JP); ARAI YASUYUKI (JP); SHIBATA NORIKO (JP)	US201 29-Aug-2016 615249 543A
US7622326B2	24-Nov-2009	Manufacturing process of a chip package structure	HO KWUN YAO (TW); KUNG MORISS (TW)	US308 26-May-2006 92506A
US7157755B2	2-Jan-2007	Polymer sacrificial light absorbing structure and method	GOODNER MICHAEL D (US)	US564 11-Feb-2005 5405A

US2008206915A1	28-Aug-2008	MANUFACTURING METHOD FOR DISPLAY DEVICE	YAMAZAKI SHUNPEI (JP)	US114 93708A	5-May-2008
US7253115B2	7-Aug-2007	Dual damascene etch processes	TANAKA HIROYA (JP); SIM CHEE KHIANG IVAN (SG); JAIN ALOK (SG); ISHIKAWA YOSHIO (JP)	US360 23603A	6-Feb-2003
US7598114B2	6-Oct-2009	Sacrificial benzocyclobutene/norbornene polymers for making air gap semiconductor devices	LI YOUNGFU (US); KIRCHHOFF ROBERT A (US); NIU JASON Q (US); FOSTER KENNETH L (US)	US544 42804A	30-Jan-2004
US7585785B2	8-Sep-2009	Sacrificial benzocyclobutene copolymers for making air gap semiconductor devices	KIRCHHOFF ROBERT A (US); NIU JASON Q (US); LI YONGFU (US); FOSTER KENNETH L (US)	US544 41504A	30-Jan-2004
US7510893B2	31-Mar-2009	Method of manufacturing a display device using droplet emitting means	YAMAZAKI SHUNPEI (JP); HOSOYA KUNIO (JP)	US771 27704A	4-Feb-2004
US7294909B2	13-Nov-2007	Electronic package repair process	CASEY JON A (US); BALZ JAMES G (US); BERGER MICHAEL (US); COHEN JEROME (US); HENDRICKS CHARLES (US); INDYK RICHARD (US); LAPLANTE MARK (US); LONG DAVID C (US); MAIORINO LORI A (US); MERRYMAN ARTHUR G (US); POMERANTZ GLENN A (US); RITA ROBERT A (US); SEMKOW KRISTYNA W (US); SPENCER PATRICK E (US); SUNDLOF BRIAN R (US); SURPRENANT RICHARD P (US); WALL DONALD R (US); WASSICK THOMAS A (US); WILEY KATHLEEN M (US)	US991 6105A	5-Apr-2005
US7205225B2	17-Apr-2007	Method of manufacturing a semiconductor device and semiconductor device obtained by using such a method	FURUKAWA YUKIKO (BE)	US544 51905A	3-Aug-2005
US9218956B2	22-Dec-2015	Capping coating for 3D integration applications	PURUSHOTHAMAN SAMPATH (US); TOPOL ANNA W (US)	US201 414494 946A	24-Sep-2014
US2006134407A1	22-Jun-2006	Adhesive sheet and layered product	YOSHITOMI TAKASHI (JP); KOJIMA KAZUNORI (JP); NAKAMURA TSUTOMU (JP); ISHIWATA TOYOAKI (JP); SAWAKI TORU (JP)	US543 81305A	1-Aug-2005
US7250227B2	31-Jul-2007	Organic electroluminescent element, material for positive hole injecting layer, and organic electroluminescent display	ITAI YUICHIRO (JP); IIDA TAKASHI (JP); KODAMA JUN (JP)	US192 35305A	29-Jul-2005
US7879717B2	1-Feb-2011	Polycarbosilane buried etch stops in interconnect structures	HUANG ELBERT E (US); KUMAR KAUSHIK A (US); MALONE KELLY (US); PFEIFFER DIRK (US); SANKARAPANDIAN MUTHUMANICKAM (US); TYBERG CHRISTY S (US)	US140 85408A	17-Jun-2008
US2011226981A1	22-Sep-2011	MULTILAYERED CAP BARRIER IN MICROELECTRONIC INTERCONNECT STRUCTURES	HEDRICK JEFFREY C (US); HUANG ELBERT E (US)	US201 113117 536A	27-May-2011
US7256146B2	14-Aug-2007	Method of forming a ceramic diffusion barrier layer	COHEN STEPHAN A (US); GATES STEPHEN MCCONNELL (US); HEDRICK JEFFREY C (US); HUANG ELBERT E (US); PFEIFFER DIRK (US)	US128 49305A	13-May-2005

US6929982B2	16-Aug-2005	Patterning layers comprised of spin-on ceramic films	GATES STEPHEN M (US); HEDRICK JEFFREY C (US); HUANG ELBERT E (US); PFEIFFER DIRK (US)	US915 10-Aug-2004 08704A
US7081640B2	25-Jul-2006	Organic semiconductor element having high insulation strength and fabrication method thereof	UCHIDA YOSHIHIKO (JP); NAKAMURA KENJI (JP)	US765 28-Jan-2004 22004A
US7915181B2	29-Mar-2011	Repair and restoration of damaged dielectric materials and films	FAN WENYA (US); LU VICTOR (US); THOMAS MICHAEL (US); DANIELS BRIAN (US); NGUYEN TIFFANY (US); ZHOU DE LING (US); NAMAN ANANTH (US); JIN LEI (US); BHANAP ANIL (US)	US543 26-Jan-2004 34704A
US8475666B2	2-Jul-2013	Method for making toughening agent materials	RAMOS TERESA A (US); ROTH ROBERT R (US); BHANAP ANIL S (US); APEN PAUL G (US); ENDISCH DENIS H (US); DANIELS BRIAN J (US); NAMAN ANANTH (US); IWAMOTO NANCY (US); LEUNG ROGER Y (US)	US940 15-Sep-2004 68604A
US7648897B2	19-Jan-2010	Method for manufacturing conductive layer and semiconductor device	YAMAZAKI SHUNPEI (JP); WATANABE YASUKO (JP); ARAI YASUYUKI (JP)	US650 8-Jan-2007 69307A
US6923891B2	2-Aug-2005	Copper interconnects	CHEAH LI KANG (SG); SHI XU (SG); HU LANG (SG)	US340 10-Jan-2003 89803A
US8052834B2	8-Nov-2011	Substrate treating system, substrate treating device, program, and recording medium	YOSHIDA TAKUSHI (JP); WASHIO MASAYA (JP)	US541 8-Jul-2005 50705A
US7033863B2	25-Apr-2006	Semiconductor device and manufacturing method for the same	TOKUSHIGE NOBUAKI (JP)	US732 11-Dec-2003 81403A
US7259101B2	21-Aug-2007	Treating a monoxide precursor to form a composite material comprising nanoparticles and an oxide matrix;isolating the nanoparticles from the composite material by treating the oxide matrix to an echant medium comprises a hydrogen fluoride source	ZURCHER FABIO (US); RIDLEY BRENT (US); KUNZE KLAUS (US); HAUBRICH SCOTT (US); ROCKENBERGER JOERG (US)	US271 10-Nov-2005 04205A
US2005087873A1	28-Apr-2005	Method and structure for selective surface passivation	WU CHIH I (US); LEU JIHPERNG (US)	US948 22-Sep-2004 04604A
US6930034B2	16-Aug-2005	Robust ultra-low k interconnect structures using bridge-then-metallization fabrication sequence	COLBURN MATTHEW E (US); HUANG ELBERT E (US); NITTA SATYANARAYANA V (US); PURUSHOTHAMAN SAMPATH (US); SAENGER KATHERINE L (US)	US331 27-Dec-2002 03802A
US7863754B2	4-Jan-2011	Semiconductor device and manufacturing method thereof	KUWABARA HIDEAKI (JP); TAKAYAMA TORU (JP); GOTO YUUGO (JP); MARUYAMA JUNYA (JP); OHNO YUMIKO (JP); YAMAZAKI SHUNPEI (JP)	US374 14-Mar-2006 03706A
US2004186206A1	23-Sep-2004	Polishing composition	YONEDA YASUHIRO (JP); TAKASHINA SHIGEAKI (JP); HAGIHARA TOSHIYA (JP)	US740 22-Dec-2003 45803A
US7361718B2	22-Apr-2008	Alkali-soluble gap fill material forming composition for lithography	TAKEI SATOSHI (JP); ISHII KAZUHISA (JP); ARASE SHINYA (JP)	US540 20-Jul-2005 38905A

US2010019319A1	28-Jan-2010	Manufacturing method of thin-film transistor, thin-film transistor sheet, and electric circuit	HIRAI KATSURA (JP)	US148 21-Apr-2008 60308A
US2004195222A1	7-Oct-2004	Laser irradiation method, laser irradiation apparatus, and method for manufacturing semiconductor device	TANAKA KOICHIRO (JP); YAMAZAKI SHUNPEI (JP)	US744 24-Dec-2003 10003A
USRE41369E	8-Jun-2010	Semiconductor device and method of manufacturing the same	JOBETTO HIROYASU (JP)	US788 19-Apr-2007 39707A
US7056824B2	6-Jun-2006	Electronic device manufacture	MIRTH GEORGE P (US)	US742 19-Dec-2003 42403A
US7361593B2	22-Apr-2008	Methods of forming vias in multilayer substrates	FREEMAN WILLIAM R (US); JIANG HONG JIN (SG)	US277 30-Dec-2004 4504A
US7186654B2	6-Mar-2007	Chemical mechanical polishing slurry and method of manufacturing semiconductor device by using the same	MATSUI YUKITERU (JP)	US369 21-Feb-2003 64703A
US7086918B2	8-Aug-2006	Low temperature process for passivation applications	HSIAO MARK (US); TAKEHARA TAKAKO (US); SHANG QUANYUAN (US); HARSHBARGER WILLIAM R (US)	US317 11-Dec-2002 77402A
US7795325B2	14-Sep-2010	Adhesive composition, adhesive composition for circuit connection, connected body semiconductor device	KATOOGI SHIGEKI (JP); SUTO HOKO (JP); YUSA MASAMI (JP)	US492 26-Jun-2009 49209A
US6977035B2	20-Dec-2005	Method for electrolytic copper plating	TSUCHIDA HIDEKI (JP); KUSAKA MASARU (JP); HAYASHI SHINJIRO (JP)	US723 26-Nov-2003 21903A
US7238462B2	3-Jul-2007	Undercoating material for wiring, embedded material, and wiring formation method	NAKAMURA ETSUKO (JP); WAKIYA KAZUMASA (JP)	US721 26-Nov-2003 16403A
US2006014376A1	19-Jan-2006	Stacked via-stud with improved reliability in copper metallurgy	AGARWALA BIRENDRA N (US); BARILE CONRAD A (US); DALAL HORMAZDYAR M (US); ENGEL BRETT H (US); LANE MICHAEL (US); LEVINE ERNEST (US); LIU XIAO H (US); MCGAHAY VINCENT (US); MCGRATH JOHN F (US); MURRAY CONAL E (US); NAYAK JAWAHAR P (US); NGUYEN DU B (US); RATHORE HAZARA S (US); SHAW THOMAS M (US)	US230 20-Sep-2005 84105A
US7506610B2	24-Mar-2009	Plasma processing apparatus and method	KOSHIISHI AKIRA (JP); HIROSE JUN (JP); OGASAWARA MASAHIRO (JP); HIRANO TAICHI (JP); SASAKI HIROMITSU (JP); YOSHIDA TETSUO (JP); SAITO MICHISHIGE (JP); ISHIHARA HIROYUKI (JP); OYABU JUN (JP); NUMATA KOHJI (JP)	US137 26-May-2005 51605A
US7494561B2	24-Feb-2009	Plasma processing apparatus and method, and electrode plate for plasma processing apparatus	KOSHIISHI AKIRA (JP); HIROSE JUN (JP); OGASAWARA MASAHIRO (JP); HIRANO TAICHI (JP); SASAKI HIROMITSU (JP); YOSHIDA TETSUO (JP); SAITO MICHISHIGE (JP); ISHIHARA HIROYUKI (JP); OYABU JUN (JP); NUMATA KOHJI (JP)	US137 26-May-2005 49205A

US7374976B2	20-May-2008	Method for fabricating thin film transistor	MAEKAWA SHINJI (JP); AKIMOTO KENGO (JP)	US713 21903A	17-Nov-2003
US7332406B2	19-Feb-2008	Air gap interconnect structure and method	PARK HYUN MOG (US); KLOSTER GRANT M (US)	US986 41404A	10-Nov-2004
US6900126B2	31-May-2005	Method of forming metallized pattern	CARTER KENNETH RAYMOND (US); HART MARK WHITNEY (US); HAWKER CRAIG JON (US); SCOTT JOHN CAMPBELL (US)	US301 31802A	20-Nov-2002
US7306892B2	11-Dec-2007	Undercoating containing chromogen; covering with photoresist which forms images when exposed to radiation wavelengths	BARCLAY GEORGE G (US); CAMERON JAMES F (US)	US718 48703A	20-Nov-2003
US7648913B2	19-Jan-2010	Method of electroless deposition of thin metal and dielectric films with temperature controlled stages of film growth	IVANOV IGOR C (US)	US533 04206A	19-Sep-2006
US7033068B2	25-Apr-2006	Substrate processing apparatus for processing substrates using dense phase gas and sonic waves	CHING GIL (FR); PERRUT VINCENT (FR); RUCH VINCENT (FR); FRESQUET GILLES (FR)	US730 6005A	4-Mar-2005
US7759053B2	20-Jul-2010	forming an aluminum-comprising conductive metal line over a semiconductor substrate, exposing conductive line to a solution comprising an inorganic acid (H3PO4 or H2SO4) hydrogen peroxide and a carboxylic acid buffering agent (diammonium citrate, ammonium oxalate)	YATES DONALD L (US)	US497 68806A	31-Jul-2006
US9676966B2	13-Jun-2017	Chemical mechanical polishing composition and process	NOJO HARUKI (JP); YOSHIDA AKITOSHI (JP); KASHIHARA HIROFUMI (JP); BERAR PASCAL (US)	US534 69903A	13-Nov-2003
US2007087124A1	19-Apr-2007	COMPOSITION FOR FORMING POROUS FILM, POROUS FILM AND METHOD FOR FORMING THE SAME, INTERLEVEL INSULATOR FILM, AND SEMICONDUCTOR DEVICE	IWABUCHI MOTOAKI (JP); YAGIHASHI FUJIO (JP); HAMADA YOSHITAKA (JP); NAKAGAWA HIDEO (JP); SASAGO MASARU (JP)	US537 69706A	2-Oct-2006
US7504325B2	17-Mar-2009	Laser doping processing method and method for manufacturing semiconductor device	KOEZUKA JUNICHI (JP); TAKADA SADAOKO (JP)	US700 57103A	5-Nov-2003
US8491987B2	23-Jul-2013	Selectively coated self-aligned mask	COLBURN MATTHEW E (US); GATES STEPHEN M (US); HEDRICK JEFFREY C (US); HUANG ELBERT (US); NITTA SATYANARAYANA V (US); PURUSHOTHAMAN SAMPATH (US); SANKARAPANDIAN MUTHUMANICKAM (US)	US164 64708A	30-Jun-2008
US7485341B2	3-Feb-2009	Nonlithographic method to produce masks by selective reaction, articles produced, and composition for same	COLBURN MATTHEW E (US); GATES STEPHEN M (US); HEDRICK JEFFREY C (US); HUANG ELBERT (US); NITTA SATYANARAYANA V (US); PURUSHOTHAMAN SAMPATH (US); SANKARAPANDIAN MUTHUMANICKAM (US)	US421 30603A	23-Apr-2003
US2005042874A1	24-Feb-2005	Removing sacrificial material by thermal decomposition	MEAGLEY ROBERT P (US); MOON PETER K (US); O BRIEN KEVIN P (US)	US953 74404A	29-Sep-2004
US7923194B2	12-Apr-2011	Sacrificial compositions and methods of fabricating a structure using sacrificial compositions	KOHL PAUL A (US); JOSEPH PAUL J (US); REED HOLLIE K (US); BIDSTRUP ALLEN SUE ANN (US); WHITE CELESTA E (US); HENDERSON CLIFFORD (US)	US273 11408A	18-Nov-2008

US6855636B2	15-Feb-2005	Electrode fabrication methods for organic electroluminescent devices	THEISS STEVEN D (US); LE HA T (US); TOLBERT WILLIAM A (US); WOLK MARTIN B (US); BAUDE PAUL F (US)	US285 10302A	31-Oct-2002
US6861755B2	1-Mar-2005	Semiconductor device	HOSODA TSUTOMU (JP); YAMANOE AKIRA (JP)	US694 98503A	29-Oct-2003
US7223652B2	29-May-2007	Capacitor and manufacturing method thereof, semiconductor device and substrate for a semiconductor device	OOI KIYOSHI (JP); HORIKAWA YASUYOSHI (JP); YAMASAKI TOMOO (JP)	US485 5605A	1-Feb-2005
US7435165B2	14-Oct-2008	Transparent microporous materials for CMP	PRASAD ABANESHWAR (US)	US282 48902A	28-Oct-2002
US2007141857A1	21-Jun-2007	Target designs and related methods for enhanced cooling and reduced deflection and deformation	STROTHERS SUSAN D (US); HORT WERNER H (US); MCNEIL FREDERICK K (US)	US531 76303A	24-Oct-2003
US7270761B2	18-Sep-2007	Fluorine free integrated process for etching aluminum including chamber dry clean	WANG XIKUN (US); CHEN HUI (US); JIANG ANBEI (US); SHIH HONG (US); MAK STEVE S Y (US)	US273 58002A	18-Oct-2002
US7105836B2	12-Sep-2006	Method and apparatus for cooling a reticle during lithographic exposure	DEL PUERTO SANTIAGO (US); GALBURT DANIEL N (US); MCCULLOUGH ANDREW W (US); ROUX STEPHEN (US); OTTENS JOOST JEROEN (NL)	US273 40502A	18-Oct-2002
US7332431B2	19-Feb-2008	Method of manufacturing semiconductor device	MAEKAWA SHINJI (JP)	US685 38003A	16-Oct-2003
US6953041B2	11-Oct-2005	Compositions of transition metal species in dense phase carbon dioxide and methods of use thereof	DEYOUNG JAMES P (US); MCCLAIN JAMES B (US); GROSS STEPHEN M (US); WAGNER MARK I (US)	US267 27602A	9-Oct-2002
US7244168B2	17-Jul-2007	Methods for reducing delamination during chemical mechanical polishing	CHEN YUFEI (US); SUN LIZHONG (US); LEE DOOHAN (US); HSU WEI YUNG (US)	US393 27806A	30-Mar-2006
US8197882B2	12-Jun-2012	Method for forming thin film pattern, thin film manufacturing device, conductive thin film wiring, electro-optic device, electronic apparatus, and non-contact card medium	HASEI HIRONORI (JP); HIRAI TOSHIMITSU (JP)	US636 69106A	8-Dec-2006
US7098474B2	29-Aug-2006	thin film material of a carbon based material, silicon based material, silicon carbide based material, and cadmium sulfide based material, is between the hole injection layer and the hole transporting layer; heat resistance	KANNO HIROSHI (JP); YONEDA KIYOSHI (JP); NISHIMURA KAZUKI (JP); HAMADA YUJI (JP)	US668 60903A	24-Sep-2003
US9638662B2	2-May-2017	Apparatuses and methods for manipulating droplets	POLLACK MICHAEL G (US); PAMULA VAMSEE K (US); FAIR RICHARD B (US)	US201 514817 834A	4-Aug-2015
US2005173803A1	11-Aug-2005	Interlayer adhesion promoter for low k materials	LU VICTOR (US); LEUNG ROGER Y (US); FAN WENYA (US); NAMAN ANANTH (US); ZHOU DE LING (US)	US517 57504A	9-Dec-2004
US2004084150A1	6-May-2004	Photoresist implant crust removal	GEORGE RENE (US); ZAJAC JOHN (US); DEVINE DANIEL J (US); RANFT CRAIG (US); KADAVANICH ANDREAS (US)	US665 26703A	17-Sep-2003

US7807267B2	5-Oct-2010	Method of modifying porous film, modified porous film and use of same	KOHMURA KAZUO (JP); OIKE SHUNSUKE (JP); KUBOTA TAKESHI (JP); MURAKAMI MASAMI (JP); KURANO YOSHITO (JP)	US526 3-Mar-2005 68805A
US7827930B2	9-Nov-2010	Apparatus for electroless deposition of metals onto semiconductor substrates	LUBOMIRSKY DMITRY (US); SHANMUGASUNDRAM ARULKUMAR (US); ELLWANGER RUSSELL (US); PANCHAM IAN A (US); CHEBOLI RAMAKRISHNA (US); WEIDMAN TIMOTHY W (US)	US434 26-Jan-2005 4205A
US7311779B2	25-Dec-2007	Heating apparatus to heat wafers using water and plate with turbolators	NGUYEN SON T (US); ROSEN GARY J (US); PANCHAM IAN A (US)	US680 6-Oct-2003 35903A
US2007199507A1	30-Aug-2007	APPARATUS TO IMPROVE WAFER TEMPERATURE UNIFORMITY FOR FACE-UP WET PROCESSING	PANCHAM IAN A (US); NGUYEN SON T (US); ROSEN GARY J (US)	US743 2-May-2007 41307A
US8367552B2	5-Feb-2013	Method for fabrication of in-laid metal interconnects	DAAMEN ROEL (BE); NGUYEN HOANG VIET (BE); HOOFMAN ROMANO JULMA OSCAR MARIA (BE); VERHEIJDEN GREJA JOHANNA ADRIANA MARIA (BE)	US526 4-Aug-2003 42203A
US2005148183A1	7-Jul-2005	Polishing pad, platen hole cover, polishing apparatus, polishing method, and method for fabricating semiconductor device	SHIRO KUNIYASU (JP); KOBAYASHI TSUTOMU (JP); HASHISAKA KAZUHIKO (JP)	US502 26-Jul-2004 39704A
US7485971B2	3-Feb-2009	Electronic device package	FULLER JASON L (US); HALL FRANK L (US); JIANG TONGBI (US)	US216 31-Aug-2005 81405A
US7473582B2	6-Jan-2009	Method for fabricating semiconductor component with thinned substrate having pin contacts	WOOD ALAN G (US); DOAN TRUNG TRI (US)	US371 9-Mar-2006 76606A
US7498670B2	3-Mar-2009	Semiconductor structures having electrophoretically insulated vias	FARNWORTH WARREN M (US); COLLINS DALE W (US); MCDONALD STEVEN M (US)	US504 15-Aug-2006 40506A
US2004040217A1	4-Mar-2004	Polishing composition	TAKASHINA SHIGEAKI (JP); YONEDA YASUHIRO (JP); HAGIHARA TOSHIYA (JP)	US637 11-Aug-2003 56803A
US2012100304A1	26-Apr-2012	MICROMETRIC DIRECT-WRITE METHODS FOR PATTERNING CONDUCTIVE MATERIAL AND APPLICATIONS TO FLAT PANEL DISPLAY REPAIR	CRUCHON DUPEYRAT SYLVAIN (US); ZHANG HUA (US); ELGHANIAN ROBERT (US); DEMERS LINETTE (US); AMRO NABIL (US); DISAWAL SANDEEP (US); BUSSAN JOHN (US)	US201 24-Oct-2011 113279 793A
US7005378B2	28-Feb-2006	Processes for fabricating conductive patterns using nanolithography as a patterning tool	CROCKER JR PERCY VANDORN (US); DEMERS LINETTE (US); AMRO NABIL A (US)	US647 26-Aug-2003 43003A
US7854962B2	21-Dec-2010	Vapor deposition of a metal oxide /nitride, dielectric thin films on semiconductor wafers by supplying the gas produced by evaporation or sublimation of the metal material; providing a heater, a carrier gas, temperature controller and baffle to maintain uniform gas diffusion and coating	KASAI SHIGERU (JP); TANAKA SUM (JP); SAITO TETSUYA (JP); YAMAMOTO NORIHIKO (JP); YANAGITANI KENICHI (JP)	US320 21-Jan-2009 19709A
US7473443B2	6-Jan-2009	Composition for forming silicon film and method for forming silicon film	MATSUKI YASUO (JP); IWASAWA HARUO (JP); KATO HITOSHI (JP)	US515 26-Nov-2004 72804A

US2006160014A1	20-Jul-2006	Photosensitive composition for interlayer dielectric and method of forming patterned interlayer dielectric	NAGAHARA TATSURO (JP); MATSUO HIDEKI (JP)	US524 10-Feb-2005 52705A
US7022582B2	4-Apr-2006	Microelectronic process and structure	SEZI RECAI (DE)	US631 31-Jul-2003 58703A
US8652343B2	18-Feb-2014	Method for selectively removing material from the surface of a substrate, masking material for a wafer, and wafer with masking material	HAUSNER MARTIN (DE)	US524 14-Aug-2003 52503A
US8231735B2	31-Jul-2012	Polishing slurry for chemical mechanical polishing and method for polishing substrate	HAGA KOUJI (JP); OOTSUKI YUTO (JP); KURATA YASUSHI (JP); ENOMOTO KAZUHIRO (JP)	US905 28-Sep-2007 27907A
US6800938B2	5-Oct-2004	Semiconductor device having amorphous barrier layer for copper metallurgy	CHEN FEN (US)	US215 8-Aug-2002 12102A
US2004162011A1	19-Aug-2004	Aqueous dispersion for chemical mechanical polishing and production process of semiconductor device	KONNO TOMOHISA (JP); MOTONARI MASAYUKI (JP); HATTORI MASAYUKI (JP); KAWAHASHI NOBUO (JP)	US626 25-Jul-2003 52103A
US7871705B2	18-Jan-2011	Carbon fiber composite transfer member with reflective surfaces	MILLER CHRIS L (US); UCHIDA DAISUKE (JP); KOBAYASHI TAKASHI (JP); AOYAGI KENICHI (JP); TAKEMURA SHINICHI (JP)	US259 28-Oct-2008 81608A
US6972440B2	6-Dec-2005	Enhanced T-gate structure for modulation doped field effect transistors	SINGH DINKAR (US); SAENGER KATHERINE LYNN (US); PATEL VISHNUBHAI V (US); GRILL ALFRED (US); KOESTER STEVEN JOHN (US)	US750 2-Jan-2004 69704A
US7311810B2	25-Dec-2007	Two position anneal chamber	MOK YEUK FAI EDWIN (US); NGUYEN SON T (US)	US823 13-Apr-2004 84904A
US2005173052A1	11-Aug-2005	Method for processing an electronic part	MITARAI YOSHIAKI (JP)	US672 28-Feb-2005 0405A
US8939428B2	27-Jan-2015	Liquid flow controller and precision dispense apparatus and system	LAVERDIERE MARC (US); MCLOUGHLIN ROBERT F (US); GONNELLA GEORGE (US); GASHGAEI IRAJ (US); MARRS JENNIFER (US)	US201 29-Mar-2013 313853 674A
US6811474B2	2-Nov-2004	Polishing composition containing conducting polymer	CHERIAN ISAAC K (US); ZHANG JIAN (US); SUN FRED (US); WANG SHUMIN (US); KLINGENBERG ERIC H (US)	US199 19-Jul-2002 70402A
US7064079B2	20-Jun-2006	Method of removing polymer and apparatus for doing the same	SONODA HIROYUKI (JP); KAWAGUCHI HIDEHIKO (JP); TANAKA MORIMITSU (JP); OHNO HIROKI (JP)	US615 10-Jul-2003 80603A
US6987307B2	17-Jan-2006	Stand-alone organic-based passive devices	WHITE GEORGE E (US); SWAMINATHAN MADHAVAN (US); SUNDARAM VENKATESH (US); DALMIA SIDHARTH (US)	US405 28-Mar-2003 02403A
US2007148985A1	28-Jun-2007	Method of manufacturing trench structure for device	MIZUTANI NOBUTAKA (JP); FITRIANTO (JP); TSUKAGOSHI ISAO (JP); HIROSE KEIZO (JP); HOSHINO SATOHIKO (JP)	US648 3-Jan-2007 56107A

US6918984B2	19-Jul-2005	Photocurable adhesive compositions, reaction products of which have low halide ion content	MURRAY HELEN M (IE); WIGHAM JONATHAN P (IE); CAHILL JOHN E (IE); LAKES AISLING (IE); HOLLOWAY MATTHEW J (IE); LEDWIDGE EADAON D (IE); WARD MARY B (IE)	US176 24-Jun-2002 64802A
US7550825B2	23-Jun-2009	Interlayer dielectric and pre-applied die attach adhesive materials	SANTOS BENEDICTO DELOS (US); HUNEKE JAMES T (US); LIU PUWEI (US); YANG KANG (US); JI QING (US)	US758 5-Jun-2007 08907A
US8377358B2	19-Feb-2013	Method for encapsulating the edge of a flexible sheet	KEENIHAN JAMES R (US); CLAREY TODD M (US)	US989 1-May-2009 74709A
US7163301B2	16-Jan-2007	Method and apparatus for managing actinic intensity transients in a lithography mirror	DEL PUERTO SANTIAGO (US)	US169 29-Jun-2005 00905A
US6620741B1	16-Sep-2003	Method for controlling etch bias of carbon doped oxide films	GRACIAS DAVID H (US); PARK HYUN MOG (US); RAMACHANDRARAO VIJAYAKUMAR S (US)	US166 10-Jun-2002 15002A
US7053355B2	30-May-2006	System and method for lithography process monitoring and control	YE JUN (US); PEASE R FABIAN W (US); CHEN XUN (US)	US212 25-Aug-2005 30805A
US6936543B2	30-Aug-2005	CMP method utilizing amphiphilic nonionic surfactants	SCHROEDER DAVID J (US); MOEGGENBORG KEVIN J (US); CHOU HOMER (US); CHAMBERLAIN JEFFREY P (US); HAWKINS JOSEPH D (US); CARTER PHILLIP (US)	US269 11-Oct-2002 86402A
US6974777B2	13-Dec-2005	CMP compositions for low-k dielectric materials	MOEGGENBORG KEVIN J (US); CHOU HOMER (US); HAWKINS JOSEPH D (US); CHAMBERLAIN JEFFREY P (US)	US165 7-Jun-2002 10002A
US8800631B2	12-Aug-2014	Laminate body, method, and apparatus for manufacturing ultrathin substrate using the laminate body	NODA KAZUKI (JP); IWASAWA MASARU (JP)	US201 19-Aug-2011 113213 553A
US2010301265A1	2-Dec-2010	POLISHING SLURRY AND METHOD OF POLISHING	KURATA YASUSHI (JP); KAMIGATA YASUO (JP); ANZAI SOU (JP); TERAZAKI HIROKI (JP)	US855 12-Aug-2010 26810A
US7252718B2	7-Aug-2007	Forming a passivating aluminum fluoride layer and removing same for use in semiconductor manufacture	CARTER MELVIN K (US)	US448 27-Aug-2003 12703A
US2005181576A1	18-Aug-2005	Method for forming inorganic porous film	OGAWA SHINICHI (JP); NASUNO TAKASHI (JP); KAJI NARUHIKO (JP)	US515 22-Nov-2004 23904A
US6969681B2	29-Nov-2005	Method for fabricating a semiconductor component using contact printing	FARNWORTH WARREN M (US)	US203 1-Dec-2004 104A
US6838772B2	4-Jan-2005	Semiconductor device	SAITOH TOSHIO (JP); ISHIKAWA KENSUKE (JP); ASHIHARA HIROSHI (JP); SAITO TATSUYUKI (JP)	US437 15-May-2003 90003A
US7453101B2	18-Nov-2008	Semiconductor device with organic compound layer	NAKAMURA OSAMU (JP); KUWABARA HIDEAKI (JP); SHIBATA NORIKO (JP)	US285 5-Jan-2005 3605A
US6930032B2	16-Aug-2005	Under bump metallurgy structural design for high reliability bumped packages	SARIHAN VIJAY (US); FAY OWEN (US); KESER LIZABETH ANN (US)	US145 14-May-2002 50002A

US6806520B2	19-Oct-2004	Method of making transistors	THEISS STEVEN D (US); HAASE MICHAEL A (US); THEISS SILVA K (US)	US719 21-Nov-2003 20903A
US8696929B2	15-Apr-2014	Polishing slurry and polishing method	KURATA YASUSHI (JP); MASUDA KATSUYUKI (JP); ONO HIROSHI (JP); KAMIGATA YASUO (JP); ENOMOTO KAZUHIRO (JP)	US808 6-Jun-2007 04707A
US7018748B2	28-Mar-2006	Process for producing hard masks	SEBALD MICHAEL (DE); RICHTER ERNST CHRISTIAN (DE)	US425 29-Apr-2003 23303A
US7211145B2	1-May-2007	Substrate processing apparatus and substrate processing method	GOSHI GENTARO (JP)	US422 23-Apr-2003 40803A
US6884700B2	26-Apr-2005	Method of manufacturing device, device, and electronic apparatus	AOKI TAKASHI (JP); FURUSAWA MASAHIRO (JP); YUDASAKA ICHIO (JP)	US420 22-Apr-2003 52503A
US6767749B2	27-Jul-2004	Method for making piezoelectric resonator and surface acoustic wave device using hydrogen implant layer splitting	KUB FRANCIS J (US); HOBART KARL D (US)	US126 22-Apr-2002 66202A
US2007190265A1	16-Aug-2007	High order silane composition, and method of forming silicon film using the composition	AOKI TAKASHI (JP); FURUSAWA MASAHIRO (JP); MATSUKI YASUO (JP); IWASAWA HARUO (JP); TAKEUCHI YASUMASA (JP)	US787 16-Apr-2007 44507A
US6953600B2	11-Oct-2005	Conductive film forming composition, conductive film, and method for forming the same	YOKOYAMA YASUAKI (JP); MATSUKI YASUO (JP); SAKONO IKUO (JP); KOBAYASHI KAZUKI (JP); TAKEUCHI YASUMASA (JP)	US410 10-Apr-2003 15403A
US9061317B2	23-Jun-2015	Porogens, porogenated precursors and methods for using the same to provide porous organosilica glass films with low dielectric constants	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUIS (US); LUKAS AARON SCOTT (US); HAAS MARY KATHRYN (US)	US201 5-Apr-2012 213439 911A
US8951342B2	10-Feb-2015	Methods for using porogens for low k porous organosilica glass films	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUISE (US); LUKAS AARON SCOTT (US); HAAS MARY KATHRYN (US)	US201 1-Nov-2011 113286 634A
US8293001B2	23-Oct-2012	Porogens, porogenated precursors and methods for using the same to provide porous organosilica glass films with low dielectric constants	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUISE (US); LUKAS AARON SCOTT (US); XIAO MANCHAO (US); NORMAN JOHN ANTHONY THOMAS (US)	US201 21-Feb-2011 113031 387A
US2008268177A1	30-Oct-2008	Porogens, Porogenated Precursors and Methods for Using the Same to Provide Porous Organosilica Glass Films with Low Dielectric Constants	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUIS (US); LUKAS AARON SCOTT (US); HAAS MARY KATHRYN (US)	US115 5-May-2008 08708A
US7943195B2	17-May-2011	Mixing of glass with hydrocarbons; chemical vapor deposition; mixing organosilane and/or organosiloxane precursors with porogens; neohexyl-1,3,5,7-tetramethylcyclo-tetrasiloxane	VRTIS RAYMOND NICHOLAS (US); O NEILL MARK LEONARD (US); VINCENT JEAN LOUISE (US); LUKAS AARON SCOTT (US); XIAO MANCHAO (US); NORMAN JOHN ANTHONY THOMAS (US)	US115 6-May-2008 83808A
US7146910B2	12-Dec-2006	Method for fabricating pattern, apparatus for fabricating pattern, conductive film wiring, method for fabricating device, electro-optical apparatus, and electronic apparatus	HASEI HIRONORI (JP)	US953 30-Sep-2004 51904A
US7986041B2	26-Jul-2011	Semiconductor device	TANAKA JUN (JP); OTANI MIHARU (JP); OGATA KIYOSHI (JP); SUZUKI YASUMICHI (JP); HOTTA KATSUHIKO (JP)	US815 15-Jun-2010 97610A

US2007275569A1	29-Nov-2007	METHODS AND APPARATUS FOR E-BEAM TREATMENT USED TO FABRICATE INTEGRATED CIRCUIT DEVICES	MOGHADAM FARHAD (US); ZHAO JUN (US); WEIDMAN TIMOTHY (US); ROBERTS RICK J (US); XIA LI QUN (US); DEMOS ALEXANDROS T (US)	US838 14-Aug-2007 74207A
US7381442B2	3-Jun-2008	Semiconductors; films; formed by crosslinking silicon containing pre-polymers at low gel temperatures via metal-ion-free onium or nucleophile catalyst	LU VICTOR Y (US); LEUNG ROGER Y (US); DENG ERIC (US); XIE SONGYUAN (US)	US507 13-Sep-2004 41104A
US2005147925A1	7-Jul-2005	System and method for analog replication of microdevices having a desired surface contour	HARCHANKO JOHN S (US); BANISH MICHELE (US)	US722 7-Mar-2005 2705A
US6888234B2	3-May-2005	Semiconductor device and manufacturing method for the same	TOKUSHIGE NOBUAKI (JP)	US405 3-Apr-2003 93903A
US6899816B2	31-May-2005	Electroless deposition method	PADHI DEENESH (US); YAHALOM JOSEPH (US); RAMANATHAN SIVAKAMI (US); MCGUIRK CHRIS R (US); GANDIKOTA SRINIVAS (US); DIXIT GIRISH (US)	US117 3-Apr-2002 71102A
US2003190818A1	9-Oct-2003	Enhanced processing of performance films using high-diffusivity penetrants	CARBONELL RUBEN (US); DESIMONE JOSEPH M (US); MCCLAIN JAMES B (US); DEYOUNG JAMES (US)	US115 3-Apr-2002 35202A
US6946382B2	20-Sep-2005	Process for making air gap containing semiconducting devices and resulting semiconducting device	TOWNSEND III PAUL H (US); FOSTER KENNETH L (US)	US505 24-Aug-2004 51104A
US7238421B2	3-Jul-2007	Pressure sensitive adhesive film for protection of semiconductor wafer surface and method of protecting semiconductor wafer with the pressure sensitive adhesive film	SAIMOTO YOSHIHISA (JP); KATAOKA MAKOTO (JP); MIYAKAWA MASAFUMI (JP); HAYAKAWA SHINICHI (JP); IGARASHI KOUJI (JP)	US506 7-Sep-2004 80604A
US6861377B1	1-Mar-2005	Surface treatment method, surface-treated substrate, method for forming film pattern, method for making electro-optical device, electro-optical device, and electronic apparatus	HIRAI TOSHIMITSU (JP); HASEI HIRONORI (JP)	US386 13-Mar-2003 44703A
US6827639B2	7-Dec-2004	Polishing particles and a polishing agent	NISHIDA HIROYASU (JP); WAKAMIYA YOSHINORI (JP); KOMATSU MICHIO (JP)	US394 24-Mar-2003 21703A
US7347951B2	25-Mar-2008	Method of manufacturing electronic device	UEMATSU IKUO (JP); HAYAMIZU NAOYA (JP)	US206 18-Aug-2005 03605A
US2003183332A1	2-Oct-2003	Screen printed thermal expansion standoff	SIMILA CHARLES E (US)	US106 26-Mar-2002 54502A
US6773873B2	10-Aug-2004	pH buffered compositions useful for cleaning residue from semiconductor substrates	SEIJO MA FATIMA (US); WOJTCZAK WILLIAM A (US); BERNHARD DAVID (US); BAUM THOMAS H (US); MINSEK DAVID (US)	US105 25-Mar-2002 70402A
US2005079705A1	14-Apr-2005	Process for producing semiconductor device and semiconductor device	TAKEUCHI KOICHI (JP)	US506 7-Sep-2004 79204A
US7098121B2	29-Aug-2006	Method of forming a film of predetermined pattern on a surface as well as device manufactured by employing the same, and method of manufacturing device	MORI YOSHIKI (JP); MIYAKAWA TAKUYA (JP); SATO MITSURU (JP); ASUKE SHINTARO (JP); TAKAGI KENICHI (JP)	US367 19-Feb-2003 85403A
US7364622B2	29-Apr-2008	Method and apparatus for fabricating a device, and the device and an electronic equipment	HASEI HIRONORI (JP); HIRAI TOSHIMITSU (JP)	US382 7-Mar-2003 57603A

US7776647B2	17-Aug-2010	Semiconductor components and methods of fabrication with circuit side contacts, conductive vias and backside conductors	FARNWORTH WARREN M (US); WOOD ALAN G (US); DOAN TRUNG TRI (US)	US496 18006A	31-Jul-2006
US6992115B2	31-Jan-2006	inert until activated, then undergo an irreversible intramolecular crosslinking reaction; dielectrics; pseudo high dilution process; solution polymerization	HAWKER CRAIG JON (US); MILLER ROBERT DENNIS (US); HEDRICK JAMES LUPTON (US); LEE VICTOR YEE WAY (US)	US775 71304A	9-Feb-2004
US7378124B2	27-May-2008	light active materials comprises electrostatic microcapsules comprising organic light emitting diodes (OLED) encapsulated within polymer shells	DANIELS JOHN JAMES (US)	US716 79403A	19-Nov-2003
US7193193B2	20-Mar-2007	Magnetic annealing of ferromagnetic thin films using induction heating	BERGSTROM PAUL L (US); TROMBLEY MELISSA L (US)	US796 1805A	14-Mar-2005
US6878909B2	12-Apr-2005	Induction heating of thin films	BERGSTROM PAUL L (US); TROMBLEY MELISSA L (US)	US376 49703A	28-Feb-2003
US7163883B2	16-Jan-2007	Edge seal for a semiconductor device	AGARWALA BIRENDRA N (US); DALAL HORMAZDYAR MINOCHER (US); LINIGER ERIC G (US); LLERA HURLBURT DIANA (US); NGUYEN DU BINH (US); PROCTER RICHARD W (US); RATHORE HAZARA SINGH (US); TIAN CHUNYAN E (US); ENGEL BRETT H (US)	US694 50003A	27-Oct-2003
US7521168B2	21-Apr-2009	Resist composition for electron beam, EUV or X-ray	MIZUTANI KAZUYOSHI (JP); TAKAHASHI HYOU (JP)	US361 50503A	11-Feb-2003
US7550317B2	23-Jun-2009	Method for manufacture of wafer level package with air pads	KIM GU SUNG (KR)	US601 80806A	20-Nov-2006
US7033447B2	25-Apr-2006	Halogen-resistant, anodized aluminum for use in semiconductor processing apparatus	LIN YIXING (US); WEST BRIAN T (US); WU SHUN JACKSON (US); STOW CLIFFORD C (US); THACH SENH (US); WANG HONG (US); SUN JENNIFER Y (US)	US137 78202A	3-May-2002
US7476875B2	13-Jan-2009	Contact opening metrology	KADYSHEVITCH ALEXANDER (IL); TALBOT CHRIS (US); SHUR DMITRY (IL); HEGEDUS ANDREAS G (US)	US779 22407A	17-Jul-2007
US7413775B2	19-Aug-2008	Insulating film material containing an organic silane compound, its production method and semiconductor device	HARA DAIJI (JP); YOSHIDA KEISUKE (JP)	US347 31206A	6-Feb-2006
US2010276392A1	4-Nov-2010	CMP SYSTEM UTILIZING HALOGEN ADDUCT	GRUMBINE STEVEN (US); DE REGE THESAURO FRANCESCO (US)	US838 81310A	19-Jul-2010
US7316603B2	8-Jan-2008	Compositions and methods for tantalum CMP	CARTER PHILLIP W (US); ZHANG JIAN (US); GRUMBINE STEVEN K (US); DE REGE THESAURO FRANCESCO (US)	US235 76505A	26-Sep-2005
US7097541B2	29-Aug-2006	CMP method for noble metals	DEREGE THESAURO FRANCESCO (US); BRUSIC VLASTA (US); BAYER BENJAMIN P (US)	US376 17203A	27-Feb-2003
US2005077188A1	14-Apr-2005	Endpoint for electrochemical processing	MAO DAXIN (US); JIA RENHE (US); WANG ZHIHONG (US); TIAN YUAN (US); LIU FENG Q (US); GALBURT VLADIMIR (US); KO SEN HOU (US); TSAI STAN D (US); CHEN LIANG YUH (US)	US940 60304A	14-Sep-2004

US7135775B2	14-Nov-2006	Enhancement of an interconnect	CHAMBERS STEPHEN T (US); DUBIN VALERY M (US); OTT ANDREW W (US); HAU RIEGE CHRISTINE S (US)	US292 32602A	12-Nov-2002
US7591922B2	22-Sep-2009	Substrate processing apparatus and substrate processing method	OKAMOTO YOSHIO (JP)	US101 73905A	8-Apr-2005
US7479462B2	20-Jan-2009	Thin films and methods for the preparation thereof	RANTALA JUHA T (FI); REID JASON S (US); VISWANATHAN NUNGAVRAM S (US); TORMANEN T TEEMU T (FI)	US213 42705A	29-Aug-2005
US9136246B2	15-Sep-2015	Integrated chip package structure using silicon substrate and method of manufacturing the same	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW); HUANG CHING CHENG (TW)	US755 04204A	9-Jan-2004
US8471361B2	25-Jun-2013	Integrated chip package structure using organic substrate and method of manufacturing the same	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW); HUANG CHING CHENG (TW)	US201 113031 163A	18-Feb-2011
US7226817B2	5-Jun-2007	Method of manufacturing	TANADA YOSHIFUMI (JP); ISOBE ATSUO (JP); SHIBATA HIROSHI (JP); YAMAZAKI SHUNPEI (JP)	US330 01502A	27-Dec-2002
US7091287B2	15-Aug-2006	Nanopore forming material for forming insulating film for semiconductors and low dielectric insulating film comprising the same	KWON WON JONG (KR); KO MIN JIN (KR); KANG GWI GWON (KR); SHIN DONG SEOK (KR); MOON MYUNG SUN (KR); KANG JUNG WON (KR); NAM HAE YOUNG (KR); KIM YOUNG DUK (KR); CHOI BUM GYU (KR)	US331 00302A	27-Dec-2002
US6800423B2	5-Oct-2004	Radiation-sensitive composition and method for forming patterns and fabricating semiconductor devices	YOKOYAMA YOSHIYUKI (JP); HATTORI TAKASHI (JP)	US294 61802A	15-Nov-2002
US7466735B2	16-Dec-2008	Manufacturing method of semiconductor device	TANAKA KOICHIRO (JP)	US480 88606A	6-Jul-2006
US7319055B2	15-Jan-2008	Method of fabricating a semiconductor device utilizing crystallization of semiconductor region with laser beam	KOKUBO CHIHO (JP); SHIGA AIKO (JP); TANADA YOSHIFUMI (JP); YAMAZAKI SHUNPEI (JP)	US941 84804A	16-Sep-2004
US7407849B2	5-Aug-2008	Self-aligned printing	SIRRINGHAUS HENNING (GB); BANACH MICHAEL J (GB); STONE NICHOLAS JIM (GB); WILSON DAVID WILLIAM JOSEPH (GB); MACKENZIE JOHN DEVIN (US); HUCK WILHELMUS THEODORUS STEFA (GB); SELE CHRISTOPH WILHELM (GB)	US499 66505A	9-Mar-2005
US7135389B2	14-Nov-2006	Irradiation method of laser beam	YAMAZAKI SHUNPEI (JP); KOKUBO CHIHO (JP); SHIGA AIKO (JP); TANAKA KOICHIRO (JP); MIYAIRI HIDEKAZU (JP); DAIRIKI KOJI (JP)	US318 29002A	13-Dec-2002
US6761814B2	13-Jul-2004	SUPERIOR FILLING PROPERTIES AND SUPERIOR PLANARIZATION OF THE DEPOSITED METAL LAYER IS PROVIDED. THIS IS ACHIEVED BY A METHOD HAVING A F/R RATIO, THE RATIO OF THE ELECTRIC CURRENT DENSITIES BETWEEN THE FORWARD ELECTROLYSIS AND THE REVERSE	KUSAKA MASARU (JP); TSUCHIDA HIDEKI (JP)	US327 58802A	20-Dec-2002

US7090896B2	15-Aug-2006	Process for producing dielectric layers by using multifunctional carbosilanes	KIRCHMEYER STEPHAN (DE); GAISER DETLEF (DE); KRAUS HARALD (DE); MERKER UDO (DE)	US319 13-Dec-2002 12102A
US2006143990A1	6-Jul-2006	Polishing fluid for metal, and polishing method	ONO HIROSHI (JP); MASUDA KATSUYUKI (JP); HABIRO MASANOBU (JP)	US560 12-Dec-2005 22805A
US8486837B2	16-Jul-2013	Polishing slurry for metal, and polishing method	ONO HIROSHI (JP); MASUDA KATSUYUKI (JP); HABIRO MASANOBU (JP)	US318 29-Dec-2008 37608A
USRE45781E	27-Oct-2015	Toughness, adhesion and smooth metal lines of porous low K dielectric interconnect structures	HEDRICK JEFFREY C (US); LEE KANG WOOK (US); MALONE KELLY (US); TYBERG CHRISTY S (US)	US201 10-Feb-2014 414176 526A
US7112048B2	26-Sep-2006	BOC BGA package for die with I-shaped bond pad layout	LIM THIAM CHYE (SG); TAN KAY KIT (SG); LEE KIAN CHAI (SG); TAN VICTOR CHER KHNG (SG); TAN KWANG HONG (SG); LIM CHONG PEI ANDREW (SG); TAN YONG KIAN (SG); LEE TECK KHENG (SG); KHOO SIAN YONG (SG); TANG YOKE KUIN (SG)	US408 8-Apr-2003 99003A
US7763320B2	27-Jul-2010	Depositing an organic compound material over the substrate from a deposition source, heating to decrease a gas in the film	YAMAZAKI SHUNPEI (JP); MURAKAMI MASAKAZU (JP)	US858 21-Sep-2007 96207A
US7560397B2	14-Jul-2009	Laser irradiation method and method of manufacturing a semiconductor device	YAMAZAKI SHUNPEI (JP); SHIBATA HIROSHI (JP); TANAKA KOICHIRO (JP); HIROKI MASAOKI (JP); AKIBA MAI (JP)	US709 22-Feb-2007 20007A
US7892602B2	22-Feb-2011	Cyclical deposition of refractory metal silicon nitride	CHUNG HUA (US); CHEN LING (US); CHIN BARRY L (US)	US422 7-Jun-2006 82606A
US7531890B2	12-May-2009	Multi-chip package (MCP) with a conductive bar and method for manufacturing the same	KIM GU SUNG (KR)	US131 16-May-2005 25305A
US2005003590A1	6-Jan-2005	Method for defining a source and a drain and a gap inbetween	BLEES MARTIN HILLEBRAND (NL); BOEHMER MARCEL RENE (NL)	US497 4-Jun-2004 92604A
US6821897B2	23-Nov-2004	Method for copper CMP using polymeric complexing agents	SCHROEDER DAVID J (US); CARTER PHILLIP (US); CHAMBERLAIN JEFFREY P (US); MILLER KYLE (US); CHERIAN ISAAC K (US)	US246 18-Sep-2002 28002A
US7071562B2	4-Jul-2006	Interconnects with improved barrier layer adhesion	NGO MINH VAN (US); HOPPER DAWN (US)	US662 16-Sep-2003 52503A
US8696808B2	15-Apr-2014	Laser irradiation apparatus	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); HIROKI MASAOKI (JP); TANAKA KOICHIRO (JP); SHIGA AIKO (JP); MURAKAMI SATOSHI (JP); AKIBA MAI (JP)	US514 5-Sep-2006 96906A
US7445974B2	4-Nov-2008	Laser beam irradiating apparatus, laser beam irradiating method, and method of manufacturing a semiconductor device	TANAKA KOICHIRO (JP)	US996 6-Apr-2005 6205A
US7517773B2	14-Apr-2009	Method of manufacturing a thin film transistor	TANADA YOSHIFUMI (JP); NAKAJIMA KAZUYA (JP)	US480 6-Jul-2006 92906A

US7057279B2	6-Jun-2006	High-frequency circuit block, its manufacturing method, high-frequency module device, and its manufacturing method	OGAWA TSUYOSHI (JP)	US466 73103A	18-Jul-2003
US6889431B2	10-May-2005	First conductor layer and the epitaxial dielectric layer are formed without exposing the first conductor layer to atmospheric oxygen before the epitaxial dielectric layer is deposited	OKABE HIROSHI (JP); YAMADA HIROZI (JP); TAKEDA ERIKO (JP); YAMAMOTO KAZUNORI (JP); KURIYA HIROYUKI (JP); YAMAGUCHI MASANORI (JP); OTSUKA KAZUHISA (JP); HIRATA YOSHITAKA (JP); SHIMADA YASUSHI (JP)	US784 4802A	21-Feb-2002
US2005072213A1	7-Apr-2005	Use of id semiconductor materials as chemical sensing materials, produced and operated close to room temperature	BESNARD ISABELLE (FR); VOSSMEYER TOBIAS (DE); YASUDA AKIO (DE); BURGHARD MARKO (DE); SCHLECHT ULRICH (DE)	US496 38004A	18-Nov-2004
US7439115B2	21-Oct-2008	Semiconductor fabricating apparatus	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); HIROKI MASAOKI (JP); TANAKA KOICHIRO (JP); SHIGA AIKO (JP); AKIBA MAI (JP)	US370 00906A	8-Mar-2006
US7351647B2	1-Apr-2008	Method of irradiating a laser beam, apparatus for irradiating a laser beam and method of fabricating semiconductor devices	TANAKA KOICHIRO (JP)	US387 79306A	24-Mar-2006
US7235516B2	26-Jun-2007	Semiconductor cleaning composition comprising an ethoxylated surfactant	MORINAGA HITOSHI (JP); MOCHIZUKI HIDEAKI (JP); ITOU ATSUSHI (JP)	US294 65802A	15-Nov-2002
US6962860B2	8-Nov-2005	Method of manufacturing a semiconductor device	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); HIROKI MASAOKI (JP); TANAKA KOICHIRO (JP); SHIGA AIKO (JP); SHIMOMURA AKIHISA (JP); AKIBA MAI (JP)	US289 21902A	7-Nov-2002
US7468312B2	23-Dec-2008	Laser irradiation apparatus, laser irradiation method, and method of manufacturing a semiconductor device	TANAKA KOICHIRO (JP)	US244 2304A	30-Dec-2004
US6727176B2	27-Apr-2004	Method of forming reliable Cu interconnects	NGO MINH VAN (US); HALLIYAL ARVIND (US); PATON ERIC (US)	US986 26701A	8-Nov-2001
US6617609B2	9-Sep-2003	Organic thin film transistor with siloxane polymer interface	KELLEY TOMMIE W (US); BOARDMAN LARRY D (US); DUNBAR TIMOTHY D (US); JONES TODD D (US); MUYRES DAWN V (US); PELLERITE MARK J (US); SMITH TERRANCE P (US)	US126 5501A	5-Nov-2001
US7352000B2	1-Apr-2008	Organic thin film transistor with polymeric interface	KELLEY TOMMIE W (US); BOARDMAN LARRY D (US); DUNBAR TIMOTHY D (US); JONES TODD D (US); MUYRES DAWN V (US); PELLERITE MARK J (US); SMITH TERRANCE P (US)	US227 50105A	15-Sep-2005
US8481428B2	9-Jul-2013	Polishing slurry and polishing method	AMANOKURA JIN (JP); SAKURADA TAKAFUMI (JP); ANZAI SOU (JP); FUKASAWA MASATO (JP); SASAKI SHOUICHI (JP)	US201 113299 699A	18-Nov-2011
US7510933B2	31-Mar-2009	Fabrication method of semiconductor integrated circuit device	TAKAHASHI OSAMU (JP); OGASAWARA KUNIO (JP)	US802 45107A	23-May-2007
US7892952B2	22-Feb-2011	Laser apparatus, laser irradiation method, manufacturing method for semiconductor device, semiconductor device, production system for semiconductor device using the laser apparatus, and electronic equipment	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); HIROKI MASAOKI (JP); TANAKA KOICHIRO (JP); SHIGA AIKO (JP); AKIBA MAI (JP)	US185 73705A	21-Jul-2005

US7300516B2	27-Nov-2007	Laser irradiation method and laser irradiation apparatus, and method for fabricating semiconductor device	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP)	US962 46804A	13-Oct-2004
US6832949B2	21-Dec-2004	Window member for chemical mechanical polishing and polishing pad	KONNO TOMOHISA (JP); MOTONARI MASAYUKI (JP); HATTORI MASAYUKI (JP); HASEGAWA KOU (JP); KAWAHASHI NOBUO (JP)	US279 84302A	25-Oct-2002
US7001253B2	21-Feb-2006	Boron-containing polishing system and method	ZHOU RENJIE (US); GRUMBINE STEVEN K (US); CHERIAN ISSAC K (US)	US801 31604A	16-Mar-2004
US7732002B2	8-Jun-2010	Method for the fabrication of conductive electronic features	KODAS TOIVO T (US); HAMPDEN SMITH MARK J (US); VANHEUSDEN KAREL (US); DENHAM HUGH (US); STUMP AARON D (US); SCHULT ALLEN B (US); ATANASSOVA PAOLINA (US); KUNZE KLAUS (US)	US274 49502A	18-Oct-2002
US2009250656A1	8-Oct-2009	Free Radical-Forming Activator Attached to Solid and Used to Enhance CMP Formulations	SIDDIQUI JUNAID AHMED (US); SMALL ROBERT J (US); CASTILLO DANIEL HERNANDEZ (US)	US419 62509A	7-Apr-2009
US7429338B2	30-Sep-2008	Surface modified colloidal abrasives, including stable bimetallic surface coated silica sols for chemical mechanical planarization	SIDDIQUI JUNAID AHMED (US)	US487 44306A	17-Jul-2006
US7288178B2	30-Oct-2007	Methods of and apparatus for making high aspect ratio microelectromechanical structures	COHEN ADAM L (US); ZHANG GANG (US); LE QUI T (US); LOCKARD MICHAEL S (US); SMALLEY DENNIS R (US)	US271 57402A	15-Oct-2002
US2009029553A1	29-Jan-2009	Free radical-forming activator attached to solid and used to enhance CMP formulations	SCOTT BRANDON SHANE (US); SMALL ROBERT J (US)	US232 71208A	23-Sep-2008
US8148191B2	3-Apr-2012	Combined etching and doping media	KLEIN SYLKE (DE); KUEBELBECK ARMIN (DE); STOCKUM WERNER (DE); SCHMIDT WILFRIED (DE); SCHUM BERTHOLD (DE)	US246 51608A	7-Oct-2008
US2005031795A1	10-Feb-2005	Method for creating adhesion during fabrication of electronic devices	CHAUDHURY MANOJ KUMAR (US); GOODWIN ANDREW JAMES (IE); LEE YEONG JOO (US); PARBHOO BHUKANDAS (GB); GARDNER GEOFFREY BRUCE (US)	US909 89204A	2-Aug-2004
US7780785B2	24-Aug-2010	Gas delivery apparatus for atomic layer deposition	CHEN LING (US); KU VINCENT (US); WU DIEN YEH (US); CHUNG HUA (US); OUYE ALAN (US); NAKASHIMA NORMAN (US); CHANG MEI (US)	US281 07902A	25-Oct-2002
US8668776B2	11-Mar-2014	Gas delivery apparatus and method for atomic layer deposition	CHEN LING (US); KU VINCENT (US); WU DIEN YEH (US); CHUNG HUA (US); OUYE ALAN (US); NAKASHIMA NORMAN (US)	US797 99910A	10-Jun-2010
US6737744B2	18-May-2004	Semiconductor device including porous insulating material and manufacturing method therefor	FUKUYAMA SHUN ICHI (JP)	US935 0202A	11-Mar-2002
US7453095B2	18-Nov-2008	Light emitting device and manufacturing method thereof	KONUMA TOSHIMITSU (JP)	US844 8005A	18-Mar-2005
US8044372B2	25-Oct-2011	Laser apparatus, laser irradiation method, semiconductor manufacturing method, semiconductor device, and electronic equipment	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP); MIYAIRI HIDEKAZU (JP); SHIGA AIKO (JP); SHIMOMURA AKIHISA (JP); AKIBA MAI (JP)	US812 55707A	20-Jun-2007
US2004201064A1	14-Oct-2004	Organic thin-film semiconductor element and manufacturing method for the same	HIRAI KATSURA (JP); FUNAYAMA SATOSHI (JP); EGUCHI TOSHIYA (JP); YAMAMOTO NAOTO (JP)	US835 49304A	28-Apr-2004

US8384508B2	26-Feb-2013	Method for making high-performance RF integrated circuits	LIN MOU SHIUNG (TW); LEE JIN YUAN (TW)	US201 113077 009A	31-Mar-2011
US2003037960A1	27-Feb-2003	Layered circuit boards and methods of production thereof	OHR STEPHEN S (US)	US940 27801A	27-Aug-2001
US7857756B2	28-Dec-2010	Architecture tool and methods of use	WARREN WILLIAM L (US); PARKHILL ROBERT L (US); STEWART ROBERT L (US); KACHURIN ANATOLY M (US); TAYLOR ROBERT M (US); CHURCH KENNETH H (US)	US891 51204A	15-Jul-2004
US6743563B2	1-Jun-2004	Photoresist compositions	CAMERON JAMES F (US); ABLAZA SHERI L (US)	US930 88001A	15-Aug-2001
US7173180B2	6-Feb-2007	Coating a silica semiconductive layer with a starting mixture comprising a polysilane or silane compound, silicon particles, and doping; heating and/or light in containing oxygen and/or ozone, or oxygen-free; silicon hydride-free; safe, easy to handle	SHIHO HIROSHI (JP); KATO HITOSHI (JP)	US404 92106A	17-Apr-2006
US6692546B2	17-Feb-2004	Chemical mechanical polishing compositions for metal and associated materials and method of using same	MA YING (US); WOJTCZAK WILLIAM (US); REGULSKI CARY (US); BAUM THOMAS H (US); BERNHARD DAVID D (US); VERMA DEEPAK (US)	US932 41501A	17-Aug-2001
US2006160475A1	20-Jul-2006	Chemical mechanical polishing compositions for metal and associated materials and method of using same	MA YING (US); WOJTCZAK WILLIAM (US); REGULSKI CARY (US); BAUM THOMAS H (US); BERNHARD DAVID D (US); VERMA DEEPAK (US)	US386 30706A	22-Mar-2006
US2008011228A1	17-Jan-2008	Semiconductor device, method for manufacturing the same, and plating solution	INOUE HIROAKI (JP); KIMURA NORIO (JP); WANG XINMING (JP); MATSUMOTO MORIJI (JP); KANAYAMA MAKOTO (JP)	US898 44007A	12-Sep-2007
US2003032292A1	13-Feb-2003	Fabrication method of semiconductor integrated circuit device	NOGUCHI JUNJI (JP)	US198 14302A	19-Jul-2002
US8767782B2	1-Jul-2014	Laser irradiating device, laser irradiating method and manufacturing method of semiconductor device	TANAKA KOICHIRO (JP)	US201 113185 824A	19-Jul-2011
US7284690B2	23-Oct-2007	Article to be processed having ID, and production method thereof	TAKADA TAKESHI (JP); MIMURA TOSHIHIKO (JP); OKADA NAOTO (JP)	US185 78205A	21-Jul-2005
US7205085B2	17-Apr-2007	A radiation sensitive dielectric constant changing composition comprising (A) a decomposable compound, (B) a nondecomposable compound, (C) a radiation sensitive decomposer and (D) a stabilizer. A simple method, has a	NISHIMURA ISAO (JP); BESSHO NOBUO (JP); KUMANO ATSUSHI (JP); YAMADA KENJI (JP)	US381 58903A	1-Apr-2003
US2007111392A1	17-May-2007	Method for thermally releasing chip cut piece from thermal release type pressure sensitive adhesive sheet, electronic component and circuit board	MURATA AKIHISA (JP); OSHIMA TOSHIYUKI (JP); ARIMITSU YUKIO (JP); KIUCHI KAZUYUKI (JP); SATO MASAACKI (JP); KAWANISHI MICHIROU (JP)	US650 44907A	8-Jan-2007
US2021082967A1	18-Mar-2021	Metal Wiring and Method of Manufacturing the Same, and Metal Wiring Substrate and Method of Manufacturing the Same	ONO KOJI (JP); SUZAWA HIDEOMI (JP)	US202 017106 860A	30-Nov-2020

US7485896B2	3-Feb-2009	Light emitting device	YAMAZAKI SHUNPEI (JP); KOYAMA JUN (JP)	US717 14-Mar-2007 67707A
US7060909B2	13-Jun-2006	For the formation of an insulating film comprising a low dielectric constant polymeric material and a sublimating material(a silicone compound) which are dissolved in a solvent	FUKUYAMA SHUN ICHI (JP)	US194 15-Jul-2002 31802A
US7104869B2	12-Sep-2006	Barrier removal at low polish pressure	TSAI STAN (US); MAVLIEV RASHID (US); SUN LIZHONG (US); LIU FENG Q (US); CHEN LIANG YUH (US); MORAD RATSON (US)	US187 27-Jun-2002 85702A
US7196400B2	27-Mar-2007	Semiconductor device with enhanced orientation ratio and method of manufacturing same	YAMAZAKI SHUNPEI (JP); MITSUKI TORU (JP); KASAHARA KENJI (JP)	US835 30-Apr-2004 07704A
US2003062068A1	3-Apr-2003	Method of and system for cleaning a semiconductor wafer simultaneously using electrolytically ionized water and diluted hydrofluoric acid	KO HYUNG HO (KR); LEE KUN TACK (KR); PARK IM SOO (KR); HAN YONG PIL (KR); HA SONG ROK (KR)	US135 1-May-2002 45202A
US6715871B2	6-Apr-2004	Method of forming film pattern, device for forming film pattern, conductive film wiring, electro-optical device, electronic device, and non-contact card medium	HASHIMOTO TAKASHI (JP); FURUSAWA MASAHIRO (JP)	US179 26-Jun-2002 38702A
US2002197418A1	26-Dec-2002	Molecular beam epitaxy effusion cell for use in vacuum thin film deposition and a method therefor	MIZUKAMI TOKIO (JP); SAITO TATEO (JP); KIDO JUNJI (JP)	US161 31-May-2002 24802A
US2003094593A1	22-May-2003	Silica and a silica-based slurry	HELLRING STUART D (US); MCCANN COLIN P (US); BABU SURYADEVARA V (US); LI YUZHUAO (US); NARAYANAN SATISH (US)	US882 14-Jun-2001 54901A
US6656241B1	2-Dec-2003	Chemical-mechanical planarization of semiconductor and other microelectronic substrates; silica has a hydroxyl content of 7 or greater hydroxyls per square nanometer of surface area	HELLRING STUART D (US); MCCANN COLIN P (US); KAHLE CHARLES F (US); LI YUZHUAO (US); KELEHER JASON (US)	US882 14-Jun-2001 54801A
US7960901B2	14-Jun-2011	Piezoelectric device having a ferroelectric film including a ferroelectric material	NATORI EIJI (JP); KIJIMA TAKESHI (JP); FURUYAMA KOICHI (JP); TASAKI YUZO (JP)	US662 26-Apr-2010 61910A
US7240429B2	10-Jul-2007	Manufacturing method for a printed circuit board	SHIRAISHI YOSHIHIKO (JP); KONDO KOJI (JP)	US909 3-Aug-2004 43404A
US7244310B2	17-Jul-2007	Over-clocking in a microdeposition control system to improve resolution	EDWARDS CHARLES O (US); ALBERTALLI DAVID (US); BIELICH HOWARD WALTER (US); MIDDLETON JAMES (US)	US479 14-Jun-2004 31604A
US7270712B2	18-Sep-2007	Industrial microdeposition system for polymer light emitting diode displays, printed circuit boards and the like	EDWARDS CHARLES O (US); ALBERTALLI DAVID (US); BIELICH HOWARD WALTER (US); MIDDLETON JAMES (US); BRUNER SCOTT R (US)	US479 18-Aug-2004 31804A
US2003006477A1	9-Jan-2003	Porous materials	GALLAHGER MICHAEL K (US); GORE ROBERT H (US); LAMOLA ANGELO A (US); YOU YUJIAN (US)	US961 24-Sep-2001 80801A
US6834656B2	28-Dec-2004	During etching, from semiconductors/wafers; dielectrics; integrated circuits	QINGYUAN HAN (US); WALDFRIED CARLO (US); ESCORCIA ORLANDO (US); DAHROOGE GARY (US); BERRY IVAN (US)	US864 23-May-2001 00301A

US6896744B2	24-May-2005	Method for cleaning a surface of a substrate	MORINAGA HITOSHI (JP); MOCHIZUKI HIDEAKI (JP)	US718 24-Nov-2003 57403A
US7629686B2	8-Dec-2009	Bumped die and wire bonded board-on-chip package	KINSMAN LARRY D (US)	US523 20-Sep-2006 91506A
US7045878B2	16-May-2006	Selectively bonded thin film layer and substrate layer for processing of useful devices	FARIS SADEG M (US)	US950 12-Sep-2001 90901A
US6638864B2	28-Oct-2003	Method for removing resist material	TOYODA EIJI (JP); IOKA HARUO (JP)	US146 17-May-2002 89502A
US6861347B2	1-Mar-2005	Method for forming metal wiring layer of semiconductor device	LEE KYOUNG WOO (KR); SHIN HONG JAE (KR); KIM JAE HAK (KR); LEE SOO GEUN (KR)	US114 2-Apr-2002 27402A
US2005150516A1	14-Jul-2005	Semiconductor manufacturing method and apparatus	FUJII TOSHIAKI (JP); YOKOYAMA SHIN (JP)	US486 10-Aug-2004 20704A
US6831313B2	14-Dec-2004	Ferroelectric composite material, method of making same and memory utilizing same	UCHIYAMA KIYOSHI (US); PAZ DE ARAUJO CARLOS A (US); JOSHI VIKRAM (US); SOLAYAPPAN NARAYAN (US); CELINSKA JOLANTA (US); MCMILLAN LARRY D (US)	US332 22-Jul-2003 48103A
US7682221B2	23-Mar-2010	Integrated endpoint detection system with optical and eddy current monitoring	SWEDEK BOGUSLAW A (US); BIRANG MANOOCHER (US); JOHANSSON NILS (US)	US677 21-Feb-2007 45007A
US6746963B2	8-Jun-2004	Method for processing coating film and method for manufacturing semiconductor element with use of the same method	FUJII YASUSHI (JP); IIDA HIROYUKI (JP); SATO ISAO (JP); WAKIYA KAZUMASA (JP); YOKOI SHIGERU (JP)	US136 30-Apr-2002 74402A
US6693049B2	17-Feb-2004	Method for filling fine hole	IGUCHI ETSUKO (JP); TANAKA TAKESHI (JP)	US134 29-Apr-2002 75702A
US9997543B2	12-Jun-2018	Semiconductor device and method of manufacturing the same	ARAO TATSUYA (JP)	US201 12-May-2016 615153 127A
US6696361B2	24-Feb-2004	Post-CMP removal of surface contaminants from silicon wafer	HU SHAO CHUNG (TW); TSAI TENG CHUN (TW); HSU CHIA LIN (TW); WEI YUNG TSUNG (TW)	US854 10-May-2001 00601A
US6851432B2	8-Feb-2005	Aqueous cleaning composition comprising an alkanolamine, a tetraalkylammonium hydroxide, nonmetallic fluoride salt, a corrosion inhibitor, e.g. ascorbic acid or its derivatives alone or in combination, balance water for removal of	NAGHSHINEH SHAHRIAR (US); HASHEMI YASSAMAN (US)	US414 16-Apr-2003 89803A
US7060204B2	13-Jun-2006	Organic compositions	LI BO (US); IWAMOTO NANCY (US); KOROLEV BORIS (US); APEN PAUL G (US); LAU KREISLER (US); SIKONIA JOHN G (US); NAMAN ANANTH (US); GEBREBRHAN AMAUEL (US); SLEIMAN NASSRIN (US); ZHEREBIN RUSLAN (US)	US404 2-Apr-2003 04703A

US6998178B2	14-Feb-2006	Organic compositions	APEN PAUL G (US); BEDWELL WILLIAM B (US); IWAMOTO NANCY (US); KOROLEV BORIS A (US); LAU KREISLER S (US); LI BO (US); NAMAN ANANTH (US)	US404 2-Apr-2003 64403A
US7049005B2	23-May-2006	Organic compositions	APEN PAUL G (US); BEDWELL WILLIAM B (US); IWAMOTO NANCY (US); KOROLEV BORIS A (US); LAU KREISLER S (US); LI BO (US); NAMAN ANANTH (US)	US160 30-May-2002 77302A
US7902038B2	8-Mar-2011	Detachable substrate with controlled mechanical strength and method of producing same	ASPAR BERNARD (FR); MORICEAU HUBERT (FR); RAYSSAC OLIVIER (FR); GHYSELEN BRUNO (FR)	US474 10-Jun-2004 98404A
US7713369B2	11-May-2010	Detachable substrate or detachable structure and method for the production thereof	ASPAR BERNARD (FR); MORICEAU HUBERT (FR); ZUSSY MARC (FR); RAYSSAC OLIVIER (FR)	US468 30-Apr-2004 22304A
US7501653B2	10-Mar-2009	Method of manufacturing semiconductor device having a circuit including thin film transistors	ARAI YASUYUKI (JP); MAEKAWA SHINJI (JP)	US222 12-Sep-2005 76305A
US6670278B2	30-Dec-2003	Method of plasma etching of silicon carbide	LI SI YI (US); ZHU HELEN H (US); SADJADI S M REZA (US); PIRKLE DAVID R (US); BOWERS JAMES (US); GOSS MICHAEL (US)	US820 30-Mar-2001 72601A
US7166535B2	23-Jan-2007	Plasma etching of silicon carbide	LI SI YI (US); SADJADI S M REZA (US); TIETZ JAMES V (US)	US430 6-May-2003 01303A
US7311852B2	25-Dec-2007	Method of plasma etching low-k dielectric materials	LI SI YI (US); ZHU HELEN H (US); SADJADI S M REZA (US); TIETZ JAMES V (US); HELMER BRYAN A (US)	US820 30-Mar-2001 69501A
US2005064248A1	24-Mar-2005	Cerium oxide containing ceramic components and coatings in semiconductor processing equipment and methods of manufacture thereof	O DONNELL ROBERT J (US); DAUGHERTY JOHN E (US)	US983 9-Nov-2004 62204A
US2004081762A1	29-Apr-2004	Method for forming metal pattern	TSUSHIMA HIROSHI (JP)	US469 4-Sep-2003 77803A
US7230336B2	12-Jun-2007	Dual damascene copper interconnect to a damascene tungsten wiring level	ADAMS CHARLOTTE D (US); STAMPER ANTHONY K (US)	US338 7-Jan-2003 62403A
US6863795B2	8-Mar-2005	Plating a wafer by exposing to a first solution of a sulfur depolarizing compound to brighten and level; exposing to a metal compound solution, applying a current; elimination of depletion/monitoring of additives and defects (bumps)	TEERLINCK IVO (BE); MERTENS PAUL (BE)	US105 21-Mar-2002 02702A
US8513112B2	20-Aug-2013	Barrier-metal-free copper damascene technology using enhanced reflow	AHN KIE Y (US); FORBES LEONARD (US)	US201 31-May-2012 213484 824A
US9040843B2	26-May-2015	Multilayer printed wiring board	TOYODA YUKIHIKO (JP); KAWAMURA YOICHIRO (JP); IKEDA TOMOYUKI (JP)	US201 14-Sep-2012 213617 012A
US7087982B2	8-Aug-2006	Nitrogen-containing polymers as porogens in the preparation of highly porous, low dielectric constant materials	HUANG ELBERT EMIN (US); MAGBITANG TEDDIE (US); MILLER ROBERT DENNIS (US); VOLKSEN WILLI (US)	US366 13-Feb-2003 78003A

US6812551B2	2-Nov-2004	Defect-free dielectric coatings and preparation thereof using polymeric nitrogenous porogens	HAWKER CRAIG JON (US); HEDRICK JAMES LUPTON (US); HUANG ELBERT EMIN (US); LEE VICTOR YEE WAY (US); MAGBITANG TEDDIE (US); MECERREYES DAVID (US); MILLER ROBERT DENNIS (US); VOLKSEN WILLI (US)	US371 21-Feb-2003 27003A
US6713587B2	30-Mar-2004	Electrodepositable dielectric coating compositions and methods related thereto	MCCOLLUM GREGORY J (US); MORIARITY THOMAS C (US); OLSON KEVIN C (US); SANDALA MICHAEL G (US); WANG ALAN E (US); WILSON CRAIG A (US); ZAWACKY STEVEN R (US)	US184 27-Jun-2002 19502A
US2004069636A1	15-Apr-2004	Metal pattern formation	MEYER HEINRICH (DE); GRIESER UDO (DE)	US469 27-Aug-2003 37403A
US7618904B2	17-Nov-2009	Method of manufacturing a semiconductor device	YAMAZAKI SHUNPEI (JP); MITSUKI TORU (JP); TAKANO TAMAE (JP)	US498 3-Aug-2006 06406A
US2008213579A1	4-Sep-2008	Organic light emitting device having a protective barrier	LEE CHUNG J (US); CHEN CHIEH (US); KUMAR ATUL (US)	US759 14-Mar-2008 9508A
US2012171795A1	5-Jul-2012	METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE	YAMAZAKI SHUNPEI (JP); MITSUKI TORU (JP); TAKANO TAMAE (JP)	US201 15-Mar-2012 213421 171A
US7001825B2	21-Feb-2006	Semiconductor structures having multiple conductive layers in an opening, and methods for fabricating same	HALAHAN PATRICK B (US); SINIAGUINE OLEG (US)	US144 16-Dec-2004 6404A
US2002160600A1	31-Oct-2002	Method of fabricating low-dielectric constant interlevel dielectric films for BEOL interconnects with enhanced adhesion and low-defect density	ECKERT ANDREW ROBERT (US); HAY JOHN C (US); HEDRICK JEFFREY CURTIS (US); LEE KANG WOOK (US); LINIGER ERIC GERHARD (US); SIMONYI EVA ERIKA (US)	US789 21-Feb-2001 42201A
US6786945B2	7-Sep-2004	Polishing compound and method for polishing substrate	MACHII YOUICHI (JP); KOYAMA NAOYUKI (JP); NISHIYAMA MASAYA (JP); YOSHIDA MASATO (JP)	US467 13-Aug-2003 86403A
US8308967B2	13-Nov-2012	Wet etched insulator and electronic circuit component	SAKAYORI KATSUYA (JP); MOMOSE TERUTOSHI (JP); KAWANO SHIGEKI (JP); TOGASHI TOMOKO (JP); AMASAKI HIROKO (JP); SAKIHAMA NOBUHIRO (JP); YAMAZAKI TSUYOSHI (JP); UCHIYAMA MICHIAKI (JP); YAGI HIROSHI (JP)	US201 13-Jan-2011 113006 135A
US6602351B2	5-Aug-2003	Remove water, entrained solvents and solid particles using high density carbon dioxide	DEYOUNG JAMES P (US); MCCLAIN JAMES B (US); GROSS STEPHEN M (US)	US951 13-Sep-2001 24701A
US6641678B2	4-Nov-2003	Methods for cleaning microelectronic structures with aqueous carbon dioxide systems	DEYOUNG JAMES P (US); MCCLAIN JAMES B (US); GROSS STEPHEN M (US); DESIMONE JOSEPH M (US)	US951 13-Sep-2001 24901A
US6905555B2	14-Jun-2005	Providing enclosed pressure vessel containing supercritical carbon dioxide; adding a second fluid to vessel, forming an interface between supercritical fluid and second fluid; displacing supercritical fluid from vessel with pressure	DEYOUNG JAMES P (US); MCCLAIN JAMES B (US); GROSS STEPHEN M (US); WAGNER MARK I (US)	US448 30-May-2003 47403A
US7592035B2	22-Sep-2009	Method of coating microelectronic substrates	DEYOUNG JAMES P (US); MCCLAIN JAMES B (US); GROSS STEPHEN M (US); TAYLOR DOUG (US); WAGNER MARK I (US); BRAINARD DAVID (US)	US261 28-Oct-2005 29905A

US2005056941A1	17-Mar-2005	Method of fabricating a semiconductor device	VANHAELEMEERSCH SERGE (BE); MAEX KAREN (BE)	US962 8-Oct-2004 33904A
US6612917B2	2-Sep-2003	Abrasive article suitable for modifying a semiconductor wafer	BRUXVOORT WESLEY J (US)	US778 7-Feb-2001 53001A
US6543674B2	8-Apr-2003	Multilayer interconnection and method	LEE MICHAEL G (US); WONG CONNIE M (US); WANG WEN CHOU VINCENT (US)	US778 6-Feb-2001 65801A
US7224064B2	29-May-2007	Semiconductor device having conductive interconnections and porous and nonporous insulating portions	YOSHIE TORU (JP)	US420 24-Jan-2005 3305A
US7459354B2	2-Dec-2008	Method for manufacturing a semiconductor device including top gate thin film transistor and method for manufacturing an active matrix device including top gate thin film transistor	YAMAZAKI SHUNPEI (JP); OHNUMA HIDETO (JP); TAKANO TAMAE (JP); MITSUKI TORU (JP)	US896 23-Jul-2004 90604A
US6921782B2	26-Jul-2005	Metal chelate, thermosetting resin and a silane coupling agent having alkoxy groups that hydrolyze and react with the metal chelate to cause the thermosetting resin to undergo cationic polymerization; lower temperature curing	MATSUSHIMA TAKAYUKI (JP)	US539 24-Jan-2002 5602A
US6402592B1	11-Jun-2002	Electrochemical methods for polishing copper films on semiconductor substrates	ZHU MEI (US); IVANOV IGOR (US); TING CHIU H (US)	US761 17-Jan-2001 32701A
US2007278654A1	6-Dec-2007	Method of making an electronic package	JIMAREZ LISA J (US); JIMAREZ MIGUEL A (US); MARKOVICH VOYA R (US); MILKOVICH CYNTHIA S (US); PERRY CHARLES H (US); PETERSON BRENDA L (US)	US778 16-Jul-2007 15507A
US2002125461A1	12-Sep-2002	Ammonium oxalate-containing polishing system and method	CHOU HOMER (US); HAWKINS JOSEPH D (US); ZHOU RENJIE (US)	US435 10-Jan-2002 3402A
US6790515B2	14-Sep-2004	Greensheet carriers and processing thereof	KNICKERBOCKER JOHN U (US); NATARAJAN GOVINDARAJAN (US)	US411 11-Apr-2003 90603A
US6998579B2	14-Feb-2006	Chamber for uniform substrate heating	INAGAWA MAKOTO (US); HOSOKAWA AKIHIRO (US)	US736 15-Dec-2003 20203A
US7255898B2	14-Aug-2007	Zirconia toughened ceramic components and coatings in semiconductor processing equipment and method of manufacture thereof	O DONNELL ROBERT J (US); CHANG CHRISTOPHER C (US); DAUGHERTY JOHN E (US)	US442 22-May-2003 98003A
US6790242B2	14-Sep-2004	DEPOSITING FIRST INTERMEDIATE COATING ON SURFACE OF COMPONENT OF SEMICONDUCTOR PROCESSING EQUIPMENT; DEPOSITING SECOND INTERMEDIATE COATING ON FIRST INTERMEDIATE LAYER; DEPOSITING FULLERENE CONTAINING COATING TO FORM EROSION RESISTANT SURFACE	O DONNELL ROBERT J (US); CHANG CHRISTOPHER C (US); DAUGHERTY JOHN E (US)	US749 29-Dec-2000 92300A
US8486841B2	16-Jul-2013	Corrosion resistant component of semiconductor processing equipment and method of manufacture thereof	O DONNELL ROBERT J (US); CHANG CHRISTOPHER C (US); DAUGHERTY JOHN E (US)	US559 14-Sep-2009 17709A
US7022948B2	4-Apr-2006	Chamber for uniform substrate heating	SHANG QUANYUAN (US); KARDOKUS JANINE (US); HOSOKAWA AKIHIRO (US)	US885 6-Jul-2004 46804A

US6927002B2	9-Aug-2005	Capable of developing a small quantity of and various kinds of semiconductor devices in short time	HATTORI TAKASHI (JP); GOTOH YASUKO (JP); SATOH HIDETOSHI (JP); TANAKA TOSHIHIKO (JP); SHIRAIISHI HIROSHI (JP)	US269 7301A	27-Dec-2001
US7872246B2	18-Jan-2011	Laser annealing method and semiconductor device fabricating method	TANAKA KOICHIRO (JP)	US219 64908A	25-Jul-2008
US2005042860A1	24-Feb-2005	Method for eliminating reaction between photoresist and OSG	DANIELS BRIAN J (US); DUNNE JUDE A (US); KENNEDY JOSEPH T (US)	US949 14204A	24-Sep-2004
US7722962B2	25-May-2010	Solder foil, semiconductor device and electronic device	SOGA TASAO (JP); HATA HANAE (JP); ISHIDA TOSHIHARU (JP); NAKATSUKA TETSUYA (JP); OKAMOTO MASAhide (JP); MIURA KAZUMA (JP)	US451 61004A	31-Mar-2004
US2002110956A1	15-Aug-2002	Chip lead frames	KUMAMOTO TAKASHI (JP); ICHIKAWA KINYA (JP)	US878 12301A	8-Jun-2001
US8779030B2	15-Jul-2014	Method for patterning metal using nanoparticle containing precursors	PERRY JOSEPH W (US); MARDER SETH R (US); STELLACCI FRANCESCO (US)	US736 69507A	18-Apr-2007
US6576562B2	10-Jun-2003	Manufacturing method of semiconductor device using mask pattern having high etching resistance	OHUCHI JUNKO (JP); SATO YASUHIKO (JP); SHIOBARA EISHI (JP); HAYASHI HISATAKA (JP); OHIWA TOKUHISA (JP); ONISHI YASUNOBU (JP)	US144 5901A	14-Dec-2001
US6692903B2	17-Feb-2004	ETCHING WITH A ENERGIZED PROCESS GAS, AND BEFORE, DURING, OR AFTER EXPOSING TO AN ENERGIZED CLEANING GAS, EXPOSING SUBSTRATE TO ENERGIZED TREATING GAS OF A HALOGEN SPECIES AND A HYDROGEN SPECIES TO ENHANCE CLEANING	CHEN HAOJIANG (US); PAPANU JAMES S (US); KAWAGUCHI MARK (US); HERCHEN HARALD (US); HWANG JENG H (US); JIN GUANGXIANG (US); PALAGASHVILI DAVID (US)	US737 37300A	13-Dec-2000
US2007087492A1	19-Apr-2007	METHOD FOR FORMING SEMICONDUCTOR FILM, METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND ELECTROOPTIC DEVICE, APPARATUS FOR PERFORMING THE SAME, AND SEMICONDUCTOR DEVICE AND ELECTROOPTIC DEVICE	YAMANAKA HIDEO (JP)	US556 30606A	3-Nov-2006
US6794307B2	21-Sep-2004	Method for cleaning residual debris from semiconductor surfaces	CHEN GARY (US); LI LI (US)	US427 97903A	2-May-2003
US7806983B2	5-Oct-2010	Substrate temperature control in an ALD reactor	CHIANG TONY P (US); LEESER KARL F (US); BROWN JEFFREY A (US); BABCOKE JASON E (US)	US921 60404A	18-Aug-2004
US7318869B2	15-Jan-2008	Variable gas conductance control for a process chamber	CHIANG TONY P (US); LEESER KARL F (US); BROWN JEFFREY A (US); BABCOKE JASON E (US)	US930 53604A	30-Aug-2004
US6756236B2	29-Jun-2004	Method of producing a ferroelectric memory and a memory device	FORD WILLIAM (DE); WESSELS JURINA (DE); VOSSMEYER TOBIAS (DE); TOMITA HIDEKI (JP)	US634 701A	4-Dec-2001
US2004187451A1	30-Sep-2004	Substrate transport apparatus, pod and method	SUZUKI YOKO (JP); TANAKA AKIRA (JP); KISHI TAKASHI (JP)	US766 56504A	29-Jan-2004

US2002123240A1	5-Sep-2002	Electronic device manufacture	GALLAGHER MICHAEL K (US); YOU YUJIAN (US); ROCHE MAUREEN (US)	US997 69701A	30-Nov-2001
US2003121906A1	3-Jul-2003	Resistive heaters and uses thereof	ABBOTT RICHARD C (US); MAGNANT GARY P (US); GLENN WILLIAM A (US)	US219 58902A	15-Aug-2002
US7217605B2	15-May-2007	Laser irradiation method and method of manufacturing a semiconductor device	KAWASAKI RITSUKO (JP); NAKAJIMA SETSUO (JP)	US988 38901A	19-Nov-2001
US7762870B2	27-Jul-2010	Polishing pad and cushion layer for polishing pad	ONO KOICHI (JP); SHIMOMURA TETSUO (JP); NAKAMORI MASAHICO (JP); YAMADA TAKATOSHI (JP); KOMAI SHIGERU (JP); TSUTSUMI MASAYUKI (JP)	US366 98106A	2-Mar-2006
US7176420B2	13-Feb-2007	Resistive heaters and uses thereof	ABBOTT RICHARD C (US); MAGNANT GARY P (US); GLENN WILLIAM A (US)	US152 86205A	15-Jun-2005
US6812127B2	2-Nov-2004	Method of forming semiconductor device including silicon oxide with fluorine, embedded wiring layer, via holes, and wiring grooves	OSHIMA TAKAYUKI (JP); MIYAZAKI HIROSHI (JP); AOKI HIDEO (JP); OHMORI KAZUTOSHI (JP)	US987 91401A	16-Nov-2001
US6508919B1	21-Jan-2003	Optimized liners for dual damascene metal wiring	LICATA THOMAS J (US); HILLMAN JOSEPH T (US)	US723 87400A	28-Nov-2000
US7569177B2	4-Aug-2009	Method of producing ceramic multilayer substrates, and green composite laminate	SAITOH YOSHIFUMI (JP); KAWAKAMI HIROMICHI (JP)	US274 50105A	16-Nov-2005
US6844270B2	18-Jan-2005	Polymers and photoresist compositions for short wavelength imaging	ZAMPINI ANTHONY (US); CHO SUNGSEO (US)	US994 13001A	26-Nov-2001
US6806210B2	19-Oct-2004	MIXTURES OF GROUP V COMPOUNDS AND SOLVENTS, USED TO FORM DIELECTRIC LAYERS ON SILICON SUBSTRATES; HEAT TREATMENT	SHIHO HIROSHI (JP); KATO HITOSHI (JP); HASHIMOTO SACHIKO (JP); YONEKURA ISAMU (JP); MATSUKI YASUO (JP)	US181 77802A	22-Jul-2002
US6905800B1	14-Jun-2005	Masking material overcoated with photoresist; removal using stripping gas	YUEN STEPHEN (US); JAIN MOHIT (US); LILL THORSTEN B (US)	US718 31900A	21-Nov-2000
US2002106587A1	8-Aug-2002	Two mask via pattern to improve pattern definition	LUKANC TODD (US); LYONS CHRISTOPHER F (US)	US790 53701A	23-Feb-2001
US2006160351A1	20-Jul-2006	Metal interconnect layer of semiconductor device and method for forming a metal interconnect layer	AHN JONG HYON (KR)	US385 40006A	21-Mar-2006
US7144761B2	5-Dec-2006	Semiconductor device and method for fabricating the same	NAKAGWA HIDEO (JP); TAMAOKA EIJI (JP); KUBOTA MASAFUMI (JP); UEDA TETSUYA (JP)	US958 28204A	6-Oct-2004
US6770573B2	3-Aug-2004	Method for fabricating an ultralow dielectric constant material	GRILL ALFRED (US); PATEL VISHNUBHAI V (US)	US340 00003A	10-Jan-2003

US2006276113A1	7-Dec-2006	Polishing cloth, polishing apparatus and method of manufacturing semiconductor devices	HIRABAYASHI HIDEAKI (JP); SAITO AKIKO (JP); SAKURAI NAOAKI (JP); OSHIBE YOSHIHIRO (JP); ISHIDOYA MASAHIRO (JP)	US505 17-Aug-2006 46406A
US6894375B2	17-May-2005	Semiconductor device, semiconductor module and hard disk	SAKAMOTO NORIAKI (JP); KOBAYASHI YOSHIYUKI (JP); SAKAMOTO JUNJI (JP); OKADA YUKIO (JP); IGARASHI YUSUKE (JP); MAEHARA EIJU (JP); TAKAHASHI KOUJI (JP)	US652 29-Aug-2003 18403A
US6967401B2	22-Nov-2005	Semiconductor device, semiconductor module and hard disk	SAKAMOTO NORIAKI (JP); KOBAYASHI YOSHIYUKI (JP); SAKAMOTO JUNJI (JP); OKADA YUKIO (JP); IGARASHI YUSUKE (JP); MAEHARA EIJU (JP); TAKAHASHI KOUJI (JP)	US810 16-Mar-2001 14101A
US6933604B2	23-Aug-2005	Semiconductor device, semiconductor module and hard disk	SAKAMOTO NORIAKI (JP); KOBAYASHI YOSHIYUKI (JP); SAKAMOTO JUNJI (JP); OKADA YUKIO (JP); IGARASHI YUSUKE (JP); MAEHARA EIJU (JP); TAKAHASHI KOUJI (JP)	US810 16-Mar-2001 11701A
US6635956B2	21-Oct-2003	Semiconductor device, semiconductor module and hard disk	SAKAMOTO NORIAKI (JP); KOBAYASHI YOSHIYUKI (JP); SAKAMOTO JUNJI (JP); OKADA YUKIO (JP); IGARASHI YUSUKE (JP); MAEHARA EIJU (JP); TAKAHASHI KOUJI (JP)	US238 9-Sep-2002 43302A
US7187015B2	6-Mar-2007	High-density metal capacitor using dual-damascene copper interconnect	TSAU LIMING (US)	US858 22-Mar-2005 6605A
US7084063B2	1-Aug-2006	Fabrication method of semiconductor integrated circuit device	NOGUCHI JUNJI (JP); ASAKA SHOJI (JP); KONISHI NOBUHIRO (JP); OHASHI NAOHUMI (JP); MARUYAMA HIROYUKI (JP)	US742 23-Dec-2003 93203A
US2002038905A1	4-Apr-2002	Semiconductor device provided in thin package and method for manufacturing the same	SUGIZAKI YOSHIAKI (JP)	US961 25-Sep-2001 30401A
US2003066549A1	10-Apr-2003	Substrate processing method, and apparatus therefor	NODA SEIJI (JP); HORIBE HIDEO (JP); MIYAMOTO MAKOTO (JP); OYA IZUMI (JP); KUZUMOTO MASAKI (JP)	US111 1-May-2002 91302A
US6852648B2	8-Feb-2005	Semiconductor device having a low dielectric constant dielectric material and process for its manufacture	NALAMASU OMKARAM (US); PAI CHIEN SHING (US); REICHMANIS ELSA (US); YANG SHU (US)	US435 9-May-2003 56103A
US7294453B2	13-Nov-2007	Electronic device manufacture	GALLAGHER MICHAEL K (US); YOU YUJIAN (US)	US782 19-Feb-2004 65704A
US6967407B2	22-Nov-2005	Semiconductor device and method of manufacturing the semiconductor device	OTANI MIHARU (JP); TANAKA JUN (JP); HOTTA KATSUHIKO (JP); SUZUKI YASUMICHI (JP); INOUE TAKASHI (JP)	US333 27-May-2003 83803A
US6787472B2	7-Sep-2004	Utilization of disappearing silicon hard mask for fabrication of semiconductor structures	GIVENS JOHN H (US); JOST MARK E (US)	US352 27-Jan-2003 46403A

US7145412B2	5-Dec-2006	Electronic and optical devices and methods of forming these devices	HUNT ANDREW T (US); ALLEN MARK G (US); KIESLING DAVID (US); SCHWERZEL ROBERT E (US); JIANG YONGDONG (US); GLADDEN FE ALMA (US); WEGMAN JOHN (US); ZHAO ZHIYONG (US); VINSON MATTHEW SCOTT (US); MCENTYRE J ERIC (US); FLANAGAN SCOTT (US); POLLEY TODD (US); KENNEY J STEVENSON (US)	US362 24-Jul-2003 43503A
US6982484B2	3-Jan-2006	Semiconductor joining substrate utilizing a tape with adhesive and copper-clad laminate sheet	OGURA MIKIHIRO (JP); KIGOSHI SYOUJI (JP); TOKUNAGA MASAMI (JP); TSUTSUMI YASUAKI (JP); KAMEI RYUICHI (JP); SHIMIZU KEN (JP)	US111 23-Apr-2002 30202A
US2007281156A1	6-Dec-2007	Nanoscale wires and related devices	LIEBER CHARLES M (US); DUAN XIANGFENG (US); CUI YI (US); HUANG YU (US); GUDIENSEN MARK (US); LAUHON LINCOLN J (US); WANG JIANFANG (US); PARK HONGKUN (US); WEI QINGQIAO (US); LIANG WENJIE (US); SMITH DAVID C (GB); WANG DELI (US); ZHONG ZHAOHUI (US)	US386 21-Mar-2006 08006A
US2006003497A1	5-Jan-2006	Semiconductor device packages including hermetic packaging elements for at least partially encapsulating conductive elements and other package elements for protecting the portions of semiconductor devices not covered by the hermetic package elements, and packaging methods	FARNWORTH WARREN M (US)	US214 30-Aug-2005 69505A
US7078788B2	18-Jul-2006	Microelectronic substrates with integrated devices	VU QUAT T (US); LI JIAN (US); TOWLE STEVEN (US)	US964 13-Oct-2004 23804A
US2020251492A1	6-Aug-2020	DENSE ARRAYS AND CHARGE STORAGE DEVICES	LEE THOMAS H (US)	US202 17-Apr-2020 016851 282A
US6602436B2	5-Aug-2003	Controlling a ratio of platen speed to carrier speed (PS to CS) within a specific range	MANDIGO GLENN C (US); BARKER II ROSS E (US); LACK CRAIG D (US); SULLIVAN IAN G (US); GOLDBERG WENDY B (US)	US925 9-Aug-2001 20901A
US6348142B1	19-Feb-2002	Electroplating multi-trace circuit board substrates using single tie bar	VIVARES VALERIE (US); FONTECHA EDWIN R (US)	US633 7-Aug-2000 62000A
US6455479B1	24-Sep-2002	Stripping composition	SAHBARI JAVAD J (US)	US785 16-Feb-2001 77101A
US2008119029A1	22-May-2008	WAFER SCALE THIN FILM PACKAGE	CALETKA DAVID VINCENT (US); PARK SEUNGBAE (US); SATHE SANJEEV BALWANT (US)	US156 17-Jan-2008 0408A
US6853087B2	8-Feb-2005	Component and antennae assembly in radio frequency identification devices	NEUHAUS HERBERT J (US); WERNLE MICHAEL E (DE); BLUM FREDERICK A (US); KOBER MICHAEL (DE)	US957 19-Sep-2001 40101A
US2002027294A1	7-Mar-2002	Electrical component assembly and method of fabrication	NEUHAUS HERBERT J (US); KENNEY MICHAEL J (US); WERNLE MICHAEL E (DE)	US812 19-Mar-2001 14001A
US7034389B2	25-Apr-2006	Flip chip package, circuit board thereof and packaging method thereof	MORIMOTO KENJI (JP); OCHI HIROSHI (JP)	US839 6-May-2004 15704A

US6586791B1	1-Jul-2003	Transistor insulator layer incorporating superfine ceramic particles	LEE TZU CHEN (US); O BRYAN NELSON B (US)	US619 30200A	19-Jul-2000
US7428907B2	30-Sep-2008	Substrate processing apparatus	OKUDA SEIICHIRO (JP); SUGIMOTO HIROAKI (JP); KURODA TAKUYA (JP); SATO MASANOBU (JP); HIRAE SADA O (JP); YASUDA SHUICHI (JP); MORINISHI KENYA (JP); IMAI MASAYOSHI (JP)	US838 92604A	5-May-2004
US8603899B2	10-Dec-2013	Method of manufacturing a semiconductor device	ASAMI TAKETOMI (JP); ICHIJO MITSUHIRO (JP); TORIUMI SATOSHI (JP)	US201 213660 449A	25-Oct-2012
US9117860B2	25-Aug-2015	Controlled ambient system for interface engineering	BOYD JOHN (US); DORDI YEZDI (US); ARUNAGIRI TIRUCHIRAPALLI (US); MOORING BENJAMIN W (US); PARKS JOHN (US); THIE WILLIAM (US); REDEKER FRITZ C (US); HOWALD ARTHUR M (US); SCHOEPP ALAN (US); HEMKER DAVID (US); WOODS CARL (US); YOON HYUNGSUK ALEXANDER (US); OWCZARZ ALEKSANDER (US)	US639 75206A	15-Dec-2006
US2009304914A1	10-Dec-2009	Self assembled monolayer for improving adhesion between copper and barrier layer	NALLA PRAVEEN (US); THIE WILLIAM (US); BOYD JOHN (US); ARUNAGIRI TIRUCHIRAPALLI (US); YOON HYUNGSUK ALEXANDER (US); REDEKER FRITZ C (US); DORDI YEZDI (US)	US639 01206A	13-Dec-2006
US6734029B2	11-May-2004	Method for forming conductive film pattern, and electro-optical device and electronic apparatus	FURUSAWA MASAHIRO (JP)	US896 93001A	29-Jun-2001
US6528145B1	4-Mar-2003	Polymer and ceramic composite electronic substrates	BERGER DANIEL GEORGE (US); FAROOQ SHAJI (US); HERRON LESTER WYNN (US); HUMENIK JAMES N (US); KNICKERBOCKER JOHN ULRICH (US); PASCO ROBERT WILLIAM (US); PERRY CHARLES H (US); SACHDEV KRISHNA G (US)	US606 35900A	29-Jun-2000
US6337277B1	8-Jan-2002	Clean chemistry low-k organic polymer etch	CHOU WEN BEN (US); DHINDSA RAJINDER (US); CHEN CHING HWA (US)	US606 84200A	28-Jun-2000
US7189663B2	13-Mar-2007	Organic semiconductor device having an active dielectric layer comprising silsesquioxanes	BAO ZHENAN (US); KUCK VALERIE JEANNE (US); PACZKOWSKI MARK ANTHONY (US)	US422 4005A	25-Jan-2005
US6511908B2	28-Jan-2003	Method of manufacturing a dual damascene structure using boron nitride as trench etching stop film	KINOSHITA TAKAO (JP); ORITA KUNIHIKO (JP)	US886 46701A	22-Jun-2001
US8440388B2	14-May-2013	Method to restore hydrophobicity in dielectric films and materials	HACKER NIGEL P (US); THOMAS MICHAEL (US); DRAGE JAMES S (US)	US287 99205A	28-Nov-2005
US6696759B2	24-Feb-2004	TOGETHER, THE DIAMOND OR DIAMOND-LIKE CARBON POLISH-STOP LAYER AND THE PROTECTIVE LAYER ARE USED AS A HARD-MASK FOR PATTERNING THE TRENCHES THAT WILL BECOME THE METAL FEATURES	CLEVENGER LAWRENCE A (US); HSU LOUIS L C (US); STEPHENS JEREMY K (US); WISE MICHAEL (US)	US211 2301A	30-Oct-2001
US7074640B2	11-Jul-2006	Method of making barrier layers	MALONEY DAVID J (US); LEE WAI M (US); ROMAN JR PAUL J (US); FURY MICHAEL A (US)	US442 86003A	20-May-2003

US6566276B2	20-May-2003	Method of making electronic materials	MALONEY DAVID J (US); LEE WAI M (US); ROMAN JR PAUL J (US); FURY MICHAEL A (US); HILL ROSS H (CA)	US875 11501A	6-Jun-2001
US6645837B2	11-Nov-2003	Method of manufacturing semiconductor device	GOSAIN DHARAM PAL (JP); NOMOTO KAZUMASA (JP); MACHIDA AKIO (JP); NAKAGOE MIYAKO (JP); USUI SETSUO (JP)	US871 03301A	31-May-2001
US2005170760A1	4-Aug-2005	Polishing apparatus	HOMMA YOSHIO (JP); KONDO SEIICHI (JP); SAKUMA NORIYUKI (JP); YAMADA YOUHEI (JP); KIMURA TAKESHI (JP); NEZU HIROKI (JP)	US973 0305A	4-Apr-2005
US6828247B2	7-Dec-2004	Method for etching organic film, method for fabricating semiconductor device and pattern formation method	NAKAGAWA HIDEO (JP); HAYASHI TOSHIO (JP); MORIKAWA YASUHIRO (JP)	US214 75402A	9-Aug-2002
US6518191B2	11-Feb-2003	Using plasma generated from a gas including an amine such as methylamine.	NAKAGAWA HIDEO (JP)	US798 91301A	6-Mar-2001
US6551175B2	22-Apr-2003	Polishing composition	KOICHI NAITO (JP); SHIGEO FUJII (JP)	US852 76401A	11-May-2001
US8470647B2	25-Jun-2013	Semiconductor device and manufacturing method thereof	SUZAWA HIDEOMI (JP); ONO KOJI (JP); TAKAYAMA TORU (JP); ARAO TATSUYA (JP); YAMAZAKI SHUNPEI (JP)	US620 57607A	5-Jan-2007
US7169689B2	30-Jan-2007	Method of manufacturing a semiconductor device	YAMAZAKI SHUNPEI (JP); ASAMI TAKETOMI (JP); ICHIJO MITSUHIRO (JP); MITSUKI TORU (JP); KANAKUBO YOKO (JP)	US662 5305A	28-Feb-2005
US2003077918A1	24-Apr-2003	Simplified method to produce nanoporous silicon-based films	WU HUI JUNG (US); DRAGE JAMES S (US); BRUNGARDT LISA (US); RAMOS TERESA A (US); SMITH DOUGLAS M (US)	US215 53102A	9-Aug-2002
US7163892B2	16-Jan-2007	Process for producing integrated circuit, and substrate with integrated circuit	TONAI ATSUSHI (JP); HIRAI TOSHIHARU (JP); KOYANAGI TSUGUO (JP); MATSUDA MASAYUKI (JP); KOMATSU MICHIO (JP)	US275 08702A	1-Nov-2002
US6458718B1	1-Oct-2002	Fluorine-containing materials and processes	TODD MICHAEL A (US)	US841 52501A	24-Apr-2001
US8951902B2	10-Feb-2015	Methods of removing contaminant impurities during the manufacture of a thin film transistor by applying water in which ozone is dissolved	ASAMI TAKETOMI (JP); ICHIJO MITSUHIRO (JP); TORIUMI SATOSHI (JP); OHTSUKI TAKASHI (JP); YAMAZAKI SHUNPEI (JP)	US201 213362 049A	31-Jan-2012
US7951654B2	31-May-2011	Method of fabricating semiconductor device	TANAKA KOICHIRO (JP)	US704 61710A	12-Feb-2010
US6720249B1	13-Apr-2004	Protective hardmask for producing interconnect structures	DALTON TIMOTHY J (US); JAHNES CHRISTOPHER V (US); LIU JOYCE C (US); PURUSHOTHAMAN SAMPATH (US)	US550 94300A	17-Apr-2000
US2001037821A1	8-Nov-2001	Integrated chemical-mechanical polishing	STALEY BRADLEY J (US); BOGUSH GREGORY H (US); CHAMBERLAIN JEFFREY P (US); FEENEY PAUL M (US); WALTERS ALICIA F (US); GRUMBINE STEVEN K (US); MUELLER BRIAN L (US); SCHROEDER DAVID J (US)	US829 10101A	9-Apr-2001

US6451697B1	17-Sep-2002	Method for abrasive-free metal CMP in passivation domain	SUN LIZHONG (US); LI SHIJIAN (US); REDEKER FRITZ (US)	US544 28100A	6-Apr-2000
US2008132059A1	5-Jun-2008	Semiconductor integrated circuit device and fabrication method for semiconductor integrated circuit device	NOGUCHI JUNJI (JP); OHASHI NAOHUMI (JP); SAITO TATSUYUKI (JP)	US790 76007A	27-Apr-2007
US6787191B2	7-Sep-2004	Coating composition for the production of insulating thin films	HANAHATA HIROYUKI (JP); ARAKI TORU (JP); NAKAMURA MIKIHICO (JP)	US240 78902A	4-Oct-2002
US7070670B2	4-Jul-2006	Epoxy resin; bonding semiconductor chips	TOMIYAMA TAKEO (JP); INADA TEIICHI (JP); YASUDA MASAOKI (JP); HATAKEYAMA KEIICHI (JP); HASEGAWA YUUJI (JP); NISHIYAMA MASAYA (JP); MATSUZAKI TAKAYUKI (JP); URUNO MICHIO (JP); SUZUKI MASAO (JP); IWAKURA TETSUROU (JP); SHIMADA YASUSHI (JP); TANAKA YUUKO (JP); KURIYA HIROYUKI (JP); SUMIYA KEIJI (JP)	US240 26503A	21-Feb-2003
US6554912B2	29-Apr-2003	Polymer remover	SAHBARI JAVAD J (US)	US921 05201A	2-Aug-2001
US2001036721A1	1-Nov-2001	Process for metallizing at least one insulating layer of a component	DALLNER CLAUS (DE); LOWACK KLAUS (DE); SCHMID GUNTER (DE); SEZI RECAI (DE)	US817 96601A	27-Mar-2001
US6871773B2	29-Mar-2005	Composite metallic ultrafine particles and process for producing the same	FUKUNAGA AKIRA (JP); NAGASAWA HIROSHI (JP); KAGOSHIMA KAORI (JP); EMOTO MAKIKO (JP)	US804 08504A	19-Mar-2004
US7572669B2	11-Aug-2009	Nanocylinder arrays	TUOMINEN MARK (US); SCHOTTER JOERG (DE); THURN ALBRECHT THOMAS (DE); RUSSELL THOMAS P (US)	US708 73507A	21-Feb-2007
US7384832B2	10-Jun-2008	Method of manufacturing a semiconductor device	TANAKA KOICHIRO (JP)	US800 49007A	4-May-2007
US2001023082A1	20-Sep-2001	Grind and single wafer etch process to remove metallic contamination in silicon wafers	VEPA KRISHNA (US); DOBSON DUNCAN (US)	US808 73601A	15-Mar-2001
US2012156372A1	21-Jun-2012	Nozzle-based, Vapor-phase, Plume Delivery Structure for Use in Production of Thin-film Deposition Layer	BIRKMIRE ROBERT W (US); HANKET GREGORY M (US); RUSSELL T W FRASER (US); ESER ERTEN (US)	US201 113006 086A	13-Jan-2011
US6503570B2	7-Jan-2003	Cyclosilane compound, and solution composition and process for forming a silicon film	MATSUKI YASUO (JP); EBATA SATOSHI (JP)	US802 91801A	12-Mar-2001
US7638377B2	29-Dec-2009	Semiconductor device and manufacturing method thereof	TANAKA KOICHIRO (JP); OHNUMA HIDETO (JP); KOKUBO CHIHIO (JP)	US710 65807A	23-Feb-2007
US2006197231A1	7-Sep-2006	Backend metallization method and device obtained therefrom	CHO CHIH CHEN (US)	US403 92306A	14-Apr-2006

US7273802B2	25-Sep-2007	Methods for consolidating previously unconsolidated conductive material to form conductive structures or contact pads or secure conductive structures to contact pads	WILLIAMS VERNON M (US)	US925 24-Aug-2004 57204A
US7582564B2	1-Sep-2009	Process and composition for conductive material removal by electrochemical mechanical polishing	WANG ZHIHONG (US); WANG YOU (US); MAO DAXIN (US); JIA RENHE (US); TSAI STAN D (US); HU YONGQI (US); TIAN YUAN A (US); CHEN LIANG YUH (US)	US123 5-May-2005 27405A
US2009120803A9	14-May-2009	Pad for electrochemical processing	BUTTERFIELD PAUL (US); CHEN LIANG YUH (US); HU YONGQI (US); MANENS ANTOINE (US); MAVLIEV RASHID (US); TSAI STAN (US)	US345 31-Jan-2006 63406A
US2007004110A1	4-Jan-2007	Beam homogenizer, laser irradiation apparatus, semiconductor device, and method of fabricating the semiconductor device	TANAKA KOICHIRO (JP)	US518 11-Sep-2006 24006A
US6890403B2	10-May-2005	Apparatus and process for controlling the temperature of a substrate in a plasma reactor	CHEUNG JEFF S (US); DEMOS ALEXANDROS T (US)	US189 2-Jul-2002 08002A
US7635866B2	22-Dec-2009	Semiconductor device and its manufacturing method	NAKAJIMA SETSUO (JP); KAWASAKI RITSUKO (JP)	US553 26-Oct-2006 00906A
US6770501B2	3-Aug-2004	Deuterium reservoirs and ingress paths	BURNHAM JAY (US); CARTIER EDUARD A (US); FERENC THOMAS G (US); MITTL STEVEN W (US); STAMPER ANTHONY K (US)	US277 23-Oct-2002 83502A
US6830778B1	14-Dec-2004	Direct printing of thin-film conductors using metal-chelate inks	SCHULZ DOUGLAS L (US); CURTIS CALVIN J (US); GINLEY DAVID S (US)	US887 21-Mar-2002 6002A
US6387754B2	14-May-2002	Method of forming an on-chip decoupling capacitor with bottom hardmask	DALTON TIMOTHY J (US); COWLEY ANDREW P (US); EMMI PETER A (US); KALTALIOGLU ERDEM (US); MCGAHAY VINCENT J (US)	US887 22-Jun-2001 38101A
US6949203B2	27-Sep-2005	System level in-situ integrated dielectric etch process particularly useful for copper dual damascene	HSIEH CHANG LIN (US); MA DIANA XIAOBING (US); SHIEH BRIAN SY YUAN (US); YIN GERALD ZHEYAO (US); SUN JENNIFER (US); THACH SENH (US); LUO LEE (US); BJORKMAN CLAES H (US)	US379 3-Mar-2003 43903A
US6793835B2	21-Sep-2004	System level in-situ integrated dielectric etch process particularly useful for copper dual damascene	LUO LEE (US); BJORKMAN CLAES H (US); SHIEH BRIAN SY YUAN (US); YIN GERALD ZHEYAO (US)	US280 24-Oct-2002 66402A
US7384860B2	10-Jun-2008	Method of manufacturing a semiconductor device	NAKAMURA OSAMU (JP); KATSUMURA MANABU (JP); YAMAZAKI SHUNPEI (JP)	US941 15-Sep-2004 00004A
US6713376B2	30-Mar-2004	Method of manufacturing a contract element and a multi-layered wiring substrate, and wafer batch contact board	SUGIHARA OSAMU (JP)	US170 14-Jun-2002 35302A
US2008296165A1	4-Dec-2008	PLATING APPARATUS	KUNISAWA JUNJI (JP); ODAGAKI MITSUKO (JP); MAKINO NATSUKI (JP); MISHIMA KOJI (JP); NAKAMURA KENJI (JP); INOUE HIROAKI (JP); KIMURA NORIO (JP); MATSUDA TETSUO (JP); KANEKO HISASHI (JP); HAYASAKA NOBUO (JP); OKUMURA KATSUYA (JP); TSUJIMURA MANABU (JP); MORITA TOSHIYUKI (JP)	US127 27-May-2008 65308A

US6645682B2	11-Nov-2003	Thinner for rinsing photoresist and method of treating photoresist layer	PARK HONG SICK (KR); JU JIN HO (KR); LEE YU KYUNG (KR); KANG SUNG CHUL (KR); OH SAE TAE (KR); KANG DOEK MAN (KR)	US169 03302A	25-Jun-2002
US7268062B2	11-Sep-2007	Method of crystallizing a semiconductor film using laser irradiation	TANAKA KOICHIRO (JP); NAKAYA TOMOKO (JP)	US902 7105A	28-Mar-2005
US6780517B2	24-Aug-2004	FOR USE IN SEMICONDUCTOR DEVICES	CHEN TIAN AN (US); GEORGE ANNA M (US); LAU KREISTLER S Y (US); WU HUI JUNG (US)	US163 14402A	4-Jun-2002
US6638143B2	28-Oct-2003	Ion exchange materials for chemical mechanical polishing	WANG YUCHUN (US); TSAI STAN D (US); WIJEKON KAPILA (US); BAJAJ RAJEEV (US); REDEKER FRED C (US)	US737 41400A	14-Dec-2000
US7041599B1	9-May-2006	High through-put Cu CMP with significantly reduced erosion and dishing	LI SHIJIAN (US); REDEKER FRED C (US); WHITE JOHN (US); EMAMI RAMIN (US)	US469 70999A	21-Dec-1999
US6380076B2	30-Apr-2002	Dielectric filling of electrical wiring planes	KIRCHHOFF MARKUS (DE); ROGALLI MICHAEL (DE); WEGE STEPHAN (DE)	US741 30800A	18-Dec-2000
US8754577B2	17-Jun-2014	EL display device	NISHI TAKESHI (JP); ISHIMARU NORIKO (JP)	US201 113104 091A	10-May-2011
US6708702B2	23-Mar-2004	Liquid processing apparatus with storage tank having an internal and external tank	KAMIKAWA YUJI (JP)	US729 22700A	5-Dec-2000
US6770337B2	3-Aug-2004	Thermal transfer of microstructured layers	DEBE MARK K (US); WOLK MARTIN B (US)	US356 04703A	31-Jan-2003
US2010255184A1	7-Oct-2010	Film Deposition Apparatus and a Method of Manufacturing a Light Emitting Device Using the Apparatus	YAMAZAKI SHUNPEI (JP); KONUMA TOSHIMITSU (JP); FUKUNAGA TAKESHI (JP)	US759 77610A	14-Apr-2010
US6136702A	24-Oct-2000	Thin film transistors	CHANDROSS EDWIN ARTHUR (US); CRONE BRIAN KEITH (US); DODABALAPUR ANANTH (US); FILAS ROBERT WILLIAM (US)	US450 52599A	29-Nov-1999
US7104267B2	12-Sep-2006	Planarized copper cleaning for reduced defects	EMAMI RAMIN (US); LI SHIJIAN (US); KO SEN HOU (US); REDEKER FRED C (US); CHANDRACHOD MADHAVI (US)	US727 13300A	29-Nov-2000
US7336685B2	26-Feb-2008	Laser irradiation apparatus, laser irradiation method, and method for manufacturing a semiconductor device	TANAKA KOICHIRO (JP)	US756 77604A	14-Jan-2004
US6723691B2	20-Apr-2004	Post chemical-mechanical planarization (CMP) cleaning composition	NAGHSHINEH SHAHRIAR (US); BARNES JEFF (US); OLDAK EWA B (US)	US781 85901A	12-Feb-2001
US6492308B1	10-Dec-2002	Post chemical-mechanical planarization (CMP) cleaning composition	NAGHSHINEH SHAHRIAR (US); BARNES JEFF (US); XU DINGYING (US)	US587 88300A	6-Jun-2000
US7892635B2	22-Feb-2011	Precursors for porous low-dielectric constant materials for use in electronic devices	HAWKER CRAIG JON (US); HEDRICK JAMES L (US); MILLER ROBERT D (US); VOLKSEN WILLI (US)	US375 0708A	26-Feb-2008

US6350393B2	26-Feb-2002	Use of CsOH in a dielectric CMP slurry	FRANCIS ALICIA F (US); MUELLER BRIAN L (US); DIRKSEN JAMES A (US); FEENEY PAUL M (US)	US428 96599A	4-Nov-1999
US6992018B2	31-Jan-2006	Chemical fluid deposition for the formation of metal and metal alloy films on patterned and unpatterned substrates	WATKINS JAMES J (US); BLACKBURN JASON M (US); LONG DAVID P (US); LAZORCIK JASON L (US)	US745 84303A	24-Dec-2003
US6582767B1	24-Jun-2003	Microstamping pattern of alkanethiol to surface; surface treating silicon polymer with aqueous solution of metal salt; electroless deposition	FUKUSHIMA MOTOO (JP); Tabei EIICHI (JP); FURIHATA TOMOYOSHI (JP); ARAKAWA MASAYA (JP)	US702 85200A	1-Nov-2000
US6882045B2	19-Apr-2005	Multi-chip module and method for forming and method for deplating defective capacitors	MASSINGILL THOMAS J (US); MCCORMACK MARK THOMAS (US); WANG WEN CHOU VINCENT (US)	US997 58901A	29-Nov-2001
US6203613B1	20-Mar-2001	INTRODUCING METAL NITRATE-CONTAINING PRECURSOR INTO REACTOR CONTAINING SUBSTRATE TO FORM METAL CONTAINING FILM	GATES STEPHEN MCCONNELL (US); NEUMAYER DEBORAH ANN (US)	US421 09699A	19-Oct-1999
US2005116347A1	2-Jun-2005	Deposition of fluorosilsesquioxane films	HACKER NIGEL P (US)	US220 6304A	22-Dec-2004
US6586846B2	1-Jul-2003	Low cost decal material used for packaging	HO CHUNG WEN (US)	US846 53901A	2-May-2001
US6583071B1	24-Jun-2003	Ultrasonic spray coating of liquid precursor for low K dielectric coatings	WEIDMAN TIMOTHY (US); LU YUNFENG (US); NAULT MICHAEL P (US); BARNES MICHAEL (US); MOGHADAM FARHAD (US)	US692 66000A	18-Oct-2000
US6489248B2	3-Dec-2002	Method and apparatus for etch passivating and etching a substrate	ZHANG LUKE (US); WANG RUIPING (US); ADISAPUTRO IDA ARIANI (US); KIM KWANG SOO (US)	US938 20801A	23-Aug-2001
US6403471B1	11-Jun-2002	Method of forming a dual damascene structure including smoothing the top part of a via	LOU CHINE GIE (TW)	US429 60199A	28-Oct-1999
US10366962B2	30-Jul-2019	Three dimensional device integration method and integrated device	ENQUIST PAUL M (US); FOUNTAIN JR GAIUS GILLMAN (US)	US201 615385 545A	20-Dec-2016
US6656842B2	2-Dec-2003	Barrier layer buffing after Cu CMP	LI SHIJIAN (US); REDEKER FRED C (US); EMAMI RAMIN (US); KO SEN HOU (US); WHITE JOHN M (US)	US401 64399A	22-Sep-1999
US2004013982A1	22-Jan-2004	Fabrication of finely featured devices by liquid embossing	JACOBSON JOSEPH M (US); BULTHAUP COLIN A (US); WILHELM ERIC J (US); HUBERT BRIAN N (US)	US320 86902A	17-Dec-2002
US6441475B2	27-Aug-2002	Chip scale surface mount package for semiconductor device and process of fabricating the same	ZANDMAN FELIX (US); KASEM Y MOHAMMED (US); HO YUEH SE (US)	US733 82300A	8-Dec-2000
US2001036749A1	1-Nov-2001	Apparatus and methods for integrated circuit planarization	LEVERT JOSEPH A (US); TOWERY DANIEL LYNNE (US); ENDISCH DENIS (US)	US860 94901A	18-May-2001
US6794113B2	21-Sep-2004	Negative resist composition, method for the formation of resist patterns and process for the production of electronic devices	NOZAKI KOJI (JP); NAMIKI TAKAHISA (JP); YANO EI (JP); KON JUNICHI (JP); KOZAWA MIWA (JP)	US291 67102A	12-Nov-2002

US6365327B1	2-Apr-2002	Process for manufacturing in integrated circuit including a dual-damascene structure and an integrated circuit	CHITTIPEDDI SAILESH (US); MERCHANT SAILESH MANSINH (US)	US386 06599A	30-Aug-1999
US6524957B2	25-Feb-2003	Method of forming in-situ electroplated oxide passivating film for corrosion inhibition	MERCHANT SAILESH MANSINH (US); MISRA SUDHANSHU (US); ROY PRADIP KUMAR (US)	US953 70601A	17-Sep-2001
US9144151B2	22-Sep-2015	Current-carrying structures fabricated using voltage switchable dielectric materials	KOSOWSKY LEX (US)	US284 79008A	24-Sep-2008
US6717101B2	6-Apr-2004	Method and apparatus for laser ablation of a target material	MORRIS JAMES H (US); POWERS MICHAEL (US); RIEGER HARRY (US)	US264 24802A	3-Oct-2002
US2007190906A1	16-Aug-2007	POLISHING MEDIUM FOR CHEMICAL-MECHANICAL POLISHING, AND POLISHING METHOD	UCHIDA TAKESHI (JP); KAMIGATA YASUO (JP); TERASAKI HIROKI (JP); KURATA YASUSHI (JP); HOSHINO TETSUYA (JP); IGARASHI AKIKO (JP)	US737 50207A	19-Apr-2007
US6852635B2	8-Feb-2005	Method for bottomless deposition of barrier layers in integrated circuit metallization schemes	SATTA ALESSANDRA (BE); MAEX KAREN (BE); ELMERS KAI ERIK (FI); SAANILA VILLE ANTERO (FI); SOININEN PEKKA JUHA (FI); HAUKKA SUVI P (FI)	US731 65603A	8-Dec-2003
US6413854B1	2-Jul-2002	PATTERNING DIELECTRIC; DEPOSITION METAL IN OPENINGS; REMOVAL; DEPOSITING BARRIER, ADHESION LAYER	UZOH CYPRIAN E (US); EDELSTEIN DANIEL C (US); FALTERMEIER CHERYL (US); LOCKE PETER S (US)	US382 11099A	24-Aug-1999
US6572780B2	3-Jun-2003	Methods for fabricating flexible circuit structures	MCCORMACK MARK THOMAS (US); ROMAN JAMES (US); ZHANG LEI (US); BEILIN SOLOMON I (US)	US872 62901A	31-May-2001
US7338913B2	4-Mar-2008	Semiconductor device, manufacturing method thereof, and electronic device	KASAHARA KENJI (JP); KAWASAKI RITSUKO (JP); OHTANI HISASHI (JP); YAMAZAKI SHUNPEI (JP)	US406 29503A	4-Apr-2003
US7744666B2	29-Jun-2010	Polishing medium for chemical-mechanical polishing, and method of polishing substrate member	KURATA YASUSHI (JP); KAMIGATA YASUO (JP); UCHIDA TAKESHI (JP); TERASAKI HIROKI (JP); IGARASHI AKIKO (JP)	US201 24205A	11-Aug-2005
US6867140B2	15-Mar-2005	Metal layer; mixture of liquid carrier, oxidizer and terminating compound	WANG SHUMIN (US); KAUFMAN VLASTA BRUSIC (US); GRUMBINE STEVEN K (US); CHERIAN ISAAC K (US)	US353 51203A	29-Jan-2003
US6852632B2	8-Feb-2005	Method of polishing a multi-layer substrate	WANG SHUMIN (US); KAUFMAN VLASTA BRUSIC (US); GRUMBINE STEVEN K (US); CHERIAN ISAAC K (US); ZHOU RENJIE (US)	US353 54203A	29-Jan-2003
US2008138979A1	12-Jun-2008	SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND MANUFACTURING METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE	NOGUCHI JUNJI (JP); OHASHI NAOFUMI (JP); TAKEDA KENICHI (JP); SAITO TATSUYUKI (JP); YAMAGUCHI HIZURU (JP); OWADA NOBUO (JP)	US187 9008A	23-Jan-2008
US6583065B1	24-Jun-2003	Sidewall polymer forming gas additives for etching processes	WILLIAMS RANEY (US); CHINN JEFFREY (US); TREVOR JITSKE (US); LILL THORSTEN B (US); NALLAN PADMAPANI (US); VARGA TAMAS (US); MACE HERVE (FR)	US366 50999A	3-Aug-1999
US6488872B1	3-Dec-2002	Microfabricated devices and method of manufacturing the same	BEEBE DAVID J (US); MOORE JEFFREY S (US)	US625 20400A	21-Jul-2000

US7258768B2	21-Aug-2007	Method of fabricating an EL display device, and apparatus for forming a thin film	YAMAZAKI SHUNPEI (JP)	US902 79204A	2-Aug-2004
US6750550B1	15-Jun-2004	CURABLE POLYMER COMPOSITION INCLUDING SPHERICAL FILLER HAVING SPECIFIED PARTICLE SIZE AND ASPECT RATIO; ADHESIVE THAT CAN BOND SEMICONDUCTOR CHIP TO MOUNTING COMPONENT ACROSS UNIFORM GAP AND THOROUGHLY RELAX MECHANICAL STRESSES ACTING ON CHIP	YAMAKAWA KIMIO (JP); ISSHIKI MINORU (JP); MINE KATSUTOSHI (JP)	US597 21800A	20-Jun-2000
US6444083B1	3-Sep-2002	Corrosion resistant component of semiconductor processing equipment and method of manufacturing thereof	STEGEER ROBERT (US); CHANG CHRIS (US)	US343 69299A	30-Jun-1999
US7342251B2	11-Mar-2008	Method of manufacturing an electro-optical device	YAMAZAKI SHUNPEI (JP); MIZUKAMI MAYUMI (JP); KONUMA TOSHIMITSU (JP)	US202 14305A	12-Aug-2005
US7737023B2	15-Jun-2010	Method of manufacture of semiconductor integrated circuit device and semiconductor integrated circuit device	UNO SHOUOCHI (JP); MAEKAWA ATSUSHI (JP); YUNOGAMI TAKASHI (JP); TAGO KAZUTAMI (JP); NOJIRI KAZUO (JP); MACHIDA SHUNTARO (JP); TOKUNAGA TAKAFUMI (JP)	US194 04408A	19-Aug-2008
US7144606B2	5-Dec-2006	Plasma treatment to enhance adhesion and to minimize oxidation of carbon-containing layers	HUANG JUDY (US)	US995 00204A	22-Nov-2004
US6518392B2	11-Feb-2003	Encapped oligomeric polybenzoxazole, polybenzothiazole, polyamic acid or polyamic acid esters as precursors for dielectric compounds	CARTER KENNETH R (US); HEDRICK JAMES L (US); LEE VICTOR YEE WAY (US); MCHERRON DALE C (US); MILLER ROBERT D (US)	US803 44701A	8-Mar-2001
US9069133B2	30-Jun-2015	Anti-reflective coating for photolithography and methods of preparation thereof	BALDWIN TERESA (US); KENNEDY JOSEPH (US); IWAMOTO NANCY (US); NAKANO TADASHI (JP); BEDWELL WILLIAM (US); STUCK JASON (US); SUEDEMEYER ARLENE (US); HEBERT MELLO (US)	US495 68602A	12-Nov-2002
US6234875B1	22-May-2001	Method of modifying a surface	PENDERGRASS JR DANIEL B (US)	US328 91699A	9-Jun-1999
US6562698B2	13-May-2003	Dual laser cutting of wafers	MANOR RAN (IL)	US864 62001A	24-May-2001
US6555447B2	29-Apr-2003	Method for laser scribing of wafers	WEISSHAUS ILAN (IL); MANOR RAN (IL); WERTHEIM ODED (IL)	US817 95901A	27-Mar-2001
US2014284306A1	25-Sep-2014	METHOD FOR MANUFACTURING POROUS STRUCTURE AND METHOD FOR FORMING PATTERN	ASAKAWA KOJI (JP); HIRAOKA TOSHIRO (JP); AKASAKA YOSHIHIRO (JP); HOTTA YASUYUKI (JP)	US201 414295 657A	4-Jun-2014
US2005182151A1	18-Aug-2005	Low dielectric constant polyorganosilicon materials generated from polycarbosilanes	APEN PAUL (US); WU HUI JUNG (US)	US284 2305A	3-Jan-2005
US8822828B2	2-Sep-2014	Multi-layer printed circuit board and method of manufacturing multi-layer printed circuit board	ASAI MOTOO (JP); WANG DONGDONG (JP); MORI TAKAHIRO (JP)	US201 113089 378A	19-Apr-2011

US6406622B1	18-Jun-2002	Apparatus for filtering a fluid	TSUIHIJI MOTOYUKI (JP); IINUMA HIROFUMI (JP)	US538 29-Mar-2000 33500A
US6750475B1	15-Jun-2004	Method for fabricating electric interconnections and interconnection substrate having electric interconnections fabricated by the same method	IZUMI YOSHIHIRO (JP); CHIKAMA YOSHIMASA (JP); OCHI HISAO (JP)	US573 17-May-2000 46400A
US8314426B2	20-Nov-2012	Semiconductor device and method of fabricating the same	KOKUBO CHIHO (JP); YAMAGATA HIROKAZU (JP); YAMAZAKI SHUNPEI (JP)	US201 15-Sep-2011 113233 120A
US7348300B2	25-Mar-2008	Acetylenic diol ethylene oxide/propylene oxide adducts and processes for their manufacture	LASSILA KEVIN RODNEY (US); UHRIN PAULA ANN (US); ZHANG PENG (US); KING CURZI DANIELLE MEGAN (US); BARBER LESLIE COX (US); ROSS BRENDA FAYE (US)	US485 1-Feb-2005 7605A
US7452426B2	18-Nov-2008	Contacting the substrate with a process solution of surfactants; reducing the number of defects in the manufacture of semiconductor devices; reducing dynamic surface tension while minimizing foaming	ZHANG PENG (US); ROSS BRENDA FAYE (US)	US519 12-Sep-2006 47606A
US8748898B2	10-Jun-2014	Semiconductor device and manufacturing method thereof	YAMAZAKI SHUNPEI (JP)	US201 30-Dec-2011 113341 012A
US6855035B2	15-Feb-2005	Apparatus and method for producing substrate with electrical wire thereon	HOMMA YOSHIO (JP); SAKUMA NORIYUKI (JP); OHASHI NAOFUMI (JP); IMAI TOSHINORI (JP)	US214 8-Aug-2002 36902A
US6527847B1	4-Mar-2003	Coating composition	MATSUKI YASUO (JP)	US701 30-Nov-2000 37700A
US6541354B1	1-Apr-2003	Method for forming silicon film	SHIMODA TATSUYA (JP); MIYASHITA SATORU (JP); SEKI SHUNICHI (JP); FURUSAWA MASAHIRO (JP); YUDASAKA ICHIO (JP); TAKEUCHI YASUMASA (JP); MATSUKI YASUO (JP)	US701 30-Nov-2000 64700A
US6514801B1	4-Feb-2003	Method for manufacturing thin-film transistor	YUDASAKA ICHIO (JP); SHIMODA TATSUYA (JP); SEKI SHUNICHI (JP)	US701 30-Nov-2000 51100A
US6517911B1	11-Feb-2003	Process for the formation of silicon oxide films	MATSUKI YASUO (JP)	US700 30-Nov-2000 72600A
US6579736B2	17-Jun-2003	Semiconductor device and method of manufacturing thereof	YAMAZAKI SHUNPEI (JP)	US123 17-Apr-2002 19802A
US7335964B2	26-Feb-2008	Semiconductor structures	JUENGLING WERNER (US); DONOHUE KEVIN G (US)	US123 6-May-2005 63205A
US6593077B2	15-Jul-2003	Method of making thin films dielectrics using a process for room temperature wet chemical growth of SiO based oxides on a substrate	FAUR MARIA (US); FAUR HORIA M (US); FAUR MIRCEA (US)	US891 26-Jun-2001 83201A
US6695903B1	24-Feb-2004	Dopant pastes for the production of p, p+, and n, n+ regions in semiconductors	KUEBELBECK ARMIN (DE); ZIELINSKI CLAUDIA (DE); HEIDER LILIA (DE); STOCKUM WERNER (DE)	US936 12-Sep-2001 28501A

US6323169B1	27-Nov-2001	AQUEOUS STRIPPING COMPOSITION CONTAINING OXIDIZING AGENT, CHELATING AGENT, WATER SOLUBLE FLUORINE COMPOUND SELECTED FROM AMMONIUM FLUORIDE, ACID AMMONIUM FLUORIDE, MONOETHANOLAMINE FLUORIDE, AND TETRAMETHYLAMMONIUM FLUORIDE	ABE KOJIRO (JP); FUKUDA HIDEKI (JP); ABE HISAKI (JP); MARUYAMA TAKETO (JP)	US517 3-Mar-2000 59200A
US6287972B1	11-Sep-2001	System and method for residue entrapment utilizing a polish and sacrificial fill for semiconductor fabrication	ZIGER DAVID (US); BRUGGE HUNTER (US)	US262 4-Mar-1999 43999A
US6638694B2	28-Oct-2003	Resist stripping agent and process of producing semiconductor devices using the same	IKEMOTO KAZUTO (JP); ABE HISAKI (JP); MARUYAMA TAKETO (JP); AOYAMA TETSUO (JP)	US375 28-Feb-2003 10503A
US7981733B2	19-Jul-2011	Laser irradiation method, laser irradiation apparatus, and semiconductor device	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP)	US106 21-Apr-2008 64308A
US9097953B2	4-Aug-2015	Semiconductor device, and method of forming the same	YAMAZAKI SHUNPEI (JP); TANAKA KOICHIRO (JP)	US201 26-Dec-2012 213727 258A
US6258192B1	10-Jul-2001	Multi-thickness, multi-layer green sheet processing	NATARAJAN GOVINDARAJAN (US)	US249 10-Feb-1999 98699A
US8007627B2	30-Aug-2011	Electronic component mounting method and apparatus	NISHIDA KAZUTO (JP); NISHIKAWA HIDENOBU (JP); WADA YOSHINORI (JP); OTANI HIROYUKI (JP)	US641 23-Feb-2005 2205A
US6716663B2	6-Apr-2004	Method for removing foreign matter, method for forming film, semiconductor device and film forming apparatus	MORITA KIYOYUKI (JP); OHTSUKA TAKASHI (JP); UEDA MICHIIHITO (JP)	US230 29-Aug-2002 25802A
US6799303B2	28-Sep-2004	Speed typing apparatus and method	BLUMBERG MARVIN R (US)	US912 26-Jul-2001 50901A
US2010035424A1	11-Feb-2010	Semiconductor Device and Fabrication Method Thereof	YAMAZAKI SHUNPEI (JP); ASAMI TAKETOMI (JP); KITAKADO HIDEHITO (JP); ARAI YASUYUKI (JP)	US579 14-Oct-2009 02009A
US6280640B1	28-Aug-2001	Process for manufacturing a chip carrier substrate	HURWITZ DROR (IL); YOFIS BORIS (IL); KATZ DROR (IL); IGNER EVA (IL)	US303 3-May-1999 42299A
US7491655B2	17-Feb-2009	Semiconductor device and method of fabricating the same	YAMAZAKI SHUNPEI (JP)	US930 31-Aug-2004 47504A
US6146986A	14-Nov-2000	Lithographic method for creating damascene metallization layers	WAGGANER ERIC D (US)	US227 8-Jan-1999 22299A
US8900477B2	2-Dec-2014	Materials for polishing liquid for metal, polishing liquid for metal, method for preparation thereof and polishing method using the same	UCHIDA TAKESHI (JP); HOSHINO TETSUYA (JP); TERAZAKI HIROKI (JP); KAMIGATA YASUO (JP); KOYAMA NAOYUKI (JP); HONMA YOSHIO (JP); KONDOH SEIICHI (JP)	US155 17-Jan-2008 3308A

US6534459B1	18-Mar-2003	Resist residue remover	YATA TAKASHI (JP); TERAYAMA SHIGEKI (JP); KOINUMA YUTAKA (JP); OHGUSHI TAKERU (JP)	US635 9-Aug-2000 48700A
US9660159B2	23-May-2017	Wiring material, semiconductor device provided with a wiring using the wiring material and method of manufacturing thereof	TAKAYAMA TORU (JP); SATO KEIJI (JP); YAMAZAKI SHUNPEI (JP)	US201 17-Jan-2013 313743 914A
US7816191B2	19-Oct-2010	Wiring material, semiconductor device provided with a wiring using the wiring material and method of manufacturing thereof	TAKAYAMA TORU (JP); SATO KEIJI (JP); YAMAZAKI SHUNPEI (JP)	US786 13-Apr-2007 88007A
US7776712B2	17-Aug-2010	Method of forming a semiconductor device	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); SUZAWA HIDEOMI (JP); TAKAYAMA TORU (JP)	US799 2-May-2007 71307A
US7462517B2	9-Dec-2008	Electro-optical device and semiconductor circuit	OHTANI HISASHI (JP); KOYAMA JUN (JP); YAMAZAKI SHUNPEI (JP)	US339 26-Jan-2006 67106A
US6579804B1	17-Jun-2003	Contact structure and production method thereof and probe contact assembly using same	ZHOU YU (US); YU DAVID (US); ALDAZ ROBERT EDWARD (US); KHOURY THEODORE A (US)	US696 25-Oct-2000 07700A
US2003201184A1	30-Oct-2003	Method and associated apparatus for tilting a substrate upon entry for metal deposition	DORDI YEZDI N (US); STEVENS JOSEPH J (US); SUGARMAN MICHAEL N (US)	US424 28-Apr-2003 47903A
US9035316B2	19-May-2015	Device comprising EL element electrically connected to P-channel transistor	YAMAZAKI SHUNPEI (JP)	US201 23-Jan-2013 313747 503A
US6519843B2	18-Feb-2003	Method of forming a chip carrier by joining a laminate layer and stiffener	LAUFFER JOHN M (US); MARCELLO HEIKE (US); RUSSELL DAVID J (US)	US772 30-Jan-2001 41801A
US9627460B2	18-Apr-2017	Method of fabricating a semiconductor device	YAMAZAKI SHUNPEI (JP)	US201 13-Feb-2015 514621 668A
US9366971B2	14-Jun-2016	Display device comprising dual transistor with LDD regions overlapping the gate electrodes and one of a source electrode and a drain electrode of first transistor is electrically connected to the second gate electrode	ADACHI HIROKI (JP)	US201 9-Oct-2014 414510 463A
US6208077B1	27-Mar-2001	Organic electroluminescent device with a non-conductive fluorocarbon polymer layer	HUNG LIANG SUN (US)	US186 5-Nov-1998 53898A
US6664029B1	16-Dec-2003	Method of forming pattern	IMAI GENJI (JP); OHNISHI KENGO (JP); HONMA HIROYUKI (JP); KOGURE HIDEO (JP)	US582 30-Aug-2000 55700A
US11549192B2	10-Jan-2023	Electroplating apparatus for tailored uniformity profile	MAYER STEVEN T (US); PORTER DAVID W (US); BUCKALEW BRYAN L (US); RASH ROBERT (US)	US202 4-Jan-2021 117247 991A

US6724609B2	20-Apr-2004	Electrostatic sensing chuck using area matched electrodes	SUN HOI CHEONG (US); DESAI NITIN V (US); ROACH WILLIAM R (US); LUDINGTON DAVID NORMAN (US); PLETCHER TIMOTHY ALLEN (US); KELLER DAVID (US); LANG FRANK B (US); SOUTHGATE PETER D (US); MCGINN JOSEPH T (US)	US389 4-Jan-2002 3102A
US6268662B1	31-Jul-2001	Wire bonded flip-chip assembly of semiconductor devices	TEST HOWARD R (US); SHIH WEI YAN (US); SUBIDO WILLMAR (US)	US418 14-Oct-1999 04299A
US6767755B2	27-Jul-2004	Method of producing electrooptical device and method of producing driving substrate for driving electrooptical device	YAMANAKA HIDEO (JP); YAMOTO HISAYOSHI (JP); SATO YUUCHI (JP); YAGI HAJIME (JP)	US300 20-Nov-2002 38702A
US6951826B2	4-Oct-2005	Silicon carbide deposition for use as a low dielectric constant anti-reflective coating	BENCHER CHRISTOPHER (US); FENG JOE (US); SHEK MEI YEE (US); NGAI CHRIS (US); HUANG JUDY (US)	US684 9-Oct-2003 07903A
US7670945B2	2-Mar-2010	In situ deposition of a low & K dielectric layer, barrier layer, etch stop, and anti-reflective coating for damascene application	HUANG JUDY H (US)	US345 29-Dec-2008 43108A
US7064070B2	20-Jun-2006	Removal of CMP and post-CMP residue from semiconductors using supercritical carbon dioxide process	MULLEE WILLIAM H (US); DE LEEUWE MARC (US); ROBERSON JR GLENN A (US); PALMER BENTLEY J (US)	US396 24-Mar-2003 61203A
US6451436B1	17-Sep-2002	Coating liquid for forming a silica-containing film with a low-dielectric constant and substrate coated with such a film	KOMATSU MICHIO (JP); NAKASHIMA AKIRA (JP); EGAMI MIKI (JP)	US577 24-May-2000 50700A
US6153724A	28-Nov-2000	Preparation of cross-linked 2-dimensional polymers with sidedness from α,β -lactones	HOLLINGSWORTH RAWLE I (US)	US159 24-Sep-1998 30598A
US6066196A	23-May-2000	REACTING COPPER SOURCE PRECURSOR FOR USE IN THE CHEMICAL VAPOR DEPOSITION OF FILMS COMPRISING COPPER, COMPRISING A MIXTURE OF AT LEAST ONE LIGAND-STABILIZED COPPER (I) BETA-DIKETONATE PRECURSOR AND ONE COPPER(II) BETA-DIKETONATE PRECURSOR	KALOYEROS ALAIN E (US); ARKLES BARRY C (US)	US157 21-Sep-1998 90198A
US6410415B1	25-Jun-2002	Flip chip mounting technique	ESTES RICHARD H (US); CLAYTON JAMES E (US); ITO KOJI (JP); AKITA MASANORI (JP); MORI TOSHIHIRO (JP); WADA MINORU (JP)	US724 28-Nov-2000 01900A
US6495458B2	17-Dec-2002	Method for producing low carbon/oxygen conductive layers	MARSH EUGENE P (US)	US923 7-Aug-2001 85101A
US6893726B2	17-May-2005	Polysiloxane reaction product of silica and a hydrolyzate of an alkoxysilane and a readily decomposable resin	NAKASHIMA AKIRA (JP); KOMATSU MICHIO (JP)	US649 26-Aug-2003 57503A
US8491807B2	23-Jul-2013	Abrasive liquid for metal and method for polishing	UCHIDA TAKESHI (JP); MATSUZAWA JUN (JP); HOSHINO TETSUYA (JP); KAMIGATA YASUO (JP); TERAZAKI HIROKI (JP); HONMA YOSHIO (JP); KONDOH SEIICHI (JP)	US201 26-Aug-2011 113218 590A
US6297154B1	2-Oct-2001	Process for semiconductor device fabrication having copper interconnects	GROSS MICHAL EDITH (US); LINGK CHRISTOPH (US)	US143 28-Aug-1998 03798A

US2003062600A1	3-Apr-2003	Process for optimizing mechanical strength of nanoporous silica	WU HUI JUNG (US); DRAGE JAMES S (US); RAMOS TERESA (US); SMITH DOUGLAS M (US); WALLACE STEPHEN (US); RODERICK KEVIN (US); BRUNGARDT LISA BETH (US)	US260 30-Sep-2002 87102A
US6232157B1	15-May-2001	Thin film transistors	DODABALAPUR ANANTH (US); LIN YEN YI (US); RAJU VENKATARAM REDDY (US)	US450 29-Nov-1999 52299A
US6085415A	11-Jul-2000	Methods to produce insulated conductive through-features in core materials for electric packaging	GANDHI PRADEEP (US); FU SAMUEL (US); LEGERTON GARY E (US); BAXTER DANIEL E (US); ROBINETTE WILLIAM C (US)	US123 27-Jul-1998 56398A
US6300672B1	9-Oct-2001	Silicon oxynitride cap for fluorinated silicate glass film in intermetal dielectric semiconductor fabrication	LEE GILL YONG (US)	US120 22-Jul-1998 63098A
US6218302B1	17-Apr-2001	Method for forming a semiconductor device	BRAECKELMANN GREGOR (US); VENKATRAMAN RAMNATH (US); HERRICK MATTHEW THOMAS (US); SIMPSON CINDY R (US); FIORDALICE ROBERT W (US); DENNING DEAN J (US); JAIN AJAY (US); CAPASSO CRISTIANO (US)	US121 21-Jul-1998 06898A
US7282398B2	16-Oct-2007	Crystalline semiconductor thin film, method of fabricating the same, semiconductor device and method of fabricating the same	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); TAKANO TAMAE (JP)	US894 29-Jun-2001 12501A
US8809133B2	19-Aug-2014	Crystalline semiconductor thin film, method of fabricating the same, semiconductor device, and method of fabricating the same	YAMAZAKI SHUNPEI (JP); OHTANI HISASHI (JP); TAKANO TAMAE (JP)	US201 28-Dec-2011 113338 366A
US6022812A	8-Feb-2000	DIELECTRIC POLYSILICATE FILMS BY VAPOR DEPOSITION OF TETRA-ALKOXYSILANE(S) ON A SUBSTRATE; EXPOSING TO WATER AND ACID OR BASE CATALYST TO GEL; DRYING; HIGH POROSITY; LOW DIELECTRIC CONSTANT; SEMICONDUCTORS; INTEGRATED CIRCUITS	SMITH DOUGLAS M (US); RAMOS TERESA (US); RODERICK KEVIN H (US)	US111 7-Jul-1998 08398A
US7579308B2	25-Aug-2009	Compositions and processes for photoresist stripping and residue removal in wafer level packaging	LEE WAI MUN (US)	US120 2-May-2005 05405A
US7543592B2	9-Jun-2009	Compositions and processes for photoresist stripping and residue removal in wafer level packaging	LEE WAI MUN (US)	US260 28-Oct-2005 39105A
US2006094613A1	4-May-2006	Compositions and processes for photoresist stripping and residue removal in wafer level packaging	LEE WAI M (US)	US119 2-May-2005 55905A
US7256490B2	14-Aug-2007	Test carrier for semiconductor components having conductors defined by grooves	FARNWORTH WARREN M (US); WOOD ALAN G (US)	US591 2-Nov-2006 74406A
US6277481B1	21-Aug-2001	Adhesive composition and adhesive sheet	SUGINO TAKASHI (JP); SENOO HIDEO (JP); NAKATA YASUKAZU (JP)	US347 6-Jul-1999 63499A

US2004170825A1	2-Sep-2004	Device cover having a gapped adhesive preform thereon for covering a device on an electronic substrate	CHUNG KEVIN KWONG TAI (US)	US704 73803A	10-Nov-2003
US6410985B1	25-Jun-2002	SEED LAYER COMPRISING ALUMINUM HAVING A ZINC COATING BETWEEN SIDEWALLS AND A BOTTOM OF THE GROOVE AND THE SILVER.	CHAN TSU C (US); CHIU ANTHONY M (US); SMITH GREGORY C (US)	US563 95800A	2-May-2000
US6120661A	19-Sep-2000	Apparatus for processing glass substrate	HIRANO SHINSUKE (JP); TAKATSU KEI (JP); KADOMURA SHINGO (JP)	US327 22499A	7-Jun-1999
US6509386B1	21-Jan-2003	Porous insulating compounds and method for making same	KOHL PAUL A (US)	US544 63800A	5-Apr-2000
US6435947B2	20-Aug-2002	CMP polishing pad including a solid catalyst	MUELLER BRIAN L (US); WANG SHUMIN (US)	US766 75001A	22-Jan-2001
US6599370B2	29-Jul-2003	Stabilized alkaline compositions for cleaning microelectronic substrates	SKEE DAVID C (US)	US859 14201A	16-May-2001
US6432830B1	13-Aug-2002	CLEANING USING REDUCING GAS	MERRY WALTER RICHARDSON (US)	US798 4598A	15-May-1998
US8178967B2	15-May-2012	Low fabrication cost, high performance, high reliability chip scale package	LEE JIN YUAN (TW); LEI MING TA (TW); HUANG CHING CHENG (TW); LIN CHUEN JYE (TW)	US930 21007A	31-Oct-2007
US9369175B2	14-Jun-2016	Low fabrication cost, high performance, high reliability chip scale package	LEE JIN YUAN (TW); LEI MING TA (TW); HUANG CHING CHENG (TW); LIN CHUEN JYE (TW)	US930 21307A	31-Oct-2007
US6383724B1	7-May-2002	Organic removal process	CARTER LAWRENCE E (US); NELSON STEVEN L (US)	US551 07200A	18-Apr-2000
US6114227A	5-Sep-2000	Chamber for reducing contamination during chemical vapor deposition	LEKSELL DAVID (US); CHAN MING XI (US); ELLUL JOSEPH P (US); LUCE JEANNE L (US); RYAN DAVID T (US); SHAREEF IQBAL A (US); LEE CHUNG J (US); CAMPBELL STEPHEN M (US); FOGGIATO GIOVANNI ANTONIO (US)	US280 25899A	29-Mar-1999
US5988485A	23-Nov-1999	Flux cleaning for flip chip technology using environmentally friendly solvents	MASTER RAJ N (US); STARR ORION K (US); KHAN MOHAMMAD Z (US)	US406 5198A	17-Mar-1998
US6098867A	8-Aug-2000	Automated brush fluxing system for application of controlled amount of flux to packages	MASTER RAJ N (US); GUARDADO MARIA G (US); KHAN MOHAMMAD ZUBAIR (US)	US405 1198A	17-Mar-1998
US6312766B1	6-Nov-2001	ION BEAM DEPOSITION, WHEREIN THE SUBSTRATE IS COOLED TO LESS THAN-100 DEGREES C. DURING DEPOSITION TO PROVIDE THE LAYER WITH AT LEAST 10 VOLUME PERCENT POROSITY.	PAI CHIEN SHING (US); ZHU WEI (US)	US205 84098A	4-Dec-1998
US7919412B2	5-Apr-2011	Over-passivation process of forming polymer layer over IC chip	CHEN YING CHIH (TW); LIN MOU SHIUNG (TW); CHOU CHIU MING (TW)	US273 54608A	19-Nov-2008

US2008251925A1	16-Oct-2008	TOP LAYERS OF METAL FOR INTEGRATED CIRCUITS	LIN MOU SHIUNG (TW); CHOU CHIU MING (TW); CHOU CHIEN KANG (TW)	US142 20-Jun-2008 82908A
US7678624B2	16-Mar-2010	Semiconductor device and method for manufacturing same	YAMAZAKI SHUNPEI (JP); FUKUNAGA TAKESHI (JP)	US519 12-Sep-2006 51406A
US6395374B1	28-May-2002	Method of making microwave, multifunction modules using fluoropolymer composite substrates	MCANDREW JOSEPH (US); LOGOTHETIS JAMES J (US)	US579 26-May-2000 91500A
US6545368B2	8-Apr-2003	Use of an oxide surface to facilitate gate break on a carrier substrate for a semiconductor device	WENSEL RICHARD W (US)	US132 25-Apr-2002 48102A
US5997658A	7-Dec-1999	Aqueous stripping and cleaning compositions	PETERS DARRYL W (US); WARD IRL E (US); MICHELOTTI FRANCIS (US); RIDDLE JR FLOYD (US)	US493 9-Jan-1998 798A
US6465359B2	15-Oct-2002	Etchant for use in a semiconductor processing method and system	YAMADA MASAHIRO (JP); ITO YOUNBUN (JP); INAZAWA KOUICHIRO (JP); TOURE ABRON (US); HINATA KUNIIHIKO (US); SAKIMA HIROMI (US)	US398 17-Sep-1999 47299A
US6033984A	7-Mar-2000	Dual damascene with bond pads	SCHNABEL RAINER FLORIAN (US); NING XIAN J (US); SPULER BRUNO (US)	US997 23-Dec-1997 68297A
US6355565B2	12-Mar-2002	STABILIZED SILICA IN AN AQUEOUS SUSPENSION; AN OXIDIZING AGENT COMPRISING AN METALLIC ION AND AN ANION; ACID HAVING THE SAME ANION AS SAID OXIDIZING AGENT TO ADJUST THE PH TO 1.2 TO 1.4.	FEENEY PAUL M (US); KRYWANCZYK TIMOTHY C (US); DAVID LAWRENCE D (US); TIERSCH MATTHEW T (US); WHITE ERIC J (US)	US904 12-Jul-2001 32301A
US6083844A	4-Jul-2000	Techniques for etching an oxide layer	BUI LE GIAO QUYNH (US); ARIMA JOHN (US)	US996 22-Dec-1997 07197A
US6998344B2	14-Feb-2006	Method for fabricating semiconductor components by forming conductive members using solder	AKRAM SALMAN (US); FARNWORTH WARREN M (US); WOOD ALAN G (US)	US815 31-Mar-2004 08304A
US6093635A	25-Jul-2000	High integrity borderless vias with HSQ gap filled patterned conductive layers	TRAN KHANH (US); HUANG RICHARD J (US); CHAN SIMON S (US); YOU LU (US)	US993 18-Dec-1997 12497A
US6232237B1	15-May-2001	Method for fabricating semiconductor device	TAMAOKA EIJI (JP); AOI NOBUO (JP); UEDA TETSUYA (JP)	US206 8-Dec-1998 98298A
US6296780B1	2-Oct-2001	System and method for etching organic anti-reflective coating from a substrate	YAN CHUN (US); YE YAN (US); MA DIANA (US)	US986 8-Dec-1997 42797A
US6537918B2	25-Mar-2003	Method for etching silicon oxynitride and dielectric antireflection coatings	IONOV PAVEL (US); KIM SUNG HO (US); LI DEAN (TW); YAN CHUN (US); WANG JAMES CHANG (US)	US920 31-Jul-2001 25101A

US7651725B2	26-Jan-2010	DEPOSITING A LOW DIELECTRIC CONSTANT FILM BY REACTION OF AN ORGANO SILANE COMPOUND AND AN OXIDIZING GAS; OXIDIZED ORGANO SILANE FILM HAS EXCELLENT BARRIER PROPERTIES FOR USE AS A LINER OR CAP LAYER ADJACENT OTHER DIELECTRIC LAYERS; integrated circuits	YAU WAI FAN (US); CHEUNG DAVID (US); JENG SHIN PUU (US); LIU KUOWEI (US); YU YUNG CHENG (US)	US923 24-Oct-2007 03707A
US6221685B1	24-Apr-2001	Method of producing photovoltaic element	ICHINOSE HIROFUMI (JP); MURAKAMI TSUTOMU (JP); UENO YUKIE (JP)	US203 2-Dec-1998 36198A
US6730541B2	4-May-2004	Wafer-scale assembly of chip-size packages	HEINEN KATHERINE G (US); EDWARDS DARVIN R (US); JACOBS ELIZABETH G (US)	US186 5-Nov-1998 97398A
US6110649A	29-Aug-2000	Process for manufacture of integrated circuit device	CARTER KENNETH RAYMOND (US); HAWKER CRAIG JON (US); HEDRICK JAMES LUPTON (US); MILLER ROBERT DENNIS (US); POGGE BERNHARD (US)	US974 19-Nov-1997 58097A
US7829144B2	9-Nov-2010	Method of forming a metal film for electrode	MATSUSE KIMIHIRO (JP); OTSUKI HAYASHI (JP)	US320 11-Jan-2005 6005A
US6861356B2	1-Mar-2005	Method of forming a barrier film and method of forming wiring structure and electrodes of semiconductor device having a barrier film	MATSUSE KIMIHIRO (JP); OTSUKI HAYASHI (JP)	US225 22-Aug-2002 22802A
US7517462B2	14-Apr-2009	Electrochemical fabrication methods incorporating dielectric materials and/or using dielectric substrates	COHEN ADAM L (US); LOCKARD MICHAEL S (US); KIM KIEUN (US); LE QUI T (US); ZHANG GANG (US); FRODIS URI (US); MCPHERSON DALE S (US); SMALLEY DENNIS R (US)	US290 3-Jan-2005 1405A
US2008230391A1	25-Sep-2008	Methods for Electrochemically Fabricating Structures Using Adhered Masks, Incorporating Dielectric Sheets, and/or Seed layers That Are Partially Removed Via Planarization	LOCKARD MICHAEL S (US); SMALLEY DENNIS R (US); LARSEN WILLA M (US); CHEN RICHARD T (US)	US928 30-Oct-2007 16907A
US6069092A	30-May-2000	ETCHING SILICON DIOXIDE SURFACE WITHIN HEATED CHEMICAL REACTOR USING FLUOROHYDROCARBON PLASMA GENERATED BY APPLYING A RADIO FREQUENCY POWER TO THE LOWER ELECTRODE SUPPORTING THE SUBSTRATE	IMAI SHINICHI (JP); JIWARI NOBUHIRO (JP)	US178 26-Oct-1998 43198A
US6086679A	11-Jul-2000	Deposition systems and processes for transport polymerization and chemical vapor deposition	LEE CHUNG J (US); WANG HUI (US); FOGGIATO GIOVANNI ANTONIO (US)	US958 24-Oct-1997 35297A
US2004234779A1	25-Nov-2004	Fluorinated aromatic precursors	LEE CHUNG J (US); WANG HUI (US); FOGGIATO GIOVANNI ANTONIO (US)	US724 1-Dec-2003 97003A
US7042091B2	9-May-2006	Fluorinated hard mask for micropatterning of polymers	BAKLANOV MIKHAIL RODIONOVICH (BE); VANHAELEMEERSCH SERGE (BE); MAEX KAREN (BE); WAETERLOOS JOOST (BE); DECLERCK GILBERT (BE)	US844 27-Apr-2001 95901A
US6051502A	18-Apr-2000	FORMING BLOCKING LAYER; ANISOTROPICALLY ETCHING CONDUCTIVE SHAPE	FRANKAMP HARLAN H (US); BLALOCK GUY T (US)	US953 20-Oct-1997 91097A

US6060384A	9-May-2000	DEPOSITING A DIELECTRIC LAYER OF HYDROGEN SILSESQUOXANE (HSQ) CONTAINING SI-H BONDS, FORMING AN OPENING IN ABOVE LAYER TO EXPOSE CONDUCTIVE LAYER, TREATING DIELECTRIC LAYER HYDROGEN PLASMA, FILLING THE GAP WITH CONDUCTIVE MATERIAL	CHEN ROBERT C (US); SHIELDS JEFFREY A (US); DAWSON ROBERT (US); TRAN KHANH (US)	US177 23-Oct-1998 48298A
US6464762B1	15-Oct-2002	ELECTROLYTE COMPRISING SODIUM ACID TARTRATE OR POTASSIUM SODIUM TARTRATE AND INDIUM NITRATE; LOW TEMPERATURE, HIGH SPEED PLATING OF RADIATION TRANSPARENT COATINGS HAVING UNIFORM THICKNESS	ARAO KOZO (JP)	US819 21-Mar-2001 03901A
US6821559B2	23-Nov-2004	Method of forming particulate materials for thin-film solar cells	EBERSPACHER CHRIS (US); PAULS KAREN LEA (US)	US898 3-Jul-2001 82301A
US6040418A	21-Mar-2000	Fluorinated polyimides, laminated substrates and polyamic acid solutions	YAMAMOTO TOMOHIKO (JP); TSUMIYAMA TATSUO (JP); SUGIMOTO KOUJI (JP)	US128 4-Aug-1998 66598A
US6971950B2	6-Dec-2005	Polishing silicon wafers	DUDOVICZ WALTER (US)	US689 22-Oct-2003 67803A
US6492732B2	10-Dec-2002	Interconnect structure with air gap compatible with unlanded vias	LEE ELLIS (TW); SUN SHIH WEI (TW)	US849 4-May-2001 66601A
US6194304B1	27-Feb-2001	Semiconductor device and method of fabricating the same	MOROZUMI YUKIO (JP); ASAHINA MICHIO (JP); MORIYA NAOHIRO (JP); MATSUMOTO KAZUKI (JP); SUZUKI EIJI (JP)	US300 27-Apr-1999 37899A
US6645833B2	11-Nov-2003	Method for producing layered structures on a substrate, substrate and semiconductor components produced according to said method	BRENDEL ROLF (DE)	US447 7-Apr-2000 00000A
US6033977A	7-Mar-2000	Dual damascene structure	GUTSCHE MARTIN (US); TOBBEN DIRK (US)	US884 30-Jun-1997 72997A
US5932378A	3-Aug-1999	FORMING RECESSES IN TRANSPARENT SUBSTRATE; THEN OPACITY LAYER; PATTERNING	LEE JUN SEOK (KR)	US416 13-Mar-1998 0098A
US5846884A	8-Dec-1998	Methods for metal etching with reduced sidewall build up during integrated circuit manufacturing	NAEEM MUNIR D (US); BURNS STUART M (US); GRECO NANCY (US); GRECO STEVE (US); GREWAL VIRINDER (DE); LEVINE ERNEST (US); NARITA MASAKI (JP); SPULER BRUNO (US)	US879 20-Jun-1997 72797A
US7056839B2	6-Jun-2006	Method of forming a silica insulation film with a reduced dielectric constant	ENDO KAZUHIKO (JP)	US173 18-Dec-2001 9601A
US2011092066A1	21-Apr-2011	Bumping Electronic Components Using Transfer Substrates	MACKAY JOHN (US)	US911 25-Oct-2010 21010A
US5985762A	16-Nov-1999	Method of forming a self-aligned copper diffusion barrier in vias	GEFFKEN ROBERT M (US); LUCE STEPHEN E (US)	US858 19-May-1997 13997A

US2004103919A1	3-Jun-2004	Single wafer cleaning with ozone	KENNY MICHAEL (US); AEGETER BRIAN (US); BERGMAN ERIC (US); SCRANTON DANA (US)	US721 25-Nov-2003 49503A
US6465363B1	15-Oct-2002	Vacuum processing method and vacuum processing apparatus	KASAI MASARU (JP)	US429 28-Oct-1999 55899A
US6517662B2	11-Feb-2003	Process for making semiconductor chip assembly	CULNANE THOMAS M (US); GAYNES MICHAEL A (US); KODNANI RAMESH R (US); PIERSON MARK V (US); WOYCHIK CHARLES G (US)	US397 16-Sep-1999 73999A
US7011889B2	14-Mar-2006	Polysilsequioxanes used as a low dielectric etch stop	BEDWELL WILLIAM B (US); HACKER NIGEL P (US); LEUNG ROGER Y (US); IWAMOTO NANCY (US); NEDBAL JAN (US); XIE SONGYUAN (US); MORO LORENZA (US); MUKHERJEE SHYAMA P (US)	US789 19-Feb-2002 1902A
US9752247B2	5-Sep-2017	Multi-layer encapsulated structures	COHEN ADAM L (US)	US201 4-Sep-2013 314017 510A
US6337365B1	8-Jan-2002	Electronic/electric components used in clean room and substrate treatment apparatus	MATSUO TAKENOBU (JP); WAKABAYASHI TSUYOSHI (JP); SAITO MISAKO (JP); KOBAYASHI SADA O (JP); WAKAYAMA YOSHIHIDE (JP); IMAFUKU MASAYUKI (JP)	US381 24-Sep-1999 66799A
US5849641A	15-Dec-1998	Methods and apparatus for etching a conductive layer to improve yield	ARNETT DAVID R (US); MUSSER JEFFREY V (US)	US820 19-Mar-1997 53397A
US6153525A	28-Nov-2000	Methods for chemical mechanical polish of organic polymer dielectric films	HENDRICKS NEIL H (US); TOWERY DANIEL L (US)	US234 13-Feb-1998 1598A
US6841525B2	11-Jan-2005	Consisting essentially of phosphoric acid and acetic acid	HINEMAN MAX (US); BLALOCK GUY T (US)	US935 22-Aug-2001 23401A
US6384001B2	7-May-2002	EXPOSING SURFACE TO DILUTE MIXTURE OF PHOSPHORIC ACID AND ACETIC ACID; FOR SEMICONDUCTORS	HINEMAN MAX (US); BLALOCK GUY T (US)	US808 3-Mar-1997 01497A
US2008113257A1	15-May-2008	MEMBRANE ELECTRODE ASSEMBLIES FOR USE IN FUEL CELLS	HAMPDEN SMITH MARK J (US); KODAS TOIVO T (US); ATANASSOV PLAMEN (US); KUNZE KLAUS (US); NAPOLITANO PAUL (US); BHATIA RIMPLE (US); DERICOTTE DAVID E (US); ATANASSOVA PAOLINA (US)	US742 30-Apr-2007 27507A
US2010269634A1	28-Oct-2010	PRODUCTION OF METAL NANOPARTICLES	VANHEUSDEN KAREL (US); KUNZE KLAUS (US); KIM HYUNGRK (US); STUMP AARON D (US); SCHULT ALLEN B (US); HAMPDEN SMITH MARK J (US); EDWARDS CHUCK (US); JAMES ANTHONY R (US); CARUSO JAMES (US); KODAS TOIVO T (US); HAUBRICH SCOTT THOMAS (US); KOWALSKI MARK H (US)	US829 2-Jul-2010 65810A
US2006160373A1	20-Jul-2006	Processes for planarizing substrates and encapsulating printable electronic features	KOWALSKI MARK H (US); VANHEUSDEN KAREL (US); EDWARDS CHUCK (US)	US331 13-Jan-2006 23906A
US7226547B2	5-Jun-2007	Electroluminescent phosphor powders, methods for making phosphor powders and devices incorporating same	HAMPDEN SMITH MARK J (US); KODAS TOIVO T (US); CARUSO JAMES (US); POWELL QUINT H (US); KUNZE KLAUS (US); SKAMSER DANIEL J (US)	US410 24-Apr-2006 70006A

US7713899B2	11-May-2010	Method of producing membrane electrode assemblies for use in proton exchange membrane and direct methanol fuel cells	HAMPDEN SMITH MARK J (US); KODAS TOIVO T (US); ATANASSOVA PAOLINA (US); BHATIA RIMPLE (US); MIESEM ROSS A (US); NAPOLITANO PAUL (US); RICE GORDON L (US)	US428 3-Jul-2006 53306A
US7599165B2	6-Oct-2009	Palladium-containing particles, method and apparatus of manufacturing palladium-containing devices made therefrom	HAMPDEN SMITH MARK J (US); KODAS TOIVO T (US); POWELL QUINT H (US); SKAMSER DANIEL J (US); CARUSO JAMES (US); CHANDLER CLIVE D (US)	US671 6-Feb-2007 96907A
US7553512B2	30-Jun-2009	Applying flowable precursor composition to organic substrate wherein precursor comprises molecular precursor to conductive phase and powder of insulating material, heating substrate to convert molecular precursor to conductive phase	KODAS TOIVO T (US); HAMPDEN SMITH MARK J (US); VANHEUSDEN KAREL (US); DENHAM HUGH (US); STUMP AARON D (US); SCHULT ALLEN B (US); ATANASSOVA PAOLINA (US); KUNZE KLAUS (US)	US286 1-Nov-2002 36302A
US2006043346A1	2-Mar-2006	Precursor compositions for the deposition of electrically conductive features	KODAS TOIVO T (US); HAMPDEN SMITH MARK J (US); VANHEUSDEN KAREL (US); DENHAM HUGH (US); STUMP AARON D (US); SCHULT ALLEN B (US); ATANASSOVA PAOLINA (US); KUNZE KLAUS (US)	US203 12-Aug-2005 43505A
US2007122932A1	31-May-2007	Methods and compositions for the formation of recessed electrical features on a substrate	KODAS TOIVO T (US); HAMPDEN SMITH MARK J (US); VANHEUSDEN KAREL (US); DENHAM HUGH (US); STUMP AARON D (US); SCHULT ALLEN B (US); ATANASSOVA PAOLINA (US); KUNZE KLAUS (US)	US642 21-Dec-2006 66506A
US7316790B2	8-Jan-2008	Securing a document by applying a metal sulfide phosphor powder containing particles that are spherical and have an average particle size of 0.3 to not greater than 10 mu m.; up-converter particles; emits at least two different wavelengths	HAMPDEN SMITH MARK J (US); KODAS TOIVO T (US); CARUSO JAMES (US); SKAMSER DANIEL J (US); POWELL QUINT H (US); KUNZE KLAUS (US)	US397 3-Apr-2006 93806A
US7727630B2	1-Jun-2010	Coated nickel-containing powders	KODAS TOIVO T (US); HAMPDEN SMITH MARK J (US); CARUSO JAMES (US); POWELL QUINT H (US); SKAMSER DANIEL J (US); CHANDLER CLIVE D (US)	US134 5-Jun-2008 00608A
US6261938B1	17-Jul-2001	Fabrication of sub-micron etch-resistant metal/semiconductor structures using resistless electron beam lithography	BEAUVAIS JACQUES (CA); DROUIN DOMINIQUE (CA); LAVALLEE ERIC (CA)	US156 17-Sep-1998 00998A
US6702910B2	9-Mar-2004	Process for producing a chip	NOGUCHI HAYATO (JP); EBE KAZUYOSHI (JP)	US940 28-Aug-2001 99301A
US6271273B1	7-Aug-2001	DISPERSION OF ORGANO POLYSILICA DIELECTRIC MATERIAL WITH DISPERSION OF CROSSLINKABLE POLYMER, CURING ORGANOPOLYSILICA AND CROSSLINKING	YOU YUJIAN (US); LAMOLA ANGELO A (US); GORE ROBERT H (US); GALLAGHER MICHAEL K (US); ANNAN NIKOI (US)	US685 10-Oct-2000 75000A
US6849373B2	1-Feb-2005	Light absorber, crosslinking	PAVELCHEK EDWARD K (US); DOCANTO MANUEL (US)	US904 14-Jul-2001 58701A
US6291619B1	18-Sep-2001	HEAT RESISTANCE	MAEKAWA YASUNARI (JP); MIWA TAKAO (JP); UENO TAKUMI (JP); OKABE YOSHIKI (JP)	US355 29-Jul-1999 50699A
US7312415B2	25-Dec-2007	Plasma method with high input power	OHMI TADAHIRO (JP); NITTA TAKAHISA (JP); HIRAYAMA MASAKI (JP); TAKANO HARUYUKI (JP); KAIWARA RYU (JP)	US706 10-Nov-2003 42303A

US6190937B1	20-Feb-2001	Method of producing semiconductor member and method of producing solar cell	NAKAGAWA KATSUMI (JP); YONEHARA TAKAO (JP); NISHIDA SHOJI (JP); SAKAGUCHI KIYOFUMI (JP)	US999 29-Dec-1997 13297A
US2003203547A1	30-Oct-2003	Process for producing semiconductor article	SAKAGUCHI KIYOFUMI (JP); YONEHARA TAKAO (JP); NISHIDA SHOJI (JP); YAMAGATA KENJI (JP)	US338 9-Jan-2003 84703A
US6072147A	6-Jun-2000	Plasma processing system	KOSHIISHI AKIRA (JP); OYABU JUN (JP)	US982 2-Dec-1997 38897A
US6068787A	30-May-2000	Composition and slurry useful for metal CMP	GRUMBINE STEVEN K (US); STREINZ CHRISTOPHER C (US); MUELLER BRIAN L (US)	US891 11-Jul-1997 46897A
US6313233B1	6-Nov-2001	Curable resin composition cured products	KUROSAWA TAKAHIKO (JP); YAMADA KINJI (JP); MATSUBARA MINORU (JP); INOUE YASUTAKE (JP); SHINODA TOMOTAKA (JP); GOTOU KOUHEI (JP)	US447 29-Nov-1999 95299A
US6348099B1	19-Feb-2002	Methods and apparatus for depositing premetal dielectric layer at sub-atmospheric and high temperature conditions	XIA LI QUN (US); YIEH ELLIE (US); NEMANI SRINIVAS (US)	US334 16-Jun-1999 43799A
US5812403A	22-Sep-1998	Methods and apparatus for cleaning surfaces in a substrate processing system	FONG GARY (US); XIA LI QUN (US); NEMANI SRINIVAS (US); YIEH ELLIE (US)	US748 13-Nov-1996 09596A
US6099647A	8-Aug-2000	Methods and apparatus for forming ultra-shallow doped regions using doped silicon oxide films	YIEH ELLIE (US); XIA LI QUN (US); GEE PAUL (US); NGUYEN BANG (US)	US409 30-Sep-1999 76399A
US5935334A	10-Aug-1999	Substrate processing apparatus with bottom-mounted remote plasma system	FONG GARY (US); SILVESTRE IRWIN (US)	US747 13-Nov-1996 83096A
US6444037B1	3-Sep-2002	Chamber liner for high temperature processing chamber	FRANKEL JONATHAN (US); SIVARAMAKRISHNAN VISWESWAREN (US)	US746 13-Nov-1996 74896A
US6544638B2	8-Apr-2003	Electronic chip package	FISCHER PAUL J (US); KORLESKI JOSEPH E (US)	US950 10-Sep-2001 13101A
US6021564A	8-Feb-2000	Method for reducing via inductance in an electronic assembly and article	HANSON DAVID A (US)	US159 23-Sep-1998 14098A
US5841102A	24-Nov-1998	Multiple pulse space processing to enhance via entrance formation at 355 nm	NODDIN DAVID B (US)	US744 8-Nov-1996 41396A
US6184577B1	6-Feb-2001	Electronic component parts device	TAKEMURA KENZO (JP); WATANABE ITSUO (JP); NAGAI AKIRA (JP); WATANABE OSAMU (JP); KOJIMA KAZUYOSHI (JP); NAKASO AKISHI (JP); YAMAMOTO KAZUNORI (JP); TSURU YOSHIYUKI (JP); INADA TEIICHI (JP); SHIMADA YASUSHI (JP)	US308 30-Aug-1999 52599A
US2005218517A1	6-Oct-2005	Semiconductor flip-chip package and method for the fabrication thereof	CAPOTE MIGUEL A (US); ZHOU ZHIMING (US); ZHU XIAOQI (US); ZHOU LIGUI (US)	US855 28-May-2004 70804A

US5773197A	30-Jun-1998	Integrated circuit device and process for its manufacture	CARTER KENNETH RAYMOND (US); HEDRICK JAMES LUPTON (US); MILLER ROBERT DENNIS (US)	US739 13496A	28-Oct-1996
US5767014A	16-Jun-1998	Integrated circuit and process for its manufacture	HAWKER CRAIG JON (US); HEDRICK JAMES LUPTON (US); MILLER ROBERT DENNIS (US)	US739 13396A	28-Oct-1996
US6043167A	28-Mar-2000	Method for forming low dielectric constant insulating film	LEE YOUNG HIE (US); KIM DONG SUN (US); PARK JIN WON (KR)	US947 50397A	10-Oct-1997
US5816158A	6-Oct-1998	Inverted stamping process	ROSS RICHARD J (US)	US952 33698A	2-Feb-1998
US6162725A	19-Dec-2000	Process of patterning conductive layer into electrode through lift-off using photo-resist mask imperfectly covered with the conductive layer	TANAKA YOSHITO (JP)	US933 07797A	18-Sep-1997
US5897336A	27-Apr-1999	Direct chip attach for low alpha emission interconnect system	BROUILLETTE GUY PAUL (CA); DANOVITCH DAVID HIRSCH (CA); LIEHR MICHAEL (US); MOTSIFF WILLIAM THOMAS (US); ROLDAN JUDITH MARIE (US); SAMBUCETTI CARLOS JUAN (US); SARAF RAVI F (US)	US864 19697A	28-May-1997
US2004134873A1	15-Jul-2004	Abrasive-free chemical mechanical polishing composition and polishing process containing same	YAO LI (US); SMALL ROBERT J (US)	US689 04303A	21-Oct-2003
US9234293B2	12-Jan-2016	Electrolytic copper process using anion permeable barrier	BASKARAN RAJESH (US); BATZ JR ROBERT W (US); KIM BIOH (US); RITZDORF THOMAS L (US); KLOCKE JOHN LEE (US); HANSON KYLE M (US)	US201 414507 692A	6-Oct-2014
US6027958A	22-Feb-2000	Transferred flexible integrated circuit	VU DUY PHACH (US); DINGLE BRENDA (US); CHEONG NGWE K (US)	US680 21096A	11-Jul-1996
US5936845A	10-Aug-1999	IC package and IC probe card with organic substrate	SOEJIMA KOJI (JP); TAKAHASHI NOBUAKI (JP); SENBA NAOJI (JP); SHIMADA YUZO (JP)	US880 39097A	23-Jun-1997
US8480804B2	9-Jul-2013	Thin film, method and apparatus for forming the same, and electronic component incorporating the same	HONDA KAZUYOSHI (JP); ODAGIRI MASARU (JP); TAKAHASHI KIYOSHI (JP); ECHIGO NORIYASU (JP); SUNAGARE NOBUKI (JP)	US761 03610A	15-Apr-2010
US5950106A	7-Sep-1999	Method of patterning a metal substrate using spin-on glass as a hard mask	MAY CHARLES E (US); DAWSON ROBERT (US)	US647 51096A	14-May-1996
US2003196599A1	23-Oct-2003	Apparatus for clamping a planar substrate	SUN HOI CHEONG STEVE (US); BRYCKI BOGDAN (US)	US423 78503A	25-Apr-2003
US6716529B2	6-Apr-2004	Adhesive sheet for semiconductor connecting substrate, adhesive-backed tape for TAB, adhesive-backed tape for wire bonding connection, semiconductor connecting substrate and semiconductor device	SAWAMURA YASUSHI (JP); KIGOSHI SHOJI (JP); HATANO TAKU (JP); KONISHI YUKITSUNA (JP); ANDO YOSHIO (JP)	US940 51301A	29-Aug-2001
US6248852B1	19-Jun-2001	Germanosiloxane materials and optical components comprising the same	RISEN JR WILLIAM M (US); WANG YONG ZHONG (US); HONORE ATHENA (US)	US913 9398A	1-Oct-1998

US6582982B2	24-Jun-2003	Composition for wiring, a wiring using the composition, manufacturing method thereof, a display using the wiring and a manufacturing method thereof	JEONG CHANG OH (KR); KIM YANG SUN (KR); HUR MYUNG KOO (KR); TAK YOUNG JAE (KR); HONG MUN PYO (KR); KIM CHI WOO (KR); KIM JANG SOO (KR); YOU CHUN GI (KR)	US962 26-Sep-2001 21001A
US6017144A	25-Jan-2000	Method and apparatus for depositing highly oriented and reflective crystalline layers using a low temperature seeding layer	GUO TED TIE (US); NAIK MEHUL BHAGUBHAI (US); CHEN LIANG YU (US); MOSELY RODERICK CRAIG (US); BEINGLASS ISRAEL (US)	US736 24-Oct-1996 62996A
US7041771B1	9-May-2006	comprises thermosetting epoxy resin, crosslinking agent (such as methylhexahydrophthalic anhydride) for removing oxide coatings, and tin octanoate catalyst; for electrically connecting metal bond sites in electronics	KIRSTEN KENNETH JOHN (US)	US644 28-May-1996 91296A
US5922411A	13-Jul-1999	SILAZANE-BASED POLYMER, AND AT LEAST ONE CERAMIC-TRANSFORMATION PROMOTING AGENT SELECTED FROM THE GROUP CONSISTING OF AN AMINE COMPOUND, AN ACID COMPOUND AND PEROXIDE; STEAM.	SHIMIZU YASUO (JP); MATSUO HIDEKI (JP); YAMADA KAZUHIRO (JP)	US793 7-Mar-1997 94397A
US5762259A	9-Jun-1998	Method for forming bumps on a substrate	HUBACHER ERIC M (US); HOEBENER KARL G (US)	US848 1-May-1997 79297A
US5952243A	14-Sep-1999	Removal rate behavior of spin-on dielectrics with chemical mechanical polish	FORESTER LYNN (US); CHOI DONG K (US); HOSSEINI REZA (US)	US669 24-Jun-1996 18496A
US2004076764A1	22-Apr-2004	Electron-beam processed films for microelectronics structures	FORESTER LYNN (US); HENDRICKS NEIL H (US); CHOI DONG KYU (US)	US726 2-Dec-2003 15403A
US6223429B1	1-May-2001	Method of production of semiconductor device	KANEDA AIZOU (JP); YASUDA MASAOKI (JP); WATANABE ITSUO (JP); OHTA TOMOHISA (JP); INOUE FUMIO (JP); TSUBOMATSU YOSHIKI (JP); YAMAZAKI TOSHIO (JP); OHATA HIROTO (JP); TAKEMURA KENZO (JP); NAGAI AKIRA (JP); WATANABE OSAMU (JP); SHIOZAWA NAOYUKI (JP); KOJIMA KAZUYOSHI (JP); TANAKA TOSHIKI (JP); YAMAMOTO KAZUNORI (JP)	US981 30-Jul-1998 50998A
US5674758A	7-Oct-1997	Silicon on insulator achieved using electrochemical etching	MCCARTHY ANTHONY M (US)	US484 6-Jun-1995 06295A
US5804882A	8-Sep-1998	Semiconductor device having a semiconductor chip electrically connected to a wiring substrate	TSUKAGOSHI ISAO (JP); MATSUOKA HIROSHI (JP); HIROSAWA YUKIHISA (JP); MIKAMI YOSHIKATSU (JP); DOKOCHI HISASHI (JP)	US651 21-May-1996 95496A
US6607991B1	19-Aug-2003	Method for curing spin-on dielectric films utilizing electron beam radiation	LIVESAY WILLIAM R (US); ROSS MATTHEW F (US); RUBIALES ANTHONY L (US); THOMPSON HEIKE (US); WONG SELMER (US); MARLOWE TREY (US); NARCY MARK (US)	US474 29-Dec-1999 39999A
US5792592A	11-Aug-1998	Photosensitive liquid precursor solutions and use thereof in making thin films	UCHIDA HIROTO (US); SOYAMA NOBUYUKI (US); KAGEYAMA KENSUKE (JP); OGI KATSUMI (JP); SCOTT MICHAEL C (US); MCMILLAN LARRY D (US); PAZ DE ARAUJO CARLOS A (US)	US653 24-May-1996 44496A

US5685939A	11-Nov-1997	Process for making a Z-axis adhesive and establishing electrical interconnection therewith	WOLK MARTIN B (US); ISBERG THOMAS A (US); KROPP MICHAEL A (US); DOWER WILLIAM V (US); GERBER JOEL A (US)	US402 02895A	10-Mar-1995
US6245671B1	12-Jun-2001	Semiconductor processing method of forming an electrically conductive contact plug	MATHEWS VIJU K (US); JENG NANSENG (US); FAZAN PIERRE C (US)	US243 23399A	1-Feb-1999
US5672260A	30-Sep-1997	Process for selective application of solder to circuit packages	CAREY CHARLES FRANCIS (US); FALLON KENNETH MICHAEL (US); MARKOVICH VOYA RISTA (US); POWELL DOUGLAS OLIVER (US); VLASAK GARY PAUL (US); ZARR RICHARD STUART (US)	US633 32296A	17-Apr-1996
US5908334A	1-Jun-1999	Electrical connector for power transmission in an electrostatic chuck	CHEN AIHUA (US); PARKHE VIJAY (US); EDELSTEIN SERGIO (US)	US881 52897A	24-Jun-1997
US5641996A	24-Jun-1997	Semiconductor unit package, semiconductor unit packaging method, and encapsulant for use in semiconductor unit packaging	OMOYA KAZUNORI (JP); OOBAYASHI TAKASHI (JP); SAKURAI WATARU (JP); HARADA MITSURU (JP); BESSHO YOSHIHIRO (JP)	US593 67596A	29-Jan-1996
US5866441A	2-Feb-1999	Inverted chip bonded module with high packaging efficiency	PACE BENEDICT G (US)	US767 16096A	16-Dec-1996
US5814558A	29-Sep-1998	Interconnect capacitance between metal leads	JENG SHIN PUU (US); HAVEMANN ROBERT H (US)	US658 40196A	4-Jun-1996
US5997999A	7-Dec-1999	Sintered body for manufacturing ceramic substrate	HORIUCHI MICHIO (JP); TAKEUCHI YUKIHARU (JP); HARAYAMA YOICHI (JP)	US957 30697A	23-Oct-1997
US6000339A	14-Dec-1999	Material for forming silica-base coated insulation film, process for producing the material, silica-base insulation film, semiconductor device, and process for producing the device	MATSUZAWA JUN (JP)	US765 24096A	18-Dec-1996
US5556812A	17-Sep-1996	MULTILAYER MODULES WITH DIELECTRICS AND CONDUCTING TRACKS EMBEDDING THERIN WITH POLYMERS ON NONCONDUCTORS	LEUSCHNER RAINER (DE); AHNE HELLMUT (DE); BIRKLE SIEGFRIED (DE); HAMMERSCHMIDT ALBERT (DE); SEZI RECAI (DE); NOLL TOBIAS (DE); DUMOULIN ANN (BE)	US495 24695A	27-Jun-1995
US5620910A	15-Apr-1997	Method for producing semiconductor device with a gate insulating film consisting of silicon oxynitride	TERAMOTO SATOSHI (JP)	US494 56095A	22-Jun-1995
US6220202B1	24-Apr-2001	Apparatus for producing thin films by low temperature plasma-enhanced chemical vapor deposition	FOSTER ROBERT F (US); HILLMAN JOSEPH T (US); LEBLANC RENE E (US)	US113 25298A	10-Jul-1998
US5747880A	5-May-1998	Interconnect structure with an integrated low density dielectric	HAVEMANN ROBERT H (US); JENG SHIN PUU (US); GNADE BRUCE E (US); CHO CHIH CHEN (US)	US751 90196A	18-Nov-1996
US5712192A	27-Jan-1998	Process for connecting an electrical device to a circuit substrate	LEWIS ROBERT LEE (US); SEBESTA ROBERT DAVID (US); WAITS DANIEL MARTIN (US)	US233 19394A	26-Apr-1994
US5688408A	18-Nov-1997	Multilayer printed wiring board	TSURU YOSHIYUKI (JP); ARIKE SHIGEHARU (JP); SUGIYAMA TAKASHI (JP); MIYASHITA SHINJIROU (JP); SUZUKI TAKAYUKI (JP)	US674 87696A	2-Jul-1996

US5476816A	19-Dec-1995	Process for etching an insulating layer after a metal etching step	MAUTZ KARL E (US); CADENHEAD JEFFREY G (US); ALLEN THOMAS M (US); STEVENS H ADAM (US)	US219 12394A	28-Mar-1994
US5576248A	19-Nov-1996	Group IV semiconductor thin films formed at low temperature using nanocrystal precursors	GOLDSTEIN AVERY N (US)	US217 16094A	24-Mar-1994
US5508228A	16-Apr-1996	Compliant electrically connective bumps for an adhesive flip chip integrated circuit device and methods for forming same	NOLAN ERNEST R (US); DUANE DIANA C (US); HERDER TODD H (US); BISHOP THOMAS A (US); TRAN KIMCUC T (US); FROELICH ROBERT W (US); GERMAN RANDY L (US); NELSON RICHARD D (US); LEE CHUNG J (US); BREEN MARK R (US); KESWICK KATHRYN V (US)	US195 43494A	14-Feb-1994
US5753132A	19-May-1998	Method of making electrostatic chuck with conformal insulator film	SHAMOUILIAN SHAMOUIL (US); SOMEKH SASSON (US); LEVINSTEIN HYMAN J (US); BIRANG MANOOCHER (US); SHERSTINSKY SEMYON (US); CAMERON JOHN F (US)	US725 48296A	4-Oct-1996
US5736783A	7-Apr-1998	High frequency microelectronics package	WEIN DEBORAH S (US); ANDERSON PAUL M (US); LINDNER ALAN W (US); GOETZ MARTIN (US); BABIARZ JOSEPH (US); GOING TIMOTHY (US)	US645 84896A	14-May-1996
US5728630A	17-Mar-1998	Method of making a semiconductor device	NISHIMURA HIROYUKI (JP); ADACHI HIROSHI (JP); ADACHI ETSUSHI (JP); YAMAMOTO SHIGEYUKI (JP); MINAMI SHINTARO (JP); HARADA SHIGERU (JP); TAJIMA TORU (JP); HAGI KIMIO (JP)	US743 19096A	5-Nov-1996
US5481138A	2-Jan-1996	Structure and a method for repairing electrical lines	ECONOMIKOS LAERTIS (US); SURPRENANT RICHARD P (US)	US249 41394A	26-May-1994
US7416907B2	26-Aug-2008	Semiconductor device and method for forming the same	YAMAZAKI SHUNPEI (JP); ZHANG HONGYONG (JP)	US900 46204A	28-Jul-2004
US5470693A	28-Nov-1995	Method of forming patterned polyimide films	SACHDEV KRISHNA G (US); WHITAKER JOEL R (US); AHMAD UMAR M (US)	US837 50592A	18-Feb-1992
US5541005A	30-Jul-1996	Large ceramic article and method of manufacturing	BEZAMA RASCHID J (US); CASEY JON A (US); ECKER MARIO E (US); FAROOQ SHAJI (US); FRANTZ IRENE S (US); FRASE KATHERINE G (US); GABRIELS DAVID H (US); HERRON LESTER W (US); KNICKERBOCKER JOHN U (US); KNICKERBOCKER SARAH H (US); NATARAJAN GOVINDARAJAN (US); THOMSON JOHN (US); TING YEE MING (US); TRACY SHARON L (US); TRONCILLITO ROBERT M (US); SURA VIVEK M (US); WALL DONALD R (US); YEN GIAI V (US)	US438 82595A	11-May-1995
US5478445A	26-Dec-1995	Separating anode from cathode by ion exchange membrane; for deposition of group 2B, 6B semiconductors, photovoltaic cells	BARKER JEREMY (US); MARSHALL RODNEY J (GB); SADEGHI MEHRAN (GB)	US211 77594A	11-Jul-1994
US5137836A	11-Aug-1992	Method of manufacturing a repairable multi-chip module	LAM MAN K (US)	US704 94191A	23-May-1991

US5442239A	15-Aug-1995	Structure and method for corrosion and stress-resistant interconnecting metallurgy	DIGIACOMO GIULIO (US); CAMMARANO ARMANDO S (US); DIPAOLO NUNZIO (US)	US955 09192A	1-Oct-1992
US5108541A	28-Apr-1992	Processes for electrically conductive decals filled with inorganic insulator material	SCHNEIDER MARK S (US); ACOCELLA JOHN (US); HERRON LESTER W (US); KORDUS MARK R (US); WIRTZ LOUIS H (US)	US665 63391A	6-Mar-1991
US5116459A	26-May-1992	Multilayer package, circuits	KORDUS MARK R (US); SCHNEIDER MARK S (US); WIRTZ LOUIS H (US)	US665 49791A	6-Mar-1991
US5114754A	19-May-1992	Passivation of metal in metal/polyimide structures	CRONIN JOHN E (US); FARRAR SR PAUL A (US); LINDE HAROLD G (US); PREVITI KELLY ROSEMARY A (US)	US641 03691A	14-Jan-1991
US5143750A	1-Sep-1992	METHOD OF MANUFACTURING CHEMICALLY ADSORBED FILM	YAMAGATA YOSHIKAZU (JP); MINO NORIHISA (JP); OGAWA KAZUFUMI (JP); SOGA MAMORU (JP)	US810 11491A	19-Dec-1991
US7528098B2	5-May-2009	Semiconductor process residue removal composition and process	LEE WAI MUN (US); IP KATY (US); DINH XUAN DUNG (US); MALONEY DAVID JOHN (US)	US995 23904A	24-Nov-2004
US6156661A	5-Dec-2000	CONTACTING METAL OR DIELECTRIC SURFACE WITH AQUEOUS SOLUTION WITH ACIDIC PH CONTAINING ORGANIC ACID AND HYDROXYL AMINE TO REMOVE CHEMICAL RESIDUES	SMALL ROBERT J (US)	US384 94699A	27-Aug-1999
US5114757A	19-May-1992	ENHANCEMENT OF POLYIMIDE ADHESION ON REACTIVE METALS	LINDE HAROLD G (US); PREVITI KELLY ROSEMARY A (US)	US604 70290A	26-Oct-1990
US5688617A	18-Nov-1997	Phase shift layer-containing photomask, and its production and correction	MIKAMI KOICHI (JP); MIYASHITA HIROYUKI (JP); TAKAHASHI YOICHI (JP); FUJITA HIROSHI (JP); KURIHARA MASA AKI (JP)	US644 85696A	9-May-1996
US5043244A	27-Aug-1991	Process for defined etching of substrates	CAIRNCROSS ALLAN (US); THAYER II CHESTER A (US)	US580 22990A	10-Sep-1990
US5161093A	3-Nov-1992	MULTIPLE LAMINATION HIGH DENSITY INTERCONNECT PROCESS AND STRUCTURE EMPLOYING A VARIABLE CROSSLINKING ADHESIVE	GORCZYCA THOMAS B (US); WEAVER JR STANTON E (US); WOJNAROWSKI ROBERT J (US)	US546 95990A	2-Jul-1990
US5229257A	20-Jul-1993	PROCESS FOR FORMING MULTI-LEVEL COPLANAR CONDUCTOR/INSULATOR FILMS EMPLOYING PHOTSENSITIVE POLYIMIDE POLYMER COMPOSITIONS	CRONIN JOHN E (US); KAANTA CARTER W (US); LEE PEI ING P (US); PREVITI KELLY ROSEMARY A (US); RYAN JAMES G (US); YOON JUNG H (US)	US516 41590A	30-Apr-1990
US5117279A	26-May-1992	SEMICONDUCTOR DEVICE HAVING A LOW TEMPERATURE UV-CURED EPOXY SEAL	KARPMAN MAURICE S (US)	US498 15690A	23-Mar-1990
US5320983A	14-Jun-1994	Spin-on glass processing technique for the fabrication of semiconductor devices	OUELLET LUC (CA)	US930 61592A	30-Sep-1992
US4959119A	25-Sep-1990	CARBON DIOXIDE LASER	LANTZER THOMAS D (US)	US443 30189A	29-Nov-1989

US5558795A	24-Sep-1996	Module encapsulation by induction heating	FRANK VLASTIMIL (US)	US876 30-Apr-1992 34592A
US5169310A	8-Dec-1992	Hermetic package for an electronic device and method of manufacturing same	CHANCE DUDLEY A (US); GOLAND DAVID B (US); TONG HO MING (US)	US199 11-Sep-1991 107578 63
US5180690A	19-Jan-1993	Method of forming a layer of doped crystalline semiconductor alloy material	CZUBATYJ WOLODYMYR (US); OVSHINSKY STANFORD R (US); WICKER GUY C (US); BEGLAU DAVID (US); HIMMLER RONALD (US); JABLONSKI DAVID (US); GUHA SUBHENDU (US)	US551 9-Jul-1990 68490A
US5958268A	28-Sep-1999	Removal of material by polarized radiation	ENGELSBERG AUDREY C (US); PARKER WILLIAM P (US)	US609 1-Mar-1996 44996A
US5643472A	1-Jul-1997	PROVIDING FLOW OF INERT GAS ACROSS UNDESIRE D MATERIAL ON SUBSTRATE SURFACE, IRRADIATING WITH ENERGETIC PHOTONS TO RELEASE UNDESIRE D MATERIAL WITHOUT CHANGING PROPERTIES OF SUBSTRATE	ENGELSBERG AUDREY C (US); DEHAIS JOSEPH A (US)	US306 19-Sep-1994 43194A
US5035782A	30-Jul-1991	Method for the formation of monomolecular adsorption films or built-up films of monomolecular layers using silane compounds having an acetylene or diacetylene bond	TAMURA HIDEHARU (JP); OGAWA KAZUFUMI (JP)	US371 27-Jun-1989 89389A
US5234791A	10-Aug-1993	RADIATION-CURABLE COMPOSITION AND RADIATION-SENSITIVE RECORDING MATERIAL PREPARED THEREFROM FOR USE WITH HIGH-ENERGY RADIATION	DAMMEL RALPH (DE); DOESSEL KARL FRIEDRICH (DE); LINGNAU JUERGEN (DE); THEIS JUERGEN (DE)	US369 21-Jun-1989 67789A
US4896464A	30-Jan-1990	Method of forming upstanding conductive terminals of a ceramic structure	KIM JUNGIHL (US); LOGUE JOSEPH C (US); RITSKO JOHN J (US); SHAW ROBERT R (US); WALKER GEORGE F (US)	US207 15-Jun-1988 08588A
US5277725A	11-Jan-1994	Process for fabricating a low dielectric composite substrate	ACOCCELLA JOHN (US); AGOSTINO PETER A (US); BAISE ARNOLD I (US); BATES RICHARD A (US); BRYANT RAY M (US); CASEY JON A (US); CLARKE DAVID R (US); CZORNYJ GEORGE (US); DAM ALLEN J (US); DAVID LAWRENCE D (US); DIVAKARUNI RENUKA S (US); DUNKEL WERNER E (US); GIRI AJAY P (US); HSIA LIANG CHOO (US); HUMENIK JAMES N (US); KANDETZKE STEVEN M (US); KIRBY DANIEL P (US); KNICKERBOCKER JOHN U (US); KNICKERBOCKER SARAH H (US); MASTREANI ANTHONY (US); MATTS AMY T (US); NUFER ROBERT W (US); PERRY CHARLES H (US); REDDY SRINIVASA S N (US); SCILLA SALVATORE J (US); TAKACS MARK A (US); WIGGINS LOVELL B (US)	US881 11-May-1992 44892A
US4965092A	23-Oct-1990	Screen printing, firing, drying, cooling	HAYDUK JR EDWARD A (US); YEXT WALTER F (US); TASCHLER DAVID R (US)	US345 28-Apr-1989 37989A
US5403697A	4-Apr-1995	Comprising compound which forms acid after high energy radiation and an acid-cleavable compound, polymeric binder	DOESSEL KARL FRIEDRICH (DE); DAMMEL RALPH (DE); LINGNAU JUERGEN (DE)	US881 7-May-1992 32992A

US4907038A	6-Mar-1990	Langmuir Blodgett ultrathin membrane of polyfumarate	SHIGEHARA KIYOTAKA (JP); YAMADA AKIRA (JP); HARA MASAHICO (JP); NAKAHAMA HIDENARI (JP); MIYATA SEIZO (JP); MURATA YOSHISHIGE (JP)	US478 8787A	8-May-1987
US4835593A	30-May-1989	Multilayer thin film metallurgy for pin brazing	ARNOLD ANTHONY F (US); CORSO JOSEPH A (US); KAPUR SHUKLA (US); LANGE WALTER F (US); SHIH DA YUAN (US)	US860 40886A	7-May-1986
US4692205A	8-Sep-1987	Silicon-containing polyimides as oxygen etch stop and dual dielectric coatings	SACHDEV KRISHNA G (US); KWONG RANEE W (US); GUPTA MANI R (US); CHACE MARK S (US); SACHDEV HARBANS S (US)	US824 89386A	31-Jan-1986
US4700473A	20-Oct-1987	Method of making an ultra high density pad array chip carrier	FREYMAN BRUCE J (US); DORINSKI DALE (US); SHURBOFF JOHN (US)	US902 81986A	2-Sep-1986
US4622240A	11-Nov-1986	Process for manufacturing thick-film electrical components	YEXT WALTER F (US); HAYDUK EDWARD A (US); FISHER CLARK K (US)	US797 09285A	12-Nov-1985
US6956174B2	18-Oct-2005	Tip structures	KHANDROS IGOR Y (US); MATHIEU GAETAN L (US)	US295 26999A	20-Apr-1999
US2006286828A1	21-Dec-2006	Contact Structures Comprising A Core Structure And An Overcoat	KHANDROS IGOR Y (US)	US461 74906A	1-Aug-2006
US7335528B2	26-Feb-2008	Methods of nanotube films and articles	RUECKES THOMAS (US); SEGAL BRENT M (US)	US775 204A	8-Dec-2004
US4613560A	23-Sep-1986	PHOTORESISTS, SEMICONDUCTORS	DUEBER THOMAS E (US); SCHEIBER DAVID H (US); SIMMONS III HOWARD E (US)	US687 46084A	28-Dec-1984
US4639277A	27-Jan-1987	Semiconductor material on a substrate, said substrate comprising, in order, a layer of organic polymer, a layer of metal or metal alloy and a layer of dielectric material	HAWKINS GILBERT A (US)	US626 84884A	2-Jul-1984
US4671928A	9-Jun-1987	Method of controlling the sintering of metal particles	HERRON LESTER W (US); MASTER RAJ N (US); NUFER ROBERT W (US)	US604 25984A	26-Apr-1984
US4530739A	23-Jul-1985	Method of fabricating an electroplated substrate	HANAK JOSEPH J (US); NATH PREM (US); IZU MASATSUGU (US); YOUNG JAMES (US)	US588 01384A	9-Mar-1984
US4555414A	26-Nov-1985	CURED RESIN, PRINTED CIRCUITS	HOOVER MERWIN F (US); SALAMONE ANN B (US); VANDEBULT JAN (US)	US485 32883A	15-Apr-1983
US4431685A	14-Feb-1984	APPLYING A LAYER OF NOBLE METAL BETWEEN A METALLIC SURFACE AND A PHOTORESIST AND ELECTROLESSLY DEPOSITING A METAL	CANESTARO MICHAEL J (US); MCBRIDE DONALD G (US); WELSH JOHN A (US)	US394 58882A	2-Jul-1982
US4396458A	2-Aug-1983	Method for forming planar metal/insulator structures	PLATTER VALERIA ; ROTHMAN LAURA B ; SCHAIBLE PAUL M ; SCHWARTZ GERALDINE C	US333 19681A	21-Dec-1981
US4756756A	12-Jul-1988	Forming of thick-layer, hybrid electronic printed circuits	CASSAT ROBERT (FR)	US705 72685A	26-Feb-1985

US4272561A	9-Jun-1981	POLYMER COATING, MASKING	ROTHMAN LAURA B ; TOTTA PAUL A ; WHITE JAMES F	US434 29-May-1979 1679A
US4234367A	18-Nov-1980	Method of making multilayered glass-ceramic structures having an internal distribution of copper-based conductors	HERRON LESTER W ; MASTER RAJ N ; TUMMALA RAO R	US231 23-Mar-1979 1279A
US4208257A	17-Jun-1980	Method of forming an interconnection	HARADA SEIKI (JP); HOM MA YOSHIO (JP); NOZAWA HISAO (JP); SATO AKIRA (JP)	US708 3-Jan-1979 79A
US4090006A	16-May-1978	Structure for making coplanar layers of thin films	HAVAS JANOS ; LECHATON JOHN S ; LOGAN SKINNER	US781 25-Mar-1977 24677A
US3669669A	13-Jun-1972	CYCLIC POLYISOPRENE PHOTORESIST COMPOSITIONS	KLEIN DONALD L ; MACINTYRE MICHAEL W ; ROTHMAN LAWRENCE J	US366 28-Oct-1970 9669D A